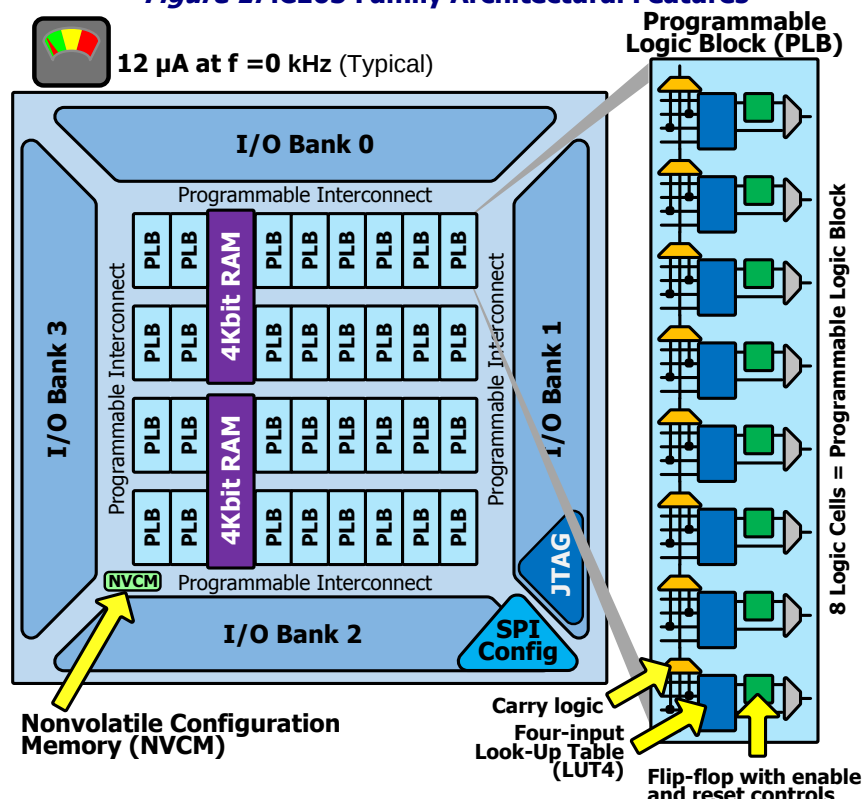


- **First high-density, ultra low-power single-chip, SRAM mobileFPGA family specifically designed for hand-held applications and long battery life**
  - ◆ 12  $\mu$ A in static mode
  - ◆ Two power/speed options
    - L: Low Power
    - T: High speed
- **Up to 256 MHz internal performance**
- **Reprogrammable from a variety of sources and methods**
  - ◆ Processor-like mode self-configures from external, commodity SPI serial Flash PROM
  - ◆ Downloaded by processor using SPI-like serial interface in as little as 20  $\mu$ s
  - ◆ In-system programmable, ASIC-like mode loads from secure, internal Nonvolatile Configuration Memory (NVCM)
    - Ideal for volume production
    - Superior design and intellectual property protection; no exposed data
- **Proven, high-volume 65 nm, low-power CMOS technology**
  - ◆ Low leakage,  $\mu$ W static power
  - ◆ Lower core voltage, lowest dynamic power
- **Flexible programmable logic and programmable interconnect fabric**
  - ◆ Over 7,600 look-up tables (LUT4) and flip-flops
  - ◆ Low-power logic and interconnect
- **Flexible I/O pins to simplify system interfaces**
  - ◆ Up to 222 programmable I/O pins
  - ◆ Four independently-powered I/O banks; support for 3.3V, 2.5V, 1.8V, and 1.5V voltage standards
  - ◆ LVCMOS, MDDR, LVDS, and SubLVDS I/O standards

**Figure 1: iCE65 Family Architectural Features**



- **Plentiful, fast, on-chip 4Kbit RAM blocks**
- **Low-cost, space-efficient packaging options**
  - ◆ Known-good die (KGD) options available
- **Complete iCEcube™ development system**
  - ◆ Windows® and Linux® support
  - ◆ VHDL and Verilog logic synthesis
  - ◆ Place and route software
  - ◆ Design and IP core libraries
  - ◆ Low-cost iCEman65 development board

**Table 1: iCE65 Ultra Low-Power Programmable Logic Family Summary**

|                                  | iCE65L01                    | iCE65L04                    | iCE65L08                    |
|----------------------------------|-----------------------------|-----------------------------|-----------------------------|
| Logic Cells (LUT + Flip-Flop)    | 1,280                       | 3,520                       | 7,680                       |
| RAM4K Memory Blocks              | 16                          | 20                          | 32                          |
| RAM4K RAM bits                   | 64K                         | 80K                         | 128K                        |
| Configuration bits (maximum)     | 245 Kb                      | 533 Kb                      | 1,057 Kb                    |
| Typical Current at 0 kHz, 1.0 V  | <b>12 <math>\mu</math>A</b> | <b>26 <math>\mu</math>A</b> | <b>54 <math>\mu</math>A</b> |
| Maximum Programmable I/O Pins    | 95                          | 176                         | 222                         |
| Maximum Differential Input Pairs | 0                           | 20                          | 25                          |

## Overview

The Lattice Semiconductor iCE65 programmable logic family is specifically designed to deliver the lowest static and dynamic power consumption of any comparable CPLD or FPGA device. iCE65 devices are designed for cost-sensitive, high-volume applications and provide on-chip, nonvolatile configuration memory (NVCM) to customize for a specific application. iCE65 devices can self-configure from a configuration image stored in an external commodity SPI serial Flash PROM or be downloaded from an external processor over an SPI-like serial port.

The three iCE65 components, highlighted in [Table 1](#), deliver from approximately 1K to nearly 8K logic cells and flip-flops while consuming a fraction of the power of comparable programmable logic devices. Each iCE65 device includes between 16 to 32 RAM blocks, each with 4Kbits of storage, for on-chip data storage and data buffering.

As pictured in [Figure 1](#), each iCE65 device consists of four primary architectural elements.

- An array of Programmable Logic Blocks (PLBs)
  - ◆ Each PLB contains eight Logic Cells (LCs); each Logic Cell consists of ...
    - A fast, four-input look-up table (LUT4) capable of implementing any combinational logic function of up to four inputs, regardless of complexity
    - A 'D'-type flip-flop with an optional clock-enable and set/reset control
    - Fast carry logic to accelerate arithmetic functions such as adders, subtracters, comparators, and counters.
  - ◆ Common clock input with polarity control, clock-enable input, and optional set/reset control input to the PLB is shared among all eight Logic Cells
- Two-port, 4Kbit RAM blocks (RAM4K)
  - ◆ 256x16 default configuration; selectable data width using programmable logic resources
  - ◆ Simultaneous read and write access; ideal for FIFO memory and data buffering applications
  - ◆ RAM contents pre-loadable during configuration
- Four I/O banks with independent supply voltage, each with multiple Programmable Input/Output (PIO) blocks
  - ◆ LVCMOS I/O standards and LVDS outputs supported in all banks
  - ◆ I/O Bank 3 supports additional SSTL, MDDR, LVDS, and SubLVDS I/O standards
- Programmable interconnections between the blocks
  - ◆ Flexible connections between all programmable logic functions
  - ◆ Eight dedicated low-skew, high-fanout clock distribution networks

## Packaging Options

iCE65 components are available in a variety of package options to support specific application requirements. The available options, including the number of available user-programmable I/O pins (PIOs), are listed in Table 2. Fully-tested Known-Good Die (KGD) DiePlus™ are available for die stacking and highly space-conscious applications. All iCE65 devices are provided exclusively in Pb-free, RoHS-compliant packages.

**Table 2: iCE65 Family Packaging Options, Maximum I/O per Package**

| Package                             | Package Body (mm)      | Package Code | Ball/Lead Pitch (mm) | 65L01                                                                                      | 65L04                                                                                        | 65L08    |
|-------------------------------------|------------------------|--------------|----------------------|--------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------|----------|
| 81-ball chip-scale BGA              | 5 x 5                  | CB81         | 0.5                  | 63 (0)                                                                                     | —                                                                                            | —        |
| 84-pin quad flat no-lead package    | 7 x 7                  | QN84         | 0.5                  | 67 (0)                                                                                     | —                                                                                            | —        |
| 100-pin very thin quad flat package | 14 x 14                | VQ100        | 0.5                  | 72 (0)  | 72 (9)                                                                                       | —        |
| 121-ball chip-scale BGA             | 6 x 6                  | CB121        | 0.5                  | 92 (0)                                                                                     | —                                                                                            | —        |
| 132-ball chip-scale BGA             | 8 x 8                  | CB132        |                      | 93 (0)  | 95 (11)   | 95 (12)  |
| 196-ball chip-scale BGA             | 8 x 8                  | CB196        |                      | —                                                                                          | 150 (18)  | 150 (18) |
| 284-ball chip-scale BGA             | 12 x 12                | CB284        |                      | —                                                                                          | 176 (20)  | 222 (25) |
| Known Good Die                      | See DiePlus data sheet | DI           | —                    | 95 (0)                                                                                     | 176 (20)                                                                                     | 222 (25) |

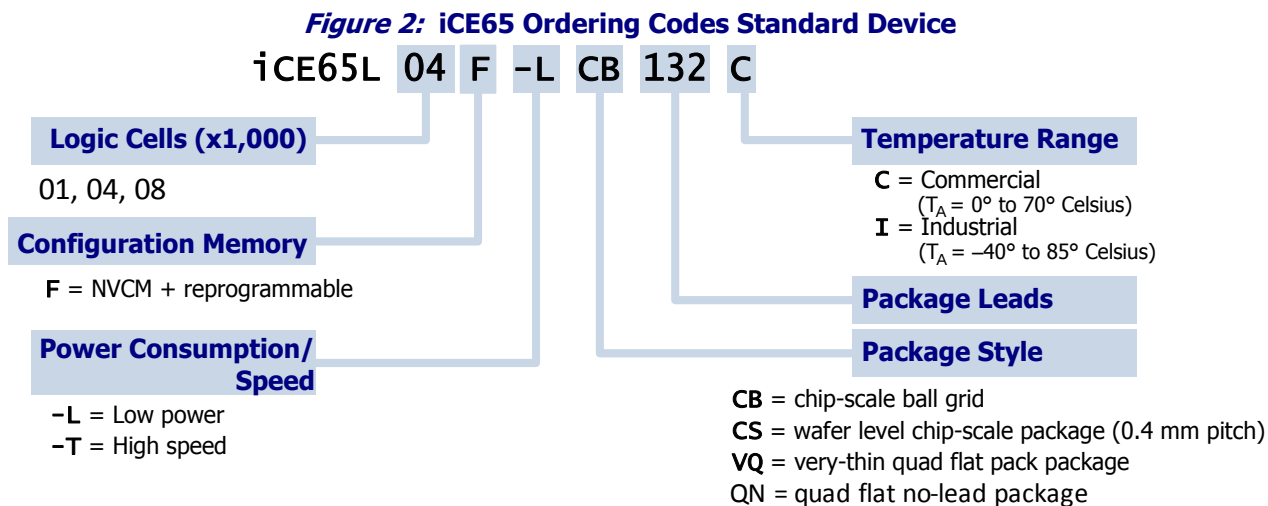
 = Common footprint allows each density migration on the same printed circuit board. (Differential input count).

The iCE65L04 and the iCE65L08 are both available in the CB196 package and have similar footprints but are not completely pin compatible. See “[Pinout Differences between iCE65L04 and iCE65L08 in CB196 Package](#)” on page 73 for more information.

When iCE65 components are supplied in the same package style, devices of different gate densities share a common footprint. The common footprint improves manufacturing flexibility. Different models of the same product can share a common circuit board. Feature-rich versions of the end application mount a larger iCE65 device on the circuit board. Low-end versions mount a smaller iCE65 device.

## Ordering Information

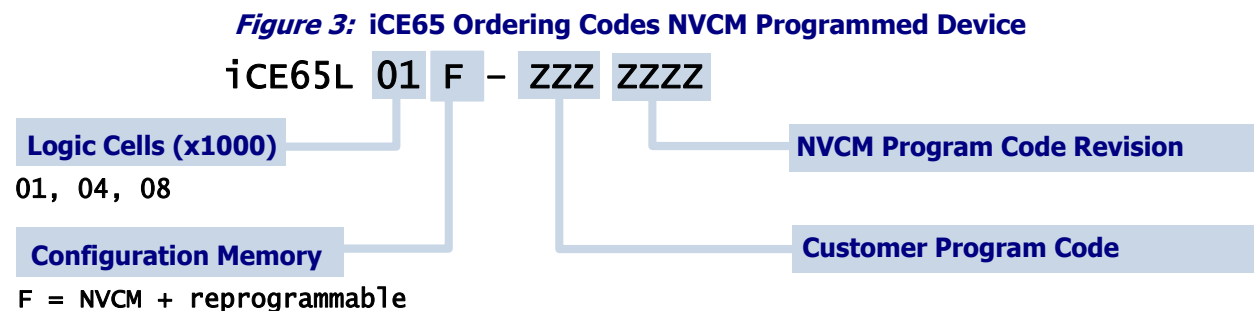
Figure 2 describes the iCE65 ordering codes for all packaged, non-NVCM Programmed components. See the separate DiePlus data sheets when ordering die-based products.



iCE65 devices offer two power consumption, speed options. Standard products (“-L” ordering code) have low standby and dynamic power consumption. The “-T” provides higher-speed logic.

Similarly, iCE65 devices are available in two operating temperature ranges, one for typical commercial applications, the other with an extended temperature range for industrial and telecommunications applications. The ordering code also specifies the device package option, as described further in Table 2.

Figure 3 describes the iCE65 ordering codes for all packaged, NVCM Programmed components.



## Programmable Logic Block (PLB)

Generally, a logic design for an iCE65 component is created using a high-level hardware description language such as Verilog or VHDL. The Lattice Semiconductor development software then synthesizes the high-level description into equivalent functions built using the programmable logic resources within each iCE65 device. Both sequential and combinational functions are constructed from an array of Programmable Logic Blocks (PLBs). Each PLB contains eight Logic Cells (LCs), as pictured in Figure 4, and share common control inputs, such as clocks, reset, and enable controls.

PLBs are connected to one another and other logic functions using the rich Programmable Interconnect resources.

### Logic Cell (LC)

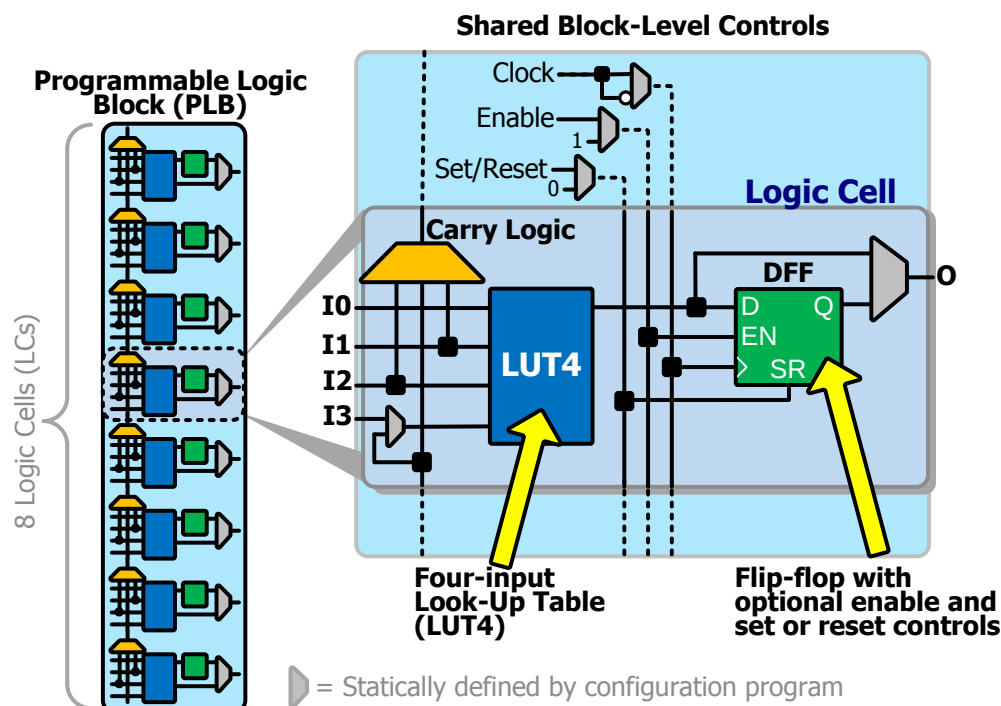
Each iCE65 device contains thousands of Logic Cells (LCs), as listed in Table 1. Each Logic Cell includes three primary logic elements, shown in Figure 4.

- A four-input **Look-Up Table (LUT4)** builds any combinational logic function, of any complexity, of up to four inputs. Similarly, the LUT4 element behaves as a 16x1 Read-Only Memory (ROM). Combine and cascade multiple LUT4s to create wider logic functions.

**Figure 4: Programmable Logic Block and Logic Cell**

- A **'D'-style Flip-Flop (DFF)**, with an optional clock-enable and reset control input, builds sequential logic functions. Each DFF also connects to a global reset signal that is automatically asserted immediately following device configuration.
- **Carry Logic** boosts the logic efficiency and performance of arithmetic functions, including adders, subtractors, comparators, binary counters and some wide, cascaded logic functions.

The output from a Logic Cell is available to all inputs to all eight Logic Cells within the Programmable Logic Block. Similarly, the Logic Cell output feeds into fabric to connect to other features on the iCE65 device.



**Look-Up Table (LUT4)**

The four-input Look-Up Table (LUT4) function implements any and all combinational logic functions, regardless of complexity, of between zero and four inputs. Zero-input functions include “High” (1) and “Low” (0). The LUT4 function has four inputs, labeled I0, I1, I2, and I3. Three of the four inputs are shared with the [Carry Logic](#) function, as shown in [Figure 4](#). The bottom-most LUT4 input connects either to the I3 input or to the Carry Logic output from the previous Logic Cell.

The output from the LUT4 function connects to the flip-flop within the same Logic Cell. The LUT4 output or the flip-flop output then connects to the programmable interconnect.

For detailed LUT4 internal timing, see [Table 54](#).

**‘D’-style Flip-Flop (DFF)**

The ‘D’-style flip-flop (DFF) optionally stores state information for the application.

The flip-flop has a data input, ‘D’, and a data output, ‘Q’. Additionally, each flip-flop has up to three control signals that are shared among all flip-flops in all Logic Cells within the PLB, as shown in [Figure 4](#). [Table 3](#) describes the behavior of the flip-flop based on inputs and upon the specific DFF design primitive used or synthesized.

**Table 3: ‘D’-Style Flip-Flop Behavior**

| DFF Primitive | Operation                               | Flip-Flop Mode     | Inputs |    |    |        | Output |
|---------------|-----------------------------------------|--------------------|--------|----|----|--------|--------|
|               |                                         |                    | D      | EN | SR | CLK    | Q      |
| All           | Cleared Immediately after Configuration | X                  | X      | X  | X  | X      | 0      |
|               | Hold Present Value (Disabled)           |                    | X      | 0  | X  | X      | Q      |
|               | Hold Present Value (Static Clock)       |                    | X      | X  | X  | 1 or 0 | Q      |
|               | Load with Input Data                    |                    | D      | 1* | 0* | ↑      | D      |
| SB_DFFR       | Asynchronous Reset                      | Asynchronous Reset | X      | X  | 1  | X      | 0      |
| SB_DFFS       | Asynchronous Set                        | Asynchronous Set   | X      | X  | 1  | X      | 1      |
| SB_DFFSR      | Synchronous Reset                       | Synchronous Reset  | X      | 1* | 1  | ↑      | 0      |
| SB_DFFSS      | Synchronous Set                         | Synchronous Set    | X      | 1* | 1  | ↑      | 1      |

X = don't care, ↑ = rising clock edge (default polarity), 1\* = High or unused, 0\* = Low or unused

The CLK clock signal is not optional and is shared among all flip-flops in a Programmable Logic Block. By default, flip-flops are clocked by the rising edge of the PLB clock input, although the clock polarity can be inverted for all the flip-flops in the PLB.

The CLK input optionally connects to one of the following clock sources.

- The output from any one of the eight [Global Buffers](#), or
- A connection from the general-purpose interconnect fabric

The EN clock-enable signal is common to all Logic Cells in a Programmable Logic Block. If the enable signal is not used, then the flip-flop is always enabled. This condition is indicated as “1\*” in [Table 3](#). The asterisk indicates that this is the default state if the control signal is not connected in the application.

Similarly, the SR set/reset signal is common to all Logic Cells in a Programmable Logic Block. If not used, then the flip-flop is never set/reset, except when cleared immediately after configuration or by the Global Reset signal. This condition is indicated as “0\*” in [Table 3](#). The asterisk indicates that this is the default state if the control signal is not connected in the application.

Each flip-flop has an additional control that defines its set or reset behavior. As defined in the configuration image, the control defines whether the set or reset operation is synchronized to the active CLK clock edge or whether it is completely asynchronous.

- The SB\_DFFR and SB\_DFFS primitives are asynchronously controlled, solely by the SR input. If the SR input is High, then an SB\_DFFR primitive is asynchronously reset and an SB\_DFFS primitive is asynchronously set.
- The SB\_DFFSR and SB\_DFFRSS primitives are synchronously controlled by both the SR input and the clock input. If the SR input is High at a rising edge of the clock input, then an SB\_DFFSR primitive is synchronously reset and an SB\_DFFSS primitive is synchronously set.

The LUT4 output or the flip-flop output then connects to the programmable interconnect.

Because of the shared control signals, the design software can pack flip-flops with common control inputs into a single PLB block, as described by Table 4. There are eight total packing options.

**Table 4: Flip-flop Packing/Sharing within a PLB**

| Group | Active Clock Edge | Clock Enable                               | Set or Reset Control (Sync. or Async) |
|-------|-------------------|--------------------------------------------|---------------------------------------|
| 1     | ↑                 | None (always enabled)                      | None                                  |
| 2     | ↓                 |                                            | PLB set/reset control                 |
| 3     | ↑                 |                                            |                                       |
| 4     | ↓                 |                                            | None                                  |
| 5     | ↑                 | Selective (controlled by PLB clock enable) | None                                  |
| 6     | ↓                 |                                            | PLB set/reset control                 |
| 7     | ↑                 |                                            |                                       |
| 8     | ↓                 |                                            | PLB set/reset control                 |

For detailed flip-flop internal timing, see Table 54.

## Carry Logic

The dedicated Carry Logic within each Logic Cell primarily accelerates and improves the efficiency of arithmetic logic such as adders, accumulators, subtractors, incrementers, decrementers, counters, ALUs, and comparators. The Carry Logic also supports wide combinational logic functions.

$$\text{COUT} = \text{I1} \bullet \text{I2} + \text{CIN} \bullet \text{I1} + \text{CIN} \bullet \text{I2} \quad [\text{Equation 1}]$$

Equation 1 and Figure 5 describe the Carry Logic structure within a Logic Cell. The Carry Logic shares inputs with the associated Look-Up Table (LUT4). The LUT4's I1 and I2 inputs directly feed the Carry Logic; inputs I0 and I3 do not. A signal cascades between Logic Cells within the Programmable Logic Block. The carry input from the previous adjacent Logic Cell optionally provides an alternate input to the LUT4 function, supplanting the I3 input.

### Low-Power Disable

To save power and prevent unnecessary signal switching, the Carry Logic function within a Logic Cell is disabled if not used. The output of a Logic Cell's Carry Logic is forced High.

### PLB Carry Input and Carry Output Connections

As shown in Figure 5, each Programmable Logic Block has a carry input signal that can be initialized High, Low, or come from the carry output signal from PLB immediately below.

Similarly, the Carry Logic output from the Programmable Logic Block connects to the PLB immediately above, which allows the Carry Logic to span across multiple PLBs in a column. As shown in Figure 6, the Carry Logic chain can be tapped mid-way through a chain or a PLB by feeding the value through a LUT4 function.

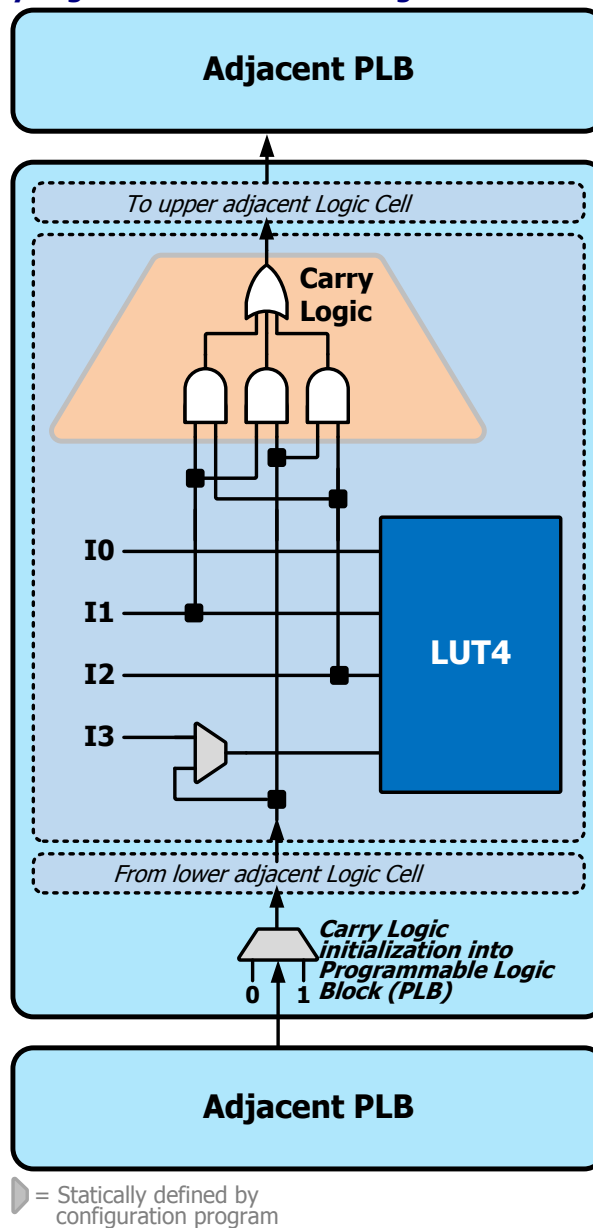
### Adder Example

Figure 6 shows an example design that uses the Carry Logic. The example is a 2-bit adder, which can be expanded into an adder of arbitrary size. The LUT4 function within a Logic Cell is programmed to calculate the sum of the two input values and the carry input,  $A[i] + B[i] + \text{CARRY\_IN}[i-1] = \text{SUM}[i]$ .

The Carry Logic generates the carry value to feed the next bit in the adder. The calculated carry value replaces the I3 input to the next LUT4 in the upper Logic Cell.

If required by the application, the carry output from the final stage of the adder is available by passing it through the final LUT4.

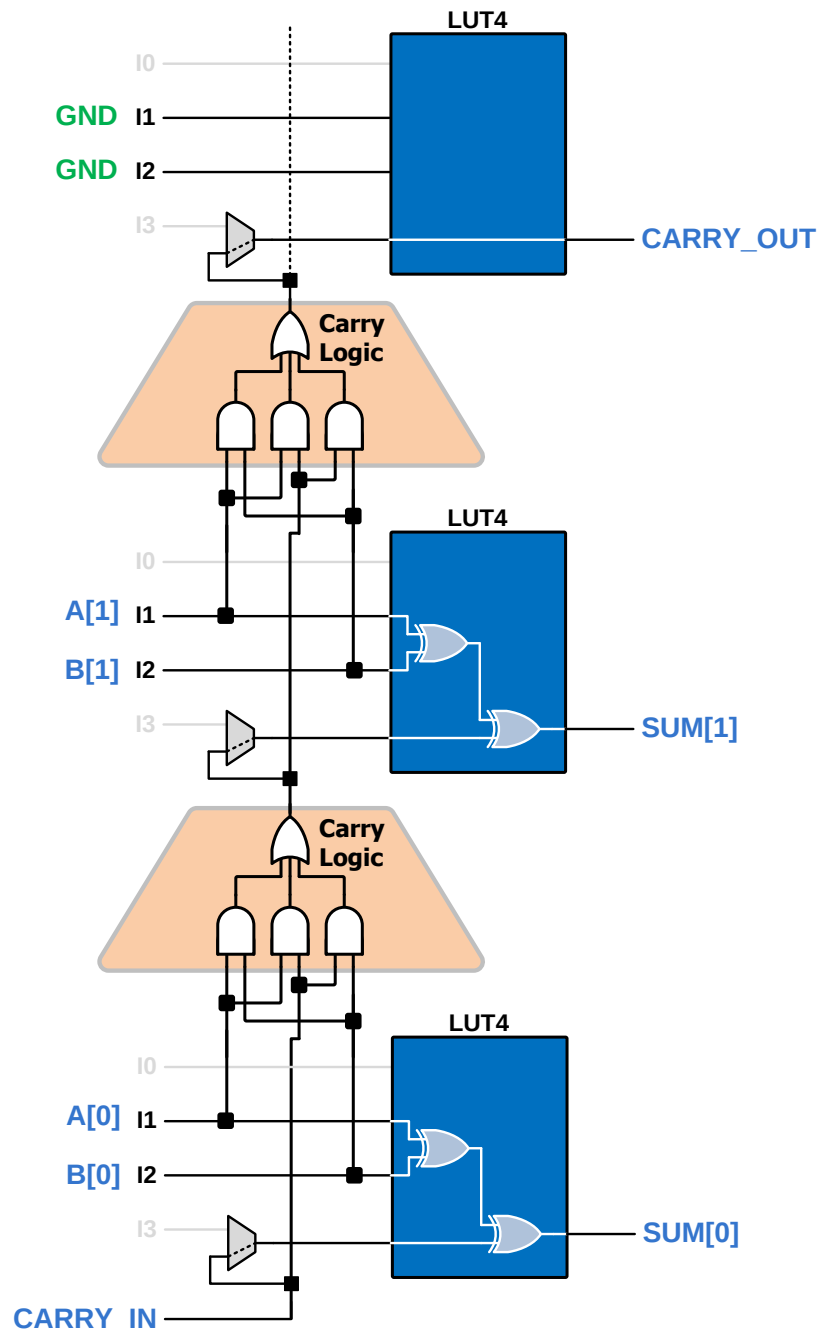
**Figure 5: Carry Logic Structure within a Logic Cell and between PLBs**



## Implementing Subtractors, Decrementers

As mentioned earlier, the Carry Logic generates a High output whenever the sum of  $I1 + I2 + \text{CARRY\_IN}$  generates a carry. The Carry Logic does not specifically have a subtract mode. To implement a subtract function or decrement function, logically invert either the  $I1$  or  $I2$  input and invert the initial carry input. This performs a 2s complement subtract operation.

**Figure 6: Two-bit Adder Example**

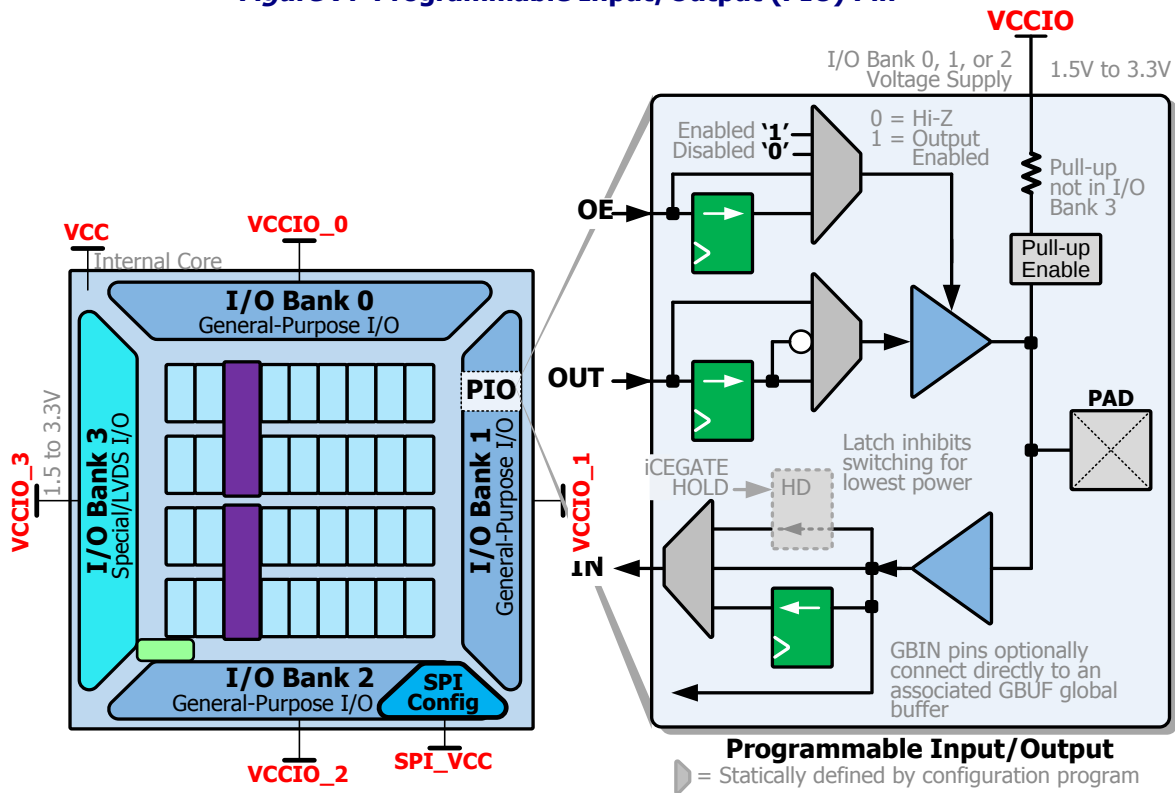


Programmable Input/Output Block (PIO)

Programmable Input/Output (PIO) blocks surround the periphery of the device and connect external components to the Programmable Logic Blocks (PLBs) and RAM4K blocks via programmable interconnect. Individual PIO pins are grouped into one of four I/O banks, as shown in Figure 7. I/O Bank 3 has additional capabilities, including LVDS differential I/O and the ability to interface to Mobile DDR memories.

Figure 7 also shows the logic within a PIO pin. When used in an application, a PIO pin becomes a signal input, an output, or a bidirectional I/O pin with a separate direction control input.

Figure 7: Programmable Input/Output (PIO) Pin



I/O Banks

PIO blocks are organized into four separate I/O banks, each with its own voltage supply input, as shown in Table 5. The voltage applied to the VCCIO pin on a bank defines the I/O standard used within the bank. Table 50 and Table 51 describe the I/O drive capabilities and switching thresholds by I/O standard. On iCE65L04 and iCE65L08 devices, I/O Bank 3, along the left edge of the die, is different than the others and supports specialized I/O standards.

I/O Bank Voltage Supply Inputs Support Different I/O Standards

Because each I/O bank has its own voltage supply, iCE65 components become the ideal bridging device between different interface standards. For example, the iCE65 device allows a 1.8V-only processor to interface cleanly with a 3.3V bus interface. The iCE65 device replaces external voltage translators.

Table 5: Supported Voltages by I/O Bank

| Bank | Device Edge  | Supply Input | 3.3V | 2.5V | 1.8V | 1.5V                                       |
|------|--------------|--------------|------|------|------|--------------------------------------------|
| 0    | Top          | VCCIO_0      | Yes  | Yes  | Yes  | Outputs only                               |
| 1    | Right        | VCCIO_1      | Yes  | Yes  | Yes  | Outputs only                               |
| 2    | Bottom       | VCCIO_2      | Yes  | Yes  | Yes  | Outputs only                               |
| 3    | Left         | VCCIO_3      | Yes  | Yes  | Yes  | iCE65L01: Outputs only<br>iCE65L04/08: Yes |
| SPI  | Bottom Right | SPI_VCC      | Yes  | Yes  | Yes  | No                                         |

If not connected to an external SPI PROM, the four pins associated with the [SPI Master Configuration Interface](#) can be used as PIO pins, supplied by the SPI\_VCC input, essentially forming a fifth “mini” I/O bank. If using an SPI Flash PROM, then connect SPI\_VCC to 3.3V.

### I/O Banks 0, 1, 2, SPI and Bank 3 of iCE65L01

[Table 6](#) highlights the available I/O standards when using an iCE65 device, indicating the drive current options, and in which bank(s) the standard is supported. I/O Banks 0, 1, 2 and SPI interface support the same standards. I/O Bank 3 has additional capabilities in iCE65L04 and iCE65L08, including support for MDDR memory standards and LVDS differential I/O.

**Table 6: I/O Standards for I/O Banks 0, 1, 2, SPI Interface Bank, and Bank 3 of iCE65L01**

| I/O Standard       | Supply Voltage | Drive Current (mA) | Attribute Name |
|--------------------|----------------|--------------------|----------------|
| 5V Input Tolerance | 3.3V           | N/A                | N/A            |
| LVCNOS33           | 3.3V           | ±11                | SB_LVCNOS      |
| LVCNOS25           | 2.5V           | ±8                 |                |
| LVCNOS18           | 1.8V           | ±5                 |                |
| LVCNOS15 outputs   | 1.5V           | ±4                 |                |

### IBIS Models for I/O Banks 0, 1, 2 and the SPI Bank

The IBIS (I/O Buffer Information Specification) file that describes the output buffers used in I/O Banks 0, 1, 2, SPI Bank and Bank 3 of iCE65L01 is available from the following link.

- [IBIS Models for I/O Banks 0, 1, 2, SPI Bank and Bank 3 of iCE65L01](#)

### I/O Bank 3 of iCE65L04 and iCE65L08

I/O Bank 3, located along the left edge of the die, has additional special I/O capabilities to support memory components and differential I/O signaling (LVDS). [Table 7](#) lists the various I/O standards supported by I/O Bank 3. The SSTL2 and SSTL18 I/O standards require the VREF voltage reference input pin which is only available on the CB284 package. Also see [Table 5I](#) for electrical characteristics.

**Table 7: I/O Standards for I/O Bank 3 Only of iCE65L04 and iCE65L08**

| I/O Standard | Supply Voltage | VREF Pin (CB284 or DiePlus) Required? | Target Drive Current (mA) | Attribute Name   |
|--------------|----------------|---------------------------------------|---------------------------|------------------|
| LVCNOS33     | 3.3V           | No                                    | ±8                        | SB_LVCNOS33_8    |
| LVCNOS25     | 2.5V           | No                                    | ±16                       | SB_LVCNOS25_16   |
|              |                |                                       | ±12                       | SB_LVCNOS25_12   |
|              |                |                                       | ±8                        | SB_LVCNOS25_8    |
|              |                |                                       | ±4                        | SB_LVCNOS25_4    |
|              |                |                                       |                           |                  |
| LVCNOS18     | 1.8V           | No                                    | ±10                       | SB_LVCNOS18_10   |
|              |                |                                       | ±8                        | SB_LVCNOS18_8    |
|              |                |                                       | ±4                        | SB_LVCNOS18_4    |
|              |                |                                       | ±2                        | SB_LVCNOS18_2    |
| LVCNOS15     | 1.5V           | No                                    | ±4                        | SB_LVCNOS15_4    |
|              |                |                                       | ±2                        | SB_LVCNOS15_2    |
| SSTL2_II     | 2.5V           | Yes                                   | ±16.2                     | SB_SSTL2_CLASS_2 |
| SSTL2_I      |                |                                       | ±8.1                      | SB_SSTL2_CLASS_1 |
| SSTL18_II    | 1.8V           | Yes                                   | ±13.4                     | SB_SSTL18_FULL   |
| SSTL18_I     |                |                                       | ±6.7                      | SB_SSTL18_HALF   |
| MDDR         | 1.8V           | No                                    | ±10                       | SB_MDDR10        |
|              |                |                                       | ±8                        | SB_MDDR8         |
|              |                |                                       | ±4                        | SB_MDDR4         |
|              |                |                                       | ±2                        | SB_MDDR2         |
| LVDS         | 2.5V           | No                                    | N/A                       | SB_LVDS_INPUT    |

Table 8 lists the I/O standards that can co-exist in I/O Bank 3, depending on the VCCIO\_3 voltage.

**Table 8: Compatible I/O Standards in I/O Bank 3 of iCE65L04 and iCE65L08**

| VCCIO_3 Voltage          | 3.3V          | 2.5V                                                                     | 1.8V                                                                                                                  | 1.5V            |
|--------------------------|---------------|--------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------|-----------------|
| Compatible I/O Standards | SB_LVCMOS33_8 | Any SB_LVCMOS25<br>SB_SSTL2_Class_2<br>SB_SSTL2_Class_1<br>SB_LVDS_INPUT | Any SB_LVCMOS18<br>SB_SSTL18_FULL<br>SB_SSTL18_HALF<br>SB_MDDR10<br>SB_MDDR8<br>SB_MDDR4<br>SB_MDDR2<br>SB_LVDS_INPUT | Any SB_LVCMOS15 |

## Programmable Output Drive Strength

Each PIO in I/O Bank 3 offers programmable output drive strength, as listed in Table 8. For the LVCMOS and MDDR I/O standards, the output driver has settings for static drive currents ranging from 2 mA to 16 mA output drive current, depending on the I/O standard and supply voltage.

The SSTL18 and SSTL2 I/O standards offer full- and half-strength drive current options

## Differential Inputs and Outputs

All PIO pins support “single-ended” I/O standards, such as LVCMOS. However, iCE65 FPGAs also support differential I/O standards where a single data value is represented by two complementary signals transmitted or received using a pair of PIO pins. The PIO pins in I/O Bank 3 of iCE65L04 and iCE65L08 support Low-Voltage Differential Swing (LVDS) and SubLVDS inputs as shown in Figure 8. Differential outputs are available in all four I/O banks.

### Differential Inputs Only on I/O Bank 3 of iCE65L04 and iCE65L08

Differential receivers are required for popular applications such as LVDS and LVPECL clock inputs, camera interfaces, and for various telecommunications standards.

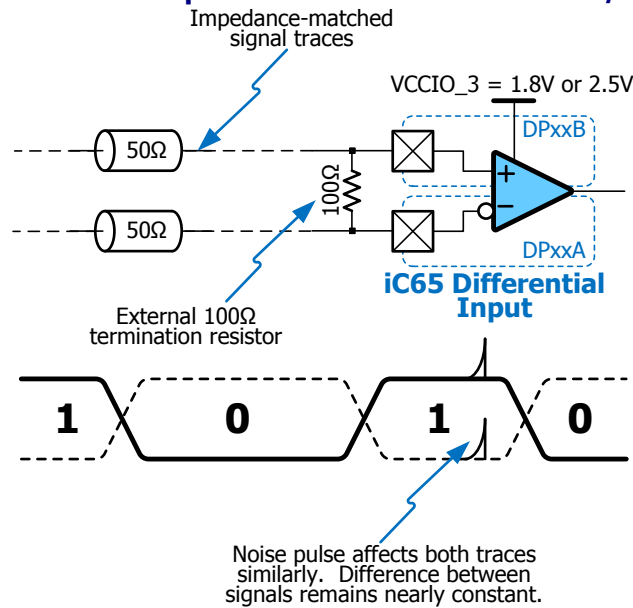
Specific pairs of PIO pins in I/O Bank 3 form a differential input. Each pair consists of a DPxxA and DPxxB pin, where “xx” represents the pair number. The DPxxB receives the true version of the signal while the DPxxA receives the complement of the signal. Typically, the resulting signal pair is routed on the printed circuit board (PCB) with matched 50Ω signal impedance. The differential signaling, the low voltage swing, and the matched signal routing are ideal for communicating very-high frequency signals. Differential signals are generally also more tolerant of system noise and generate little EMI themselves.

The LVDS input circuitry requires 2.5V on the VCCIO\_3 voltage supply. Similarly, the SubLVDS input circuitry requires 1.8V on the VCCIO\_3 voltage supply. For electrical specifications, see “Differential Inputs” on page 100.

Each differential input pair requires an external 100 Ω termination resistor, as shown in Figure 8.

The PIO pins that make up a differential input pair are indicated with a blue bounding box in the footprint diagrams and in the pinout tables.

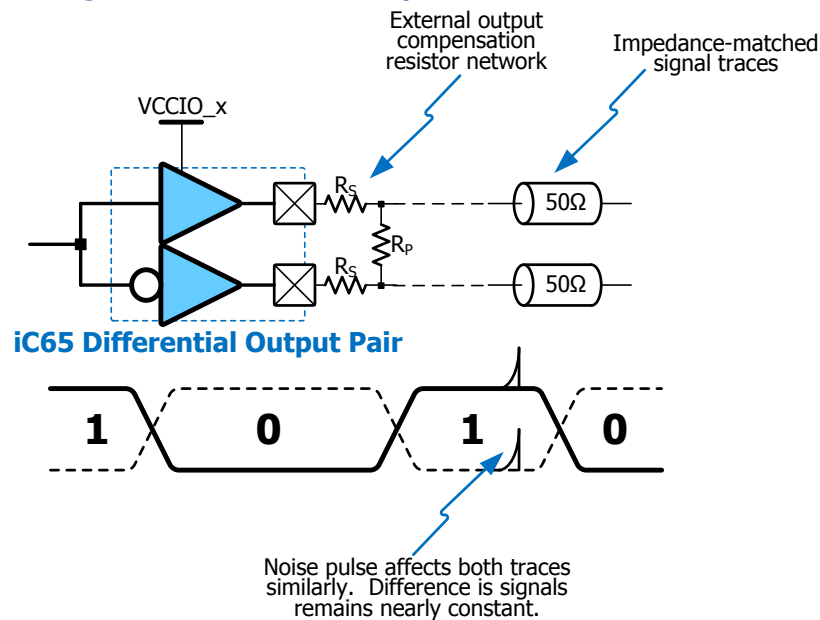
**Figure 8: Differential Inputs in iCE65L04 and iCE65L08 I/O Bank 3**



### Differential Outputs in Any Bank

Differential outputs are built using a pair of single-ended PIO pins as shown in Figure 9. Each differential I/O pair requires a three-resistor termination network to adjust output characteristic to match those for the specific differential I/O standard. The output characteristics depend on the values of the parallel resistors ( $R_P$ ) and series resistor ( $R_S$ ). Differential outputs must be located in the same I/O tile.

**Figure 9: Differential Output Pair**



For electrical characteristics, see “Differential Outputs” on page 100.

The PIO pins that make up a differential output pair are indicated with a blue bounding box in the in the tables in “Die Cross Reference” starting on page 84.

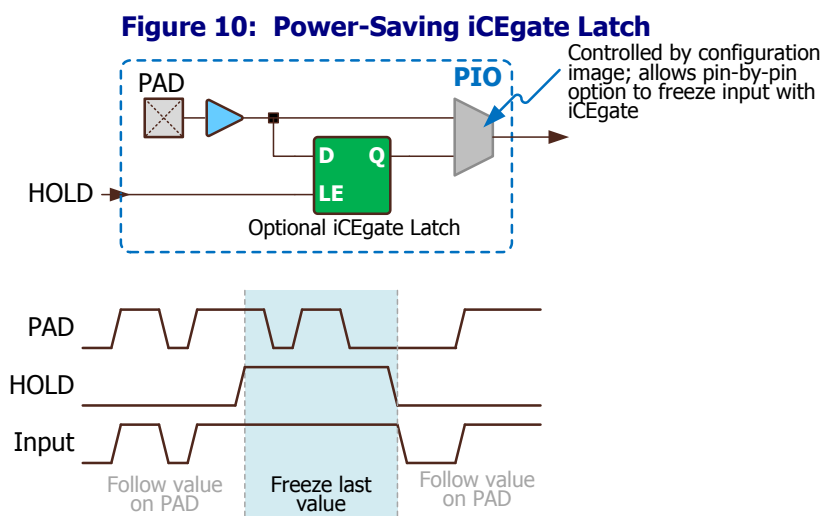
## Input Signal Path

As shown in Figure 7, a signal from a package pin optionally feeds directly into the device, or is held in an input register. The input signal connects to the programmable interconnect resources through the IN signal. Table 9 describes the input behavior, assuming that the output path is not used or if a bidirectional I/O, that the output driver is in its high-impedance state (Hi-Z). Table 9 also indicates the effect of the Power-Saving I/O Bank iCEgate Latch and the Input Pull-Up Resistors on I/O Banks 0, 1, and 2.

See Input and Output Register Control per PIO Pair for information about the registered input path.

### Power-Saving I/O Bank iCEgate Latch

To save power, the optional iCEgate latch can selectively freeze the state of individual, non-registered inputs within an I/O bank. Registered inputs are effectively frozen by their associated clock or clock-enable control. As shown in Figure 10, the iCEgate HOLD control signal captures the external value from the associated asynchronous input. The HOLD signal prevents switching activity on the PIO pad from affecting internal logic or programmable interconnect. Minimum power consumption occurs when there is no switching. However, individual pins within the I/O bank can bypass the iCEgate latch and directly feed into the programmable interconnect, remaining active during low-power operation. This behavior is described in Table 9. The decision on which asynchronous inputs use the iCEgate feature and which inputs bypass it is determined during system design. In other words, the iCEgate function is part of the source design used to create the iCE65 configuration image.



**Table 9: PIO Non-Registered Input Operations**

| Operation                                | HOLD          | Bitstream Setting      |                        | PAD       | IN                          |
|------------------------------------------|---------------|------------------------|------------------------|-----------|-----------------------------|
|                                          | iCEgate Latch | Controlled by iCEgate? | Input Pull-Up Enabled? | Pin Value | Input Value to Interconnect |
| Data Input                               | 0             | X                      | X                      | PAD       | PAD Value                   |
| Pad Floating, No Pull-up                 | 0             | X                      | No                     | Z         | (Undefined)                 |
| Pad Floating, Pull-up                    | 0             | X                      | Yes                    | Z         | 1                           |
| Data Input, Latch Bypassed               | X             | No                     | X                      | PAD       | PAD Value                   |
| Pad Floating, No Pull-up, Latch Bypassed | X             | No                     | No                     | Z         | (Undefined)                 |
| Pad Floating, Pull-up, Latch Bypassed    | X             | No                     | Yes                    | Z         | 1                           |
| Low Power Mode, Hold Last Value          | 1             | Yes                    | X                      | X         | Last Captured PAD Value     |

There are four iCEgate HOLD controls, one per each I/O bank. The iCEgate HOLD control input originates within the interconnect fabric, near the middle of the I/O edge. Consequently, the HOLD signal is optionally controlled externally through a PIO pin or from other logic within the iCE65 device.

**i** For best possible performance, the global buffer inputs (GBIN[7:0]) connect directly to the their associated global buffers (GBUF[7:0]), bypassing the PIO logic and iCEgate circuitry as shown in [Figure 7](#). Consequently, the direct GBIN-to-GBUF connection cannot be blocked by the iCEgate circuitry. However, it is possible to use iCEgate to block PIO-to-GBUF clock connections.

For additional information on using the iCEgate feature, please refer to the following application note.

AN002: Using iCEgate Blocking for Ultra-Low Power

### **Input Pull-Up Resistors on I/O Banks 0, 1, and 2**

The PIO pins in I/O Banks 0, 1, and 2 have an optional input pull-up resistor. Pull-up resistors are not provided in iCE65L04 and iCE65L08 I/O Bank 3. During the iCE65 configuration process, the input pull-up resistor is unconditionally enabled and pulls the input to within a diode drop of the associated I/O bank supply voltage (VCCIO\_#). This prevents any signals from floating on the circuit board during configuration.

After iCE65 configuration is complete, the input pull-up resistor is optional, defined by a configuration bit. The pull-up resistor is also useful to tie off unused PIO pins. The Lattice iCEcube development software defines all unused PIO pins in I/O Banks 0, 1 and 2 as inputs with the pull-up resistor turned on. The pull-up resistor value depends on the VCCIO voltage applied to the bank, as shown in [Table 49](#).



Note: JTAG inputs TCK, TDI and TMS do not have the input pull-up resistor and must be tied off to GND when unused, else VCCIO\_1 draws current.

### **No Input Pull-up Resistors on I/O Bank 3 of iCE65L04 and iCE65L08**

The PIO pins in I/O Bank 3 do not have an internal pull-up resistor. To minimize power consumption, tie unused PIO pins in Bank 3 to a known logic level or drive them as a disabled high-impedance output.

### **Input Hysteresis**

Inputs typically have about 50 mV of hysteresis, as indicated in [Table 49](#).

### **Output and Output Enable Signal Path**

As shown in [Figure 7](#), a signal from programmable interconnect feeds the OUT signal on a Programmable I/O pad. This output connects either directly to the associated package pin or is held in an optional output flip-flop. Because all flip-flops are automatically reset after configuration, the output from the output flip-flop can be optionally inverted so that an active-Low output signal is held in the disabled (High) state immediately after configuration.

Similarly, each Programmable I/O pin has an output enable or three-state control called OE. When OE = High, the OUT output signal drives the associated pad, as described in [Table 10](#). When OE = Low, the output driver is in the high-impedance (Hi-Z) state. The OE output enable control signal itself connects either directly to the output buffer or is held in an optional register. The output buffer is optionally permanently enabled or permanently disabled, either to unconditionally drive output signals, or to allow input-only signals.

**Table 10: PIO Output Operations (non-registered operation, no inversions)**

| Operation                | OUT         | OE     | PAD  |
|--------------------------|-------------|--------|------|
|                          | Data Output | Enable |      |
| <b>Three-State</b>       | X           | 0      | Hi-Z |
| <b>Drive Output Data</b> | OUT         | 1*     | OUT  |

X = don't care, 1\* = High or unused, Hi-Z = high-impedance, three-stated, floating.

See [Input and Output Register Control per PIO Pair](#) for information about the registered input path.

## Input and Output Register Control per PIO Pair

PIO pins are grouped into pairs for synchronous control. Registers within pairs of PIO pins share common input clock, output clock, and I/O clock enable control signals, as illustrated in Figure 11. The combinational logic paths are removed from the drawing for clarity.

The INCLK clock signal only controls the input flip-flops within the PIO pair.

The OUTCLK clock signal controls the output flip-flops and the output-enable flip-flops within the PIO pair.

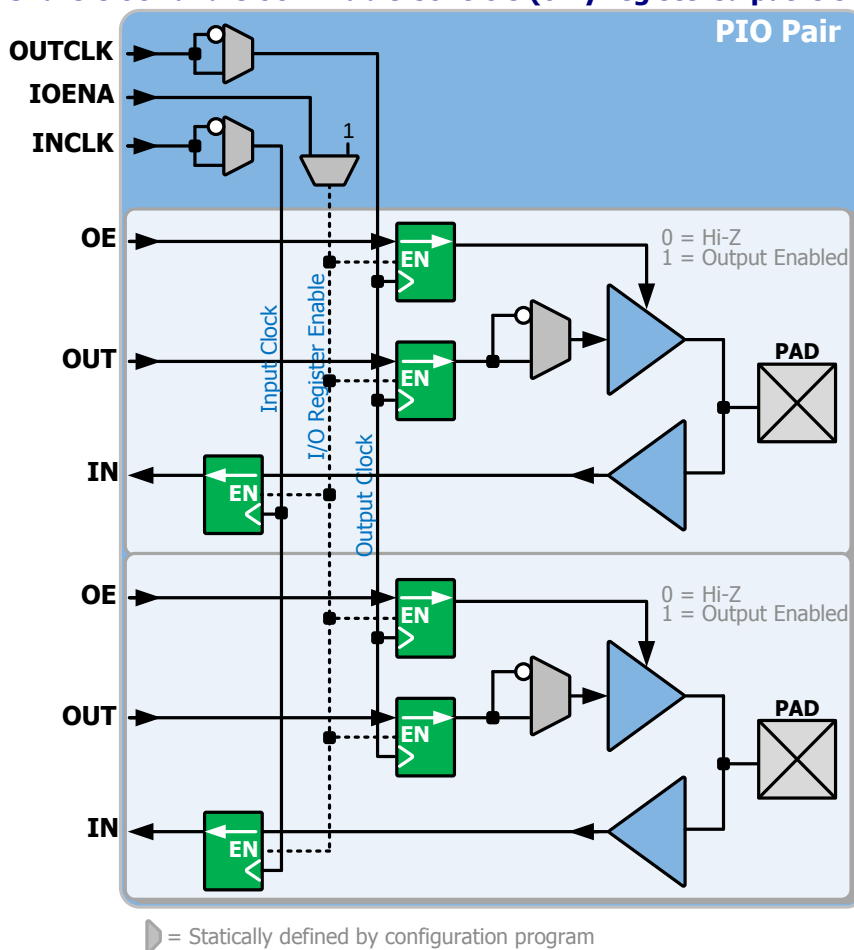
If desired in the iCE65 application, the INCLK and OUTCLK signals can be connected together.

The IOENA clock-enable input, if used, enables all registers in the PIO pair, as shown in Figure 11. By default, the registers are always enabled.



Before laying out your printed-circuit board, run the design through the iCEcube development software to verify that your selected pinout complies with these I/O register pairing requirements. See tables in “Die Cross Reference” starting on page 84.

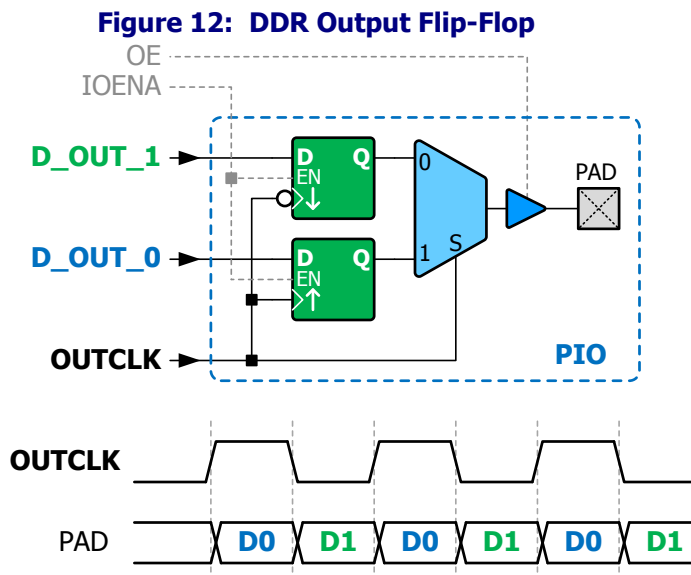
**Figure 11: PIO Pairs Share Clock and Clock Enable Controls (only registered paths shown for clarity)**



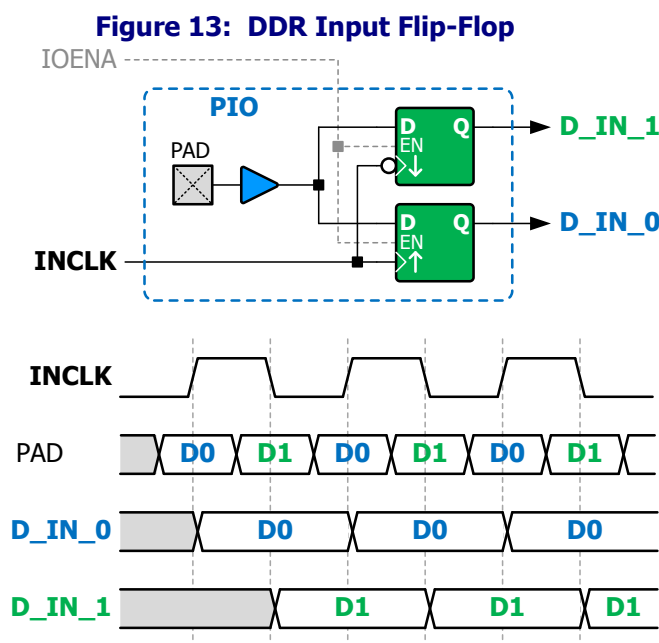
The pairing of PIO pairs is most evident in the tables in “Die Cross Reference” starting on page 84.

## Double Data Rate (DDR) Flip-Flops

Each individual PIO pin optionally has two sets of double data rate (DDR) flip-flops; one input pair and one output pair. Figure 12 demonstrates the functionality of the output DDR flip-flop. Two signals from within the iCE65 device drive the DDR output flip-flop. The D\_OUT\_0 signal is clocked by the rising edge of the OUTCLK signal while the D\_OUT\_1 signal is clocked by the falling edge of the OUTCLK signal, assuming no optional clock polarity inversion. Internally, the two individual flip-flops are multiplexed together before the data appears at the pad, effectively doubling the output data rate.



Similarly, Figure 13 demonstrates the DDR input flip-flop functionality. A double data rate (DDR) signal arrives at the pad. Internally, one value is clocked by the rising edge of the INCLK signal and another value is clocked by the falling edge of the INCLK signal. The DDR data stream is effectively de-multiplexed within the PIO pin and presented to the programmable interconnect on D\_IN\_0 and D\_IN\_1.



The DDR flip-flops provide several design advantages. Internally within the iCE65 device, the clock frequency is half the effective external data rate. The lower clock frequency eases internal timing, doubling the clock period, and slashes the clock-related power in half.

## Global Routing Resources

### Global Buffers

Each iCE65 component has eight global buffer routing connections, illustrated in Figure 14. There are eight high-drive buffers, connected to the eight low-skew, global lines. These lines are designed primarily for clock distribution but are also useful for other high-fanout signals such as set/reset and enable signals. The global buffers originate either from the Global Buffer Inputs (GBINx) or from programmable interconnect. The associated GBINx pin represents the best pin to drive a global buffer from an external source. However, the application with an iCE65 FPGA can also drive a global buffer via any other PIO pin or from internal logic using the programmable interconnect.

If not used in an application, individual global buffers are turned off to save power.

**Figure 14: High-drive, Low-skew, High-fanout Global Buffer Routing Resources**

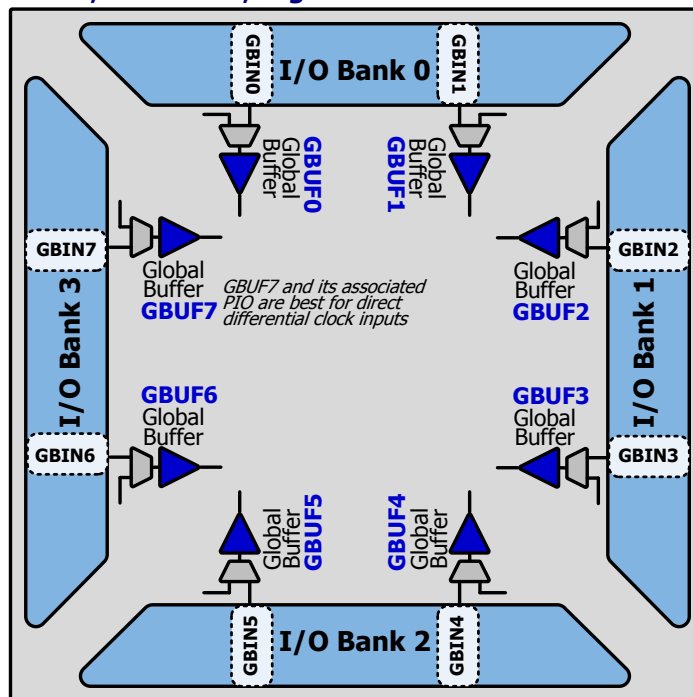


Table 11 lists the connections between a specific global buffer and the inputs on a Programmable Logic Block (PLB). All global buffers optionally connect to all clock inputs. Any four of the eight global buffers can drive logic inputs to a PLB. Even-numbered global buffers optionally drive the Reset input to a PLB. Similarly, odd-numbered buffers optionally drive the PLB clock-enable input.

**Table 11: Global Buffer (GBUF) Connections to Programmable Logic Block (PLB)**

| Global Buffer | LUT Inputs                      | Clock | Clock Enable | Reset |
|---------------|---------------------------------|-------|--------------|-------|
| <b>GBUF0</b>  | Yes, any 4 of 8<br>GBUF buffers | Yes   | Yes          | No    |
| <b>GBUF1</b>  |                                 | Yes   | No           | Yes   |
| <b>GBUF2</b>  |                                 | Yes   | Yes          | No    |
| <b>GBUF3</b>  |                                 | Yes   | No           | Yes   |
| <b>GBUF4</b>  |                                 | Yes   | Yes          | No    |
| <b>GBUF5</b>  |                                 | Yes   | No           | Yes   |
| <b>GBUF6</b>  |                                 | Yes   | Yes          | No    |
| <b>GBUF7</b>  |                                 | Yes   | No           | Yes   |

Table 12 and Table 13 list the connections between a specific global buffer and the inputs on a Programmable I/O (PIO) pair. Although there is no direct connection between a global buffer and a PIO output, such a connection is possible by first connecting through a PLB LUT4 function. Again, all global buffers optionally drive all clock inputs. However, even-numbered global buffers optionally drive the clock-enable input on a PIO pair.



The PIO clock enable connect is different between the iCE65L01/iCE65L04 and iCE65L08.

**Table 12: iCE65L01 & iCE65L04: Global Buffer (GBUF) Connections to Programmable I/O (PIO) Pair**

| Global Buffer | Output Connections           | Input Clock | Output Clock | Clock Enable |
|---------------|------------------------------|-------------|--------------|--------------|
| <b>GBUF0</b>  | No (connect through PLB LUT) | Yes         | Yes          | No           |
| <b>GBUF1</b>  |                              | Yes         | Yes          | Yes          |
| <b>GBUF2</b>  |                              | Yes         | Yes          | No           |
| <b>GBUF3</b>  |                              | Yes         | Yes          | Yes          |
| <b>GBUF4</b>  |                              | Yes         | Yes          | No           |
| <b>GBUF5</b>  |                              | Yes         | Yes          | Yes          |
| <b>GBUF6</b>  |                              | Yes         | Yes          | No           |
| <b>GBUF7</b>  |                              | Yes         | Yes          | Yes          |

**Table 13: iCE64L08: Global Buffer (GBUF) Connections to Programmable I/O (PIO) Pair**

| Global Buffer | Output Connections           | Input Clock | Output Clock | Clock Enable |
|---------------|------------------------------|-------------|--------------|--------------|
| <b>GBUF0</b>  | No (connect through PLB LUT) | Yes         | Yes          | Yes          |
| <b>GBUF1</b>  |                              | Yes         | Yes          | No           |
| <b>GBUF2</b>  |                              | Yes         | Yes          | Yes          |
| <b>GBUF3</b>  |                              | Yes         | Yes          | No           |
| <b>GBUF4</b>  |                              | Yes         | Yes          | Yes          |
| <b>GBUF5</b>  |                              | Yes         | Yes          | No           |
| <b>GBUF6</b>  |                              | Yes         | Yes          | Yes          |
| <b>GBUF7</b>  |                              | Yes         | Yes          | No           |

### Global Buffer Inputs

The iCE65 component has eight specialized GBIN/PIO pins that are optionally direct inputs to the global buffers, offering the best overall clock characteristics. As shown in Figure 15, each GBIN/PIO pin is a full-featured I/O pin but also provides a direct connection to its associated global buffer. The direct connection to the global buffer bypasses the iCEgate input-blocking latch and other PIO input logic. These special PIO pins are allocated two to an I/O Bank, a total of eight. These pins are labeled GBIN0 through GBIN7, as shown in Figure 14 and the pin locations for each GBIN input appear in Table 14.

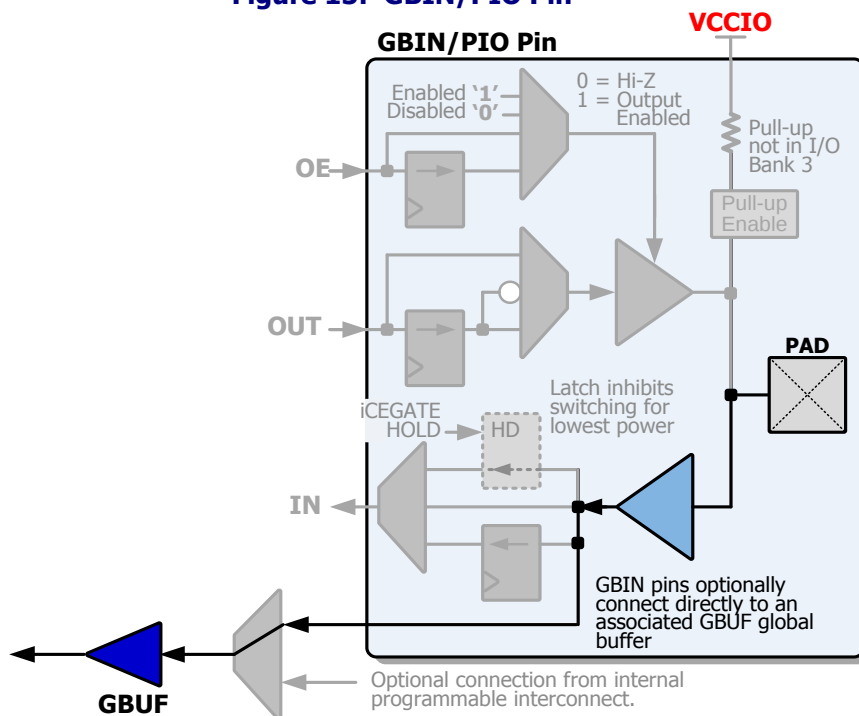
**Table 14: Global Buffer Input Ball/Pin Number by Package**

| Global Buffer Input (GBIN) | I/O Bank | VQ100 | CB132 | 'L04<br>CB196 | 'L08<br>CB196 | CB284 |
|----------------------------|----------|-------|-------|---------------|---------------|-------|
| <b>GBIN0</b>               | 0        | 90    | A6    | A7            | A7            | E10   |
| <b>GBIN1</b>               |          | 89    | A7    | E7            | E7            | E11   |
| <b>GBIN2</b>               | 1        | 63    | G14   | F10           | F10           | L18   |
| <b>GBIN3</b>               |          | 62    | F14   | G12           | G12           | K18   |
| <b>GBIN4</b>               | 2        | 34    | P8    | L7            | N8            | V12   |
| <b>GBIN5</b>               |          | 33    | P7    | P5            | M7            | V11   |
| <b>GBIN6</b>               | 3        | 15    | H1    | H1            | H1            | M5    |
| <b>GBIN7</b>               |          | 13    | G1    | G1            | H3            | L5    |



Note the clock differences between the iCE65L04 and iCE65L08 in the CB196 package.

**Figure 15: GBIN/PIO Pin**



## Differential Global Buffer Input

All eight global buffer inputs support single-ended I/O standards such as LVCMOS. Global buffer GBUF7 in I/O Bank 3 also provides an optional direct SubLVDS, LVDS, or LVPECL differential clock input, as shown in Figure 16. The GBIN7 and its associated differential I/O pad accept a differential clock signal. A 100  $\Omega$  termination resistor is required across the two pads. Optionally, swap the outputs from the LVDS or LVPECL clock driver to invert the clock as it enters the iCE65 device.

**Figure 16: LVDS or LVPECL Clock Input**

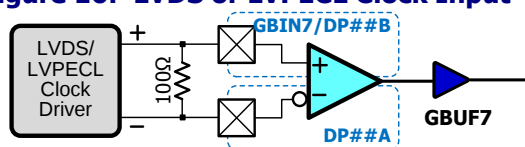


Table 15 lists the pin or ball numbers for the differential global buffer input by package style. Although this differential input is the only one that connects directly to a global buffer, other differential inputs can connect to a global buffer using general-purpose interconnect, with slightly more signal delay.

**Table 15: Differential Global Buffer Input Ball/Pin Number by Package**

| Differential Global Buffer Input (GBIN) | I/O Bank | VQ100 | CB132 | 'L04 CB196 | 'L08 CB196 | CB284 |
|-----------------------------------------|----------|-------|-------|------------|------------|-------|
| <b>GBIN7/DPxxB</b>                      | 3        | 13    | N/A   | G1         | H3         | L5    |
| <b>DPxxA</b>                            |          | 12    | N/A   | G2         | H4         | L3    |



The differential global buffer input is not available for iCE65 devices in the CB132 package. This restriction is an artifact of the pin compatibility between the CB132 and CB284 package.

Note the clock differences between the iCE65L04 and iCE65L08 in the CB196 package.

## Automatic Global Buffer Insertion, Manual Insertion

The iCEcube development software automatically assigns high-fanout signals to a global buffer. However, to manually insert a global buffer input/global buffer (GBIN/GBUF) combination, use the **SB\_IO\_GB** primitive. To insert just a global buffer (GBUF), use the **SB\_GB** primitive.

## Global Hi-Z Control

The global high-impedance control signal, GHIZ, connects to all I/O pins on the iCE65 device. This GHIZ signal is automatically asserted throughout the configuration process, forcing all user-I/O pins into their high-impedance state. Similarly, the PIO pins can be forced into their high-impedance state via the JTAG controller.

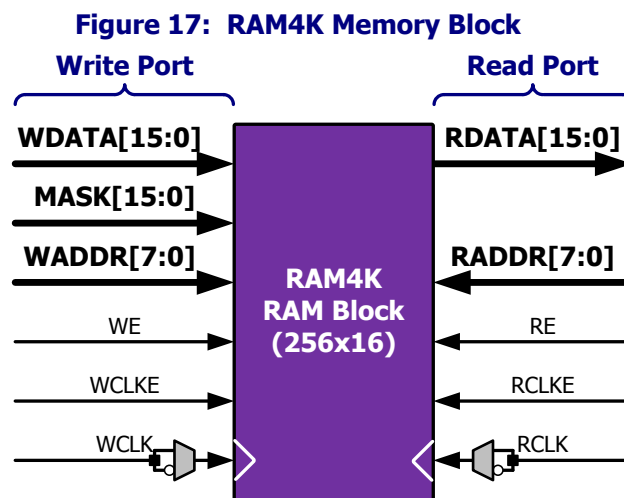
## Global Reset Control

The global reset control signal connects to all PLB and PIO flip-flops on the iCE65 device. The global reset signal is automatically asserted throughout the configuration process, forcing all flip-flops to their defined wake-up state. For PLB flip-flops, the wake-up state is always reset, regardless of the PLB flip-flop primitive used in the application. See [Table 3](#) for more information.

The PIO flip-flops are always reset during configuration, although the output flip-flop can be inverted before leaving the iCE65 device, as shown in [Figure 11](#).

## RAM

Each iCE65 device includes multiple high-speed synchronous RAM blocks (RAM4K), each 4Kbit in size. As shown in [Table 16](#) a single iCE65 integrates between 16 to 96 such blocks. Each RAM4K block is generically a 256-word deep by 16-bit wide, two-port register file, as illustrated in [Figure 17](#). The input and output connections, to and from a RAM4K block, feed into the programmable interconnect resources.



**Table 16: RAM4K Blocks per Device**

| Device   | RAM4K Blocks | Default Configuration | RAM Bits per Block | Block RAM Bits |
|----------|--------------|-----------------------|--------------------|----------------|
| iCE65L01 | 16           | 256 x 16              | 4K<br>(4,096)      | 64K            |
| iCE65L04 | 20           |                       |                    | 80K            |
| iCE65L08 | 32           |                       |                    | 128K           |

Using programmable logic resources, a RAM4K block implements a variety of logic functions, each with configurable input and output data width.

- Random-access memory (RAM)
  - ◆ Single-port RAM with a common address, enable, and clock control lines
  - ◆ Two-port RAM with separate read and write control lines, address inputs, and enable

- Register file and scratchpad RAM
- First-In, First-Out (FIFO) memory for data buffering applications
- Circuit buffer
- A 256-deep by 16-wide ROM with registered outputs, contents loaded during configuration
  - ◆ Sixteen different 8-input look-up tables
  - ◆ Function or waveform tables such as sine, cosine, etc.
  - ◆ Correlators or pattern matching operations
- Counters, sequencers

As pictured in [Figure 17](#), a RAM4K block has separate write and read ports, each with independent control signals. [Table 17](#) lists the signals for both ports. Additionally, the write port has an active-Low bit-line write-enable control; optionally mask write operations on individual bits. By default, input and output data is 16 bits wide, although the data width is configurable using programmable logic and, if needed, multiple RAM4K blocks.

The WCLK and RCLK inputs optionally connect to one of the following clock sources.

- ◆ The output from any one of the eight [Global Buffers](#), or
- ◆ A connection from the general-purpose interconnect fabric

The data contents of the RAM4K block are optionally pre-loaded during iCE65 device configuration. If the RAM4K blocks are not pre-loaded during configuration, then the resulting configuration bitstream image is smaller. However, if an uninitialized RAM4K block is used in the application, then the application must initialize the RAM contents to guarantee the data value.

See [Table 56](#) for detailed timing information.

## Signals

[Table 17](#) lists the signal names, direction, and function of each connection to the RAM4K block. See also [Figure 17](#).

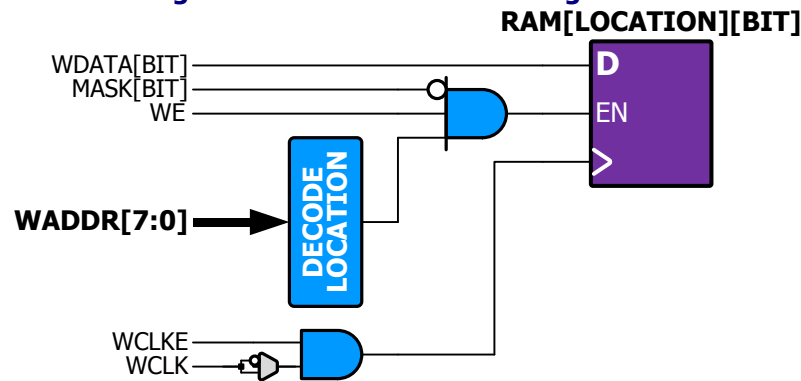
**Table 17: RAM4K Block RAM Signals**

| Signal Name | Direction | Description                                                                                 |
|-------------|-----------|---------------------------------------------------------------------------------------------|
| WDATA[15:0] | Input     | Write Data input.                                                                           |
| MASK[15:0]  | Input     | Masks write operations for individual data bit-lines.<br>0 = Write bit; 1 = Don't write bit |
| WADDR[7:0]  | Input     | Write Address input. Selects one of 256 possible RAM locations.                             |
| WE          | Input     | Write Enable input.                                                                         |
| WCLKE       | Input     | Write Clock Enable input.                                                                   |
| WCLK        | Input     | Write Clock input. Default rising-edge, but with falling-edge option.                       |
| RDATA[15:0] | Output    | Read Data output.                                                                           |
| RADDR[7:0]  | Input     | Read Address input. Selects one of 256 possible RAM locations.                              |
| RE          | Input     | Read Enable input.                                                                          |
| RCLKE       | Input     | Read Clock Enable input.                                                                    |
| RCLK        | Input     | Read Clock input. Default rising-edge, but with falling-edge option.                        |

## Write Operations

[Figure 18](#) shows the logic involved in writing a data bit to a RAM location. [Table 18](#) describes various write operations for a RAM4K block. By default, all RAM4K write operations are synchronized to the rising edge of WCLK although the clock is invertible as shown in [Figure 18](#).

**Figure 18: RAM4K Bit Write Logic**



When the WCLKE signal is Low, the clock to the RAM4K block is disabled, keeping the RAM in its lowest power mode.

**Table 18: RAM4K Write Operations**

|              | WDATA[15:0] | MASK[15:0]  | WADDR[7:0] | WE           | WCLKE        | WCLK  |                           |
|--------------|-------------|-------------|------------|--------------|--------------|-------|---------------------------|
| Operation    | Data        | Mask Bit    | Address    | Write Enable | Clock Enable | Clock | RAM Location              |
| Disabled     | X           | X           | X          | X            | X            | 0     | No change                 |
| Disabled     |             |             |            |              | 0            | X     | No change                 |
| Disabled     | X           | X           | X          | 0            | X            | X     | No change                 |
| Write Data   | WDATA[i]    | MASK[i] = 0 | WADDR      | 1            | 1            | ↑     | RAM[WADDR][i] = WDATA[i]  |
| Masked Write | X           | MASK[i] = 1 | WADDR      | 1            | 1            | ↑     | RAM[WADDR][i] = No change |

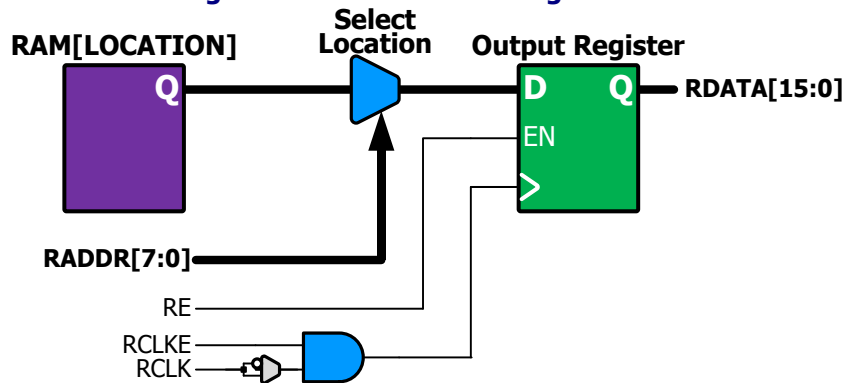
To write data into the RAM4K block, perform the following operations.

- ◆ Supply a valid address on the WADDR[7:0] address input port
- ◆ Supply valid data on the WDATA[15:0] data input port
- ◆ To write or mask selected data bits, set the associated MASK input port accordingly. For example, write operations on data bit D[i] are controlled by the associated MASK[i] input.
  - MASK[i] = 0: Write operations are enabled for data line WDATA[i]
  - MASK[i] = 1: Mask write operations are disabled for data line WDATA[i]
- ◆ Enable the RAM4K write port (WE = 1)
- ◆ Enable the RAM4K write clock (WCLKE = 1)
- ◆ Apply a rising clock edge on WCLK (assuming that the clock is not inverted)

## Read Operations

Figure 19 shows the logic involved in reading a location from RAM. Table 19 describes various read operations for a RAM4K block. By default, all RAM4K read operations are synchronized to the rising edge of RCLK although the clock is invertible as shown in Figure 19.

**Figure 19: RAM4K Read Logic**



**Table 19: RAM4K Read Operations**

| Operation                                                   | RADDR[7:0] | RE          | RCLKE        | RCLK  | RDATA[15:0] |
|-------------------------------------------------------------|------------|-------------|--------------|-------|-------------|
|                                                             | Address    | Read Enable | Clock Enable | Clock |             |
| After configuration, before first valid Read Data operation | X          | X           | X            | X     | Undefined   |
| Disabled                                                    | X          | X           | X            | 0     | No Change   |
| Disabled                                                    |            | X           | 0            | X     | No Change   |
| Disabled                                                    | X          | 0           | X            | X     | No change   |
| Read Data                                                   | RADDR      | 1           | 1            | ↑     | RAM[RADDR]  |

To read data from the RAM4K block, perform the following operations.

- ◆ Supply a valid address on the RADDR[7:0] address input port
- ◆ Enable the RAM4K read port (RE = 1)
- ◆ Enable the RAM4K read clock (RCLKE = 1)
- ◆ Apply a rising clock edge on RCLK
- ◆ After the clock edge, the RAM contents located at the specified address (RADDR) appear on the RDATA output port

### **Read Data Register Undefined Immediately after Configuration**

Unlike the flip-flops in the Programmable Logic Blocks and Programmable I/O pins, the RDATA[15:0] read data output register is not automatically reset after configuration. Consequently, immediately following configuration and before the first valid Read Data operation, the initial RDATA[15:0] read value is undefined.

### **Pre-loading RAM Data**

The data contents for a RAM4K block can be optionally pre-loaded during iCE65 configuration. If not pre-loaded during configuration, then the RAM contents must be initialized by the iCE65 application before the RAM contents are valid.

Pre-loading the RAM data in the configuration bitstream increases the size of the configuration image accordingly.

### **RAM Contents Preserved during Configuration**

RAM contents are preserved (write protected) during configuration, assuming that voltage supplies are maintained throughout. Consequently, data can be passed between multiple iCE65 configurations by leaving it in a RAM4K block and then skipping pre-loading during the subsequent reconfiguration. See [“Cold Boot Configuration Option”](#) and [“Warm Boot Configuration Option”](#) for more information.

### **Low-Power Setting**

To place a RAM4K block in its lowest power mode, keep WCLKE = 0 and RCLKE = 0. In other words, when not actively using a RAM4K block, disable the clock inputs.

## Device Configuration

As described in [Table 20](#), iCE65 components are configured for a specific application by loading a binary configuration bitstream image, generated by the Lattice development system. For high-volume applications, the bitstream image is usually permanently programmed in the on-chip NVCM. However, the bitstream image can also be stored external in a standard, low-cost commodity SPI serial Flash PROM. The iCE65 component can automatically load the image using the [SPI Master Configuration Interface](#). Similarly, the iCE65 configuration data can be downloaded from an external processor, microcontroller, or DSP processor using an SPI-like serial interface or an IEEE 1149 JTAG interface.

**Table 20: iCE65 Device Configuration Modes**

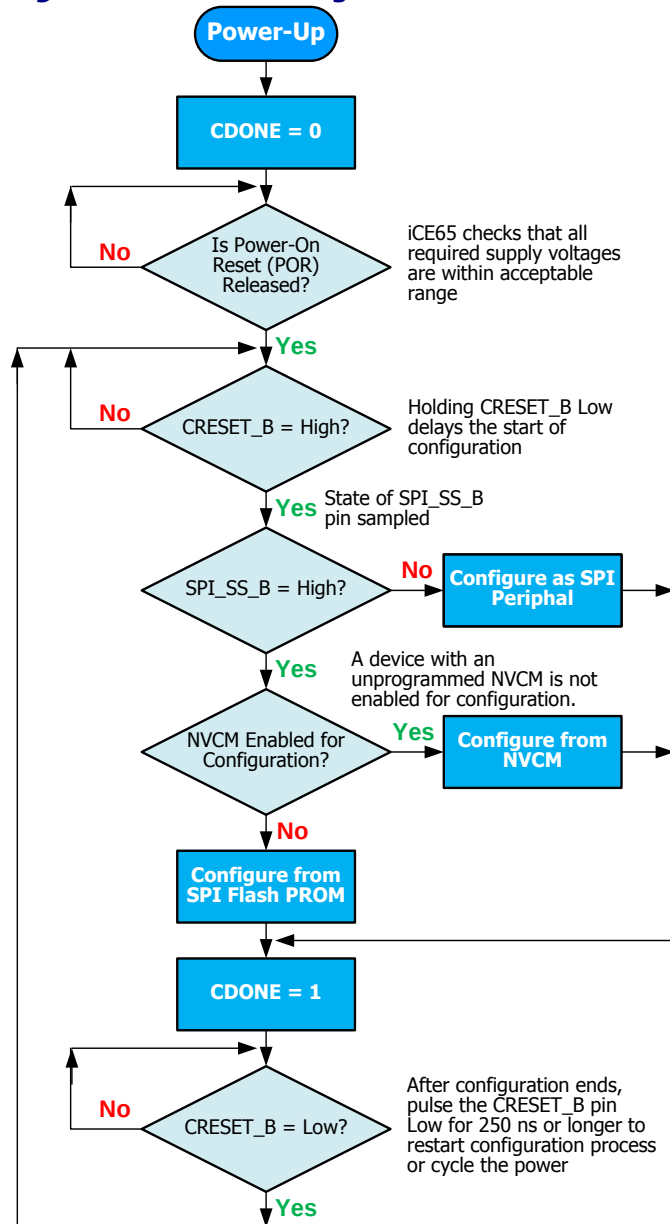
| Mode                  | Analogy              | Configuration Data Source                                                                                                                                                        |
|-----------------------|----------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>NVCM</b>           | ASIC                 | Internal, lowest-cost, secure, one-time programmable Nonvolatile Configuration Memory (NVCM)                                                                                     |
| <b>SPI Flash</b>      | Microprocessor       | External, low-cost, commodity, SPI serial Flash PROM                                                                                                                             |
| <b>SPI Peripheral</b> | Processor Peripheral | Configured by external device, such as a processor, microcontroller, or DSP using practically any data source, such as system Flash, a disk image, or over a network connection. |
| <b>JTAG</b>           | JTAG                 | JTAG configuration requires sending a special command sequence on the SPI interface to enable JTAG configuration. Configuration is controlled by and external device.            |

## Configuration Mode Selection

The iCE65 configuration mode is selected according to the following priority described below and illustrated in [Figure 20](#).

- After exiting the Power-On Reset (POR) state or when CRESET\_B returns High after being held Low for 250 ns or more, the iCE65 FPGA samples the logical value on its SPI\_SS\_B pin. Like other programmable I/O pins, the SPI\_SS\_B pin has an internal pull-up resistor (see [Input Pull-Up Resistors on I/O Banks 0, 1, and 2](#)).
- If the [SPI\\_SS\\_B](#) pin is sampled as a logic '1' (High), then ...
  - ◆ Check if the iCE65 is enabled to configure from the Nonvolatile Configuration Memory (NVCM). If the iCE65 device has NVCM memory ('F' ordering code) but the NVCM is yet unprogrammed, then the iCE65 device is not enabled to configure from NVCM. Conversely, if the NVCM is programmed, the iCE65 device will configure from NVCM.
    - If enabled to configure from NVCM, the iCE65 device configures itself using NVCM.
    - If not enabled to configure from NVCM, then the iCE65 FPGA configures using the [SPI Master Configuration Interface](#).
- If the [SPI\\_SS\\_B](#) pin is sampled as a logic '0' (Low), then the iCE65 device waits to be configured from an external controller or from another iCE65 device in SPI Master Configuration Mode using an SPI-like interface.

**Figure 20: Device Configuration Control Flow**



## Configuration Image Size

Table 23 shows the number of memory bits required to configure an iCE65 device. Two values are provided for each device. The “Logic Only” value indicates the minimum configuration size, the number of bits required to configure only the logic fabric, leaving the RAM4K blocks uninitialized. The “Logic + RAM4K” column indicates the maximum configuration size, the number of bits to configure the logic fabric and to pre-initialize all the RAM4K blocks.

**Table 21: iCE65 Configuration Image Size (Kbits)**

| Device   | MINIMUM<br>Logic Only<br>(RAM4K not initialized) | MAXIMUM<br>Logic + RAM4K<br>(RAM4K pre-initialized) |
|----------|--------------------------------------------------|-----------------------------------------------------|
| iCE65L01 | 181 Kbits                                        | 245 Kbits*                                          |
| iCE65L04 | 453 Kbits                                        | 533 Kbits                                           |
| iCE65L08 | 929 Kbits                                        | 1,057 Kbits                                         |

\* Note: only 14 of the 16 RAM4K Memory Blocks may be pre-initialized in the iCE65L01.

### Nonvolatile Configuration Memory (NVCM)

All standard iCE65 devices have an internal, nonvolatile configuration memory (NVCM). The NVCM is large enough to program a complete iCE65 device, including initializing all RAM4K block locations (MAXIMUM column in Table 23). The NVCM memory also has very high programming yield due to extensive error checking and correction (ECC) circuitry.

The NVCM is ideal for cost-sensitive, high-volume production applications, saving the cost and board space associated with an external configuration PROM. Furthermore, the NVCM provides exceptional design security, protecting critical intellectual property (IP). The NVCM contents are entirely contained within the iCE65 device and are not readable once protected by the one-time programmable Security bits. Furthermore, there is no observable difference between a programmed or un-programmed memory cell using optical or electron microscopy.

The NVCM memory has a programming interface similar to a 25-series SPI serial Flash PROM. Consequently, it can be programmed using standard device programmers before or after circuit board assembly or programmed in-system from a microprocessor or other intelligent controller. NVCM programming requires VCCIO\_1, Bank 1 voltage to be applied on power-up, at the same time as other voltage supplies.

### Configuration Control Signals

The iCE65 configuration process is self-timed and controlled by a few internal signals and device I/O pins, as described in [Table 22](#).

**Table 22: iCE65 Configuration Control Signals**

| Signal Name | Direction         | Description                                                             |
|-------------|-------------------|-------------------------------------------------------------------------|
| POR         | Internal control  | Internal Power-On Reset (POR) circuit.                                  |
| OSC         | Internal control  | Internal configuration oscillator.                                      |
| CRESET_B    | Input             | Configuration Reset input. Active-Low. No internal pull-up resistor.    |
| CDONE       | Open-drain Output | Configuration Done output. Permanent, weak pull-up resistor to VCCIO_2. |

The Power-On Reset circuit, [POR](#), automatically resets the iCE65 component to a known state during power-up (cold boot). The POR circuit monitors the relevant voltage supply inputs, as shown in [Figure 22](#). Once all supplies exceed their minimum thresholds, the configuration controller can start the configuration process.

The configuration controller begins configuring the iCE65 device, clocked by the [Internal Oscillator](#), OSC. The OSC oscillator continues controlling configuration unless the iCE65 device is configured using the [SPI Peripheral Configuration Interface](#).

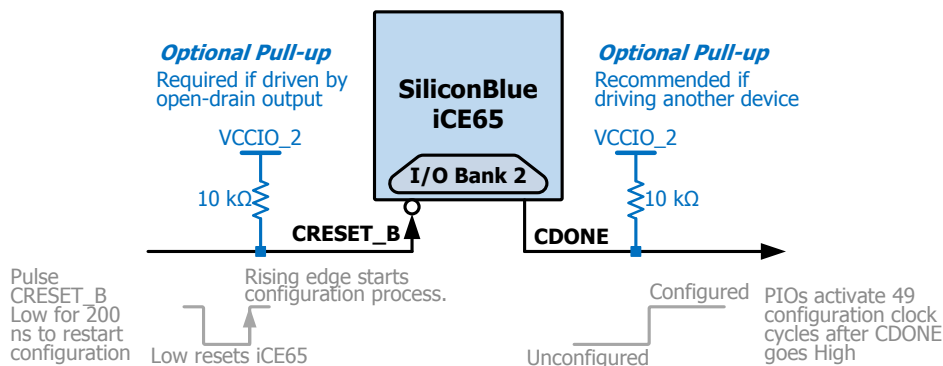
**Figure 21: iCE65 Configuration Control Pins**

Figure 21 shows the two iCE65 configuration control pins, **CRESET\_B** and **CDONE**. Table 23 lists the ball/pin numbers for the configuration control pins by package. When driven Low for at least 200 ns, the dedicated Configuration Reset input, **CRESET\_B**, resets the iCE65 device. When **CRESET\_B** returns High, the iCE65 FPGA restarts the configuration process from its power-on conditions (Cold Boot). The **CRESET\_B** pin is a pure input with no internal pull-up resistor. If driven by open-drain driver or un-driven, then connect the **CRESET\_B** pin to a 10 kΩ pull-up resistor connected to the **VCCIO\_2** supply.

**Table 23: Configuration Control Ball/Pin Numbers by Package**

| Configuration Control Pins | CB81 | QN84 | VQ100 | CB132 | CB196 | CB284 |
|----------------------------|------|------|-------|-------|-------|-------|
| <b>CRESET_B</b>            | J6   | A21  | 44    | L10   | L10   | R14   |
| <b>CDONE</b>               | H6   | B16  | 43    | M10   | M10   | T14   |

The iCE65 device signals the end of the configuration process by actively turning off the internal pull-down transistor on the Configuration Done output pin, **CDONE**. The pin has a permanent, weak internal pull-up resistor to the **VCCIO\_2** rail. If the iCE65 device drives other devices, then optionally connect the **CDONE** pin to a 10 kΩ pull-up resistor connected to the **VCCIO\_2** supply.

The PIO pins activate according to their configured function after 49 configuration clock cycles. The internal oscillator is the configuration clock source for the [SPI Master Configuration Interface](#) and when configuring from

**\* Note:** only 14 of the 16 RAM4K Memory Blocks may be pre-initialized in the iCE65L01.

Nonvolatile Configuration Memory (NVCN). When using the [SPI Peripheral Configuration Interface](#), the configuration clock source is the **SPI\_SCK** clock input pin.

### Internal Oscillator

During SPI Master or NVCN configuration mode, the controlling clock signal is generated from an internal oscillator. The oscillator starts operating at the [Default](#) frequency. During the configuration process, however, bit settings within the configuration bitstream can specify a higher-frequency mode in order to maximize SPI bandwidth and reduce overall configuration time. See [Table 57: Internal Oscillator Frequency](#) on page 105 for the specified oscillator frequency range.

Using the [SPI Master Configuration Interface](#), internal oscillator controls all the interface timing and clocks the SPI serial Flash PROM via the **SPI\_SCK** clock output pin.

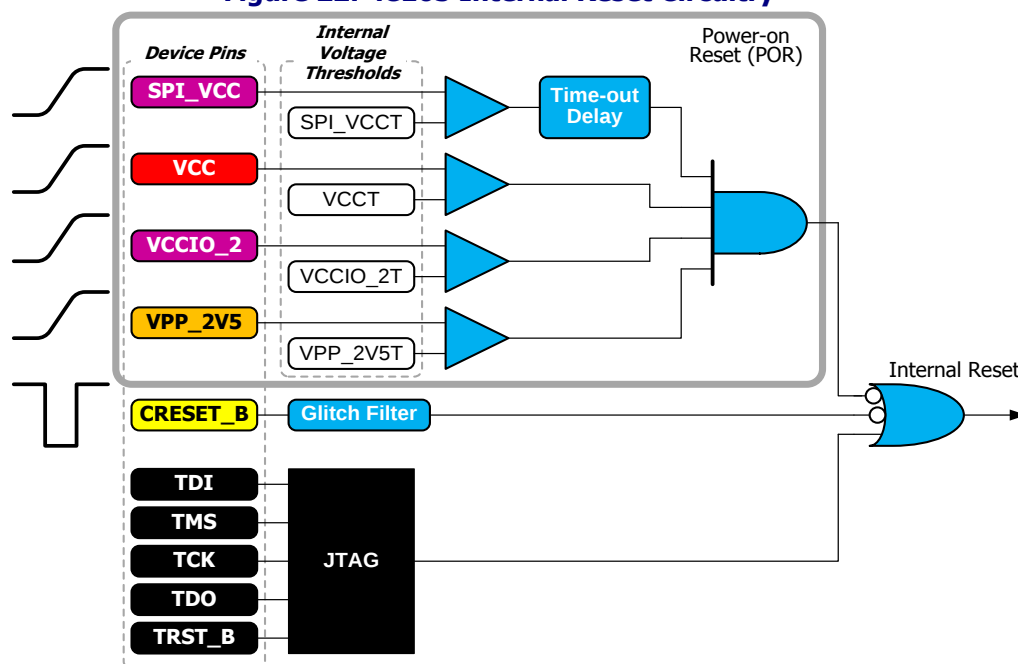
The oscillator output, which also supplies the SPI SCK clock output during the SPI Flash configuration process, has a 50% duty cycle.

### Internal Device Reset

Figure 22 presents the various signals that internally reset the iCE65 internal logic.

- Power-On Reset (POR)
- **CRESET\_B** Pin
- JTAG Interface

**Figure 22: iCE65 Internal Reset Circuitry**



### Power-On Reset (POR)

The Power-on Reset (POR) circuit monitors specific voltage supply inputs and holds the device in reset until all the relevant supplies exceed the internal voltage thresholds. The SPI\_VCC supply also has an additional time-out delay to allow an attached SPI serial PROM to power up properly. Table 24 shows the POR supply inputs. The Nonvolatile Configuration Memory (NVCN) requires that the VPP\_2V5 supply be connected, even if the application does not use the NVCN.

**Table 24: Power-on Reset (POR) Voltage Resources**

| Supply Rail    | iCE65 Production Devices |
|----------------|--------------------------|
| <b>VCC</b>     | Yes                      |
| <b>SPI_VCC</b> | Yes                      |
| <b>VCCIO_1</b> | No                       |
| <b>VCCIO_2</b> | Yes                      |
| <b>VPP_2V5</b> | Yes                      |

### CRESET\_B Pin

The CRESET\_B pin resets the iCE65 internal logic when Low.

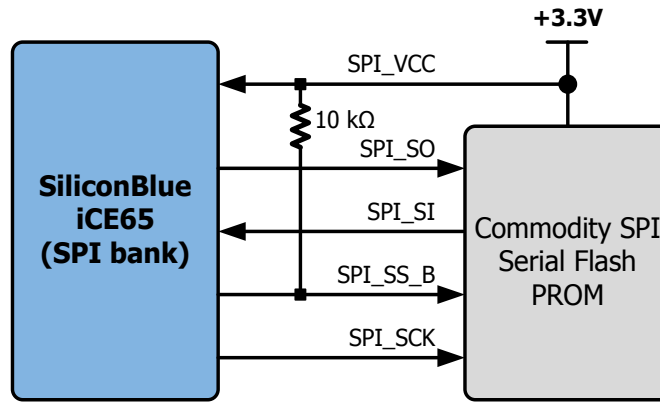
### JTAG Interface

Specific command sequences also reset the iCE65 internal logic.

### SPI Master Configuration Interface

All iCE65 devices, including those with NVCN, can be configured from an external, commodity SPI serial Flash PROM, as shown in Figure 23. The SPI configuration interface is essentially its own independent I/O bank, powered by the VCC\_SPI supply input. Presently, most commercially-available SPI serial Flash PROMs require a 3.3V supply.

**Figure 23: iCE65 SPI Master Configuration Interface**



The SPI configuration interface is used primarily during development before mass production, where the configuration is then permanently programmed in the NVCM configuration memory. However, the SPI interface can also be the primary configuration interface allowing easy in-system upgrades and support for multiple configuration images.

The SPI control signals are defined in Table 25. Table 26 lists the SPI interface ball or pins numbers by package.

**Table 25: SPI Master Configuration Interface Pins (SPI\_SS\_B High before Configuration)**

| Signal Name | Direction | Description                                                                       |
|-------------|-----------|-----------------------------------------------------------------------------------|
| SPI_VCC     | Supply    | SPI Flash PROM voltage supply input.                                              |
| SPI_SO      | Output    | SPI Serial Output from the iCE65 device.                                          |
| SPI_SI      | Input     | SPI Serial Input to the iCE65 device, driven by the select SPI serial Flash PROM. |
| SPI_SS_B    | Output    | SPI Slave Select output from the iCE65 device. Active Low.                        |
| SPI_SCK     | Output    | SPI Slave Clock output from the iCE65 device.                                     |

After configuration, the SPI port pins are available to the user-application as additional PIO pins, supplied by the SPI\_VCC input voltage, essentially providing a fifth “mini” I/O bank.

**Table 26: SPI Interface Ball/Pin Numbers by Package**

| SPI Interface        | VQ100 | CB132 | CB196 | CB284 |
|----------------------|-------|-------|-------|-------|
| <b>SPI_VCC</b>       | 50    | L11   | L11   | R15   |
| <b>PIOS/SPI_SO</b>   | 45    | M11   | M11   | T15   |
| <b>PIOS/SPI_SI</b>   | 46    | P11   | P11   | V15   |
| <b>PIOS/SPI_SS_B</b> | 49    | P13   | P13   | V17   |
| <b>PIOS/SPI_SCK</b>  | 48    | P12   | P12   | V16   |

## SPI PROM Requirements

The iCE65 mobileFPGA SPI Flash configuration interface supports a variety of SPI Flash memory vendors and product families. However, Lattice Semiconductor does not specifically test, qualify, or otherwise endorse any specific SPI Flash vendor or product family. The iCE65 SPI interface supports SPI PROMs that they meet the following requirements.

- The PROM must operate at 3.3V or 2.5V in order to trigger the iCE65 FPGA’s power-on reset circuit.
- The PROM must support the **0x0B** Fast Read command, using a 24-bit start address and has 8 dummy bits before the PROM provides first data (see Figure 25: SPI Fast Read Command).
- The PROM must have enough bits to program the iCE65 device (see Table 27: Smallest SPI PROM Size (bits), by Device, by Number of Images).
- The PROM must support data operations at the upper frequency range for the selected iCE65 internal oscillator frequency (see Table 57). The oscillator frequency is selectable when creating the FPGA bitstream image.

- For lowest possible power consumption after configuration, the PROM should also support the **0xB9** Deep Power Down command and the **0xAB** Release from Deep Power-down Command (see [Figure 24](#) and [Figure 26](#)). The low-power mode is optional.
- The PROM must be ready to accept commands 10  $\mu$ s after meeting its power-on conditions. In the PROM data sheet, this may be specified as  $t_{VSL}$  or  $t_{VCSL}$ . It is possible to use slower PROMs by holding the CRESET\_B input Low until the PROM is ready, then releasing CRESET\_B, either under program control or using an external power-on reset circuit.

The Lattice iCEman65 development board and associated programming software uses an ST Micro/Numonyx M25Pxx SPI serial Flash PROM.

### ***SPI PROM Size Requirements***

[Table 27](#) lists the minimum SPI PROM size required to configure an iCE65 device. Larger PROM sizes are allowed, but not required unless the end application uses the additional space. SPI serial PROM sizes are specified in bits. For each device size, the table shows the required minimum PROM size for “Logic Only” (no BRAM initialization) and “Logic + RAM4K” (RAM4K blocks pre-initialized). Furthermore, the table shows the PROM size for varying numbers of configuration images. Most applications will use a single image. Applications that use the Cold Boot or Warm Boot features may use more than one image.

**Table 27: Smallest SPI PROM Size (bits), by Device, by Number of Images**

| Device          | 1 Image    |               | 2 Images   |               | 3 Images   |               | 4 Images   |               |
|-----------------|------------|---------------|------------|---------------|------------|---------------|------------|---------------|
|                 | Logic Only | Logic + RAM4K | Logic Only | Logic + RAM4K | Logic Only | Logic + RAM4K | Logic Only | Logic + RAM4K |
| <b>iCE65L01</b> | 256K       | 256K          | 512K       | 512K          | 1M         | 1M            | 1M         | 1M            |
| <b>iCE65L04</b> | 512K       | 1M            | 1M         | 2M            | 2M         | 2M            | 2M         | 4M            |
| <b>iCE65L08</b> | 1M         | 2M            | 2M         | 4M            | 4M         | 4M            | 4M         | 8M            |

### ***Enabling SPI Configuration Interface***

To enable the SPI configuration mode, the SPI\_SS\_B pin must be allowed to float High. The SPI\_SS\_B pin has an internal pull-up resistor. If SPI\_SS\_B is Low, then the iCE65 component defaults to the SPI Slave configuration mode.

### ***SPI Master Configuration Process***

The iCE65 SPI Master Configuration Interface supports a variety of modern, high-density, low-cost SPI serial Flash PROMs. Most modern SPI PROMs include a power-saving Deep Power-down mode. The iCE65 component exploits this mode for additional system power savings.

The iCE65 SPI interface starts by driving **SPI\_SS\_B** Low, and then sends a Release from Power-down command to the SPI PROM, hexadecimal command code **0xAB**. [Figure 24](#) provides an example waveform. This initial command wakes up the SPI PROM if it is already in Deep Power-down mode. If the PROM is not in Deep Power-down mode, the extra command has no adverse affect other than that it requires a few additional microseconds during the configuration process. The iCE65 device transmits data on the **SPI\_SO** output, on the falling edge of the **SPI\_SCK** output. The SPI PROM does not provide any data to the iCE65 device’s **SPI\_SI** input. After sending the last command bit, the iCE65 device de-asserts SPI\_SS\_B High, completing the command. The iCE65 device then waits a minimum of 10  $\mu$ s before sending the next SPI PROM command.

**Figure 24: SPI Release from Deep Power-down Command**

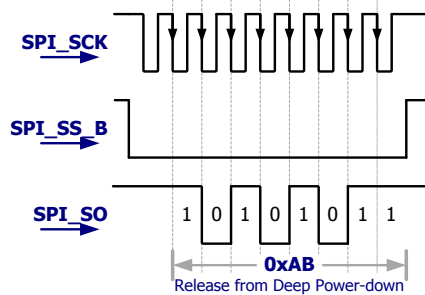
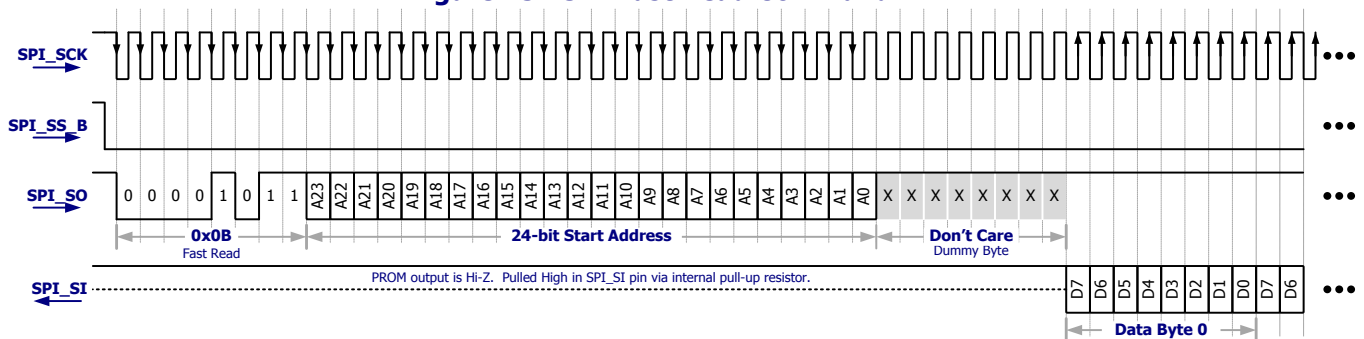


Figure 25 illustrates the next command issued by the iCE65 device. The iCE65 SPI interface again drives **SPI\_SS\_B** Low, followed by a Fast Read command, hexadecimal command code **0x0B**, followed by a 24-bit start address, transmitted on the **SPI\_SO** output. The iCE65 device provides data on the falling edge of **SPI\_SS\_B**. Upon initial power-up, the start address is always **0x00\_0000**. After waiting eight additional clock cycles, the iCE65 device begins reading serial data from the SPI PROM. Before presenting data, the SPI PROM's serial data output is high-impedance. The **SPI\_SI** input pin has an internal pull-up resistor and sees high-impedance as logic '1'.

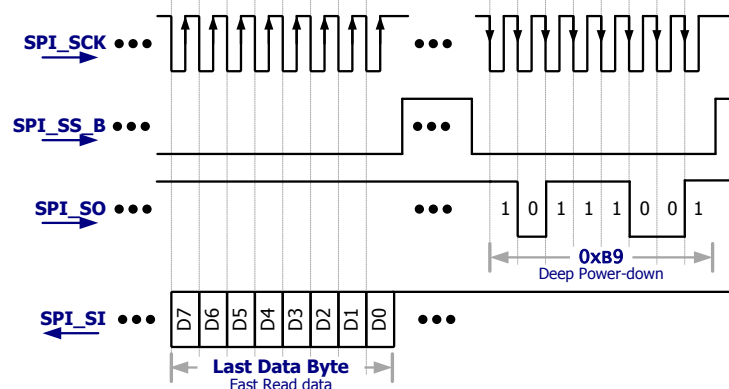
**Figure 25: SPI Fast Read Command**



The external SPI PROM supplies data on the falling edge of the iCE65 device's **SPI\_SCK** clock output. The iCE65 device captures each PROM data value on the **SPI\_SI** input, using the rising edge of the **SPI\_SCK** clock signal. The SPI PROM data starts at the 24-bit address presented by the iCE65 device. PROM data is serially output, byte by byte, with most-significant bit, D7, presented first. The PROM automatically increments an internal byte counter as long as the PROM is selected and clocked.

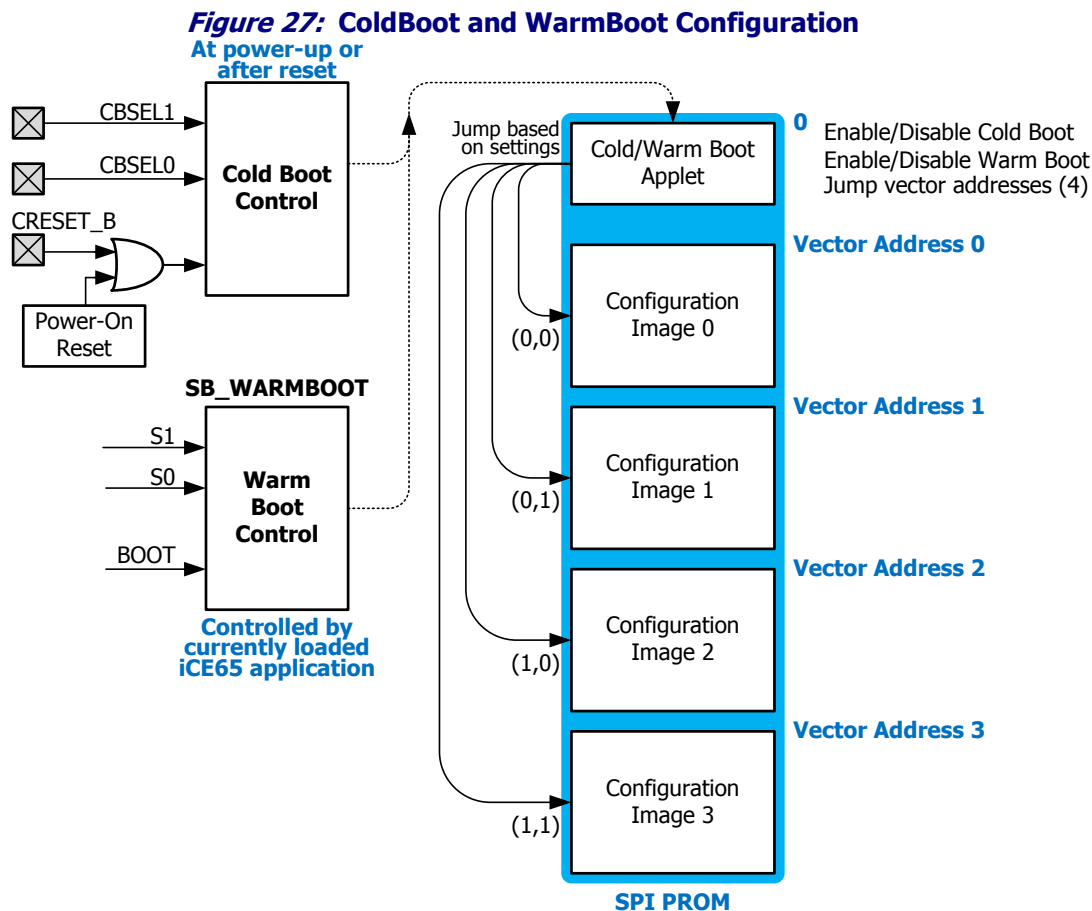
After transferring the required number configuration data bits, the iCE65 device ends the Fast Read command by de-asserting its **SPI\_SS\_B** PROM select output, as shown in Figure 26. To conserve power, the iCE65 device then optionally issues a final Deep Power-down command, hexadecimal command code **0xB9**. After de-asserting the **SPI\_SS\_B** output, the SPI PROM enters its Deep Power-down mode. The final power-down step is optional; the application may use the SPI PROM and can skip this step, controlled by a configuration option.

**Figure 26: Final Configuration Data, SPI Deep Power-down Command**



## Cold Boot Configuration Option

By default, the iCE65 FPGA is programmed with a single configuration image, either from internal NVCM memory, from an external SPI Flash PROM, or externally from a processor or microcontroller.



When self loading from NVCM or from an SPI Flash PROM, there is an additional configuration option called Cold Boot mode. When this option is enabled in the configuration bitstream, the iCE65 FPGA boots normally from power-on or a master reset (**CRESET\_B** = Low pulse), but monitors the value on two PIO pins that are borrowed during configuration, as shown in Figure 27. These pins, labeled **PIO2/CBSEL0** and **PIO2/CBSEL1**, tell the FPGA which of the four possible SPI configurations to load into the device. Table 30 provides the pin or ball locations for these pins.

- Load from initial location, either from NVCM or from address 0 in SPI Flash PROM. For Cold Boot or Warm Boot applications, the initial configuration image contains the cold boot/warm boot applet.
- Check if Cold Boot configuration feature is enabled in the bitstream.
  - ◆ If not enabled, FPGA configures normally.
  - ◆ If Cold Boot is enabled, then the FPGA reads the logic values on pins **CBSEL[1:0]**. The FPGA uses the value as a vector and then reads from the indicated vector address.
  - ◆ At the selected **CBSEL[1:0]** vector address, there is a starting address for the selected configuration image.
    - For SPI Flash PROMs, the new address is a 24-bit start address in Flash.
    - If the selected bitstream is in NVCM, then the address points to the internal NVCM.
- Using the new start address, the FPGA restarts reading configuration memory from the new location.

**Table 28: ColdBoot Select Ball/Pin Numbers by Package**

| ColdBoot Select    | CB81 | QN84 | VQ100 | CB132 | CB196 | CB284 |
|--------------------|------|------|-------|-------|-------|-------|
| <b>PIO2/CBSEL0</b> | G5   | B15  | 41    | L9    | L9    | R13   |
| <b>PIO2/CBSEL1</b> | H5   | A20  | 42    | P10   | P10   | V14   |

When creating the initial configuration image, the Lattice development software loads the start address for up to four configuration images in the bitstream. The value on the CBSEL[1:0] pins tell the configuration controller to read a specific start address, then to load the configuration image stored at the selected address. The multiple bitstreams are stored either in the SPI Flash or in the internal NVMCM.

After configuration, the CBSEL[1:0] pins become normal PIO pins available to the application.

The Cold Boot feature allows the iCE65 to be reprogrammed for special application requirements such as the following.

- A normal operating mode and a self-test or diagnostics mode.
- Different applications based on switch settings.
- Different applications based on a card-slot ID number.

## Warm Boot Configuration Option

The Warm Boot configuration is similar to the Cold Boot feature, but is completely under the control of the FPGA application.

A special design primitive, SB\_WARMBOOT, allows an FPGA application to choose between four configuration images using two internal signal ports, S1 and S0, as shown in [Figure 27](#). These internal signal ports connect to programmable interconnect, which in turn can connect to PLB logic and/or PIO pins.

After selecting the desired configuration image, the application then asserts the internal signal BOOT port High to force the FPGA to restart the configuration process from the specified vector address stored in PROM.



A Warm Boot application can only jump to another configuration image that DOES NOT have Warm Boot enabled. There is no such restriction for Cold Boot applications.

## Time-Out and Retry

When configuring from external SPI Flash, the iCE65 device looks for a synchronization word. If the device does not find a synchronization word within its timeout period, the device automatically attempts to restart the configuration process from the very beginning. This feature is designed to address any potential power-sequencing issues that may occur between the iCE65 device and the external PROM.

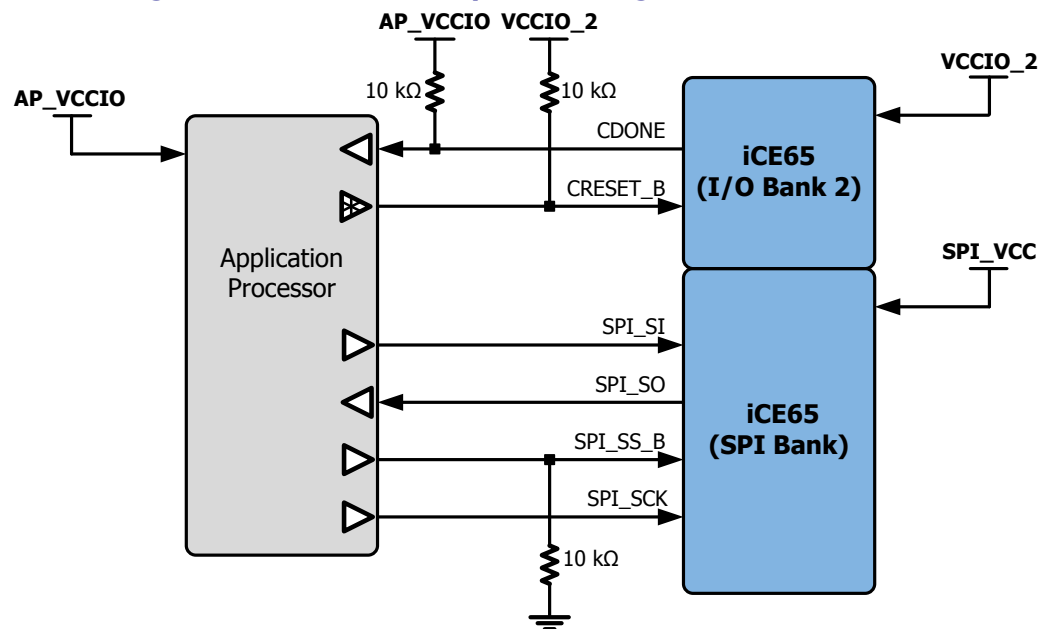
The iCE65 device attempts to reconfigure six times. If not successful after six attempts, the iCE65 FPGA automatically goes into low-power mode.

## SPI Peripheral Configuration Interface

Using the SPI peripheral configuration interface, an application processor (AP) serially writes a configuration image to an iCE65 FPGA using the iCE65's SPI interface, as shown in [Figure 23](#). The iCE65's SPI configuration interface is a separate, independent I/O bank, powered by the VCC\_SPI supply input. Typically, VCC\_SPI is the same voltage as the application processor's I/O. The configuration control signals, CDONE and CRESET\_B, are supplied by the separate I/O Bank 2 voltage input, VCCIO\_2.

This same SPI peripheral interface supports programming for the iCE65's Nonvolatile Configuration Memory (NVMCM).

**Figure 28: iCE65 SPI Peripheral Configuration Interface**



The SPI control signals are defined in [Table 25](#).

**Table 29: SPI Peripheral Configuration Interface Pins (SPI\_SS\_B Low when CRESET\_B Released)**

| Signal Name | Direction  | iCE65 I/O Supply | Description                                                                                                                                                                                     |
|-------------|------------|------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| CDONE       | AP ← iCE65 | VCCIO_2          | Configuration Done output from iCE65. Connect to a 10kΩ pull-up resistor to the application processor I/O voltage, AP_VCC.                                                                      |
| CRESET_B    | AP → iCE65 | VCCIO_2          | Configuration Reset input on iCE65. Typically driven by AP using an open-drain driver, which also requires a 10kΩ pull-up resistor to VCCIO_2.                                                  |
| SPI_VCC     | Supply     | SPI_VCC          | SPI Flash PROM voltage supply input.                                                                                                                                                            |
| SPI_SI      | AP → iCE65 | SPI_VCC          | SPI Serial Input to the iCE65 FPGA, driven by the application processor.                                                                                                                        |
| SPI_SO      | AP ← iCE65 | SPI_VCC          | SPI Serial Output from CE65 device to the application processor. Not actually used during SPI peripheral mode configuration but required if the SPI interface is also used to program the NVCN. |
| SPI_SS_B    | AP → iCE65 | SPI_VCC          | SPI Slave Select output from the application processor. Active Low. Optionally hold Low prior to configuration using a 10kΩ pull-down resistor to ground.                                       |
| SPI_SCK     | AP → iCE65 | SPI_VCC          | SPI Slave Clock output from the application processor.                                                                                                                                          |

After configuration, the SPI port pins are available to the user-application as additional PIO pins, supplied by the SPI\_VCC input voltage, essentially providing a fifth “mini” I/O bank.

### Enabling SPI Configuration Interface

The optional 10 kΩ pull-down resistor on the SPI\_SS\_B signal ensures that the iCE65 FPGA powers up in the SPI peripheral mode. Optionally, the application processor drives the SPI\_SS\_B pin Low when CRESET\_B is released, forcing the iCE65 FPGA into SPI peripheral mode.

### SPI Peripheral Configuration Process

[Figure 29](#) illustrates the interface timing for the SPI peripheral mode and [Figure 30](#) outlines the resulting configuration process. The actual timing specifications appear in [Table 60](#). The application processor (AP) begins by driving the iCE65 CRESET\_B pin Low, resetting the iCE65 FPGA. Similarly, the AP holds the iCE65’s SPI\_SS\_B pin Low. The AP must hold the CRESET\_B pin Low for at least 200 ns. Ultimately, the AP either releases the CRESET\_B pin and allows it to float High via the 10 kΩ pull-up resistor to VCCIO\_2 or drives CRESET\_B High. The iCE65 FPGA enters SPI peripheral mode when the CRESET\_B pin returns High while the SPI\_SS\_B pin is Low.

After driving CRESET\_B High or allowing it to float High, the AP must wait a minimum of  $t_{CR\_SCK}$   $\mu$ s, (see Table 60) allowing the iCE65 FPGA to clear its internal configuration memory.

After waiting for the configuration memory to clear, the AP sends the configuration image generated by the iCEcube development system. An SPI peripheral mode configuration image must not use the ColdBoot or WarmBoot options. Send the entire configuration image, without interruption, serially to the iCE65's SPI\_SI input on the falling edge of the SPI\_SCK clock input. Once the AP sends the **0x7EAA997E** synchronization pattern, the generated SPI\_SCK clock frequency must be within the specified 1 MHz to 25 MHz range (40 ns to 1  $\mu$ s clock period) while sending the configuration image. Send each byte of the configuration image with most-significant bit (msb) first. The AP sends data to the iCE65 FPGA on the falling edge of the SPI\_SCK clock. The iCE65 FPGA internally captures each incoming SPI\_SI data bit on the rising edge of the SPI\_SCK clock. The iCE65's SPI\_SO output pin is not used during SPI peripheral mode but must connect to the AP if the AP also programs the iCE65's Nonvolatile Configuration Memory (NVCM).



Prior to sending the iCE65 configuration image, an SPI NVCM shut-off sequence must be sent.

See AN014 for details.

The iCE65 configuration image must be sent as one contiguous stream without interruption.

The SPI\_SCK clock period must be between 40 ns to 1  $\mu$ s (1 MHz to 25 MHz).

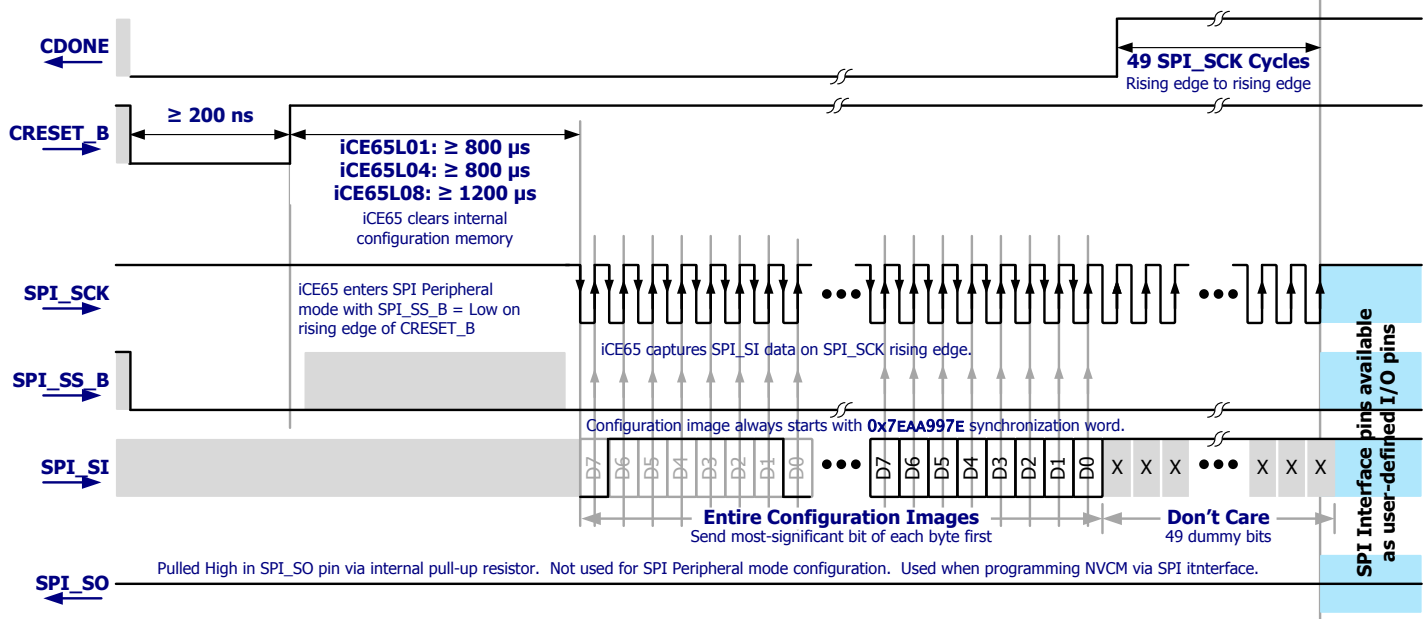
After sending the entire image, the iCE65 FPGA releases the CDONE output allowing it to float High via the 10 k $\Omega$  pull-up resistor to AP\_VCC. If the CDONE pin remains Low, then an error occurred during configuration and the AP should handle the error accordingly for the application.

After the CDONE output pin goes High, send at least 49 additional dummy bits, effectively 49 additional SPI\_SCK clock cycles measured from rising-edge to rising-edge.

After the additional SPI\_CLK cycles, the SPI interface pins then become available to the user application loaded in FPGA.

To reconfigure the iCE65 FPGA or to load a different configuration image, merely restart the configuration process by pulsing CRESET\_B Low or power-cycling the FPGA.

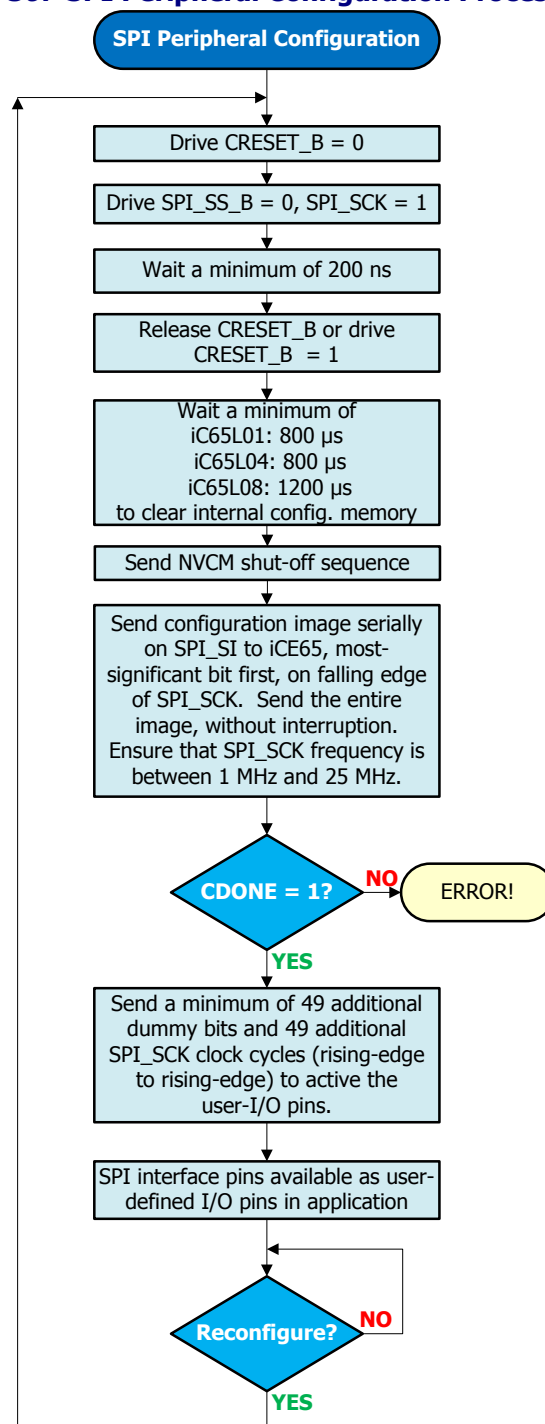
**Figure 29: Application Processor Waveforms for SPI Peripheral Mode Configuration Process**



The iCE65 configuration image must be sent as one contiguous stream without interruption.

The SPI\_SCK clock period must be between 40 ns to 1  $\mu$ s (1 MHz to 25 MHz).

**Figure 30: SPI Peripheral Configuration Process**



### Voltage Compatibility

As shown in Figure 23, there are potentially three different supply voltages involved in the SPI Peripheral interface, described in Table 30.

**Table 30: SPI Peripheral Mode Supply Voltages**

| Supply Voltage  | Description                                  |
|-----------------|----------------------------------------------|
| <b>AP_VCCIO</b> | I/O supply to the Application Processor (AP) |
| <b>VCC_SPI</b>  | Voltage supply for the iCE65 SPI interface.  |
| <b>VCCIO_2</b>  | Supply voltage for the iCE65 I/O Bank 2.     |

Table 31 describes how to maintain voltage compatibility for two interface scenarios. The easiest interface is when the Application Processor's (AP) I/O supply rail and the iCE65's SPI and VCCIO\_2 bank supply rails all connect to the same voltage. The second scenario is when the AP's I/O supply voltage is greater than the iCE65's VCCIO\_2 supply voltage.

**Table 31: CRESET\_B and CDONE Voltage Compatibility**

| Condition                                              | CRESET_B |                            |                                     | CDONE Pull-up | Requirement                                                                                                                                                                                                                                                                                    |
|--------------------------------------------------------|----------|----------------------------|-------------------------------------|---------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|                                                        | Direct   | Open-Drain                 | Pull-up                             |               |                                                                                                                                                                                                                                                                                                |
| <b>VCCIO_AP = VCC_SPI</b><br><b>VCCIO_AP = VCCIO_2</b> | OK       | OK with pull-up            | Required if using open-drain output | Recommended   | AP can directly drive CRESET_B High and Low although an open-drain output recommended is if multiple devices control CRESET_B. If using an open-drain driver, the CRESET_B input must include a 10 kΩ pull-up resistor to VCCIO_2. The 10 kΩ pull-up resistor to AP_VCCIO is also recommended. |
| <b>AP_VCCIO &gt; VCCIO_2</b>                           | N/A      | Required, requires pull-up | Required                            | Required      | The AP must control CRESET_B with an open-drain output, which requires a 10 kΩ pull-up resistor to VCCIO_2. The 10 kΩ pull-up resistor to AP_VCCIO is required.                                                                                                                                |

## JTAG Boundary Scan Port

### Overview

Each iCE65 device includes an IEEE 1149.1-compatible JTAG boundary-scan port. The port supports printed-circuit board (PCB) testing and debugging. It also provides an alternate means to configure the iCE65 device.

### Signal Connections

The JTAG port connections are listed in Table 32.

**Table 32: iCE65 JTAG Boundary Scan Signals**

| Signal Name | Direction | Description                                                                                                  |
|-------------|-----------|--------------------------------------------------------------------------------------------------------------|
| TDI         | Input     | Test Data Input. Must be tied off to GND when unused. (no pull-up resistor)*                                 |
| TMS         | Input     | Test Mode Select. Must be tied off to GND when unused. (no pull-up resistor)*                                |
| TCK         | Input     | Test Clock. Must be tied off to GND when unused. (no pull-up resistor)*                                      |
| TDO         | Output    | Test Data Output.                                                                                            |
| TRST_B      | Input     | Test Reset, active Low. Must be Low during normal device operation. Must be High to enable JTAG operations.* |

\* Must be tied off to GND or VCCIO\_1, else VCCIO\_1 draws current.

Table 33 lists the ball/pin numbers for the JTAG interface by package code. The JTAG interface is available in select package types. The JTAG port is located in I/O Bank 1 along the right edge of the iCE65 device and powered by the VCCIO\_1 supply inputs. Consequently, the JTAG interface uses the associated I/O standards for I/O Bank 1.

**Table 33: JTAG Interface Ball/Pin Numbers by Package**

| JTAG Interface | VQ100 | CB132 | CB196 | CB284 |
|----------------|-------|-------|-------|-------|
| <b>TDI</b>     | N/A   | M12   | M12   | T16   |
| <b>TMS</b>     |       | P14   | P14   | V18   |
| <b>TCK</b>     |       | L12   | L12   | R16   |
| <b>TDO</b>     |       | N14   | N14   | U18   |
| <b>TRST_B</b>  |       | M14   | M14   | T18   |

## Supported JTAG Commands

The JTAG interface supports the IEEE 1149.1 mandatory instructions, including EXTEST, SAMPLE/PRELOAD, and BYPASS.

## Package and Pinout Information

### Maximum User I/O Pins by Package and by I/O Bank

Table 34 lists the maximum number of user-programmable I/O pins by package, with additional detail showing user I/O pins by I/O bank. In some cases, a smaller iCE65 device is packaged in a larger package with unconnected (N.C.) pins or balls, resulting in fewer overall I/O pins. See Table 35 for device-specific I/O counts by package.

**Table 34: User I/O by Package, by I/O Bank**

|                                        | CB81  | QN84  | VQ100   | CB132   | CB196   | CB284   |
|----------------------------------------|-------|-------|---------|---------|---------|---------|
| <b>Package Leads</b>                   | 81    | 84    | 100     | 132     | 196     | 284     |
| <b>Package Body</b> (mm)               | 5 x 5 | 7 x 7 | 14 x 14 | 8 x 8   | 8 x 8   | 12 x 12 |
| <b>Ball Array (balls)</b>              | 9 x 9 | N/A   | N/A     | 14 x 14 | 14 x 14 | 22 x 22 |
| <b>Ball/Lead Pitch</b> (mm)            | 0.5   | 0.5   | 0.5     | 0.5     | 0.5     | 0.5     |
| <b>Maximum user I/O, all I/O banks</b> | 63    | 67    | 72      | 95      | 150     | 222     |
| PIO Pins in Bank 0                     | 17    | 17    | 19      | 26      | 37      | 60      |
| PIO Pins in Bank 1                     | 16    | 17    | 19      | 21      | 38      | 55      |
| PIO Pins in Bank 2                     | 12    | 11    | 12      | 20      | 35      | 53      |
| PIO Pins in Bank 3                     | 18    | 18    | 18      | 24      | 36      | 50      |
| PIO Pins in SPI Interface              | 4     | 4     | 4       | 4       | 4       | 4       |

## Printed Circuit Board Layout Information

For information on how to use the iCE65 packages on a printed circuit board (PCB) design, consult the following application note.

- AN010: iCE65 Printed Circuit Board (PCB Layout) Guidelines

### Maximum User I/O by Device and Package

Table 35 lists the maximum available user I/O by device and by package type. Not all devices are available in all packages. Similarly, smaller iCE65 devices may have unconnected balls in some packages. Devices sharing a common package have similar footprints.

**Table 35: Maximum User I/O by Device and Package**

| Package      | Device   |          |          |
|--------------|----------|----------|----------|
|              | iCE65L01 | iCE65L04 | iCE65L08 |
| <b>CB81</b>  | 63       | —        | —        |
| <b>QN84</b>  | 67       | —        | —        |
| <b>VQ100</b> | 72       | 72       | —        |
| <b>CB132</b> | 93       | 95       | —        |
| <b>CB196</b> | —        | 150      | 150      |
| <b>CB284</b> | —        | 176      | 222      |

## iCE65 Pin Descriptions

Table 36 lists the various iCE65 pins, alphabetically by name. The table indicates the directionality of the signal and the associated I/O bank. The table also indicates if the signal has an internal pull-up resistor enabled during configuration. Finally, the table describes the function of the pin.

**Table 36: iCE65 Pin Description**

| Signal Name                            | Direction | I/O Bank | Pull-up during Config | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |
|----------------------------------------|-----------|----------|-----------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>CDONE</b>                           | Output    | 2        | Yes                   | Configuration Done. Dedicated output. Includes a permanent weak pull-up resistor to <a href="#">VCCIO_2</a> . If driving external devices with CDONE output, connect a 10 kΩ pull-up resistor to <a href="#">VCCIO_2</a> .                                                                                                                                                                                                                                                                     |
| <b>CRESET_B</b>                        | Input     | 2        | No                    | Configuration Reset, active Low. Dedicated input. No internal pull-up resistor. Either actively drive externally or connect a 10 kΩ pull-up resistor to <a href="#">VCCIO_2</a> .                                                                                                                                                                                                                                                                                                              |
| <b>GBIN0/PIO0</b><br><b>GBIN1/PIO0</b> | Input/IO  | 0        | Yes                   | Global buffer input from I/O Bank 0. Optionally, a full-featured PIO pin.                                                                                                                                                                                                                                                                                                                                                                                                                      |
| <b>GBIN2/PIO1</b><br><b>GBIN3/PIO1</b> | Input/IO  | 1        | Yes                   | Global buffer input from I/O Bank 1. Optionally, a full-featured PIO pin.                                                                                                                                                                                                                                                                                                                                                                                                                      |
| <b>GBIN4/PIO2</b><br><b>GBIN5/PIO2</b> | Input/IO  | 2        | Yes                   | Global buffer input from I/O Bank 2. Optionally, a full-featured PIO pin.                                                                                                                                                                                                                                                                                                                                                                                                                      |
| <b>GBIN6/PIO3</b>                      | Input/IO  | 3        | No                    | Global buffer input from I/O Bank 3. Optionally, a full-featured PIO pin.                                                                                                                                                                                                                                                                                                                                                                                                                      |
| <b>GBIN7/PIO3</b>                      | Input/IO  | 3        | No                    | Global buffer input from I/O Bank 3. Optionally, a full-featured PIO pin. Optionally, a differential clock input using the associated differential input pin.                                                                                                                                                                                                                                                                                                                                  |
| <b>GND</b>                             | Supply    | All      | N/A                   | Ground. All must be connected.                                                                                                                                                                                                                                                                                                                                                                                                                                                                 |
| <b>PIOx_yy</b>                         | I/O       | 0,1,2    | Yes                   | Programmable I/O pin defined by the iCE65 configuration bitstream. The 'x' number specifies the I/O bank number in which the I/O pin resides. The 'yy' number specifies the I/O number in that bank.                                                                                                                                                                                                                                                                                           |
| <b>PIO2/CBSEL0</b>                     | Input/IO  | 2        | Yes                   | Optional ColdBoot configuration SElect input, if ColdBoot mode is enabled. A full-featured PIO pin after configuration.                                                                                                                                                                                                                                                                                                                                                                        |
| <b>PIO2/CBSEL1</b>                     | Input/IO  | 2        | Yes                   | Optional ColdBoot configuration SElect input, if ColdBoot mode is enabled. A full-featured PIO pin after configuration.                                                                                                                                                                                                                                                                                                                                                                        |
| <b>PIO3_yy/<br/>DPwwz</b>              | I/O       | 3        | No                    | Programmable I/O pin that is also half of a differential I/O pair. Only available in I/O Bank 3. The 'yy' number specifies the I/O number in that bank. The 'ww' number indicates the differential I/O pair. The 'z' indicates the polarity of the pin in the differential pair. 'A'=negative input. 'B'=positive input.                                                                                                                                                                       |
| <b>PIOS/SPI_SO</b>                     | I/O       | SPI      | Yes                   | SPI Serial Output. A full-featured PIO pin after configuration.                                                                                                                                                                                                                                                                                                                                                                                                                                |
| <b>PIOS /SPI_SI</b>                    | I/O       | SPI      | Yes                   | SPI Serial Input. A full-featured PIO pin after configuration.                                                                                                                                                                                                                                                                                                                                                                                                                                 |
| <b>PIOS /<br/>SPI_SS_B</b>             | I/O       | SPI      | Yes                   | SPI Slave Select. Active Low. Includes an internal weak pull-up resistor to SPI_VCC during configuration. During configuration, the logic level sampled on this pin determines the configuration mode used by the iCE65 device, as shown in <a href="#">Figure 20</a> . An input when sampled at the start of configuration. An input when in SPI Peripheral configuration mode (SPI_SS_B = Low). An output when in SPI Flash configuration mode. A full-featured PIO pin after configuration. |
| <b>PIOS/<br/>SPI_SCK</b>               | I/O       | SPI      | Yes                   | SPI Slave Clock. An input when in SPI Peripheral configuration mode (SPI_SS_B = Low). An output when in SPI Flash configuration mode. A full-featured PIO pin after configuration.                                                                                                                                                                                                                                                                                                             |
| <b>TDI</b>                             | Input     | 1        | No                    | JTAG Test Data Input. If using the JTAG interface, use a 10kΩ pull-up resistor to <a href="#">VCCIO_1</a> . Tie off to GND when unused.                                                                                                                                                                                                                                                                                                                                                        |

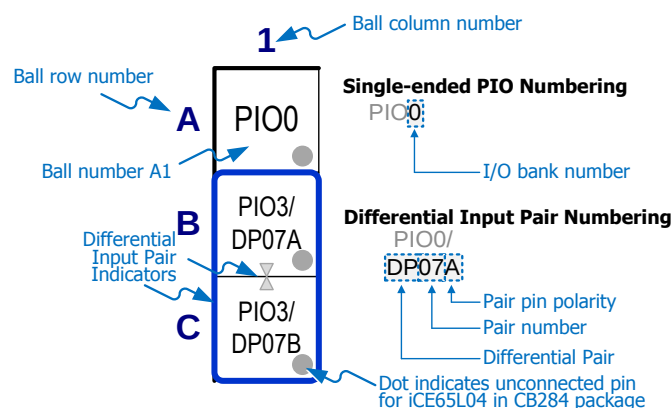
| Signal Name     | Direction         | I/O Bank | Pull-up during Config | Description                                                                                                                                                                                                   |
|-----------------|-------------------|----------|-----------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>TMS</b>      | Input             | 1        | No                    | JTAG Test Mode Select. If using the JTAG interface, use a 10kΩ pull-up resistor to <a href="#">VCCIO_1</a> . Tie off to GND when unused.                                                                      |
| <b>TCK</b>      | Input             | 1        | No                    | JTAG Test Clock. If using the JTAG interface, use a 10kΩ pull-up resistor to <a href="#">VCCIO_1</a> . Tie off to GND when unused.                                                                            |
| <b>TDO</b>      | Output            | 1        | No                    | JTAG Test Data Output.                                                                                                                                                                                        |
| <b>TRST_B</b>   | Input             | 1        | No                    | JTAG Test Reset, active Low. Keep Low during normal operation; High for JTAG operation.                                                                                                                       |
| <b>VCC</b>      | Supply            | All      | N/A                   | Internal core voltage supply. All must be connected.                                                                                                                                                          |
| <b>VCCIO_0</b>  | Supply            | 0        | N/A                   | Voltage supply to I/O Bank 0. All such pins or balls on the package must be connected. Can be disconnected or turned off without affecting the <a href="#">Power-On Reset (POR)</a> circuit.                  |
| <b>VCCIO_1</b>  | Supply            | 1        | N/A                   | Voltage supply to I/O Bank 1. All such pins or balls on the package must be connected. Required to guarantee a valid input voltage on <a href="#">TRST_B</a> JTAG pin.                                        |
| <b>VCCIO_2</b>  | Supply            | 2        | N/A                   | Voltage supply to I/O Bank 2. All such pins or balls on the package must be connected. Required input to the <a href="#">Power-On Reset (POR)</a> circuit.                                                    |
| <b>VCCIO_3</b>  | Supply            | 3        | N/A                   | Voltage supply to I/O Bank 3. All such pins or balls on the package must be connected. Can be disconnected or turned off without affecting the <a href="#">Power-On Reset (POR)</a> circuit.                  |
| <b>SPI_VCC</b>  | Supply            | SPI      | N/A                   | SPI interface voltage supply input. Must have a valid voltage even if configuring from NVCM. Required input to the <a href="#">Power-On Reset (POR)</a> circuit.                                              |
| <b>VPP_FAST</b> | Supply            | All      | N/A                   | Direct programming voltage supply. If unused, leave floating or unconnected during normal operation.                                                                                                          |
| <b>VPP_2V5</b>  | Supply            | All      | N/A                   | Programming supply voltage. When the iCE65 device is active, VPP_2V5 must be in the valid range between 2.3 V to 3.47 V to release the Power-On Reset circuit, even if the application is not using the NVCM. |
| <b>VREF</b>     | Voltage Reference | 3        | N/A                   | Input reference voltage in I/O Bank 3 for the SSTL I/O standard. This pin only appears on the CB284 package and for die-based products.                                                                       |

N/A = Not Applicable

## iCE65 Package Footprint Diagram Conventions

Figure 31 illustrates the naming conventions used in the following footprint diagrams. Each PIO pin is associated with an I/O Bank. PIO pins in I/O Bank 3 that support differential inputs are also numbered by differential input pair.

**Figure 31: CB Package Footprint Diagram Conventions**



## CB81 Chip-Scale Ball-Grid Array

The CB81 package is a full ball grid array with 0.5 mm ball pitch. The iCE65L01 device is available in this package.

### ***Footprint Diagram***

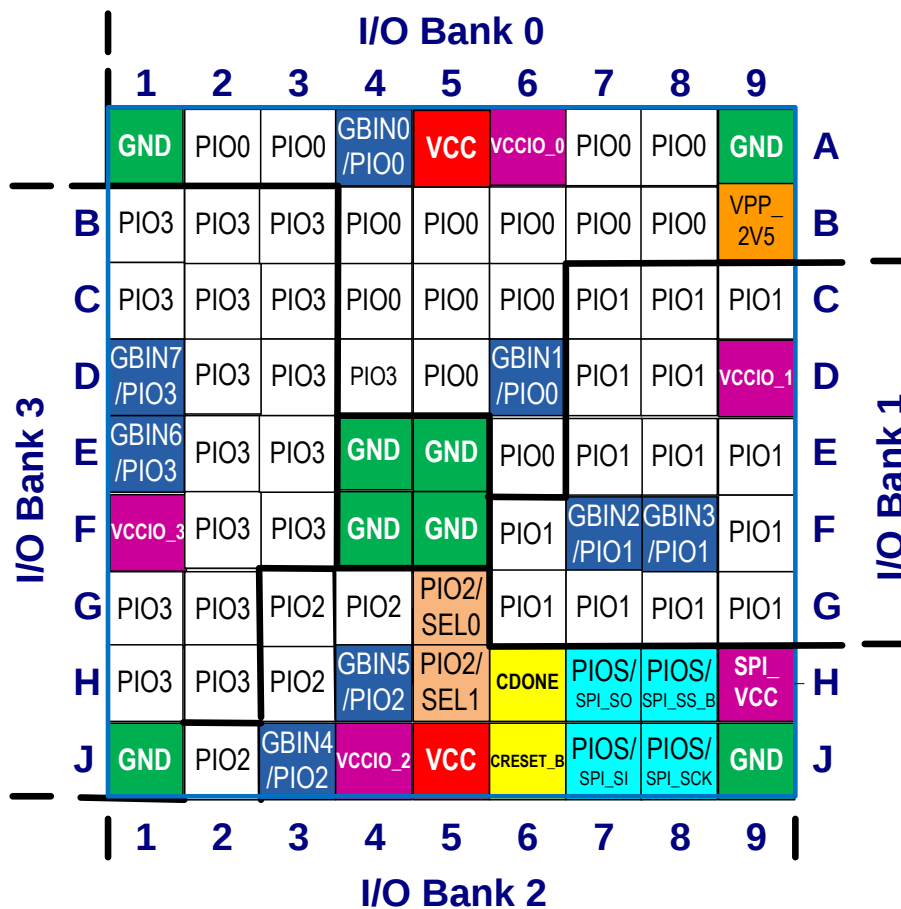
Figure 32 shows the iCE65 footprint diagram for the CB81 package.

Figure 31 shows the conventions used in the diagram.

Also see [Table 37](#) for a complete, detailed pinout for the 81-ball BGA package.

The signal pins are also grouped into the four I/O Banks and the SPI interface.

**Figure 32: iCE65L01 CB81 Chip-Scale BGA Footprint (Top View)**



## Pinout Table

Table 37 provides a detailed pinout table for the CB81 package. Pins are generally arranged by I/O bank, then by ball function.

**Table 37: iCE65 CB81 Chip-scale BGA Pinout Table**

| Ball Function      | Ball Number | Pin Type | Bank |
|--------------------|-------------|----------|------|
| <b>PIO0</b>        | A2          | PIO      | 0    |
| <b>PIO0</b>        | A3          | PIO      | 0    |
| <b>GBIN0/PIO0</b>  | A4          | GBIN     | 0    |
| <b>PIO0</b>        | A7          | PIO      | 0    |
| <b>PIO0</b>        | A8          | PIO      | 0    |
| <b>PIO0</b>        | B4          | PIO      | 0    |
| <b>PIO0</b>        | B5          | PIO      | 0    |
| <b>PIO0</b>        | B6          | PIO      | 0    |
| <b>PIO0</b>        | B7          | PIO      | 0    |
| <b>PIO0</b>        | B8          | PIO      | 0    |
| <b>PIO0</b>        | C4          | PIO      | 0    |
| <b>PIO0</b>        | C5          | PIO      | 0    |
| <b>PIO0</b>        | C6          | PIO      | 0    |
| <b>PIO0</b>        | D4          | PIO      | 0    |
| <b>PIO0</b>        | D5          | PIO      | 0    |
| <b>GBIN1/PIO0</b>  | D6          | GBIN     | 0    |
| <b>PIO0</b>        | E6          | PIO      | 0    |
| <b>VCCIO_0</b>     | A6          | VCCIO    | 0    |
| <b>PIO1</b>        | C7          | PIO      | 1    |
| <b>PIO1</b>        | C8          | PIO      | 1    |
| <b>PIO1</b>        | C9          | PIO      | 1    |
| <b>PIO1</b>        | D7          | PIO      | 1    |
| <b>PIO1</b>        | D8          | PIO      | 1    |
| <b>PIO1</b>        | E7          | PIO      | 1    |
| <b>PIO1</b>        | E8          | PIO      | 1    |
| <b>PIO1</b>        | E9          | PIO      | 1    |
| <b>PIO1</b>        | F6          | PIO      | 1    |
| <b>GBIN2/PIO1</b>  | F7          | GBIN     | 1    |
| <b>GBIN3/PIO1</b>  | F8          | GBIN     | 1    |
| <b>PIO1</b>        | F9          | PIO      | 1    |
| <b>PIO1</b>        | G6          | PIO      | 1    |
| <b>PIO1</b>        | G7          | PIO      | 1    |
| <b>PIO1</b>        | G8          | PIO      | 1    |
| <b>PIO1</b>        | G9          | PIO      | 1    |
| <b>VCCIO_1</b>     | D9          | VCCIO    | 1    |
| <b>CDONE</b>       | H6          | CONFIG   | 2    |
| <b>CRESET_B</b>    | J6          | CONFIG   | 2    |
| <b>PIO2</b>        | G3          | PIO      | 2    |
| <b>PIO2</b>        | G4          | PIO      | 2    |
| <b>PIO2/CBSEL0</b> | G5          | PIO      | 2    |
| <b>PIO2</b>        | H3          | PIO      | 2    |
| <b>GBIN5/PIO2</b>  | H4          | PIO      | 2    |
| <b>PIO2/CBSEL1</b> | H5          | PIO      | 2    |
| <b>PIO2</b>        | J2          | PIO      | 2    |
| <b>GBIN4/PIO2</b>  | J3          | PIO      | 2    |
| <b>VCCIO_2</b>     | J4          | PIO      | 2    |

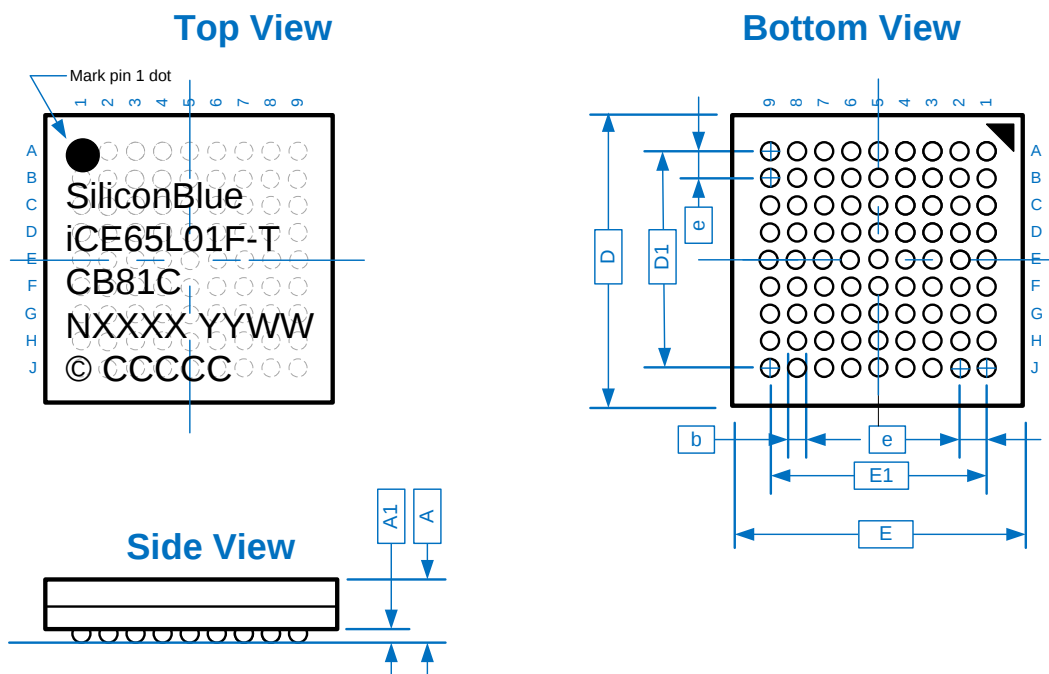
# iCE65 Ultra Low-Power mobileFPGA™ Family

| Ball Function        | Ball Number | Pin Type | Bank |
|----------------------|-------------|----------|------|
| <b>PIO3</b>          | B1          | PIO      | 3    |
| <b>PIO3</b>          | B2          | PIO      | 3    |
| <b>PIO3</b>          | B3          | PIO      | 3    |
| <b>PIO3</b>          | C1          | PIO      | 3    |
| <b>PIO3</b>          | C2          | PIO      | 3    |
| <b>PIO3</b>          | C3          | PIO      | 3    |
| <b>GBIN7/PIO3</b>    | D1          | GBIN     | 3    |
| <b>PIO3</b>          | D2          | PIO      | 3    |
| <b>PIO3</b>          | D3          | PIO      | 3    |
| <b>GBIN6/PIO3</b>    | E1          | GBIN     | 3    |
| <b>PIO3</b>          | E2          | PIO      | 3    |
| <b>PIO3</b>          | E3          | PIO      | 3    |
| <b>PIO3</b>          | F2          | PIO      | 3    |
| <b>PIO3</b>          | F3          | PIO      | 3    |
| <b>PIO3</b>          | G1          | PIO      | 3    |
| <b>PIO3</b>          | G2          | PIO      | 3    |
| <b>PIO3</b>          | H1          | PIO      | 3    |
| <b>PIO3</b>          | H2          | PIO      | 3    |
| <b>VCCIO_3</b>       | F1          | VCCIO    | 3    |
| <b>PIOS/SPI_SO</b>   | H7          | SPI      | SPI  |
| <b>PIOS/SPI_SI</b>   | J7          | SPI      | SPI  |
| <b>PIOS/SPI_SCK</b>  | J8          | SPI      | SPI  |
| <b>PIOS/SPI_SS_B</b> | H8          | SPI      | SPI  |
| <b>SPI_VCC</b>       | H9          | SPI      | SPI  |
| <b>GND</b>           | A1          | GND      | GND  |
| <b>GND</b>           | A9          | GND      | GND  |
| <b>GND</b>           | J9          | GND      | GND  |
| <b>GND</b>           | J1          | GND      | GND  |
| <b>GND</b>           | E4          | GND      | GND  |
| <b>GND</b>           | E5          | GND      | GND  |
| <b>GND</b>           | F4          | GND      | GND  |
| <b>GND</b>           | F5          | GND      | GND  |
| <b>VCC</b>           | A5          | VCC      | VCC  |
| <b>VCC</b>           | J5          | VCC      | VCC  |
| <b>VPP_2V5</b>       | B9          | VPP      | VPP  |

## Package Mechanical Drawing

**Figure 33: CB81 Package Mechanical Drawing**

**CB81:** 5 x 5 mm, 81-ball, 0.5 mm ball-pitch, chip-scale ball grid array



| Description                |   | Symbol | Min. | Nominal | Max. | Units   |
|----------------------------|---|--------|------|---------|------|---------|
| Number of Ball Columns     | X |        |      | 9       |      | Columns |
| Number of Ball Rows        | Y |        |      | 9       |      | Rows    |
| Number of Signal Balls     |   | n      |      | 81      |      | Balls   |
| Body Size                  | X | E      | 4.90 | 5.00    | 5.10 | mm      |
|                            | Y | D      | 4.90 | 5.00    | 5.10 |         |
| Ball Pitch                 |   | e      | —    | 0.50    | —    |         |
| Ball Diameter              |   | b      | 0.2  | —       | 0.3  |         |
| Edge Ball Center to Center | X | E1     | —    | 4.00    | —    |         |
|                            | Y | D1     | —    | 4.00    | —    |         |
| Package Height             |   | A      | —    | —       | 1.00 |         |
| Stand Off                  |   | A1     | 0.15 | —       | 0.25 |         |

### Top Marking Format

| Line | Content   | Description  |
|------|-----------|--------------|
| 1    | Logo      | Logo         |
| 2    | iCE65P01F | Part number  |
|      | -T        | Power/Speed  |
| 3    | CB81C     | Package type |
|      | ENG       | Engineering  |
| 4    | NXXXX     | Lot Number   |
| 5    | YYWW      | Date Code    |
| 6    | © CCCCC   | Country      |

### Thermal Resistance

| Junction-to-Ambient<br>$\theta_{JA}$ ( $^{\circ}\text{C}/\text{W}$ ) |         |
|----------------------------------------------------------------------|---------|
| 0 LFM                                                                | 200 LFM |
| 67                                                                   | 57      |

## QN84 Quad Flat Pack No-Lead

The QN84 is a Quad Flat Pack No-Lead package with a 0.5 mm pad pitch.

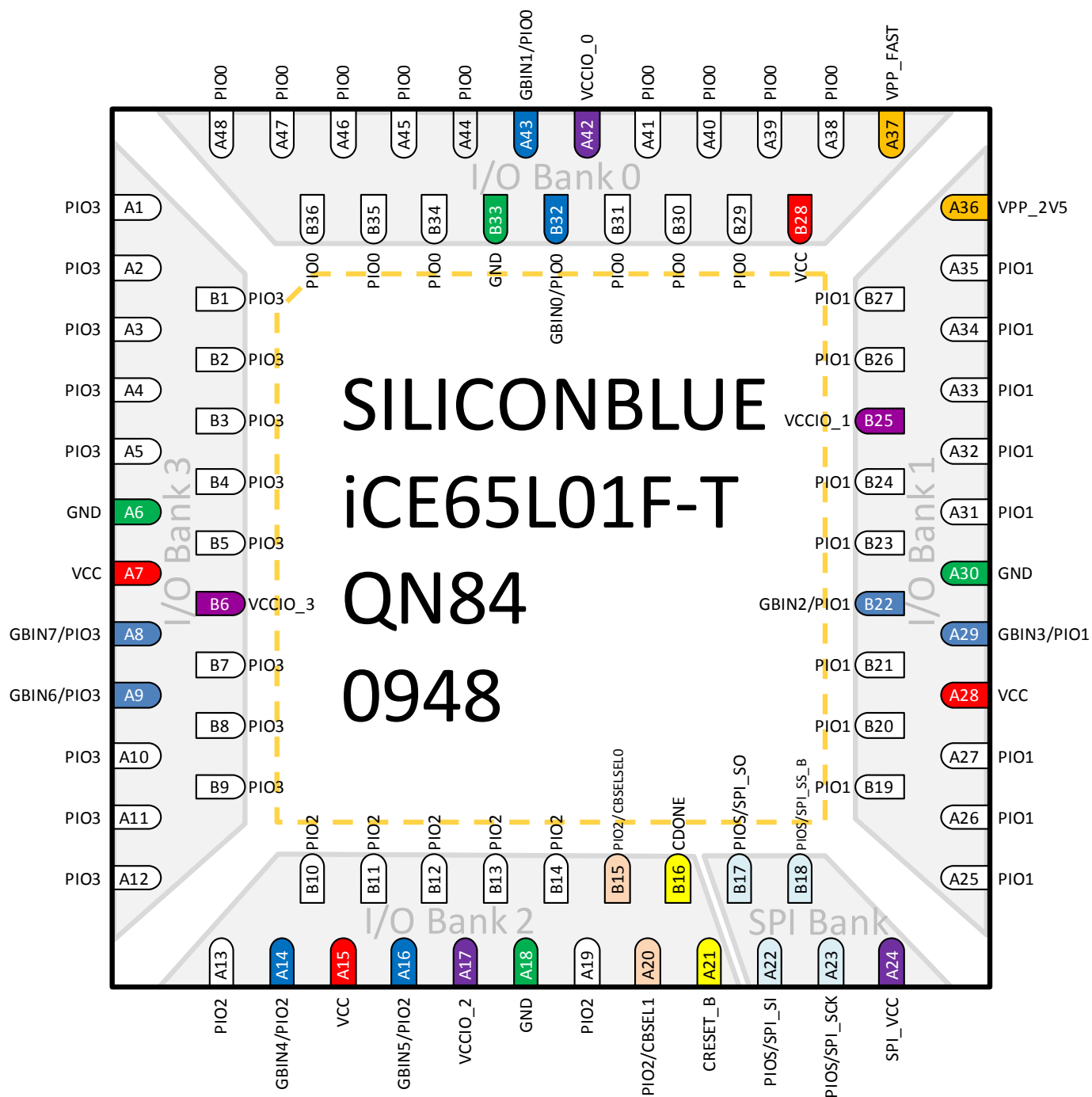
### Footprint Diagram

Figure 34 shows the iCE65 footprint diagram for the QN84 package.

Also see Table 38 for a complete, detailed pinout for the QN84 package.

The signal pins are also grouped into the four I/O Banks and the SPI interface.

Figure 34: iCE65 QN84 Quad Flat Pack No-Lead Footprint (Top View)



## Pinout Table

Table 38 provides a detailed pinout table for the QN84 package. Pins are generally arranged by I/O bank, then by ball function. The QN84 package has no JTAG pins.

Table 38: iCE65 QN84 Chip-scale BGA Pinout Table

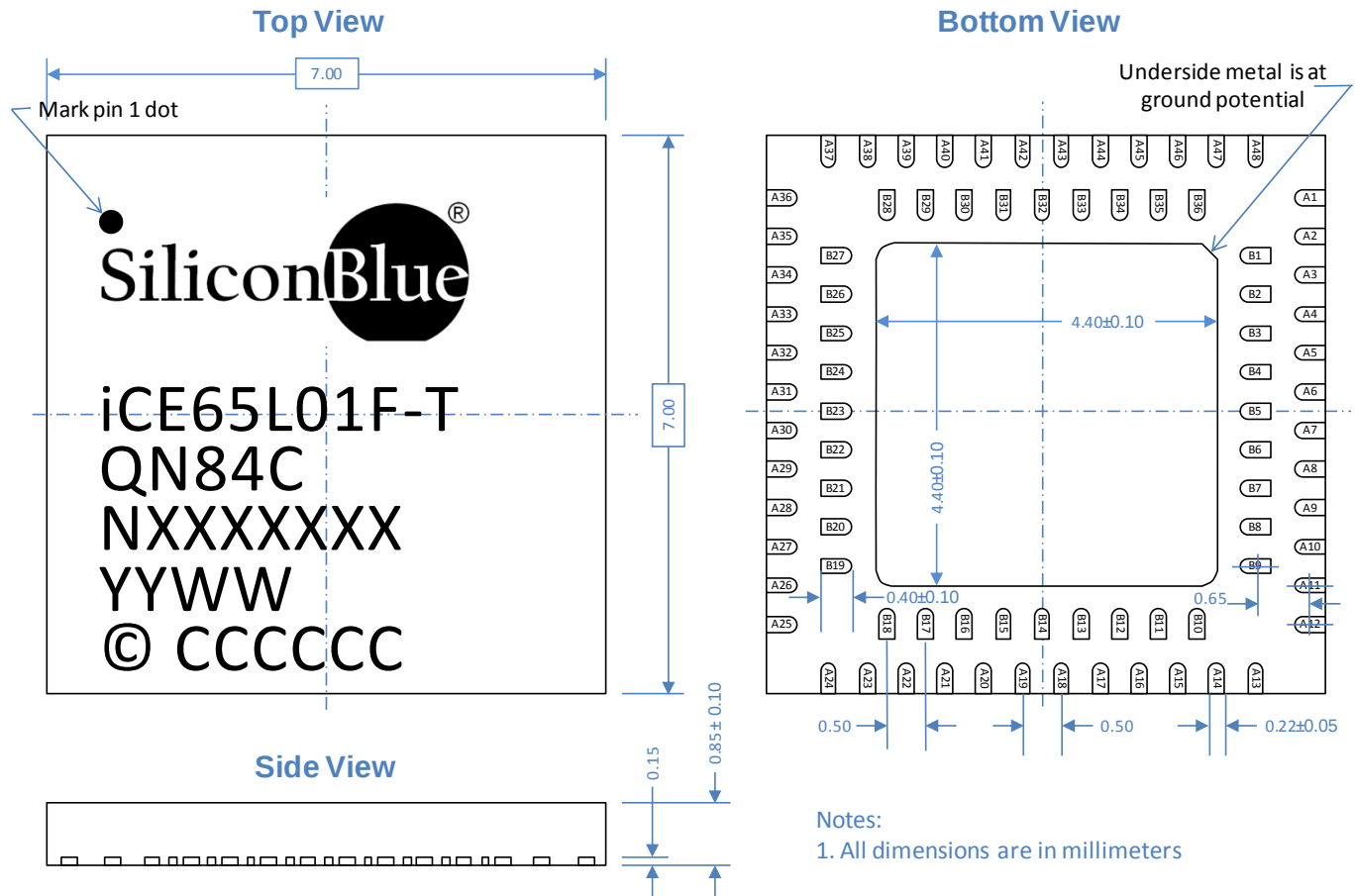
| Ball Function     | Ball Number | Pin Type | Bank |
|-------------------|-------------|----------|------|
| <b>GBIN0/PIO0</b> | B32         | GBIN     | 0    |
| <b>GBIN1/PIO0</b> | A43         | GBIN     | 0    |
| <b>PIO0</b>       | A38         | PIO      | 0    |
| <b>PIO0</b>       | A39         | PIO      | 0    |
| <b>PIO0</b>       | A40         | PIO      | 0    |
| <b>PIO0</b>       | A41         | PIO      | 0    |
| <b>PIO0</b>       | A44         | PIO      | 0    |
| <b>PIO0</b>       | A45         | PIO      | 0    |
| <b>PIO0</b>       | A46         | PIO      | 0    |
| <b>PIO0</b>       | A47         | PIO      | 0    |
| <b>PIO0</b>       | A48         | PIO      | 0    |
| <b>PIO0</b>       | B29         | PIO      | 0    |
| <b>PIO0</b>       | B30         | PIO      | 0    |
| <b>PIO0</b>       | B31         | PIO      | 0    |
| <b>PIO0</b>       | B34         | PIO      | 0    |
| <b>PIO0</b>       | B35         | PIO      | 0    |
| <b>PIO0</b>       | B36         | PIO      | 0    |
| <b>VCCIO_0</b>    | A42         | VCCIO    | 0    |
| <b>GBIN2/PIO1</b> | B22         | GBIN     | 1    |
| <b>GBIN3/PIO1</b> | A29         | GBIN     | 1    |
| <b>PIO1</b>       | A25         | PIO      | 1    |
| <b>PIO1</b>       | A26         | PIO      | 1    |
| <b>PIO1</b>       | A27         | PIO      | 1    |
| <b>PIO1</b>       | A31         | PIO      | 1    |
| <b>PIO1</b>       | A32         | PIO      | 1    |
| <b>PIO1</b>       | A33         | PIO      | 1    |
| <b>PIO1</b>       | A34         | PIO      | 1    |
| <b>PIO1</b>       | A35         | PIO      | 1    |
| <b>PIO1</b>       | B19         | PIO      | 1    |
| <b>PIO1</b>       | B20         | PIO      | 1    |
| <b>PIO1</b>       | B21         | PIO      | 1    |
| <b>PIO1</b>       | B23         | PIO      | 1    |
| <b>PIO1</b>       | B24         | PIO      | 1    |
| <b>PIO1</b>       | B26         | PIO      | 1    |
| <b>PIO1</b>       | B27         | PIO      | 1    |
| <b>VCCIO_1</b>    | B25         | VCCIO    | 1    |
| <b>CDONE</b>      | B16         | CONFIG   | 2    |
| <b>CRESET_B</b>   | A21         | CONFIG   | 2    |
| <b>GBIN4/PIO2</b> | A14         | GBIN     | 2    |
| <b>GBIN5/PIO2</b> | A16         | GBIN     | 2    |
| <b>PIO2</b>       | A13         | PIO      | 2    |
| <b>PIO2</b>       | B12         | PIO      | 2    |
| <b>PIO2</b>       | A19         | PIO      | 2    |
| <b>PIO2</b>       | B10         | PIO      | 2    |
| <b>PIO2</b>       | B11         | PIO      | 2    |
| <b>PIO2</b>       | B13         | PIO      | 2    |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| Ball Function        | Ball Number | Pin Type | Bank |
|----------------------|-------------|----------|------|
| <b>PIO2</b>          | B14         | PIO      | 2    |
| <b>PIO2/CBSEL0</b>   | B15         | PIO      | 2    |
| <b>PIO2/CBSEL1</b>   | A20         | PIO      | 2    |
| <b>VCCIO_2</b>       | A17         | PIO      | 2    |
| <b>GBIN6/PIO3</b>    | A9          | GBIN     | 3    |
| <b>GBIN7/PIO3</b>    | A8          | GBIN     | 3    |
| <b>PIO3</b>          | A1          | PIO      | 3    |
| <b>PIO3</b>          | A2          | PIO      | 3    |
| <b>PIO3</b>          | A3          | PIO      | 3    |
| <b>PIO3</b>          | A4          | PIO      | 3    |
| <b>PIO3</b>          | A5          | PIO      | 3    |
| <b>PIO3</b>          | A10         | PIO      | 3    |
| <b>PIO3</b>          | A11         | PIO      | 3    |
| <b>PIO3</b>          | A12         | PIO      | 3    |
| <b>PIO3</b>          | B1          | PIO      | 3    |
| <b>PIO3</b>          | B2          | PIO      | 3    |
| <b>PIO3</b>          | B3          | PIO      | 3    |
| <b>PIO3</b>          | B4          | PIO      | 3    |
| <b>PIO3</b>          | B5          | PIO      | 3    |
| <b>PIO3</b>          | B7          | PIO      | 3    |
| <b>PIO3</b>          | B8          | PIO      | 3    |
| <b>PIO3</b>          | B9          | PIO      | 3    |
| <b>VCCIO_3</b>       | B6          | VCCIO    | 3    |
| <b>PIOS/SPI_SO</b>   | B17         | SPI      | SPI  |
| <b>PIOS/SPI_SI</b>   | A22         | SPI      | SPI  |
| <b>PIOS/SPI_SCK</b>  | A23         | SPI      | SPI  |
| <b>PIOS/SPI_SS_B</b> | B18         | SPI      | SPI  |
| <b>SPI_VCC</b>       | A24         | SPI      | SPI  |
| <b>GND</b>           | A6          | GND      | GND  |
| <b>GND</b>           | A18         | GND      | GND  |
| <b>GND</b>           | A30         | GND      | GND  |
| <b>GND</b>           | B33         | GND      | GND  |
| <b>VCC</b>           | A7          | VCC      | VCC  |
| <b>VCC</b>           | A15         | VCC      | VCC  |
| <b>VCC</b>           | A28         | VCC      | VCC  |
| <b>VCC</b>           | B28         | VCC      | VCC  |
| <b>VPP_2V5</b>       | A36         | VPP      | VPP  |
| <b>VPP_FAST</b>      | A37         | VPP      | VPP  |

## Package Mechanical Drawing

**Figure 35: QN84 Package Mechanical Drawing**



### Top Marking Format

| Line | Content   | Description  |
|------|-----------|--------------|
| 1    | Logo      | Logo         |
| 2    | iCE65L01F | Part number  |
|      | -T        | Power/Speed  |
| 3    | QN84C     | Package type |
|      | ENG       | Engineering  |
| 4    | NXXXXXXX  | Lot Number   |
| 5    | YYWW      | Date Code    |
| 6    | © CCCCCC  | Country      |

### Thermal Resistance

| Junction-to-Ambient *<br>$\theta_{JA}$ (°C/W) |         |
|-----------------------------------------------|---------|
| 0 LFM                                         | 200 LFM |
| 45                                            | 44      |

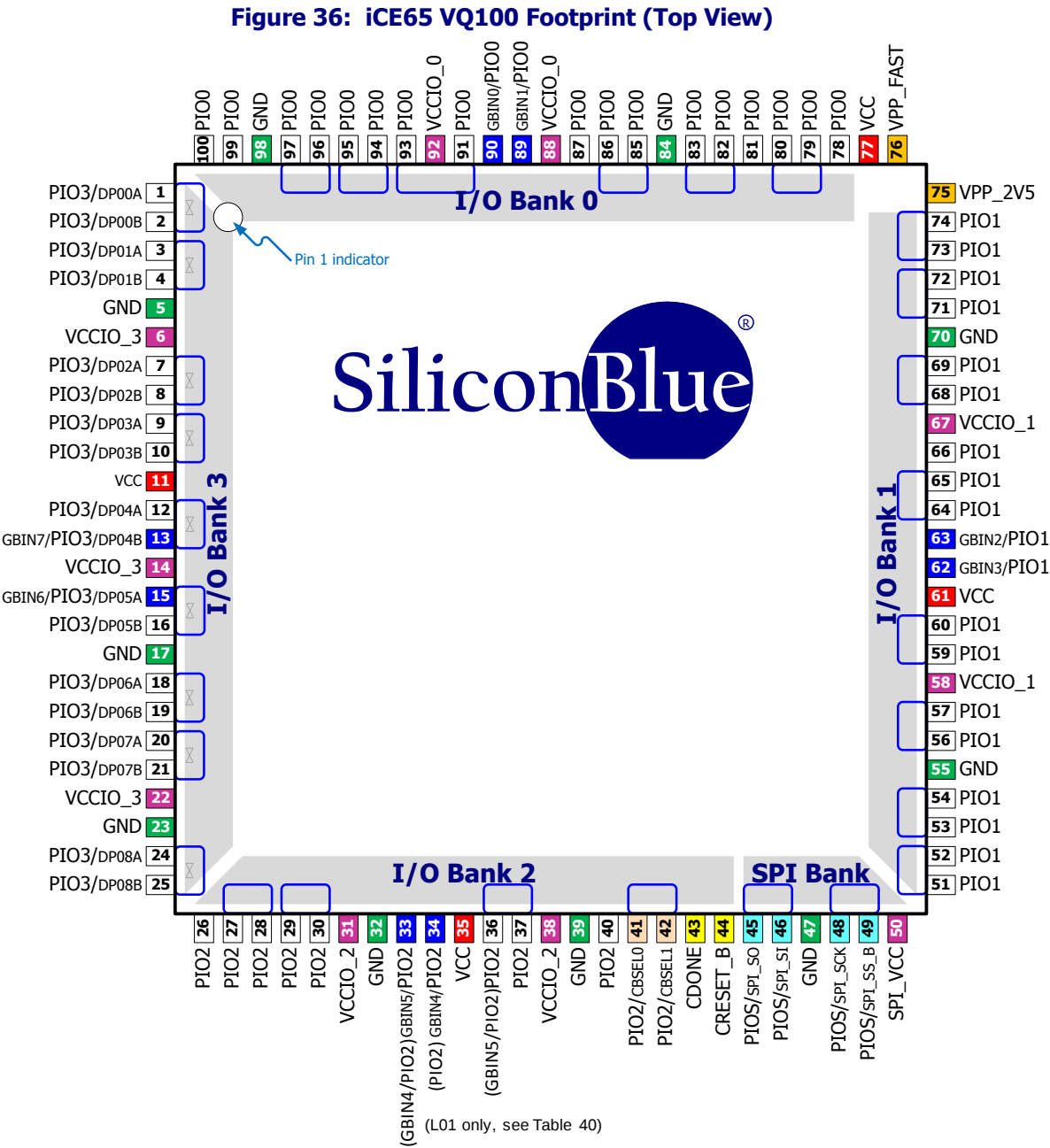
\* With PCB thermal vias

VQ100 Very-thin Quad Flat Package

The VQ100 package is a very-thin quad-flat package with 0.5 mm lead pitch. The iCE65L01 and iCE65L04 devices are available in this package.

Footprint Diagram

Figure 36 shows the footprint diagram for the 100-lead very-thin quad-flat package (VQ100). See Table 40 for a complete, detailed pinout for the 100-lead very-thin quad-flat package. The signal pins are also grouped into the four I/O Banks and the SPI interface.



Pinout Table

Table 39 provides a detailed pinout table for the VQ100 package. Pins are generally arranged by I/O bank, then by pin function. The table also highlights the differential I/O pairs in I/O Bank 3. The VQ100 package has no JTAG pins.

**Table 39: iCE65 VQ100 Pinout Table**

| Pin Function      | Pin Number                   | Type   | Bank |
|-------------------|------------------------------|--------|------|
| <b>GBIN0/PIO0</b> | 90                           | GBIN   | 0    |
| <b>GBIN1/PIO0</b> | 89                           | GBIN   | 0    |
| <b>PIO0</b>       | 78                           | PIO    | 0    |
| <b>PIO0</b>       | 79                           | PIO    | 0    |
| <b>PIO0</b>       | 80                           | PIO    | 0    |
| <b>PIO0</b>       | 81                           | PIO    | 0    |
| <b>PIO0</b>       | 82                           | PIO    | 0    |
| <b>PIO0</b>       | 83                           | PIO    | 0    |
| <b>PIO0</b>       | 85                           | PIO    | 0    |
| <b>PIO0</b>       | 86                           | PIO    | 0    |
| <b>PIO0</b>       | 87                           | PIO    | 0    |
| <b>PIO0</b>       | 91                           | PIO    | 0    |
| <b>PIO0</b>       | 93                           | PIO    | 0    |
| <b>PIO0</b>       | 94                           | PIO    | 0    |
| <b>PIO0</b>       | 95                           | PIO    | 0    |
| <b>PIO0</b>       | 96                           | PIO    | 0    |
| <b>PIO0</b>       | 97                           | PIO    | 0    |
| <b>PIO0</b>       | 99                           | PIO    | 0    |
| <b>PIO0</b>       | 100                          | PIO    | 0    |
| <b>VCCIO_0</b>    | 88                           | VCCIO  | 0    |
| <b>VCCIO_0</b>    | 92                           | VCCIO  | 0    |
| <b>GBIN2/PIO1</b> | 63                           | GBIN   | 1    |
| <b>GBIN3/PIO1</b> | 62                           | GBIN   | 1    |
| <b>PIO1</b>       | 51                           | PIO    | 1    |
| <b>PIO1</b>       | 52                           | PIO    | 1    |
| <b>PIO1</b>       | 53                           | PIO    | 1    |
| <b>PIO1</b>       | 54                           | PIO    | 1    |
| <b>PIO1</b>       | 56                           | PIO    | 1    |
| <b>PIO1</b>       | 57                           | PIO    | 1    |
| <b>PIO1</b>       | 59                           | PIO    | 1    |
| <b>PIO1</b>       | 60                           | PIO    | 1    |
| <b>PIO1</b>       | 64                           | PIO    | 1    |
| <b>PIO1</b>       | 65                           | PIO    | 1    |
| <b>PIO1</b>       | 66                           | PIO    | 1    |
| <b>PIO1</b>       | 68                           | PIO    | 1    |
| <b>PIO1</b>       | 69                           | PIO    | 1    |
| <b>PIO1</b>       | 71                           | PIO    | 1    |
| <b>PIO1</b>       | 72                           | PIO    | 1    |
| <b>PIO1</b>       | 73                           | PIO    | 1    |
| <b>PIO1</b>       | 74                           | PIO    | 1    |
| <b>VCCIO_1</b>    | 58                           | VCCIO  | 1    |
| <b>VCCIO_1</b>    | 67                           | VCCIO  | 1    |
| <b>CDONE</b>      | 43                           | CONFIG | 2    |
| <b>CRESET_B</b>   | 44                           | CONFIG | 2    |
| <b>GBIN4/PIO2</b> | iCE65L01: 33<br>iCE65L04: 34 | GBIN   | 2    |
| <b>GBIN5/PIO2</b> | iCE65L01: 36<br>iCE65L04: 33 | GBIN   | 2    |
| <b>PIO2</b>       | 26                           | PIO    | 2    |
| <b>PIO2</b>       | 27                           | PIO    | 2    |

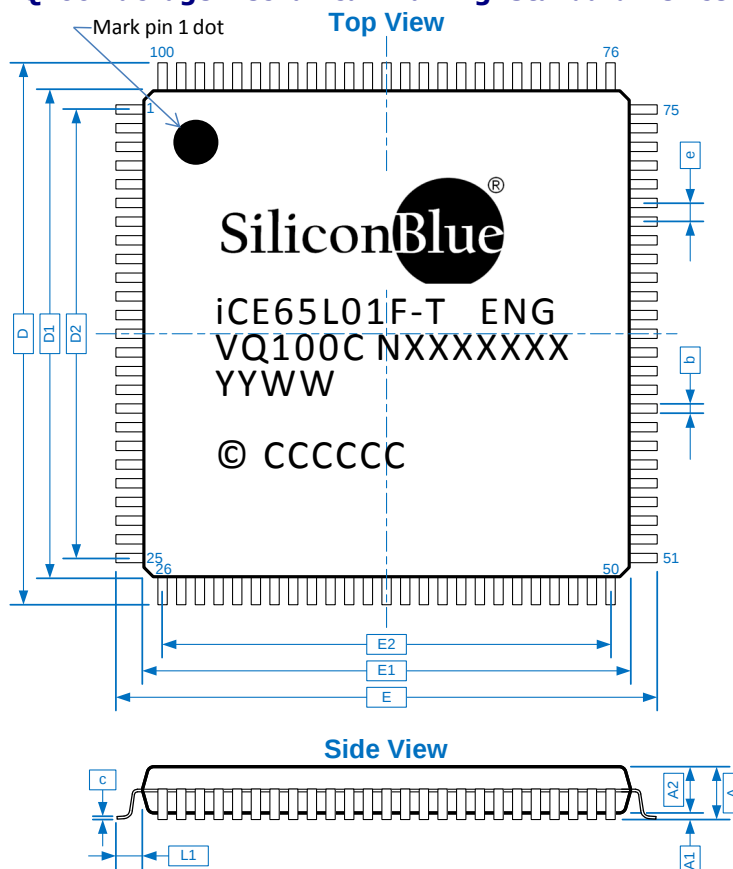
# iCE65 Ultra Low-Power mobileFPGA™ Family

| Pin Function            | Pin Number                   | Type      | Bank |
|-------------------------|------------------------------|-----------|------|
| <b>PIO2</b>             | 28                           | PIO       | 2    |
| <b>PIO2</b>             | 29                           | PIO       | 2    |
| <b>PIO2</b>             | 30                           | PIO       | 2    |
| <b>PIO2</b>             | iCE65L01: 34<br>iCE65L04: 36 | PIO       | 2    |
| <b>PIO2</b>             | 37                           | PIO       | 2    |
| <b>PIO2</b>             | 40                           | PIO       | 2    |
| <b>PIO2/CBSEL0</b>      | 41                           | PIO       | 2    |
| <b>PIO2/CBSEL1</b>      | 42                           | PIO       | 2    |
| <b>VCCIO_2</b>          | 31                           | VCCIO     | 2    |
| <b>VCCIO_2</b>          | 38                           | VCCIO     | 2    |
| <b>PIO3/DP00A</b>       | 1                            | PIO/DPIO  | 3    |
| <b>PIO3/DP00B</b>       | 2                            | PIO/DPIO  | 3    |
| <b>PIO3/DP01A</b>       | 3                            | PIO/DPIO  | 3    |
| <b>PIO3/DP01B</b>       | 4                            | PIO/DPIO  | 3    |
| <b>PIO3/DP02A</b>       | 7                            | PIO/DPIO  | 3    |
| <b>PIO3/DP02B</b>       | 8                            | PIO/DPIO  | 3    |
| <b>PIO3/DP03A</b>       | 9                            | PIO/DPIO  | 3    |
| <b>PIO3/DP03B</b>       | 10                           | PIO/DPIO  | 3    |
| <b>PIO3/DP04A</b>       | 12                           | PIO/DPIO  | 3    |
| <b>GBIN7/PIO3/DP04B</b> | 13                           | GBIN/DPIO | 3    |
| <b>GBIN6/PIO3/DP05A</b> | 15                           | GBIN/DPIO | 3    |
| <b>PIO3/DP05B</b>       | 16                           | PIO/DPIO  | 3    |
| <b>PIO3/DP06A</b>       | 18                           | PIO/DPIO  | 3    |
| <b>PIO3/DP06B</b>       | 19                           | PIO/DPIO  | 3    |
| <b>PIO3/DP07A</b>       | 20                           | PIO/DPIO  | 3    |
| <b>PIO3/DP07B</b>       | 21                           | PIO/DPIO  | 3    |
| <b>PIO3/DP08A</b>       | 24                           | PIO/DPIO  | 3    |
| <b>PIO3/DP08B</b>       | 25                           | PIO/DPIO  | 3    |
| <b>VCCIO_3</b>          | 6                            | VCCIO     | 3    |
| <b>VCCIO_3</b>          | 14                           | VCCIO     | 3    |
| <b>VCCIO_3</b>          | 22                           | VCCIO     | 3    |
| <b>PIOS/SPI_SO</b>      | 45                           | SPI       | SPI  |
| <b>PIOS/SPI_SI</b>      | 46                           | SPI       | SPI  |
| <b>PIOS/SPI_SCK</b>     | 48                           | SPI       | SPI  |
| <b>PIOS/SPI_SS_B</b>    | 49                           | SPI       | SPI  |
| <b>SPI_VCC</b>          | 50                           | SPI       | SPI  |
| <b>GND</b>              | 5                            | GND       | GND  |
| <b>GND</b>              | 17                           | GND       | GND  |
| <b>GND</b>              | 23                           | GND       | GND  |
| <b>GND</b>              | 32                           | GND       | GND  |
| <b>GND</b>              | 39                           | GND       | GND  |
| <b>GND</b>              | 47                           | GND       | GND  |
| <b>GND</b>              | 55                           | GND       | GND  |
| <b>GND</b>              | 70                           | GND       | GND  |
| <b>GND</b>              | 84                           | GND       | GND  |
| <b>GND</b>              | 98                           | GND       | GND  |
| <b>VCC</b>              | 11                           | VCC       | VCC  |
| <b>VCC</b>              | 35                           | VCC       | VCC  |

| Pin Function    | Pin Number | Type | Bank |
|-----------------|------------|------|------|
| <b>VCC</b>      | 61         | VCC  | VCC  |
| <b>VCC</b>      | 77         | VCC  | VCC  |
| <b>VPP_2V5</b>  | 75         | VPP  | VPP  |
| <b>VPP_FAST</b> | 76         | VPP  | VPP  |

### Package Mechanical Drawing

**Figure 37: VQ100 Package Mechanical Drawing: Standard Device Marking**



| Description                            | Symbol | Min. | Nominal | Max. | Units |
|----------------------------------------|--------|------|---------|------|-------|
| Leads per Edge                         | X      |      | 25      |      | Leads |
|                                        | Y      |      | 25      |      |       |
| Number of Signal Leads                 | n      |      | 100     |      |       |
| Maximum Size<br>(lead tip to lead tip) | X      | —    | 16.0    | —    | mm    |
|                                        | Y      | —    | 16.0    | —    |       |
| Body Size                              | X      | —    | 14.0    | —    |       |
|                                        | Y      | —    | 14.0    | —    |       |
| Edge Pin Center to Center              | X      | —    | 12.0    | —    |       |
|                                        | Y      | —    | 12.0    | —    |       |
| Lead Pitch                             | e      | —    | 0.50    | —    |       |
| Lead Width                             | b      | 0.17 | 0.20    | 0.27 |       |
| Total Package Height                   | A      | —    | 1.20    | —    |       |
| Stand Off                              | A1     | 0.05 | —       | 0.15 |       |
| Body Thickness                         | A2     | 0.95 | 1.00    | 1.05 |       |
| Lead Length                            | L1     | —    | 1.00    | —    |       |
| Lead Thickness                         | c      | 0.09 | —       | 0.20 |       |
| Coplanarity                            |        | —    | 0.08    | —    |       |

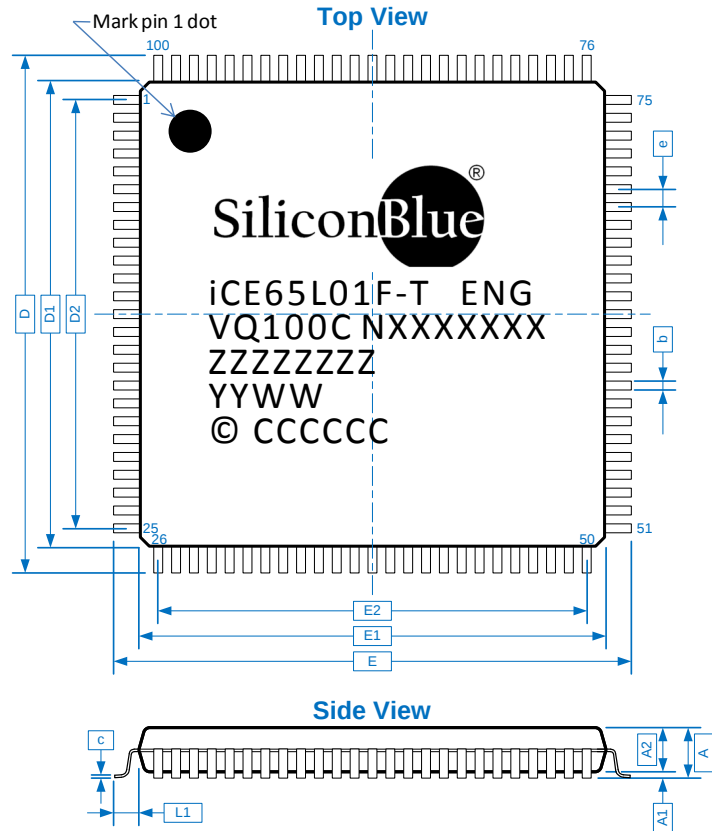
### Top Marking Format

| Line | Content            | Description                    |
|------|--------------------|--------------------------------|
| 1    | Logo               | Logo                           |
| 2    | iCE65L01F          | Part number                    |
|      | -T                 | Power/Speed                    |
|      | ENG                | Engineering                    |
| 3    | VQ100C<br>NXXXXXXX | Package type and<br>Lot number |
| 4    | YYWW               | Date Code                      |
| 5    | N/A                | Blank                          |
| 6    | © CCCCCC           | Country                        |

### Thermal Resistance

| Junction-to-Ambient<br>$\theta_{JA}$ ( $^{\circ}\text{C}/\text{W}$ ) |         |
|----------------------------------------------------------------------|---------|
| 0 LFM                                                                | 200 LFM |
| 38                                                                   | 32      |

Figure 38: VQ100 Package Mechanical Drawing: NVCM Programmed Device Marking



| Description                            | Symbol | Min. | Nominal | Max. | Units |
|----------------------------------------|--------|------|---------|------|-------|
| Leads per Edge                         | X      |      | 25      |      | Leads |
|                                        | Y      |      | 25      |      |       |
| Number of Signal Leads                 | n      |      | 100     |      | mm    |
| Maximum Size<br>(lead tip to lead tip) | X      | —    | 16.0    | —    |       |
|                                        | Y      | —    | 16.0    | —    |       |
| Body Size                              | X      | —    | 14.0    | —    |       |
|                                        | Y      | —    | 14.0    | —    |       |
| Edge Pin Center to Center              | X      | —    | 12.0    | —    |       |
|                                        | Y      | —    | 12.0    | —    |       |
| Lead Pitch                             | e      | —    | 0.50    | —    |       |
| Lead Width                             | b      | 0.17 | 0.20    | 0.27 |       |
| Total Package Height                   | A      | —    | 1.20    | —    |       |
| Stand Off                              | A1     | 0.05 | —       | 0.15 |       |
| Body Thickness                         | A2     | 0.95 | 1.00    | 1.05 |       |
| Lead Length                            | L1     | —    | 1.00    | —    |       |
| Lead Thickness                         | c      | 0.09 | —       | 0.20 |       |
| Coplanarity                            |        | —    | 0.08    | —    |       |

Top Marking Format

| Line | Content   | Description        |
|------|-----------|--------------------|
| 1    | Logo      | Logo               |
| 2    | iCE65L01F | Part number        |
|      | -T        | Power/Speed        |
|      | ENG       | Engineering        |
| 3    | VQ100C    | Package type and   |
| 4    | NXXXXXXX  | Lot number         |
|      | ZZZZZZZZ  | NVCM Program. code |
| 5    | YYWW      | Date Code          |
| 6    | © CCCCCC  | Country            |

Thermal Resistance

| Junction-to-Ambient<br>$\theta_{JA}$ (°C/W) |         |
|---------------------------------------------|---------|
| 0 LFM                                       | 200 LFM |
| 38                                          | 32      |

## CB121 Chip-Scale Ball-Grid Array

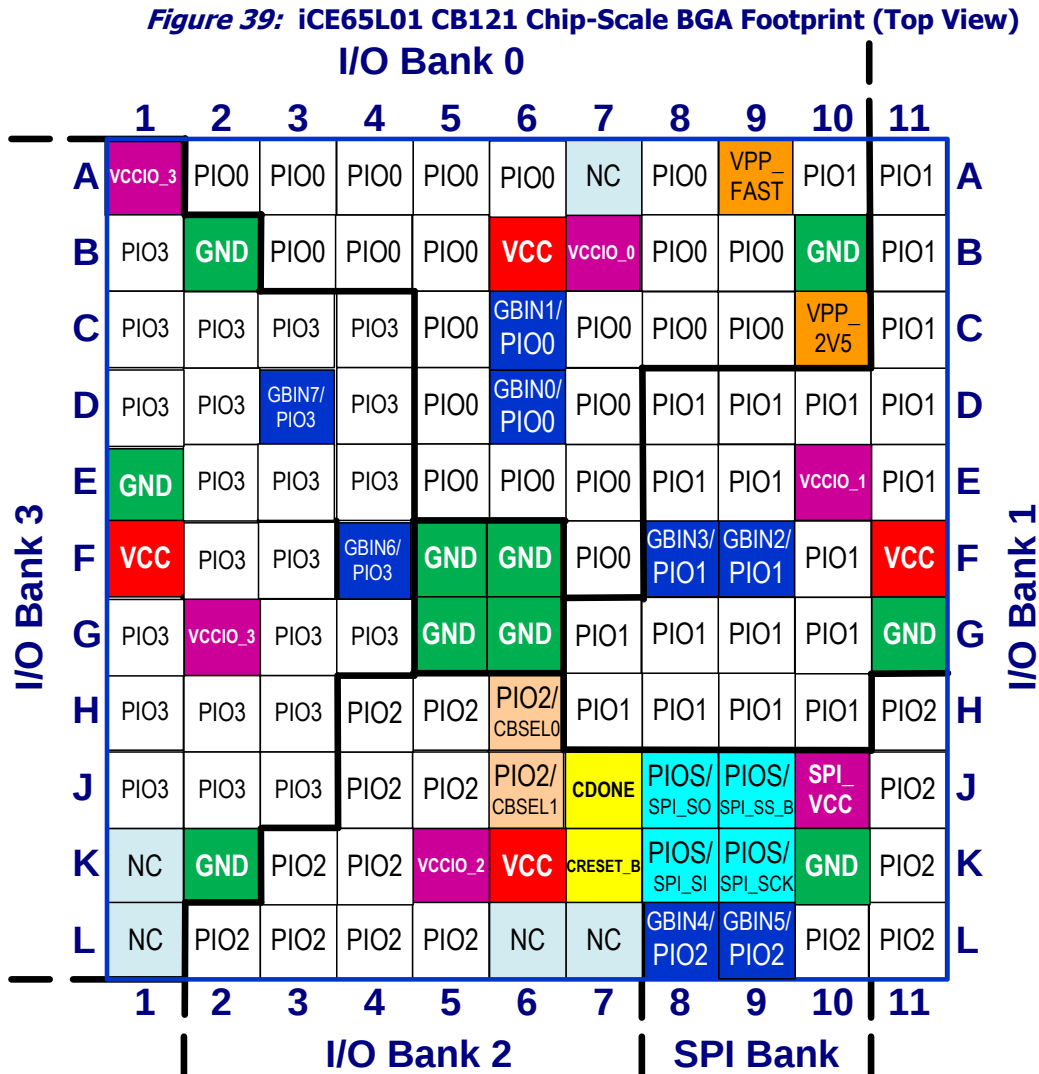
The CB121 package is a chip-scale, fully-populated, ball-grid array with 0.5 mm ball pitch.

### Footprint Diagram

Figure 39 shows the iCE65L01 chip-scale BGA footprint for the 6 x 6 mm CB121 package.

Also see Table 40 for a complete, detailed pinout for the 121-ball chip-scale BGA packages.

The signal pins are also grouped into the four I/O Banks and the SPI interface.



### Pinout Table

Table 40 provides a detailed pinout table for the iCE65L01 in the CB121 chip-scale BGA package. Pins are generally arranged by I/O bank, then by ball function.

**Table 40: iCE65L01 CB121 Chip-scale BGA Pinout Table**

| Ball Function | Ball Number | Pin Type | Bank |
|---------------|-------------|----------|------|
| GBIN0/PIO0    | D6          | GBIN     | 0    |
| GBIN1/PIO0    | C6          | GBIN     | 0    |
| PIO0          | A2          | PIO      | 0    |
| PIO0          | A3          | PIO      | 0    |
| PIO0          | A4          | PIO      | 0    |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| Ball Function | Ball Number | Pin Type | Bank |
|---------------|-------------|----------|------|
| PIO0          | A5          | PIO      | 0    |
| PIO0          | A6          | PIO      | 0    |
| PIO0          | A8          | PIO      | 0    |
| PIO0          | A10         | PIO      | 0    |
| PIO0          | B3          | PIO      | 0    |
| PIO0          | B4          | PIO      | 0    |
| PIO0          | B5          | PIO      | 0    |
| PIO0          | B8          | PIO      | 0    |
| PIO0          | B9          | PIO      | 0    |
| PIO0          | C5          | PIO      | 0    |
| PIO0          | C7          | PIO      | 0    |
| PIO0          | C8          | PIO      | 0    |
| PIO0          | C9          | PIO      | 0    |
| PIO0          | D5          | PIO      | 0    |
| PIO0          | D7          | PIO      | 0    |
| PIO0          | E5          | PIO      | 0    |
| PIO0          | E6          | PIO      | 0    |
| PIO0          | E7          | PIO      | 0    |
| PIO0          | F7          | PIO      | 0    |
| VCCIO_0       | B7          | VCCIO    | 0    |
| GBIN2/PIO1    | F9          | GBIN     | 1    |
| GBIN3/PIO1    | F8          | GBIN     | 1    |
| PIO1          | A11         | PIO      | 1    |
| PIO1          | B11         | PIO      | 1    |
| PIO1          | C11         | PIO      | 1    |
| PIO1          | D8          | PIO      | 1    |
| PIO1          | D9          | PIO      | 1    |
| PIO1          | D10         | PIO      | 1    |
| PIO1          | D11         | PIO      | 1    |
| PIO1          | E8          | PIO      | 1    |
| PIO1          | E9          | PIO      | 1    |
| PIO1          | E11         | PIO      | 1    |
| PIO1          | F10         | PIO      | 1    |
| PIO1          | G7          | PIO      | 1    |
| PIO1          | G8          | PIO      | 1    |
| PIO1          | G9          | PIO      | 1    |
| PIO1          | G10         | PIO      | 1    |
| PIO1          | H7          | PIO      | 1    |
| PIO1          | H8          | PIO      | 1    |
| PIO1          | H9          | PIO      | 1    |
| PIO1          | H10         | PIO      | 1    |
| VCCIO_1       | E10         | VCCIO    | 1    |
| CDONE         | J7          | CONFIG   | 2    |
| CRESET_B      | K7          | CONFIG   | 2    |
| GBIN4/PIO2    | L8          | GBIN     | 2    |
| GBIN5/PIO2    | L9          | GBIN     | 2    |
| PIO2          | H4          | PIO      | 2    |
| PIO2          | H5          | PIO      | 2    |
| PIO2          | H11         | PIO      | 2    |
| PIO2          | J4          | PIO      | 2    |
| PIO2          | J5          | PIO      | 2    |

| Ball Function | Ball Number | Pin Type | Bank |
|---------------|-------------|----------|------|
| PIO2          | J11         | PIO      | 2    |
| PIO2          | K3          | PIO      | 2    |
| PIO2          | K4          | PIO      | 2    |
| PIO2          | K11         | PIO      | 2    |
| PIO2          | L2          | PIO      | 2    |
| PIO2          | L3          | PIO      | 2    |
| PIO2          | L4          | PIO      | 2    |
| PIO2          | L5          | PIO      | 2    |
| PIO2          | L10         | PIO      | 2    |
| PIO2          | L11         | PIO      | 2    |
| PIO2/CBSEL0   | H6          | PIO      | 2    |
| PIO2/CBSEL1   | J6          | PIO      | 2    |
| VCCIO_2       | K5          | VCCIO    | 2    |
| PIO3          | C1          | PIO      | 3    |
| PIO3          | B1          | PIO      | 3    |
| PIO3          | D1          | PIO      | 3    |
| PIO3          | E2          | PIO      | 3    |
| PIO3          | C2          | PIO      | 3    |
| PIO3          | D2          | PIO      | 3    |
| PIO3          | C3          | PIO      | 3    |
| PIO3          | C4          | PIO      | 3    |
| PIO3          | E4          | PIO      | 3    |
| PIO3          | D4          | PIO      | 3    |
| PIO3          | F3          | PIO      | 3    |
| PIO3          | G3          | PIO      | 3    |
| PIO3          | G4          | PIO      | 3    |
| GBIN6/PIO3    | F4          | GBIN     | 3    |
| GBIN7/PIO3    | D3          | GBIN     | 3    |
| PIO3          | E3          | PIO      | 3    |
| PIO3          | F2          | PIO      | 3    |
| PIO3          | G1          | PIO      | 3    |
| PIO3          | H1          | PIO      | 3    |
| PIO3          | J1          | PIO      | 3    |
| PIO3          | H2          | PIO      | 3    |
| PIO3          | H3          | PIO      | 3    |
| PIO3          | J3          | PIO      | 3    |
| PIO3          | J2          | PIO      | 3    |
| VCCIO_3       | A1          | VCCIO    | 3    |
| VCCIO_3       | G2          | VCCIO    | 3    |
| PIOS/SPI_SO   | J8          | SPI      | SPI  |
| PIOS/SPI_SI   | K8          | SPI      | SPI  |
| PIOS/SPI_SCK  | K9          | SPI      | SPI  |
| PIOS/SPI_SS_B | J9          | SPI      | SPI  |
| SPI_VCC       | J10         | SPI      | SPI  |
| GND           | B2          | GND      | GND  |
| GND           | B10         | GND      | GND  |
| GND           | E1          | GND      | GND  |
| GND           | F5          | GND      | GND  |
| GND           | F6          | GND      | GND  |
| GND           | G5          | GND      | GND  |
| GND           | G6          | GND      | GND  |
| GND           | G11         | GND      | GND  |

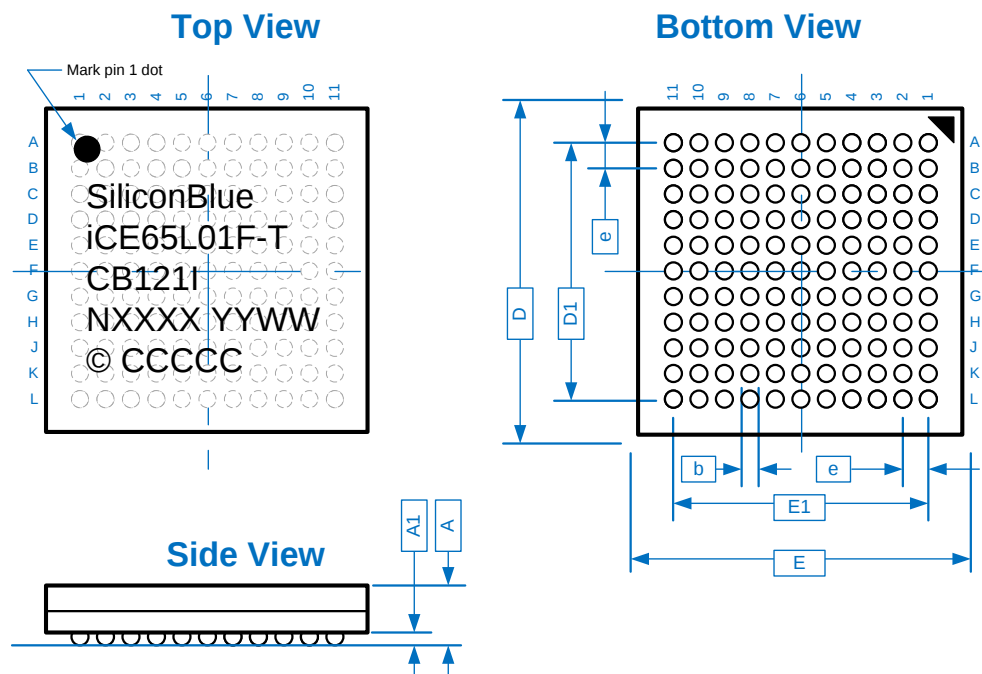
## iCE65 Ultra Low-Power mobileFPGA™ Family

| Ball Function | Ball Number | Pin Type | Bank |
|---------------|-------------|----------|------|
| GND           | K2          | GND      | GND  |
| GND           | K10         | GND      | GND  |
| VCC           | B6          | VCC      | VCC  |
| VCC           | F1          | VCC      | VCC  |
| VCC           | F11         | VCC      | VCC  |
| VCC           | K6          | VCC      | VCC  |
| VPP_2V5       | C10         | VPP      | VPP  |
| VPP_FAST      | A9          | VPP      | VPP  |

## Package Mechanical Drawing

**Figure 40: CB121 Package Mechanical Drawing**

**CB121:** 6 x 6 mm, 121-ball, 0.5 mm ball-pitch, fully-populated, chip-scale ball grid array



| Description                |   | Symbol | Min. | Nominal | Max. | Units   |
|----------------------------|---|--------|------|---------|------|---------|
| Number of Ball Columns     | X |        |      | 11      |      | Columns |
| Number of Ball Rows        | Y |        |      | 11      |      | Rows    |
| Number of Signal Balls     |   | n      |      | 121     |      | Balls   |
| Body Size                  | X | E      | 5.90 | 6.00    | 6.10 | mm      |
|                            | Y | D      | 5.90 | 6.00    | 6.10 |         |
| Ball Pitch                 |   | e      | —    | 0.50    | —    |         |
| Ball Diameter              |   | b      | 0.2  | —       | 0.3  |         |
| Edge Ball Center to Center | X | E1     | —    | 5.00    | —    |         |
|                            | Y | D1     | —    | 5.00    | —    |         |
| Package Height             |   | A      | —    | —       | 1.00 |         |
| Stand Off                  |   | A1     | 0.12 | —       | 0.20 |         |

### Top Marking Format

| Line | Content   | Description  |
|------|-----------|--------------|
| 1    | Logo      | Logo         |
| 2    | iCE65L01F | Part number  |
|      | -T        | Power/Speed  |
| 3    | CB121I    | Package type |
|      | ENG       | Engineering  |
| 4    | NXXXX     | Lot Number   |
| 5    | YYWW      | Date Code    |
| 6    | © CCCCC   | Country      |

### Thermal Resistance

| Junction-to-Ambient<br>$\theta_{JA}$ ( $^{\circ}\text{C}/\text{W}$ ) |         |
|----------------------------------------------------------------------|---------|
| 0 LFM                                                                | 200 LFM |
| 64                                                                   | 55      |

## CB132 Chip-Scale Ball-Grid Array

The CB132 package is a partially-populated ball grid array with 0.5 mm ball pitch. The empty ball rings simplify PCB layout. The iCE65L01, iCE65L04 and iCE65L08 devices are available in this package.

Footprint Diagram

Figure 41, Figure 42 and

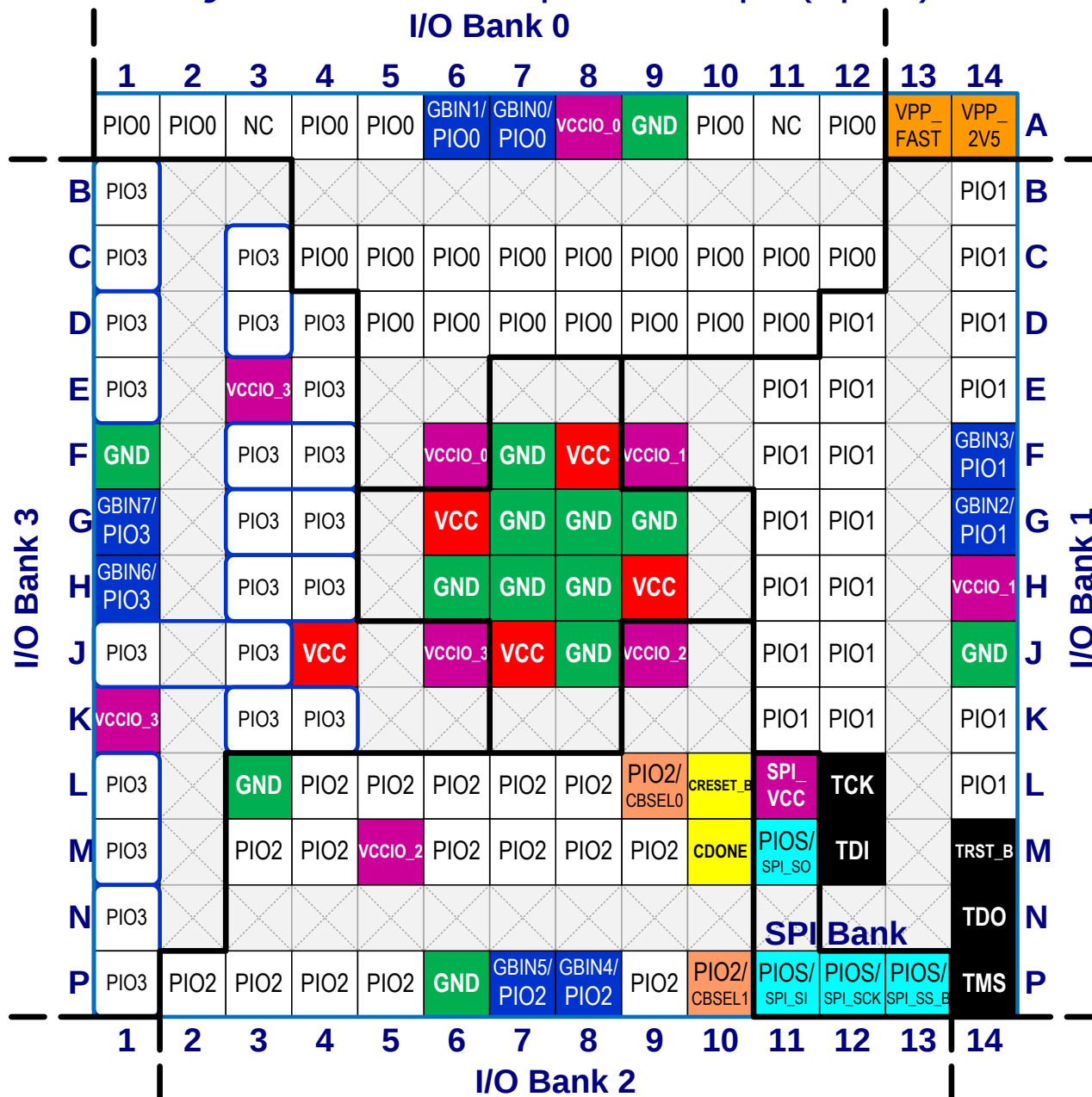
Figure 43 show the iCE65 footprint diagrams for the CB132 package in iCE65L01, iCE65L04 and iCE65L08 devices. See Figure 48 for the “universal” chip-scale BGA footprint for the CB132 and CB284 packages. The 8 x 8 mm CB132 package fits within the same ball pattern as the 12 x 12 mm CB284 package.

Figure 31 shows the conventions used in the diagram.

Also see Table 41 for a complete, detailed pinout for the 132-ball BGA package.

The signal pins are also grouped into the four I/O Banks and the SPI interface.

**Figure 41: iCE65L01 CB132 Chip-Scale BGA Footprint (Top View)**



**Figure 42: iCE65L04 CB132 Chip-Scale BGA Footprint (Top View)**

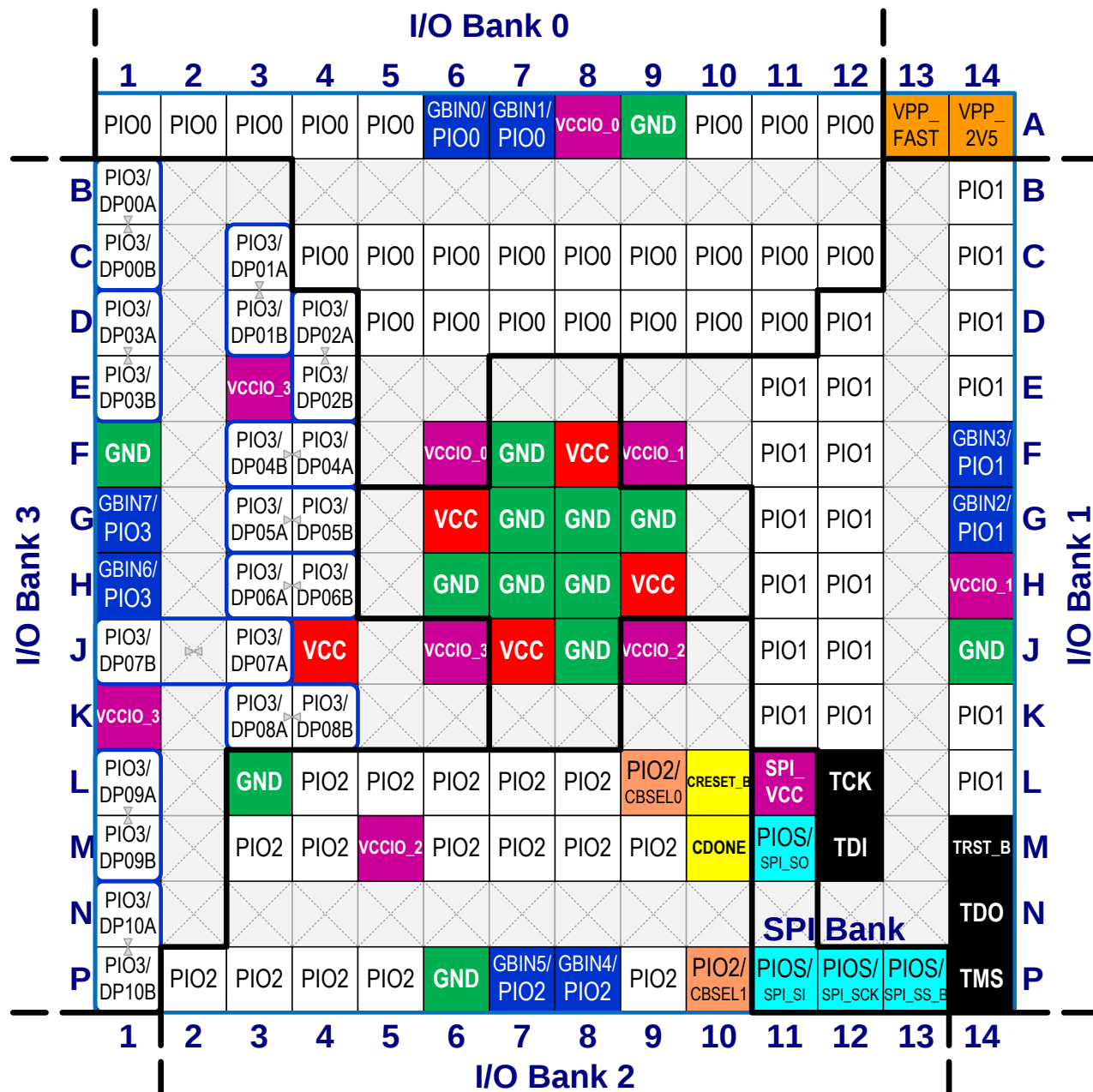
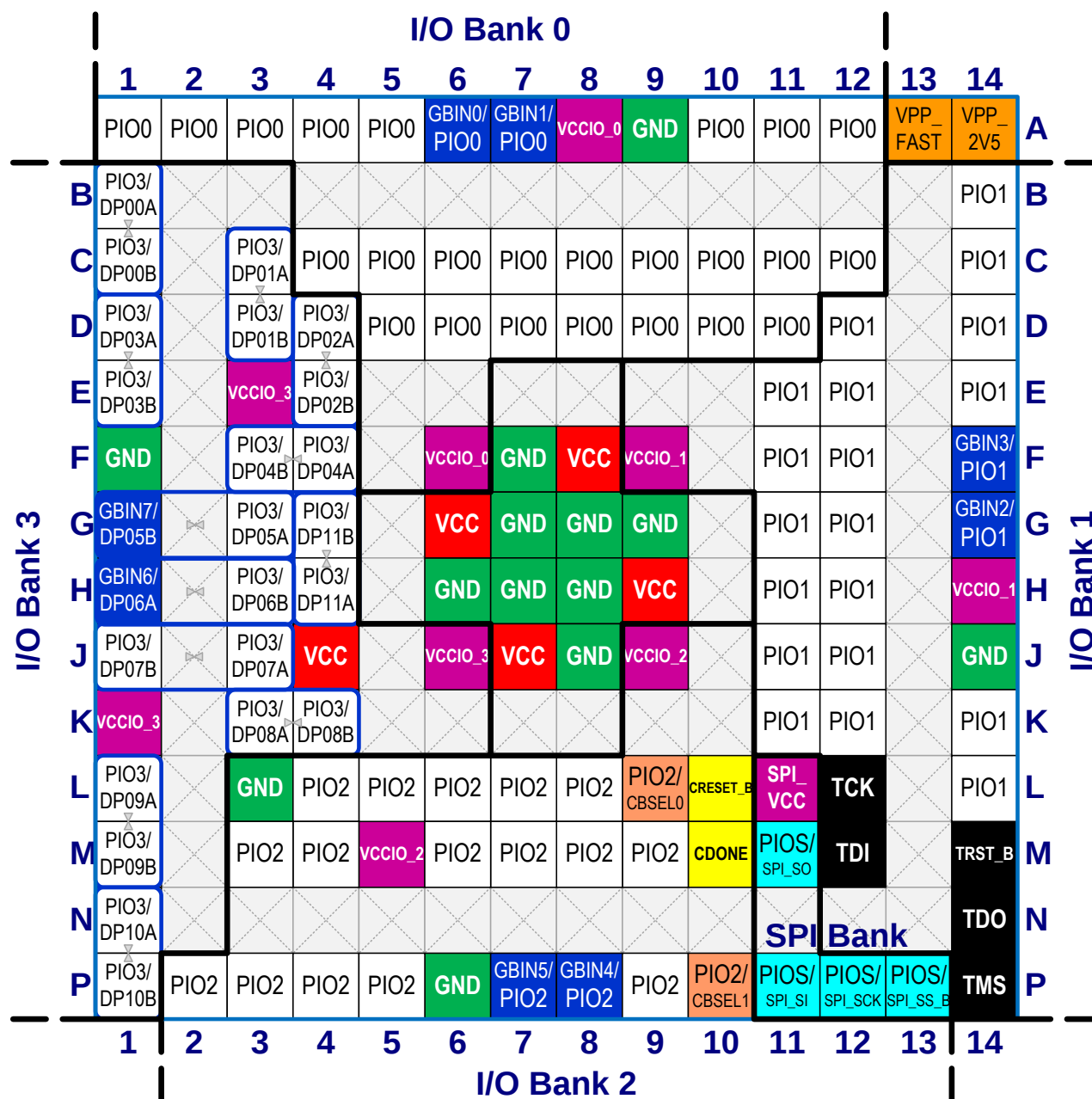


Figure 43: iCE65L08 CB132 Chip-Scale BGA Footprint (Top View)



## Pinout Table

Table 41 provides a detailed pinout table for the CB132 package. Pins are generally arranged by I/O bank, then by ball function. The table also highlights the differential I/O pairs in I/O Bank 3.

**Table 41: iCE65 CB132 Chip-scale BGA Pinout Table**

| Ball Function                                | Ball Number                      | Pin Type                         | Bank |
|----------------------------------------------|----------------------------------|----------------------------------|------|
| <b>GBIN0/PIO0</b>                            | iCE65L01: A7<br>iCE65L04/L08: A6 | GBIN                             | 0    |
| <b>GBIN1/PIO0</b>                            | iCE65L01: A6<br>iCE65L04/L08: A7 | GBIN                             | 0    |
| <b>PIO0</b>                                  | A1                               | PIO                              | 0    |
| <b>PIO0</b>                                  | A2                               | PIO                              | 0    |
| <b>iCE65L01: (NC)<br/>iCE65L04/L08: PIO0</b> | A3                               | iCE65L01: (NC)<br>iCE65L04: PIO0 | 0    |
| <b>PIO0</b>                                  | A4                               | PIO                              | 0    |
| <b>PIO0</b>                                  | A5                               | PIO                              | 0    |
| <b>PIO0</b>                                  | A10                              | PIO                              | 0    |
| <b>iCE65L01: (NC)<br/>iCE65L04/L08: PIO0</b> | A11                              | iCE65L01: (NC)<br>iCE65L04: PIO0 | 0    |
| <b>PIO0</b>                                  | A12                              | PIO                              | 0    |
| <b>PIO0</b>                                  | C10                              | PIO                              | 0    |
| <b>PIO0</b>                                  | C11                              | PIO                              | 0    |
| <b>PIO0</b>                                  | C12                              | PIO                              | 0    |
| <b>PIO0</b>                                  | C4                               | PIO                              | 0    |
| <b>PIO0</b>                                  | C5                               | PIO                              | 0    |
| <b>PIO0</b>                                  | C6                               | PIO                              | 0    |
| <b>PIO0</b>                                  | C7                               | PIO                              | 0    |
| <b>PIO0</b>                                  | C8                               | PIO                              | 0    |
| <b>PIO0</b>                                  | C9                               | PIO                              | 0    |
| <b>PIO0</b>                                  | D5                               | PIO                              | 0    |
| <b>PIO0</b>                                  | D6                               | PIO                              | 0    |
| <b>PIO0</b>                                  | D7                               | PIO                              | 0    |
| <b>PIO0</b>                                  | D8                               | PIO                              | 0    |
| <b>PIO0</b>                                  | D9                               | PIO                              | 0    |
| <b>PIO0</b>                                  | D10                              | PIO                              | 0    |
| <b>PIO0</b>                                  | D11                              | PIO                              | 0    |
| <b>VCCIO_0</b>                               | A8                               | VCCIO                            | 0    |
| <b>VCCIO_0</b>                               | F6                               | VCCIO                            | 0    |
| <b>GBIN2/PIO1</b>                            | G14                              | GBIN                             | 1    |
| <b>GBIN3/PIO1</b>                            | F14                              | GBIN                             | 1    |
| <b>PIO1</b>                                  | B14                              | PIO                              | 1    |
| <b>PIO1</b>                                  | C14                              | PIO                              | 1    |
| <b>PIO1</b>                                  | D12                              | PIO                              | 1    |
| <b>PIO1</b>                                  | D14                              | PIO                              | 1    |
| <b>PIO1</b>                                  | E11                              | PIO                              | 1    |
| <b>PIO1</b>                                  | E12                              | PIO                              | 1    |
| <b>PIO1</b>                                  | E14                              | PIO                              | 1    |
| <b>PIO1</b>                                  | F11                              | PIO                              | 1    |
| <b>PIO1</b>                                  | F12                              | PIO                              | 1    |
| <b>PIO1</b>                                  | G11                              | PIO                              | 1    |
| <b>PIO1</b>                                  | G12                              | PIO                              | 1    |
| <b>PIO1</b>                                  | H11                              | PIO                              | 1    |

# iCE65 Ultra Low-Power mobileFPGA™ Family

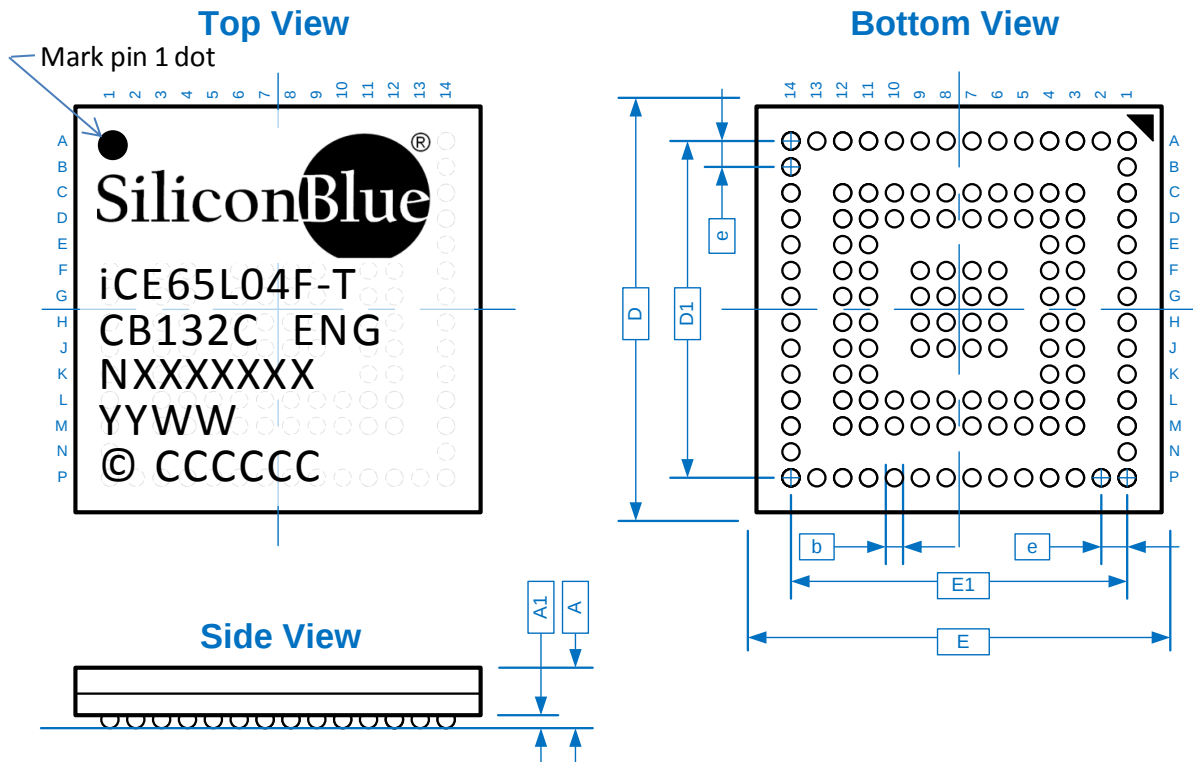
| Ball Function                                   | Ball Number | Pin Type | Bank |
|-------------------------------------------------|-------------|----------|------|
| <b>PIO1</b>                                     | H12         | PIO      | 1    |
| <b>PIO1</b>                                     | J11         | PIO      | 1    |
| <b>PIO1</b>                                     | J12         | PIO      | 1    |
| <b>PIO1</b>                                     | K11         | PIO      | 1    |
| <b>PIO1</b>                                     | K12         | PIO      | 1    |
| <b>PIO1</b>                                     | K14         | PIO      | 1    |
| <b>PIO1</b>                                     | L14         | PIO      | 1    |
| <b>TCK</b>                                      | L12         | JTAG     | 1    |
| <b>TDI</b>                                      | M12         | JTAG     | 1    |
| <b>TDO</b>                                      | N14         | JTAG     | 1    |
| <b>TMS</b>                                      | P14         | JTAG     | 1    |
| <b>TRST_B</b>                                   | M14         | JTAG     | 1    |
| <b>VCCIO_1</b>                                  | F9          | VCCIO    | 1    |
| <b>VCCIO_1</b>                                  | H14         | VCCIO    | 1    |
| <b>CDONE</b>                                    | M10         | CONFIG   | 2    |
| <b>CRESET_B</b>                                 | L10         | CONFIG   | 2    |
| <b>GBIN4/PIO2</b>                               | P8          | GBIN     | 2    |
| <b>GBIN5/PIO2</b>                               | P7          | GBIN     | 2    |
| <b>PIO2</b>                                     | L4          | PIO      | 2    |
| <b>PIO2</b>                                     | L5          | PIO      | 2    |
| <b>PIO2</b>                                     | L6          | PIO      | 2    |
| <b>PIO2</b>                                     | L7          | PIO      | 2    |
| <b>PIO2</b>                                     | L8          | PIO      | 2    |
| <b>PIO2</b>                                     | M3          | PIO      | 2    |
| <b>PIO2</b>                                     | M4          | PIO      | 2    |
| <b>PIO2</b>                                     | M6          | PIO      | 2    |
| <b>PIO2</b>                                     | M7          | PIO      | 2    |
| <b>PIO2</b>                                     | M8          | PIO      | 2    |
| <b>PIO2</b>                                     | M9          | PIO      | 2    |
| <b>PIO2</b>                                     | P2          | PIO      | 2    |
| <b>PIO2</b>                                     | P3          | PIO      | 2    |
| <b>PIO2</b>                                     | P4          | PIO      | 2    |
| <b>PIO2</b>                                     | P5          | PIO      | 2    |
| <b>PIO2</b>                                     | P9          | PIO      | 2    |
| <b>PIO2/CBSEL0</b>                              | L9          | PIO      | 2    |
| <b>PIO2/CBSEL1</b>                              | P10         | PIO      | 2    |
| <b>VCCIO_2</b>                                  | J9          | PIO      | 2    |
| <b>VCCIO_2</b>                                  | M5          | PIO      | 2    |
| <b>PIO3/DP00A</b>                               | B1          | DPIO     | 3    |
| <b>PIO3/DP00B</b>                               | C1          | DPIO     | 3    |
| <b>PIO3/DP01A</b>                               | C3          | DPIO     | 3    |
| <b>PIO3/DP01B</b>                               | D3          | DPIO     | 3    |
| <b>PIO3/DP02A</b>                               | D4          | DPIO     | 3    |
| <b>PIO3/DP02B</b>                               | E4          | DPIO     | 3    |
| <b>PIO3/DP03A</b>                               | D1          | DPIO     | 3    |
| <b>PIO3/DP03B</b>                               | E1          | DPIO     | 3    |
| <b>PIO3/DP04A</b>                               | F4          | DPIO     | 3    |
| <b>PIO3/DP04B</b>                               | F3          | DPIO     | 3    |
| <b>L01/L04: GBIN6/PIO3<br/>L08: GBIN6/DP06A</b> | H1          | GBIN     | 3    |

| Ball Function                                   | Ball Number | Pin Type | Bank |
|-------------------------------------------------|-------------|----------|------|
| <b>L01/L04: GBIN7/PIO3<br/>L08: GBIN7/DP05B</b> | G1          | GBIN     | 3    |
| <b>L01/L04: PIO3/DP05A<br/>L08: PIO3/DP05A</b>  | G3          | DPIO     | 3    |
| <b>L01/L04: PIO3/DP05B<br/>L08: PIO3/DP11B</b>  | G4          | DPIO     | 3    |
| <b>L01/L04: PIO3/DP06A<br/>L08: PIO3/DP06B</b>  | H3          | DPIO     | 3    |
| <b>L01/L04: PIO3/DP06B<br/>L08: PIO3/DP11A</b>  | H4          | DPIO     | 3    |
| <b>PIO3/DP07A</b>                               | J3          | DPIO     | 3    |
| <b>PIO3/DP07B</b>                               | J1          | DPIO     | 3    |
| <b>PIO3/DP08A</b>                               | K3          | DPIO     | 3    |
| <b>PIO3/DP08B</b>                               | K4          | DPIO     | 3    |
| <b>PIO3/DP09A</b>                               | L1          | DPIO     | 3    |
| <b>PIO3/DP09B</b>                               | M1          | DPIO     | 3    |
| <b>PIO3/DP10A</b>                               | N1          | DPIO     | 3    |
| <b>PIO3/DP10B</b>                               | P1          | DPIO     | 3    |
| <b>VCCIO_3</b>                                  | E3          | VCCIO    | 3    |
| <b>VCCIO_3</b>                                  | J6          | VCCIO    | 3    |
| <b>VCCIO_3</b>                                  | K1          | VCCIO    | 3    |
| <b>PIOS/SPI_SO</b>                              | M11         | SPI      | SPI  |
| <b>PIOS/SPI_SI</b>                              | P11         | SPI      | SPI  |
| <b>PIOS/SPI_SCK</b>                             | P12         | SPI      | SPI  |
| <b>PIOS/SPI_SS_B</b>                            | P13         | SPI      | SPI  |
| <b>SPI_VCC</b>                                  | L11         | SPI      | SPI  |
| <b>GND</b>                                      | A9          | GND      | GND  |
| <b>GND</b>                                      | F1          | GND      | GND  |
| <b>GND</b>                                      | F7          | GND      | GND  |
| <b>GND</b>                                      | G7          | GND      | GND  |
| <b>GND</b>                                      | G8          | GND      | GND  |
| <b>GND</b>                                      | G9          | GND      | GND  |
| <b>GND</b>                                      | H6          | GND      | GND  |
| <b>GND</b>                                      | H7          | GND      | GND  |
| <b>GND</b>                                      | H8          | GND      | GND  |
| <b>GND</b>                                      | J8          | GND      | GND  |
| <b>GND</b>                                      | J14         | GND      | GND  |
| <b>GND</b>                                      | L3          | GND      | GND  |
| <b>GND</b>                                      | P6          | GND      | GND  |
| <b>VCC</b>                                      | F8          | VCC      | VCC  |
| <b>VCC</b>                                      | G6          | VCC      | VCC  |
| <b>VCC</b>                                      | H9          | VCC      | VCC  |
| <b>VCC</b>                                      | J4          | VCC      | VCC  |
| <b>VCC</b>                                      | J7          | VCC      | VCC  |
| <b>VPP_2V5</b>                                  | A14         | VPP      | VPP  |
| <b>VPP_FAST</b>                                 | A13         | VPP      | VPP  |

Package Mechanical Drawing

Figure 44: CB132 Package Mechanical Drawing

**CB132:** 8 x 8 mm, 132-ball, 0.5 mm ball-pitch, chip-scale ball grid array



| Description                |   | Symbol | Min. | Nominal | Max. | Units   |
|----------------------------|---|--------|------|---------|------|---------|
| Number of Ball Columns     | X |        |      | 14      |      | Columns |
| Number of Ball Rows        | Y |        |      | 14      |      | Rows    |
| Number of Signal Balls     |   | n      |      | 132     |      | Balls   |
| Body Size                  | X | E      | 7.90 | 8.00    | 8.10 | mm      |
|                            | Y | D      | 7.90 | 8.00    | 8.10 |         |
| Ball Pitch                 |   | e      | —    | 0.50    | —    |         |
| Ball Diameter              |   | b      | 0.27 | —       | 0.37 |         |
| Edge Ball Center to Center | X | E1     | —    | 6.50    | —    |         |
|                            | Y | D1     | —    | 6.50    | —    |         |
| Package Height             |   | A      | —    | —       | 1.00 |         |
| Stand Off                  |   | A1     | 0.16 | —       | 0.26 |         |

Top Marking Format

| Line | Content   | Description  |
|------|-----------|--------------|
| 1    | Logo      | Logo         |
| 2    | iCE65L04F | Part number  |
|      | -T        | Power/Speed  |
| 3    | CB132C    | Package type |
|      | ENG       | Engineering  |
| 4    | NXXXXXXX  | Lot Number   |
| 5    | YYWW      | Date Code    |
| 6    | © CCCCCC  | Country      |

Thermal Resistance

| Junction-to-Ambient<br>$\theta_{JA}$ (°C/W) |         |
|---------------------------------------------|---------|
| 0 LFM                                       | 200 LFM |
| 42                                          | 34      |

## CB196 Chip-Scale Ball-Grid Array

The CB196 package is a chip-scale, fully-populated, ball-grid array with 0.5 mm ball pitch.

### Footprint Diagram

Figure 45 shows the iCE65L04 chip-scale BGA footprint for the 8 x 8 mm CB196 package. The footprint for the iCE65L08 is different than the iCE64L04 footprint, as shown in Figure 46. The pinout differences are highlighted by warning diamonds (◆) in the footprint diagrams and summarized in Table 43.



Although both the iCE65L04 and iCE65L08 are both available in the CB196 package and *almost* completely pin compatible, there are differences as shown in Table 43.

Figure 31 shows the conventions used in the diagram. Also see Table 42 for a complete, detailed pinout for the 196-ball chip-scale BGA packages. The signal pins are also grouped into the four I/O Banks and the SPI interface.

**Figure 45: iCE65L04 CB196 Chip-Scale BGA Footprint (Top View)**

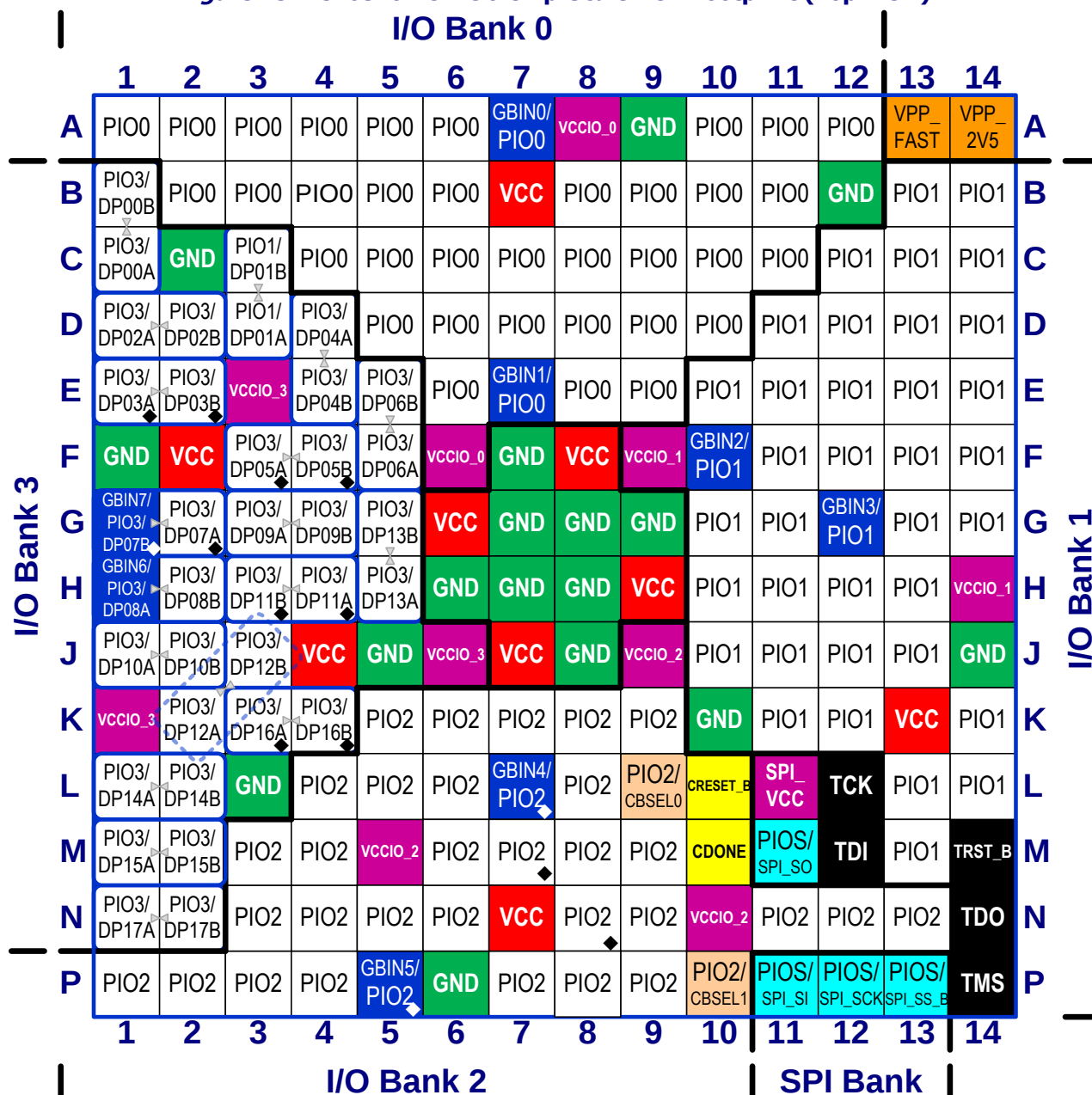
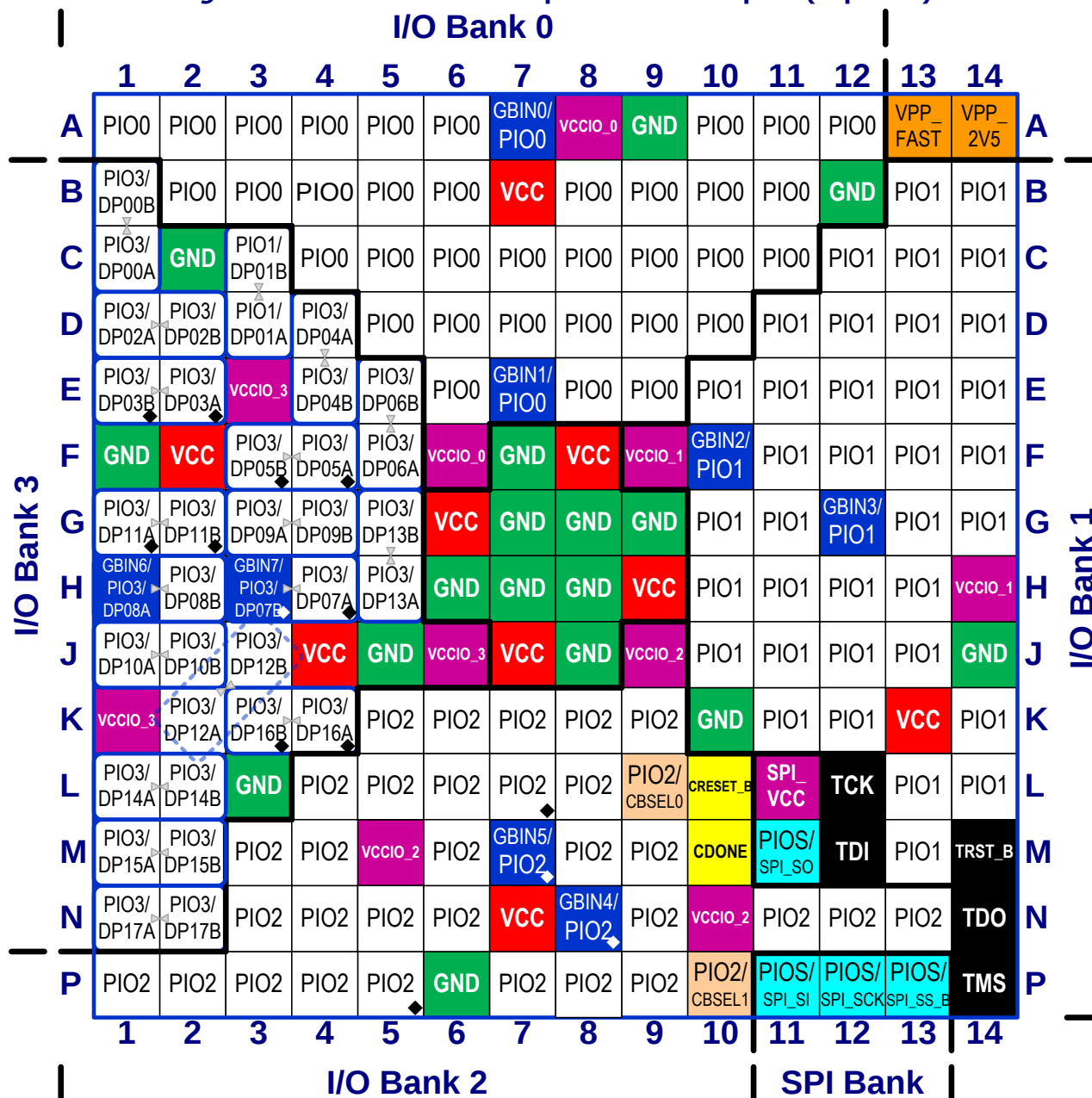


Figure 46: iCE65L08 CB196 Chip-Scale BGA Footprint (Top View)



## Pinout Table

Table 42 provides a detailed pinout table for the iCE65L04 in the CB196 chip-scale BGA package. Pins are generally arranged by I/O bank, then by ball function. The pinout for the iCE65L08 is different than the iCE64L04 pinout.



Although both the iCE65L04 and iCE65L08 are both available in the CB196 package and *almost* completely pin compatible, there are differences as shown in Table 43.

Table 42: iCE65L04 CB196 Chip-scale BGA Pinout Table

| Ball Function     | Ball Number | Pin Type | Bank |
|-------------------|-------------|----------|------|
| <b>GBIN0/PIO0</b> | A7          | GBIN     | 0    |
| <b>GBIN1/PIO0</b> | E7          | GBIN     | 0    |
| <b>PIO0</b>       | A1          | PIO      | 0    |
| <b>PIO0</b>       | A2          | PIO      | 0    |
| <b>PIO0</b>       | A3          | PIO      | 0    |
| <b>PIO0</b>       | A4          | PIO      | 0    |

| Ball Function     | Ball Number | Pin Type | Bank |
|-------------------|-------------|----------|------|
| <b>PIO0</b>       | A5          | PIO      | 0    |
| <b>PIO0</b>       | A6          | PIO      | 0    |
| <b>PIO0</b>       | A10         | PIO      | 0    |
| <b>PIO0</b>       | A11         | PIO      | 0    |
| <b>PIO0</b>       | A12         | PIO      | 0    |
| <b>PIO0</b>       | B2          | PIO      | 0    |
| <b>PIO0</b>       | B3          | PIO      | 0    |
| <b>PIO0</b>       | B4          | PIO      | 0    |
| <b>PIO0</b>       | B5          | PIO      | 0    |
| <b>PIO0</b>       | B6          | PIO      | 0    |
| <b>PIO0</b>       | B8          | PIO      | 0    |
| <b>PIO0</b>       | B9          | PIO      | 0    |
| <b>PIO0</b>       | B10         | PIO      | 0    |
| <b>PIO0</b>       | B11         | PIO      | 0    |
| <b>PIO0</b>       | C4          | PIO      | 0    |
| <b>PIO0</b>       | C5          | PIO      | 0    |
| <b>PIO0</b>       | C6          | PIO      | 0    |
| <b>PIO0</b>       | C7          | PIO      | 0    |
| <b>PIO0</b>       | C8          | PIO      | 0    |
| <b>PIO0</b>       | C9          | PIO      | 0    |
| <b>PIO0</b>       | C10         | PIO      | 0    |
| <b>PIO0</b>       | C11         | PIO      | 0    |
| <b>PIO0</b>       | D5          | PIO      | 0    |
| <b>PIO0</b>       | D6          | PIO      | 0    |
| <b>PIO0</b>       | D7          | PIO      | 0    |
| <b>PIO0</b>       | D8          | PIO      | 0    |
| <b>PIO0</b>       | D9          | PIO      | 0    |
| <b>PIO0</b>       | D10         | PIO      | 0    |
| <b>PIO0</b>       | E6          | PIO      | 0    |
| <b>PIO0</b>       | E8          | PIO      | 0    |
| <b>PIO0</b>       | E9          | PIO      | 0    |
| <b>VCCIO_0</b>    | A8          | VCCIO    | 0    |
| <b>VCCIO_0</b>    | F6          | VCCIO    | 0    |
| <b>GBIN2/PIO1</b> | F10         | GBIN     | 1    |
| <b>GBIN3/PIO1</b> | G12         | GBIN     | 1    |
| <b>PIO1</b>       | B13         | PIO      | 1    |
| <b>PIO1</b>       | B14         | PIO      | 1    |
| <b>PIO1</b>       | C12         | PIO      | 1    |
| <b>PIO1</b>       | C13         | PIO      | 1    |
| <b>PIO1</b>       | C14         | PIO      | 1    |
| <b>PIO1</b>       | D11         | PIO      | 1    |
| <b>PIO1</b>       | D12         | PIO      | 1    |
| <b>PIO1</b>       | D13         | PIO      | 1    |
| <b>PIO1</b>       | D14         | PIO      | 1    |
| <b>PIO1</b>       | E10         | PIO      | 1    |
| <b>PIO1</b>       | E11         | PIO      | 1    |
| <b>PIO1</b>       | E12         | PIO      | 1    |
| <b>PIO1</b>       | E13         | PIO      | 1    |
| <b>PIO1</b>       | E14         | PIO      | 1    |
| <b>PIO1</b>       | F11         | PIO      | 1    |
| <b>PIO1</b>       | F12         | PIO      | 1    |
| <b>PIO1</b>       | F13         | PIO      | 1    |

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| Ball Function  | Ball Number                                | Pin Type | Bank |
|----------------|--------------------------------------------|----------|------|
| PIO1           | F14                                        | PIO      | 1    |
| PIO1           | G10                                        | PIO      | 1    |
| PIO1           | G11                                        | PIO      | 1    |
| PIO1           | G13                                        | PIO      | 1    |
| PIO1           | G14                                        | PIO      | 1    |
| PIO1           | H10                                        | PIO      | 1    |
| PIO1           | H11                                        | PIO      | 1    |
| PIO1           | H12                                        | PIO      | 1    |
| PIO1           | H13                                        | PIO      | 1    |
| PIO1           | J10                                        | PIO      | 1    |
| PIO1           | J11                                        | PIO      | 1    |
| PIO1           | J12                                        | PIO      | 1    |
| PIO1           | J13                                        | PIO      | 1    |
| PIO1           | K11                                        | PIO      | 1    |
| PIO1           | K12                                        | PIO      | 1    |
| PIO1           | K14                                        | PIO      | 1    |
| PIO1           | L13                                        | PIO      | 1    |
| PIO1           | L14                                        | PIO      | 1    |
| PIO1           | M13                                        | PIO      | 1    |
| TCK            | L12                                        | JTAG     | 1    |
| TDI            | M12                                        | JTAG     | 1    |
| TDO            | N14                                        | JTAG     | 1    |
| TMS            | P14                                        | JTAG     | 1    |
| TRST_B         | M14                                        | JTAG     | 1    |
| VCCIO_1        | F9                                         | VCCIO    | 1    |
| VCCIO_1        | H14                                        | VCCIO    | 1    |
| CDONE          | M10                                        | CONFIG   | 2    |
| CRESET_B       | L10                                        | CONFIG   | 2    |
| GBIN4/PIO2 (◆) | <i>iCE65L04:</i> L7<br><i>iCE65L08:</i> N8 | GBIN     | 2    |
| GBIN5/PIO2 (◆) | <i>iCE65L04:</i> P5<br><i>iCE65L08:</i> M7 | GBIN     | 2    |
| PIO2           | K5                                         | PIO      | 2    |
| PIO2           | K6                                         | PIO      | 2    |
| PIO2           | K7                                         | PIO      | 2    |
| PIO2           | K8                                         | PIO      | 2    |
| PIO2           | K9                                         | PIO      | 2    |
| PIO2           | L4                                         | PIO      | 2    |
| PIO2           | L5                                         | PIO      | 2    |
| PIO2           | L6                                         | PIO      | 2    |
| PIO2           | L8                                         | PIO      | 2    |
| PIO2           | M3                                         | PIO      | 2    |
| PIO2           | M4                                         | PIO      | 2    |
| PIO2           | M6                                         | PIO      | 2    |
| PIO2 (◆)       | <i>iCE65L04:</i> M7<br><i>iCE65L08:</i> P5 | PIO      | 2    |
| PIO2           | M8                                         | PIO      | 2    |
| PIO2           | M9                                         | PIO      | 2    |
| PIO2           | N3                                         | PIO      | 2    |
| PIO2           | N4                                         | PIO      | 2    |
| PIO2           | N5                                         | PIO      | 2    |
| PIO2           | N6                                         | PIO      | 2    |

| Ball Function               | Ball Number                                | Pin Type | Bank |
|-----------------------------|--------------------------------------------|----------|------|
| <b>PIO2 (◆)</b>             | <i>ICE65L04:</i> N8<br><i>ICE65L08:</i> L7 | PIO      | 2    |
| <b>PIO2</b>                 | N9                                         | PIO      | 2    |
| <b>PIO2</b>                 | N11                                        | PIO      | 2    |
| <b>PIO2</b>                 | N12                                        | PIO      | 2    |
| <b>PIO2</b>                 | N13                                        | PIO      | 2    |
| <b>PIO2</b>                 | P1                                         | PIO      | 2    |
| <b>PIO2</b>                 | P2                                         | PIO      | 2    |
| <b>PIO2</b>                 | P3                                         | PIO      | 2    |
| <b>PIO2</b>                 | P4                                         | PIO      | 2    |
| <b>PIO2</b>                 | P7                                         | PIO      | 2    |
| <b>PIO2</b>                 | P8                                         | PIO      | 2    |
| <b>PIO2</b>                 | P9                                         | PIO      | 2    |
| <b>PIO2/CBSEL0</b>          | L9                                         | PIO      | 2    |
| <b>PIO2/CBSEL1</b>          | P10                                        | PIO      | 2    |
| <b>VCCIO_2</b>              | J9                                         | VCCIO    | 2    |
| <b>VCCIO_2</b>              | M5                                         | VCCIO    | 2    |
| <b>VCCIO_2</b>              | N10                                        | VCCIO    | 2    |
| <b>PIO3/DP00A</b>           | C1                                         | DPIO     | 3    |
| <b>PIO3/DP00B</b>           | B1                                         | DPIO     | 3    |
| <b>PIO3/DP01A</b>           | D3                                         | DPIO     | 3    |
| <b>PIO3/DP01B</b>           | C3                                         | DPIO     | 3    |
| <b>PIO3/DP02A</b>           | D1                                         | DPIO     | 3    |
| <b>PIO3/DP02B</b>           | D2                                         | DPIO     | 3    |
| <b>PIO3/DP03A (◆)</b>       | <i>ICE65L04:</i> E1<br><i>ICE65L08:</i> E2 | DPIO     | 3    |
| <b>PIO3/DP03B (◆)</b>       | <i>ICE65L04:</i> E2<br><i>ICE65L04:</i> E1 | DPIO     | 3    |
| <b>PIO3/DP04A</b>           | D4                                         | DPIO     | 3    |
| <b>PIO3/DP04B</b>           | E4                                         | DPIO     | 3    |
| <b>PIO3/DP05A (◆)</b>       | <i>ICE65L04:</i> F3<br><i>ICE65L08:</i> F4 | DPIO     | 3    |
| <b>PIO3/DP05B (◆)</b>       | <i>ICE65L04:</i> F4<br><i>ICE65L08:</i> F3 | DPIO     | 3    |
| <b>PIO3/DP06A</b>           | F5                                         | DPIO     | 3    |
| <b>PIO3/DP06B</b>           | E5                                         | DPIO     | 3    |
| <b>PIO3/DP07A (◆)</b>       | <i>ICE65L04:</i> G2<br><i>ICE65L08:</i> H4 | DPIO     | 3    |
| <b>GBIN7/PIO3/DP07B (◆)</b> | <i>ICE65L04:</i> G1<br><i>ICE65L08:</i> H3 | GBIN     | 3    |
| <b>GBIN6/PIO3/DP08A</b>     | H1                                         | GBIN     | 3    |
| <b>PIO3/DP08B</b>           | H2                                         | DPIO     | 3    |
| <b>PIO3/DP09A</b>           | G3                                         | DPIO     | 3    |
| <b>PIO3/DP09B</b>           | G4                                         | DPIO     | 3    |
| <b>PIO3/DP10A</b>           | J1                                         | DPIO     | 3    |
| <b>PIO3/DP10B</b>           | J2                                         | DPIO     | 3    |
| <b>PIO3/DP11A (◆)</b>       | <i>ICE65L04:</i> H4<br><i>ICE65L08:</i> G1 | DPIO     | 3    |
| <b>PIO3/DP11B (◆)</b>       | <i>ICE65L04:</i> H3<br><i>ICE65L08:</i> G2 | DPIO     | 3    |
| <b>PIO3/DP12A</b>           | K2                                         | DPIO     | 3    |
| <b>PIO3/DP12B</b>           | J3                                         | DPIO     | 3    |

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| Ball Function         | Ball Number                                  | Pin Type | Bank |
|-----------------------|----------------------------------------------|----------|------|
| <b>PIO3/DP13A</b>     | H5                                           | DPIO     | 3    |
| <b>PIO3/DP13B</b>     | G5                                           | DPIO     | 3    |
| <b>PIO3/DP14A</b>     | L1                                           | DPIO     | 3    |
| <b>PIO3/DP14B</b>     | L2                                           | DPIO     | 3    |
| <b>PIO3/DP15A</b>     | M1                                           | DPIO     | 3    |
| <b>PIO3/DP15B</b>     | M2                                           | DPIO     | 3    |
| <b>PIO3/DP16A (◆)</b> | <i>iCE65L04</i> : K3<br><i>iCE65L08</i> : K4 | DPIO     | 3    |
| <b>PIO3/DP16B (◆)</b> | <i>iCE65L08</i> : K4<br><i>iCE65L08</i> : K3 | DPIO     | 3    |
| <b>PIO3/DP17A</b>     | N1                                           | DPIO     | 3    |
| <b>PIO3/DP17B</b>     | N2                                           | DPIO     | 3    |
| <b>VCCIO_3</b>        | E3                                           | VCCIO    | 3    |
| <b>VCCIO_3</b>        | J6                                           | VCCIO    | 3    |
| <b>VCCIO_3</b>        | K1                                           | VCCIO    | 3    |
| <b>PIOS/SPI_SO</b>    | M11                                          | SPI      | SPI  |
| <b>PIOS/SPI_SI</b>    | P11                                          | SPI      | SPI  |
| <b>PIOS/SPI_SCK</b>   | P12                                          | SPI      | SPI  |
| <b>PIOS/SPI_SS_B</b>  | P13                                          | SPI      | SPI  |
| <b>SPI_VCC</b>        | L11                                          | SPI      | SPI  |
| <b>GND</b>            | A9                                           | GND      | GND  |
| <b>GND</b>            | B12                                          | GND      | GND  |
| <b>GND</b>            | C2                                           | GND      | GND  |
| <b>GND</b>            | F1                                           | GND      | GND  |
| <b>GND</b>            | F7                                           | GND      | GND  |
| <b>GND</b>            | G7                                           | GND      | GND  |
| <b>GND</b>            | G8                                           | GND      | GND  |
| <b>GND</b>            | G9                                           | GND      | GND  |
| <b>GND</b>            | H6                                           | GND      | GND  |
| <b>GND</b>            | H7                                           | GND      | GND  |
| <b>GND</b>            | H8                                           | GND      | GND  |
| <b>GND</b>            | J5                                           | GND      | GND  |
| <b>GND</b>            | J8                                           | GND      | GND  |
| <b>GND</b>            | J14                                          | GND      | GND  |
| <b>GND</b>            | K10                                          | GND      | GND  |
| <b>GND</b>            | L3                                           | GND      | GND  |
| <b>GND</b>            | P6                                           | GND      | GND  |
| <b>VCC</b>            | B7                                           | VCC      | VCC  |
| <b>VCC</b>            | F2                                           | VCC      | VCC  |
| <b>VCC</b>            | F8                                           | VCC      | VCC  |
| <b>VCC</b>            | G6                                           | VCC      | VCC  |
| <b>VCC</b>            | H9                                           | VCC      | VCC  |
| <b>VCC</b>            | J4                                           | VCC      | VCC  |
| <b>VCC</b>            | J7                                           | VCC      | VCC  |
| <b>VCC</b>            | K13                                          | VCC      | VCC  |
| <b>VCC</b>            | N7                                           | VCC      | VCC  |
| <b>VPP_2V5</b>        | A14                                          | VPP      | VPP  |
| <b>VPP_FAST</b>       | A13                                          | VPP      | VPP  |

## Pinout Differences between iCE65L04 and iCE65L08 in CB196 Package

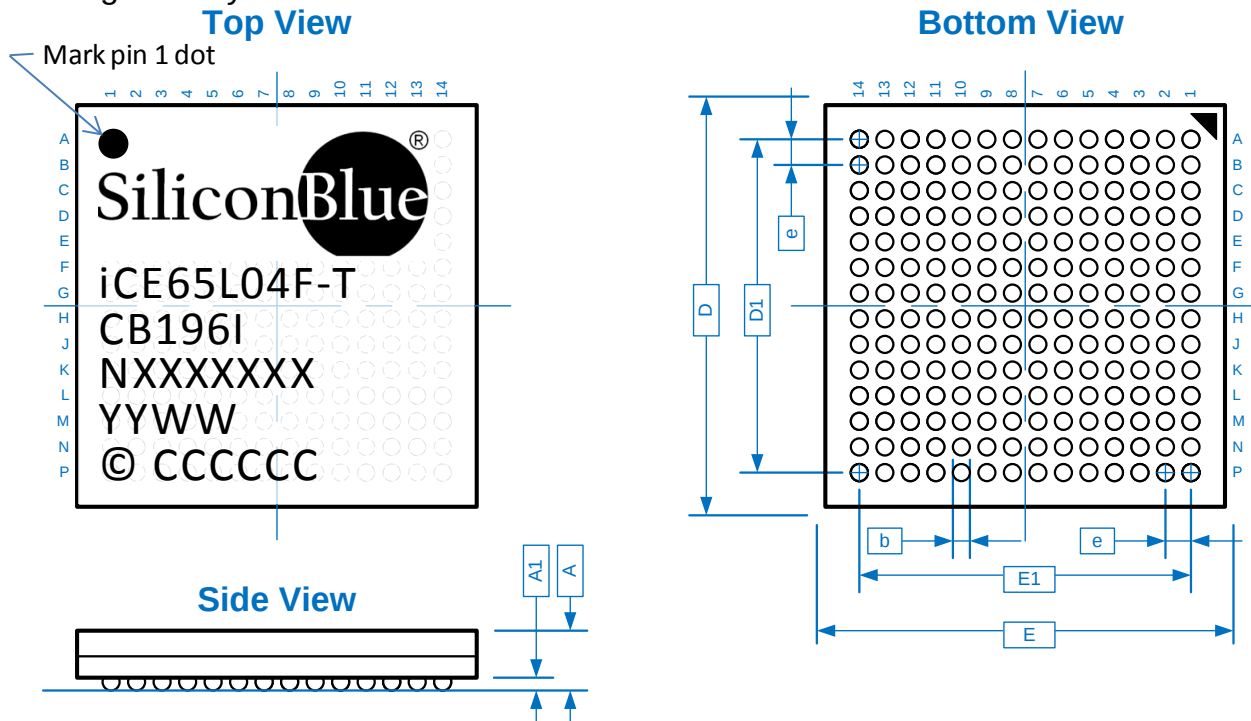
Table 43 lists the package balls that are different between the pinouts for iCE65L04 and the iCE65L08 in the CB196 package. The table also describes the functional differences between these pins, which is critical when designing a CB196 footprint that supports both the iCE65L04 and the iCE65L08 devices. In some cases, only the differential inputs are swapped; single-ended I/Os are not affected. A swapped differential pair can be inverted internally for functional equivalence. In other cases, a global buffer input is swapped with another PIO pin in the same bank.

**Table 43: Pinout Differences between iCE65L04 and iCE65L08 in CB196 Package**

| Ball Number | iCE65L04         | iCE65L08         | Functional Difference                                                                                                   |
|-------------|------------------|------------------|-------------------------------------------------------------------------------------------------------------------------|
| <b>E1</b>   | PIO3/DP03A       | PIO3/DP03B       | Differential inputs swapped, single-ended I/Os not affected                                                             |
| <b>E2</b>   | PIO3/DP03B       | PIO3/DP03A       |                                                                                                                         |
| <b>F3</b>   | PIO3/DP05A       | PIO3/DP05B       | Differential inputs swapped, single-ended I/Os not affected                                                             |
| <b>F4</b>   | PIO3/DP05B       | PIO3/DP05A       |                                                                                                                         |
| <b>G1</b>   | GBIN7/PIO3/DP07B | PIO3/DP11A       | Global buffer input GBIN7 and its associated differential input is swapped with another differential pair in I/O Bank 3 |
| <b>G2</b>   | PIO3/DP07A       | PIO3/DP11B       |                                                                                                                         |
| <b>H3</b>   | PIO3/DP11B       | GBIN7/PIO3/DP07B |                                                                                                                         |
| <b>H4</b>   | PIO3/DP11A       | PIO3/DP07A       |                                                                                                                         |
| <b>K3</b>   | PIO3/DP16A       | PIO3/DP16B       | Differential inputs swapped, single-ended I/Os not affected                                                             |
| <b>K4</b>   | PIO3/DP16B       | PIO3/DP16A       |                                                                                                                         |
| <b>L7</b>   | GBIN4/PIO2       | PIO2             | Global buffer input GBIN4 swapped with another PIO pin in I/O Bank 2                                                    |
| <b>N8</b>   | PIO2             | GBIN4/PIO2       |                                                                                                                         |
| <b>M7</b>   | PIO2             | GBIN5/PIO2       | Global buffer input GBIN5 swapped with another PIO pin in I/O Bank 2                                                    |
| <b>P5</b>   | GBIN5/PIO2       | PIO2             |                                                                                                                         |

**Figure 47:**  
**(a) iCE65L04 CB196 Package Mechanical Drawing**

**CB196:** 8 x8 mm, 196-ball, 0.5 mm ball-pitch, fully-populated, chip-scale ball grid array



| Description                | Symbol | Min. | Nominal | Max. | Units   |
|----------------------------|--------|------|---------|------|---------|
| Number of Ball Columns     | X      |      | 14      |      | Columns |
| Number of Ball Rows        | Y      |      | 14      |      | Rows    |
| Number of Signal Balls     | n      |      | 196     |      | Balls   |
| Body Size                  | X      | E    | 7.90    | 8.00 | mm      |
|                            | Y      | D    | 7.90    | 8.00 |         |
| Ball Pitch                 | e      | —    | 0.50    | —    |         |
| Ball Diameter              | b      | 0.27 | —       | 0.37 |         |
| Edge Ball Center to Center | X      | E1   | —       | 6.50 |         |
|                            | Y      | D1   | —       | 6.50 |         |
| Package Height             | A      | —    | —       | 1.00 |         |
| Stand Off                  | A1     | 0.16 | —       | 0.26 |         |

### Top Marking Format

| Line | Content   | Description  |
|------|-----------|--------------|
| 1    | Logo      | Logo         |
| 2    | iCE65L04F | Part number  |
|      | -T        | Power/Speed  |
| 3    | CB196I    | Package type |
|      | ENG       | Engineering  |
| 4    | NXXXXXXX  | Lot Number   |
| 5    | YYWW      | Date Code    |
| 6    | © CCCCCC  | Country      |

### Thermal Resistance

| Junction-to-Ambient<br>$\theta_{JA}$ (°C/W) |         |
|---------------------------------------------|---------|
| 0 LFM                                       | 200 LFM |
| 42                                          | 34      |

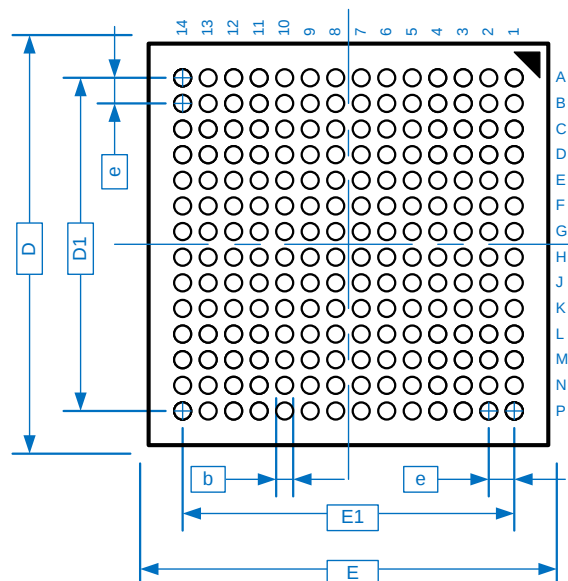
## (b) iCE65L08 CB196 Package Mechanical Drawing

**CB196:** 8 x 8 mm, 196-ball, 0.5 mm ball-pitch, fully-populated, chip-scale ball grid array

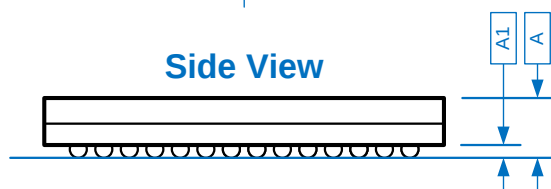
**Top View**



**Bottom View**



**Side View**



**Top Marking Format**

| Description                | Symbol | Min. | Nominal | Max. | Units   |
|----------------------------|--------|------|---------|------|---------|
| Number of Ball Columns     | X      |      | 14      |      | Columns |
| Number of Ball Rows        | Y      |      | 14      |      | Rows    |
| Number of Signal Balls     | n      |      | 196     |      | Balls   |
| Body Size                  | X      | E    | 7.90    | 8.00 | mm      |
|                            | Y      | D    | 7.90    | 8.00 |         |
| Ball Pitch                 | e      | —    | 0.50    | —    |         |
| Ball Diameter              | b      | 0.27 | —       | 0.37 |         |
| Edge Ball Center to Center | X      | E1   | —       | 6.50 |         |
|                            | Y      | D1   | —       | 6.50 |         |
| Package Height             | A      | —    | —       | 1.00 |         |
| Stand Off                  | A1     | 0.16 | —       | 0.26 |         |

| Line | Content   | Description  |
|------|-----------|--------------|
| 1    | Logo      | Logo         |
| 2    | iCE65L08F | Part number  |
|      | -T        | Power/Speed  |
| 3    | CB196C    | Package type |
|      | ENG       | Engineering  |
| 4    | NXXXXXXX  | Lot Number   |
| 5    | YYWW      | Date Code    |
| 6    | © CCCCCC  | Country      |

**Thermal Resistance**

| Junction-to-Ambient<br>$\theta_{JA}$ ( $^{\circ}\text{C}/\text{W}$ ) |         |
|----------------------------------------------------------------------|---------|
| 0 LFM                                                                | 200 LFM |
| 42                                                                   | 34      |

## CB284 Chip-Scale Ball-Grid Array

The CB284 package, partially-populated 0.5 mm pitch, ball grid array simplifies PCB layout with empty ball rings.

### Footprint Diagram

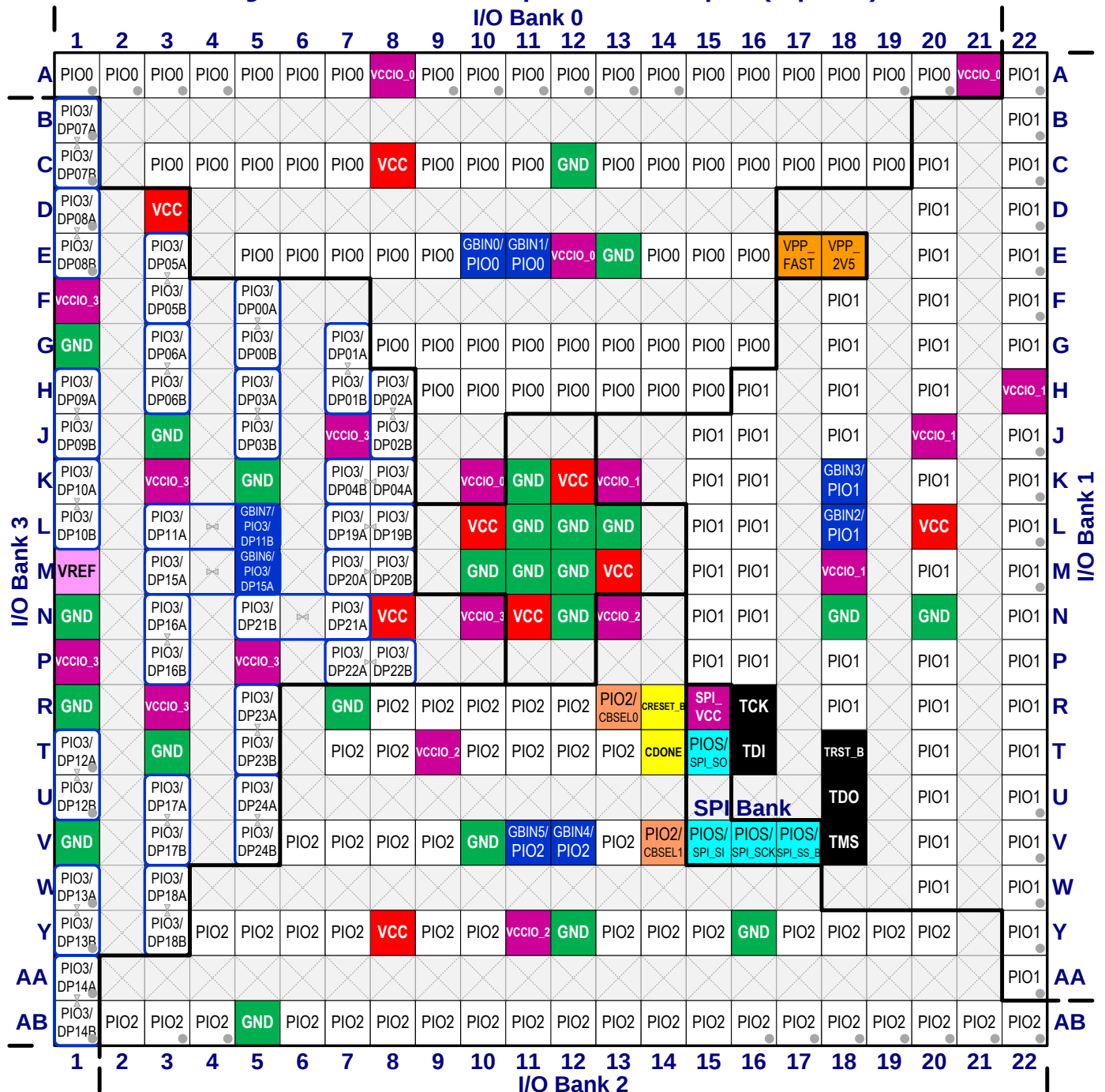
Figure 48 shows the CB284 chip-scale BGA footprint. The 8 x 8 mm CB132 package fits within the same ball pattern as the 12 x 12 mm CB284 package. In other words, the central 8 x 8 section of the CB284 footprint matches the CB132 footprint.

Figure 31 shows the conventions used in the diagram.

Also see Table 44 for a complete, detailed pinout for the 132-ball and 284-ball chip-scale BGA packages.

The signal pins are also grouped into the four I/O Banks and the SPI interface.

**Figure 48: iCE65 CB284 Chip-Scale BGA Footprint (Top View)**



## Pinout Table

Table 44 provides a detailed pinout table for the two chip-scale BGA packages. Pins are generally arranged by I/O bank, then by ball function. The balls with a black circle (●) are unconnected balls (N.C.) for the iCE65L04 in the CB284 package. The CB132 package fits within the CB284 package footprint as shown in Figure 48. The right-most column shows which CB132 ball corresponds to the CB284.

The table also highlights the differential I/O pairs in I/O Bank 3.

**Table 44: iCE65 CB284 Chip-scale BGA Pinout Table (with CB132 cross reference)**

| Ball Function     | Ball Number |          | Pin Type by Device |          | Bank | CB132 Ball Equivalent |
|-------------------|-------------|----------|--------------------|----------|------|-----------------------|
|                   | iCE65L04    | iCE65L08 | iCE65L04           | iCE65L08 |      |                       |
| <b>GBIN0/PIO0</b> | E10         |          | GBIN               | GBIN     | 0    | A6                    |
| <b>GBIN1/PIO0</b> | E11         |          | GBIN               | GBIN     | 0    | A7                    |
| <b>PIO0 (●)</b>   | A1          |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A2          |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A3          |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A4          |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0</b>       | A5          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | A6          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | A7          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A9          |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A10         |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A11         |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A12         |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A13         |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0</b>       | A15         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | A16         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | A17         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | A18         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A14         |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A19         |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0 (●)</b>   | A20         |          | N.C.               | PIO      | 0    | —                     |
| <b>PIO0</b>       | C3          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C4          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C5          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C6          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C7          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C9          |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C10         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C11         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C13         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C14         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C15         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C16         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C17         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C18         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | C19         |          | PIO                | PIO      | 0    | —                     |
| <b>PIO0</b>       | E5          |          | PIO                | PIO      | 0    | A1                    |
| <b>PIO0</b>       | E6          |          | PIO                | PIO      | 0    | A2                    |
| <b>PIO0</b>       | E7          |          | PIO                | PIO      | 0    | A3                    |
| <b>PIO0</b>       | E8          |          | PIO                | PIO      | 0    | A4                    |
| <b>PIO0</b>       | E9          |          | PIO                | PIO      | 0    | A5                    |
| <b>PIO0</b>       | E14         |          | PIO                | PIO      | 0    | A10                   |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| Ball Function     | Ball Number          | Pin Type by Device |          | Bank | CB132 Ball Equivalent |
|-------------------|----------------------|--------------------|----------|------|-----------------------|
|                   | iCE65L04<br>iCE65L08 | iCE65L04           | iCE65L08 |      |                       |
| <b>PIO0</b>       | E15                  | PIO                | PIO      | 0    | A11                   |
| <b>PIO0</b>       | E16                  | PIO                | PIO      | 0    | A12                   |
| <b>PIO0</b>       | G8                   | PIO                | PIO      | 0    | C4                    |
| <b>PIO0</b>       | G9                   | PIO                | PIO      | 0    | C5                    |
| <b>PIO0</b>       | G10                  | PIO                | PIO      | 0    | C6                    |
| <b>PIO0</b>       | G11                  | PIO                | PIO      | 0    | C7                    |
| <b>PIO0</b>       | G12                  | PIO                | PIO      | 0    | C8                    |
| <b>PIO0</b>       | G13                  | PIO                | PIO      | 0    | C9                    |
| <b>PIO0</b>       | G14                  | PIO                | PIO      | 0    | C10                   |
| <b>PIO0</b>       | G15                  | PIO                | PIO      | 0    | C11                   |
| <b>PIO0</b>       | G16                  | PIO                | PIO      | 0    | C12                   |
| <b>PIO0</b>       | H9                   | PIO                | PIO      | 0    | D5                    |
| <b>PIO0</b>       | H10                  | PIO                | PIO      | 0    | D6                    |
| <b>PIO0</b>       | H11                  | PIO                | PIO      | 0    | D7                    |
| <b>PIO0</b>       | H12                  | PIO                | PIO      | 0    | D8                    |
| <b>PIO0</b>       | H13                  | PIO                | PIO      | 0    | D9                    |
| <b>PIO0</b>       | H14                  | PIO                | PIO      | 0    | D10                   |
| <b>PIO0</b>       | H15                  | PIO                | PIO      | 0    | D11                   |
| <b>VCCIO_0</b>    | A8                   | VCCIO              | VCCIO    | 0    | —                     |
| <b>VCCIO_0</b>    | A21                  | VCCIO              | VCCIO    | 0    | —                     |
| <b>VCCIO_0</b>    | E12                  | VCCIO              | VCCIO    | 0    | A8                    |
| <b>VCCIO_0</b>    | K10                  | VCCIO              | VCCIO    | 0    | F6                    |
| <b>GBIN2/PIO1</b> | L18                  | GBIN               | GBIN     | 1    | G14                   |
| <b>GBIN3/PIO1</b> | K18                  | GBIN               | GBIN     | 1    | F14                   |
| <b>PIO1 (●)</b>   | A22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | AA22                 | N.C.               | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | B22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | C20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | C22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | D20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | D22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | E20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | E22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | F18                  | PIO                | PIO      | 1    | B14                   |
| <b>PIO1</b>       | F20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | F22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | G18                  | PIO                | PIO      | 1    | C14                   |
| <b>PIO1</b>       | G20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | G22                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | H16                  | PIO                | PIO      | 1    | D12                   |
| <b>PIO1</b>       | H18                  | PIO                | PIO      | 1    | D14                   |
| <b>PIO1</b>       | H20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | J15                  | PIO                | PIO      | 1    | E11                   |
| <b>PIO1</b>       | J16                  | PIO                | PIO      | 1    | E12                   |
| <b>PIO1</b>       | J18                  | PIO                | PIO      | 1    | E14                   |
| <b>PIO1 (●)</b>   | J22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | K15                  | PIO                | PIO      | 1    | F11                   |
| <b>PIO1</b>       | K16                  | PIO                | PIO      | 1    | F12                   |
| <b>PIO1</b>       | K20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | K22                  | N.C.               | PIO      | 1    | —                     |

| Ball Function     | Ball Number          | Pin Type by Device |          | Bank | CB132 Ball Equivalent |
|-------------------|----------------------|--------------------|----------|------|-----------------------|
|                   | ice65L04<br>ice65L08 | ice65L04           | ice65L08 |      |                       |
| <b>PIO1</b>       | L15                  | PIO                | PIO      | 1    | G11                   |
| <b>PIO1</b>       | L16                  | PIO                | PIO      | 1    | G12                   |
| <b>PIO1 (●)</b>   | L22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | M15                  | PIO                | PIO      | 1    | H11                   |
| <b>PIO1</b>       | M16                  | PIO                | PIO      | 1    | H12                   |
| <b>PIO1</b>       | M20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | M22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | N15                  | PIO                | PIO      | 1    | J11                   |
| <b>PIO1</b>       | N16                  | PIO                | PIO      | 1    | J12                   |
| <b>PIO1</b>       | N22                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | P15                  | PIO                | PIO      | 1    | K11                   |
| <b>PIO1</b>       | P16                  | PIO                | PIO      | 1    | K12                   |
| <b>PIO1</b>       | P18                  | PIO                | PIO      | 1    | K14                   |
| <b>PIO1</b>       | P20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | P22                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | R18                  | PIO                | PIO      | 1    | L14                   |
| <b>PIO1</b>       | R20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | R22                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | T20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | T22                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1</b>       | U20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | U22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | V20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | V22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1</b>       | W20                  | PIO                | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | W22                  | N.C.               | PIO      | 1    | —                     |
| <b>PIO1 (●)</b>   | Y22                  | N.C.               | PIO      | 1    | —                     |
| <b>TCK</b>        | R16                  | JTAG               | JTAG     | 1    | L12                   |
| <b>TDI</b>        | T16                  | JTAG               | JTAG     | 1    | M12                   |
| <b>TDO</b>        | U18                  | JTAG               | JTAG     | 1    | N14                   |
| <b>TMS</b>        | V18                  | JTAG               | JTAG     | 1    | P14                   |
| <b>TRST_B</b>     | T18                  | JTAG               | JTAG     | 1    | M14                   |
| <b>VCCIO_1</b>    | H22                  | VCCIO              | VCCIO    | 1    | —                     |
| <b>VCCIO_1</b>    | J20                  | VCCIO              | VCCIO    | 1    | —                     |
| <b>VCCIO_1</b>    | K13                  | VCCIO              | VCCIO    | 1    | F9                    |
| <b>VCCIO_1</b>    | M18                  | VCCIO              | VCCIO    | 1    | H14                   |
| <b>CDONE</b>      | T14                  | CONFIG             | CONFIG   | 2    | M10                   |
| <b>CRESET_B</b>   | R14                  | CONFIG             | CONFIG   | 2    | L10                   |
| <b>GBIN4/PIO2</b> | V12                  | GBIN               | GBIN     | 2    | P7                    |
| <b>GBIN5/PIO2</b> | V11                  | GBIN               | GBIN     | 2    | P8                    |
| <b>PIO2</b>       | R8                   | PIO                | PIO      | 2    | L4                    |
| <b>PIO2</b>       | R9                   | PIO                | PIO      | 2    | L5                    |
| <b>PIO2</b>       | R10                  | PIO                | PIO      | 2    | L6                    |
| <b>PIO2</b>       | R11                  | PIO                | PIO      | 2    | L7                    |
| <b>PIO2</b>       | R12                  | PIO                | PIO      | 2    | L8                    |
| <b>PIO2</b>       | T7                   | PIO                | PIO      | 2    | M3                    |
| <b>PIO2</b>       | T8                   | PIO                | PIO      | 2    | M4                    |
| <b>PIO2</b>       | T10                  | PIO                | PIO      | 2    | M6                    |
| <b>PIO2</b>       | T11                  | PIO                | PIO      | 2    | M7                    |
| <b>PIO2</b>       | T12                  | PIO                | PIO      | 2    | M8                    |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| Ball Function      | Ball Number          | Pin Type by Device |          | Bank | CB132 Ball Equivalent |
|--------------------|----------------------|--------------------|----------|------|-----------------------|
|                    | iCE65L04<br>iCE65L08 | iCE65L04           | iCE65L08 |      |                       |
| <b>PIO2</b>        | T13                  | PIO                | PIO      | 2    | M9                    |
| <b>PIO2</b>        | V6                   | PIO                | PIO      | 2    | P2                    |
| <b>PIO2</b>        | V7                   | PIO                | PIO      | 2    | P3                    |
| <b>PIO2</b>        | V8                   | PIO                | PIO      | 2    | P4                    |
| <b>PIO2</b>        | V9                   | PIO                | PIO      | 2    | P5                    |
| <b>PIO2</b>        | V13                  | PIO                | PIO      | 2    | P9                    |
| <b>PIO2</b>        | Y4                   | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y5                   | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y6                   | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y7                   | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y9                   | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y10                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y13                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y14                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y15                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y17                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y18                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y19                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | Y20                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB2                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB3                  | N.C.               | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB4                  | N.C.               | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB6                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB7                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB8                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB9                  | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB10                 | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB11                 | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB12                 | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB13                 | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB14                 | PIO                | PIO      | 2    | —                     |
| <b>PIO2</b>        | AB15                 | PIO                | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB16                 | N.C.               | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB17                 | N.C.               | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB18                 | N.C.               | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB19                 | N.C.               | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB20                 | N.C.               | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB21                 | N.C.               | PIO      | 2    | —                     |
| <b>PIO2 (●)</b>    | AB22                 | N.C.               | PIO      | 2    | —                     |
| <b>PIO2/CBSEL0</b> | R13                  | PIO                | PIO      | 2    | L9                    |
| <b>PIO2/CBSEL1</b> | V14                  | PIO                | PIO      | 2    | P10                   |
| <b>VCCIO_2</b>     | N13                  | VCCIO              | VCCIO    | 2    | J9                    |
| <b>VCCIO_2</b>     | T9                   | VCCIO              | VCCIO    | 2    | M5                    |
| <b>VCCIO_2</b>     | Y11                  | VCCIO              | VCCIO    | 2    | —                     |
| <b>PIO3/DP00A</b>  | F5                   | DPIO               | DPIO     | 3    | B1                    |
| <b>PIO3/DP00B</b>  | G5                   | DPIO               | DPIO     | 3    | C1                    |
| <b>PIO3/DP01A</b>  | G7                   | DPIO               | DPIO     | 3    | C3                    |
| <b>PIO3/DP01B</b>  | H7                   | DPIO               | DPIO     | 3    | D3                    |
| <b>PIO3/DP02A</b>  | H8                   | DPIO               | DPIO     | 3    | D4                    |
| <b>PIO3/DP02B</b>  | J8                   | DPIO               | DPIO     | 3    | E4                    |

| Ball Function           | Ball Number          | Pin Type by Device |          | Bank | CB132 Ball Equivalent |
|-------------------------|----------------------|--------------------|----------|------|-----------------------|
|                         | iCE65L04<br>iCE65L08 | iCE65L04           | iCE65L08 |      |                       |
| <b>PIO3/DP03A</b>       | H5                   | DPIO               | DPIO     | 3    | D1                    |
| <b>PIO3/DP03B</b>       | J5                   | DPIO               | DPIO     | 3    | E1                    |
| <b>PIO3/DP04A</b>       | K8                   | DPIO               | DPIO     | 3    | F4                    |
| <b>PIO3/DP04B</b>       | K7                   | DPIO               | DPIO     | 3    | F3                    |
| <b>PIO3/DP05A</b>       | E3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP05B</b>       | F3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP06A</b>       | G3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP06B</b>       | H3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP07A (●)</b>   | B1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP07B (●)</b>   | C1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP08A (●)</b>   | D1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP08B (●)</b>   | E1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP09A</b>       | H1                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP09B</b>       | J1                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP10A</b>       | K1                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP10B</b>       | L1                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP11A</b>       | L3                   | DPIO               | DPIO     | 3    | —                     |
| <b>GBIN7/PIO3/DP11B</b> | L5                   | GBIN               | GBIN     | 3    | G1                    |
| <b>PIO3/DP12A (●)</b>   | T1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP12B (●)</b>   | U1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP13A (●)</b>   | W1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP13B (●)</b>   | Y1                   | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP14A (●)</b>   | AA1                  | N.C.               | DPIO     | 3    | —                     |
| <b>PIO3/DP14B (●)</b>   | AB1                  | N.C.               | DPIO     | 3    | —                     |
| <b>GBIN6/PIO3/DP15A</b> | M5                   | GBIN               | GBIN     | 3    | H1                    |
| <b>PIO3/DP15B</b>       | M3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP16A</b>       | N3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP16B</b>       | P3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP17A</b>       | U3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP17B</b>       | V3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP18A</b>       | W3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP18B</b>       | Y3                   | DPIO               | DPIO     | 3    | —                     |
| <b>PIO3/DP19A</b>       | L7                   | DPIO               | DPIO     | 3    | G3                    |
| <b>PIO3/DP19B</b>       | L8                   | DPIO               | DPIO     | 3    | G4                    |
| <b>PIO3/DP20A</b>       | M7                   | DPIO               | DPIO     | 3    | H3                    |
| <b>PIO3/DP20B</b>       | M8                   | DPIO               | DPIO     | 3    | H4                    |
| <b>PIO3/DP21A</b>       | N7                   | DPIO               | DPIO     | 3    | J3                    |
| <b>PIO3/DP21B</b>       | N5                   | DPIO               | DPIO     | 3    | J1                    |
| <b>PIO3/DP22A</b>       | P7                   | DPIO               | DPIO     | 3    | K3                    |
| <b>PIO3/DP22B</b>       | P8                   | DPIO               | DPIO     | 3    | K4                    |
| <b>PIO3/DP23A</b>       | R5                   | DPIO               | DPIO     | 3    | L1                    |
| <b>PIO3/DP23B</b>       | T5                   | DPIO               | DPIO     | 3    | M1                    |
| <b>PIO3/DP24A</b>       | U5                   | DPIO               | DPIO     | 3    | N1                    |
| <b>PIO3/DP24B</b>       | V5                   | DPIO               | DPIO     | 3    | P1                    |
| <b>VCCIO_3</b>          | F1                   | VCCIO              | VCCIO    | 3    | —                     |
| <b>VCCIO_3</b>          | P1                   | VCCIO              | VCCIO    | 3    | —                     |

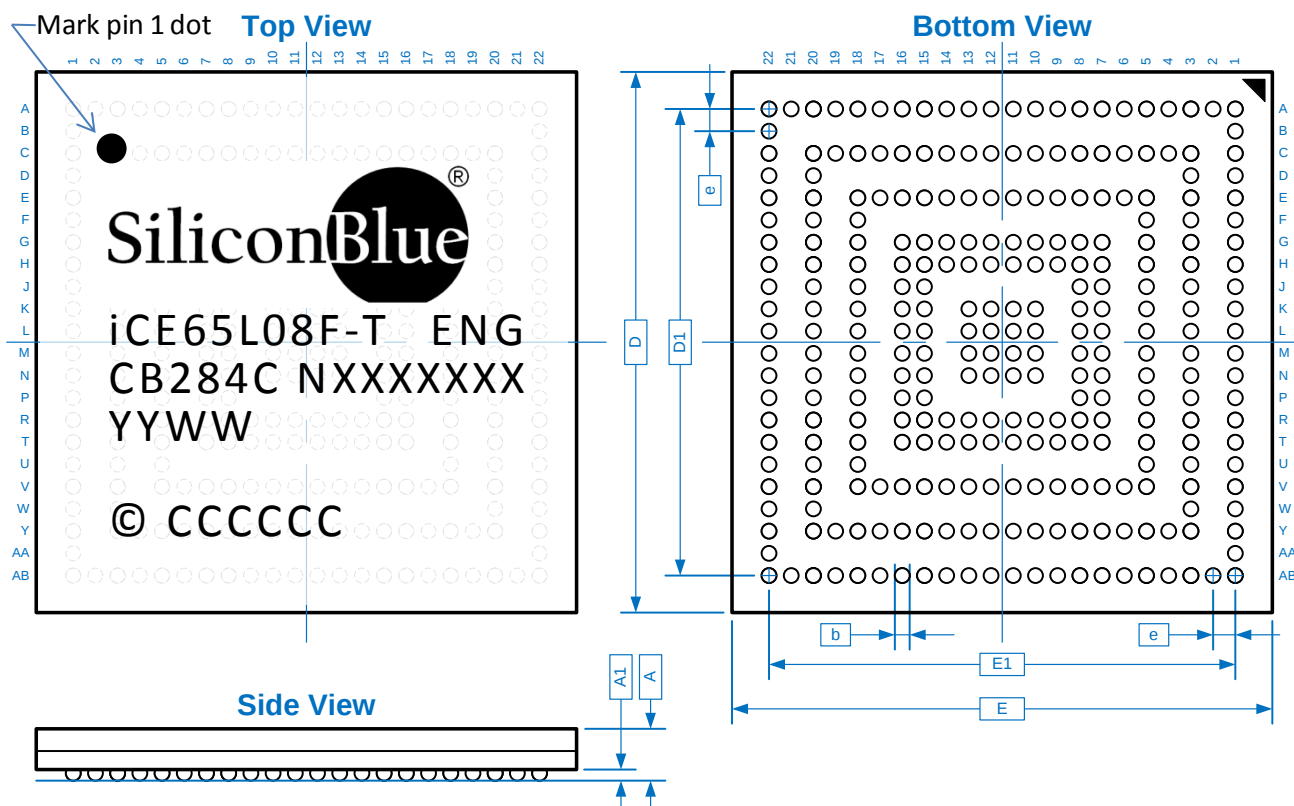
# iCE65 Ultra Low-Power mobileFPGA™ Family

| Ball Function        | Ball Number          | Pin Type by Device |          | Bank | CB132 Ball Equivalent |
|----------------------|----------------------|--------------------|----------|------|-----------------------|
|                      | iCE65L04<br>iCE65L08 | iCE65L04           | iCE65L08 |      |                       |
| <b>VCCIO_3</b>       | J7                   | VCCIO              | VCCIO    | 3    | E3                    |
| <b>VCCIO_3</b>       | K3                   | VCCIO              | VCCIO    | 3    | —                     |
| <b>VCCIO_3</b>       | N10                  | VCCIO              | VCCIO    | 3    | J6                    |
| <b>VCCIO_3</b>       | P5                   | VCCIO              | VCCIO    | 3    | K1                    |
| <b>VCCIO_3</b>       | R3                   | VCCIO              | VCCIO    | 3    | —                     |
| <b>VREF</b>          | M1                   | VREF               | VREF     | 3    | —                     |
| <b>PIOS/SPI_SO</b>   | T15                  | SPI                | SPI      | SPI  | M11                   |
| <b>PIOS/SPI_SI</b>   | V15                  | SPI                | SPI      | SPI  | P11                   |
| <b>PIOS/SPI_SCK</b>  | V16                  | SPI                | SPI      | SPI  | P12                   |
| <b>PIOS/SPI_SS_B</b> | V17                  | SPI                | SPI      | SPI  | P13                   |
| <b>SPI_VCC</b>       | R15                  | SPI                | SPI      | SPI  | L11                   |
| <b>GND</b>           | C12                  | GND                | GND      | GND  | —                     |
| <b>GND</b>           | E13                  | GND                | GND      | GND  | A9                    |
| <b>GND</b>           | J3                   | GND                | GND      | GND  | —                     |
| <b>GND</b>           | K5                   | GND                | GND      | GND  | F1                    |
| <b>GND</b>           | K11                  | GND                | GND      | GND  | F7                    |
| <b>GND</b>           | L11                  | GND                | GND      | GND  | G7                    |
| <b>GND</b>           | L12                  | GND                | GND      | GND  | G8                    |
| <b>GND</b>           | L13                  | GND                | GND      | GND  | G9                    |
| <b>GND</b>           | M10                  | GND                | GND      | GND  | H6                    |
| <b>GND</b>           | M11                  | GND                | GND      | GND  | H7                    |
| <b>GND</b>           | M12                  | GND                | GND      | GND  | H8                    |
| <b>GND</b>           | N1                   | GND                | GND      | GND  | —                     |
| <b>GND</b>           | N12                  | GND                | GND      | GND  | J8                    |
| <b>GND</b>           | N18                  | GND                | GND      | GND  | J14                   |
| <b>GND</b>           | N20                  | GND                | GND      | GND  | —                     |
| <b>GND</b>           | R7                   | GND                | GND      | GND  | L3                    |
| <b>GND</b>           | T3                   | GND                | GND      | GND  | —                     |
| <b>GND</b>           | V1                   | GND                | GND      | GND  | —                     |
| <b>GND</b>           | V10                  | GND                | GND      | GND  | P6                    |
| <b>GND</b>           | Y12                  | GND                | GND      | GND  | —                     |
| <b>GND</b>           | Y16                  | GND                | GND      | GND  | —                     |
| <b>GND</b>           | AB5                  | GND                | GND      | GND  | —                     |
| <b>GND</b>           | G1                   | GND                | GND      | GND  | —                     |
| <b>GND</b>           | R1                   | GND                | GND      | GND  | —                     |
| <b>VCC</b>           | C8                   | VCC                | VCC      | VCC  | —                     |
| <b>VCC</b>           | D3                   | VCC                | VCC      | VCC  | —                     |
| <b>VCC</b>           | K12                  | VCC                | VCC      | VCC  | F8                    |
| <b>VCC</b>           | L10                  | VCC                | VCC      | VCC  | G6                    |
| <b>VCC</b>           | L20                  | VCC                | VCC      | VCC  | —                     |
| <b>VCC</b>           | M13                  | VCC                | VCC      | VCC  | H9                    |
| <b>VCC</b>           | N8                   | VCC                | VCC      | VCC  | J4                    |
| <b>VCC</b>           | N11                  | VCC                | VCC      | VCC  | J7                    |
| <b>VCC</b>           | Y8                   | VCC                | VCC      | VCC  | —                     |
| <b>VPP_2V5</b>       | E18                  | VPP                | VPP      | VPP  | A14                   |
| <b>VPP_FAST</b>      | E17                  | VPP                | VPP      | VPP  | A13                   |

# Package Mechanical Drawing

**Figure 49: CB284 Package Mechanical Drawing**

**CB284:** 12 x 12 mm, 284-ball, 0.5 mm ball-pitch, chip-scale ball grid array



## Top Marking Format

| Description                | Symbol | Min. | Nominal | Max.  | Units   |
|----------------------------|--------|------|---------|-------|---------|
| Number of Ball Columns     | X      |      | 22      |       | Columns |
| Number of Ball Rows        | Y      |      | 22      |       | Rows    |
| Number of Signal Balls     | n      |      | 284     |       | Balls   |
| Body Size                  | X      | E    | 11.90   | 12.00 | mm      |
|                            | Y      | D    | 11.90   | 12.00 |         |
| Ball Pitch                 | e      | —    | 0.50    | —     |         |
| Ball Diameter              | b      | 0.27 | —       | 0.37  |         |
| Edge Ball Center to Center | X      | E1   | —       | 10.50 |         |
|                            | Y      | D1   | —       | 10.50 |         |
| Package Height             | A      | —    | —       | 1.00  |         |
| Stand Off                  | A1     | 0.16 | —       | 0.26  |         |

| Line | Content   | Description      |
|------|-----------|------------------|
| 1    | Logo      | Logo             |
| 2    | iCE65L08F | Part number      |
|      | -T        | Power/Speed      |
|      | ENG       | Engineering      |
| 3    | CB284C    | Package type and |
|      | NXXXXXXX  | Lot number       |
| 4    | YYWW      | Date Code        |
| 5    | N/A       | Blank            |
| 6    | © CCCCCC  | Country          |

## Thermal Resistance

| Junction-to-Ambient<br>$\theta_{JA}$ (°C/W) |         |
|---------------------------------------------|---------|
| 0 LFM                                       | 200 LFM |
| 35                                          | 28      |

## Die Cross Reference

The tables in this section list all the pads on a specific die type and provide a cross reference on how a specific pad connects to a ball or pin in each of the available package offerings. Similarly, the tables provide the pad coordinates for the die-based version of the product (DiePlus). These tables also provide a way to prototype with one package option and then later move to a different package or die.

As described in “[Input and Output Register Control per PIO Pair](#)” on page 16, PIO pairs share register control inputs. Similarly, as described in “[Differential Inputs and Outputs](#)” on page 12, a PIO pair can form a differential input or output. PIO pairs in I/O Bank 3 are optionally differential inputs or differential outputs. PIO pairs in all other I/O Banks are optionally differential outputs. In the tables, differential pairs are surrounded by a heavy blue box.

### iCE65L04

Table 45 lists all the pads on the iCE65L04 die and how these pads connect to the balls or pins in the supported package styles. Most VCC, VCCIO, and GND pads are double-bonded inside the package although the table shows only a single connection.

For additional information on the iCE65L04 DiePlus product, please refer to the following data sheet.

DiePlus Advantage FPGA Known Good Die

**Table 45: iCE65L04 Die Cross Reference**

| iCE65L04<br>Pad Name | DiePlus |       |       |       | Pad | X (µm) | Y (µm)   |
|----------------------|---------|-------|-------|-------|-----|--------|----------|
|                      | VQ100   | CB132 | CB196 | CB284 |     |        |          |
| <b>PIO3_00/DP00A</b> | 1       | B1    | C1    | F5    | 1   | 129.40 | 2,687.75 |
| <b>PIO3_01/DP00B</b> | 2       | C1    | B1    | G5    | 2   | 231.40 | 2,642.74 |
| <b>PIO3_02/DP01A</b> | 3       | C3    | D3    | G7    | 3   | 129.40 | 2,597.75 |
| <b>PIO3_03/DP01B</b> | 4       | D3    | C3    | H7    | 4   | 231.40 | 2,552.74 |
| <b>GND</b>           | 5       | F1    | F1    | K5    | 5   | 129.40 | 2,507.75 |
| <b>GND</b>           | —       | —     | —     | —     | 6   | 231.40 | 2,462.74 |
| <b>VCCIO_3</b>       | 6       | E3    | E3    | J7    | 7   | 129.40 | 2,417.75 |
| <b>VCCIO_3</b>       | —       | —     | —     | —     | 8   | 231.40 | 2,372.74 |
| <b>PIO3_04/DP02A</b> | 7       | D4    | D1    | H8    | 9   | 129.40 | 2,327.75 |
| <b>PIO3_05/DP02B</b> | 8       | E4    | D2    | J8    | 10  | 231.40 | 2,292.74 |
| <b>PIO3_06/DP03A</b> | —       | D1    | E1    | H5    | 11  | 129.40 | 2,257.75 |
| <b>PIO3_07/DP03B</b> | —       | E1    | E2    | J5    | 12  | 231.40 | 2,222.74 |
| <b>VCC</b>           | —       | —     | H9    | D3    | 13  | 129.40 | 2,187.75 |
| <b>PIO3_08/DP04A</b> | 9       | F4    | D4    | K8    | 14  | 231.40 | 2,152.74 |
| <b>PIO3_09/DP04B</b> | 10      | F3    | E4    | K7    | 15  | 129.40 | 2,117.75 |
| <b>PIO3_10/DP05A</b> | —       | —     | F3    | E3    | 16  | 231.40 | 2,082.74 |
| <b>PIO3_11/DP05B</b> | —       | —     | F4    | F3    | 17  | 129.40 | 2,047.75 |
| <b>GND</b>           | —       | H6    | A9    | M10   | 18  | 231.40 | 2,012.74 |
| <b>PIO3_12/DP06A</b> | —       | —     | F5    | G3    | 19  | 129.40 | 1,977.75 |
| <b>PIO3_13/DP06B</b> | —       | —     | E5    | H3    | 20  | 231.40 | 1,942.74 |
| <b>GND</b>           | —       | —     | A9    | J3    | 21  | 129.40 | 1,907.75 |
| <b>GND</b>           | —       | —     | —     | —     | 22  | 231.40 | 1,872.74 |
| <b>PIO3_14/DP07A</b> | —       | —     | —     | H1    | 23  | 129.40 | 1,837.75 |
| <b>PIO3_15/DP07B</b> | —       | —     | —     | J1    | 24  | 231.40 | 1,802.74 |
| <b>VCCIO_3</b>       | —       | —     | K1    | K3    | 25  | 129.40 | 1,767.75 |
| <b>VCC</b>           | 11      | G6    | G6    | L10   | 26  | 231.40 | 1,732.74 |
| <b>PIO3_16/DP08A</b> | —       | —     | —     | K1    | 27  | 129.40 | 1,697.75 |
| <b>PIO3_17/DP08B</b> | —       | —     | —     | L1    | 28  | 231.40 | 1,662.74 |

| iCE65L04<br>Pad Name       | DiePlus |       |       |       | Pad | X (μm) | Y (μm)   |
|----------------------------|---------|-------|-------|-------|-----|--------|----------|
|                            | VQ100   | CB132 | CB196 | CB284 |     |        |          |
| <b>PIO3_18/DP09A</b>       | 12      | —     | G2    | L3    | 29  | 129.40 | 1,627.75 |
| <b>GBIN7/PIO3_19/DP09B</b> | 13      | G1    | G1    | L5    | 30  | 231.40 | 1,592.74 |
| <b>VCCIO_3</b>             | 14      | J6    | J6    | N10   | 31  | 129.40 | 1,557.75 |
| <b>VREF</b>                | N/A     | N/A   | N/A   | M1    | 32  | 231.40 | 1,522.74 |
| <b>GND</b>                 | —       | —     | A9    | N1    | 33  | 129.40 | 1,487.75 |
| <b>GBIN6/PIO3_20/DP10A</b> | 15      | H1    | H1    | M5    | 34  | 231.40 | 1,452.74 |
| <b>PIO3_21/DP10B</b>       | 16      | —     | H2    | M3    | 35  | 129.40 | 1,417.75 |
| <b>GND</b>                 | 17      | H7    | A9    | M11   | 36  | 231.40 | 1,382.74 |
| <b>PIO3_22/DP11A</b>       | —       | —     | G3    | N3    | 37  | 129.40 | 1,347.75 |
| <b>PIO3_23/DP11B</b>       | —       | —     | G4    | P3    | 38  | 231.40 | 1,312.74 |
| <b>VCCIO_3</b>             | —       | —     | K1    | R3    | 39  | 129.40 | 1,277.75 |
| <b>VCCIO_3</b>             | —       | —     | —     | —     | 40  | 231.40 | 1,242.74 |
| <b>GND</b>                 | —       | —     | A9    | T3    | 41  | 129.40 | 1,207.75 |
| <b>GND</b>                 | —       | —     | —     | —     | 42  | 231.40 | 1,172.74 |
| <b>PIO3_24/DP12A</b>       | —       | —     | J1    | U3    | 43  | 129.40 | 1,137.75 |
| <b>PIO3_25/DP12B</b>       | —       | —     | J2    | V3    | 44  | 231.40 | 1,102.74 |
| <b>GND</b>                 | —       | —     | A9    | V1    | 45  | 129.40 | 1,067.75 |
| <b>PIO3_26/DP13A</b>       | —       | —     | H4    | W3    | 46  | 231.40 | 1,032.74 |
| <b>PIO3_27/DP13B</b>       | —       | —     | H3    | Y3    | 47  | 129.40 | 997.75   |
| <b>PIO3_28/DP14A</b>       | 18      | G3    | K2    | L7    | 48  | 231.40 | 962.74   |
| <b>PIO3_29/DP14B</b>       | 19      | G4    | J3    | L8    | 49  | 129.40 | 927.75   |
| <b>PIO3_30/DP15A</b>       | —       | H3    | H5    | M7    | 50  | 231.40 | 892.74   |
| <b>PIO3_31/DP15B</b>       | —       | H4    | G5    | M8    | 51  | 129.40 | 857.75   |
| <b>VCC</b>                 | —       | J4    | F2    | N8    | 52  | 231.40 | 822.74   |
| <b>PIO3_32/DP16A</b>       | 20      | J3    | L1    | N7    | 53  | 129.40 | 787.75   |
| <b>PIO3_33/DP16B</b>       | 21      | J1    | L2    | N5    | 54  | 231.40 | 752.74   |
| <b>VCCIO_3</b>             | 22      | K1    | K1    | P5    | 55  | 129.40 | 717.75   |
| <b>VCCIO_3</b>             | —       | —     | —     | —     | 56  | 231.40 | 682.74   |
| <b>GND</b>                 | 23      | L3    | L3    | R7    | 57  | 129.40 | 637.75   |
| <b>GND</b>                 | —       | —     | —     | —     | 58  | 231.40 | 592.74   |
| <b>PIO3_34/DP17A</b>       | —       | K3    | M1    | P7    | 59  | 129.40 | 547.75   |
| <b>PIO3_35/DP17B</b>       | —       | K4    | M2    | P8    | 60  | 231.40 | 502.74   |
| <b>PIO3_36/DP18A</b>       | 24      | L1    | K3    | R5    | 61  | 129.40 | 457.75   |
| <b>PIO3_37/DP18B</b>       | 25      | M1    | K4    | T5    | 62  | 231.40 | 412.74   |
| <b>PIO3_38/DP19A</b>       | —       | N1    | N1    | U5    | 63  | 129.40 | 367.75   |
| <b>PIO3_39/DP19B</b>       | —       | P1    | N2    | V5    | 64  | 231.40 | 322.74   |
| <b>PIO2_00</b>             | —       | —     | —     | AB2   | 65  | 545.00 | 139.20   |
| <b>PIO2_01</b>             | —       | P2    | L4    | V6    | 66  | 595.00 | 37.20    |
| <b>PIO2_02</b>             | —       | M3    | M3    | T7    | 67  | 645.00 | 139.20   |
| <b>GND</b>                 | —       | —     | C2    | AB5   | 68  | 695.00 | 37.20    |
| <b>PIO2_03</b>             | 26      | L4    | P1    | R8    | 69  | 745.00 | 139.20   |
| <b>PIO2_04</b>             | 27      | P3    | N3    | V7    | 70  | 795.00 | 37.20    |
| <b>PIO2_05</b>             | 28      | M4    | P2    | T8    | 71  | 845.00 | 139.20   |
| <b>PIO2_06</b>             | 29      | L5    | L5    | R9    | 72  | 895.00 | 37.20    |
| <b>PIO2_07</b>             | 30      | P4    | M4    | V8    | 73  | 930.00 | 139.20   |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| iCE65L04<br>Pad Name  | DiePlus |       |       |       | Pad | X (μm)   | Y (μm) |
|-----------------------|---------|-------|-------|-------|-----|----------|--------|
|                       | VQ100   | CB132 | CB196 | CB284 |     |          |        |
| <b>PIO2_08</b>        | —       | L6    | P3    | R10   | 74  | 965.00   | 37.20  |
| <b>VCCIO_2</b>        | 31      | M5    | M5    | T9    | 75  | 1,000.00 | 139.20 |
| <b>PIO2_09</b>        | —       | P5    | K5    | V9    | 76  | 1,035.00 | 37.20  |
| <b>PIO2_10</b>        | —       | M6    | N4    | T10   | 77  | 1,070.00 | 139.20 |
| <b>GND</b>            | 32      | P6    | H7    | V10   | 78  | 1,105.00 | 37.20  |
| <b>PIO2_11</b>        | —       | —     | P4    | Y4    | 79  | 1,140.00 | 139.20 |
| <b>PIO2_12</b>        | —       | —     | L6    | Y5    | 80  | 1,175.00 | 37.20  |
| <b>PIO2_13</b>        | —       | —     | —     | AB6   | 81  | 1,210.00 | 139.20 |
| <b>PIO2_14</b>        | —       | —     | —     | AB7   | 82  | 1,245.00 | 37.20  |
| <b>PIO2_15</b>        | —       | —     | —     | AB8   | 83  | 1,280.00 | 139.20 |
| <b>PIO2_16</b>        | —       | —     | —     | AB9   | 84  | 1,315.00 | 37.20  |
| <b>PIO2_17</b>        | —       | —     | —     | AB10  | 85  | 1,350.00 | 139.20 |
| <b>PIO2_18</b>        | —       | —     | —     | AB11  | 86  | 1,385.00 | 37.20  |
| <b>GND</b>            | —       | J8    | H8    | N12   | 87  | 1,420.00 | 139.20 |
| <b>PIO2_19</b>        | —       | —     | K6    | Y6    | 88  | 1,455.00 | 37.20  |
| <b>PIO2_20</b>        | —       | —     | N5    | Y7    | 89  | 1,490.00 | 139.20 |
| <b>VCC</b>            | —       | —     | J4    | Y8    | 90  | 1,525.00 | 37.20  |
| <b>PIO2_21</b>        | —       | —     | M6    | Y9    | 91  | 1,560.00 | 139.20 |
| <b>PIO2_22</b>        | —       | —     | N6    | Y10   | 92  | 1,595.00 | 37.20  |
| <b>GBIN5/PIO2_23</b>  | 33      | P7    | P5    | V11   | 93  | 1,630.00 | 139.20 |
| <b>GBIN4/PIO2_24</b>  | 34      | P8    | L7    | V12   | 94  | 1,665.00 | 37.20  |
| <b>PIO2_25</b>        | —       | —     | —     | AB12  | 95  | 1,700.00 | 139.20 |
| <b>VCCIO_2</b>        | —       | —     | J9    | Y11   | 96  | 1,735.00 | 37.20  |
| <b>PIO2_26</b>        | —       | —     | —     | AB13  | 97  | 1,770.00 | 139.20 |
| <b>PIO2_27</b>        | —       | —     | K7    | AB14  | 98  | 1,805.00 | 37.20  |
| <b>GND</b>            | —       | —     | J5    | Y12   | 99  | 1,840.00 | 139.20 |
| <b>PIO2_28</b>        | —       | —     | K9    | AB15  | 100 | 1,875.00 | 37.20  |
| <b>PIO2_29</b>        | —       | —     | M7    | Y13   | 101 | 1,910.00 | 139.20 |
| <b>PIO2_30</b>        | —       | —     | K8    | Y14   | 102 | 1,945.00 | 37.20  |
| <b>PIO2_31</b>        | —       | —     | P7    | Y15   | 103 | 1,980.00 | 139.20 |
| <b>PIO2_32</b>        | —       | —     | L8    | Y17   | 104 | 2,015.00 | 37.20  |
| <b>PIO2_33</b>        | —       | —     | P8    | Y18   | 105 | 2,050.00 | 139.20 |
| <b>PIO2_34</b>        | —       | —     | N8    | Y19   | 106 | 2,085.00 | 37.20  |
| <b>PIO2_35</b>        | —       | —     | M8    | Y20   | 107 | 2,120.00 | 139.20 |
| <b>VCC</b>            | 35      | J7    | J7    | N11   | 108 | 2,155.00 | 37.20  |
| <b>VCC</b>            | —       | —     | —     | —     | 109 | 2,190.00 | 139.20 |
| <b>PIO2_36</b>        | 36      | P9    | P9    | V13   | 110 | 2,225.00 | 37.20  |
| <b>PIO2_37</b>        | 37      | M7    | N9    | T11   | 111 | 2,260.00 | 139.20 |
| <b>VCCIO_2</b>        | 38      | J9    | N10   | N13   | 112 | 2,295.00 | 37.20  |
| <b>PIO2_38</b>        | —       | L7    | M9    | R11   | 113 | 2,330.00 | 139.20 |
| <b>GND</b>            | 39      | H8    | J8    | M12   | 114 | 2,365.00 | 37.20  |
| <b>PIO2_39</b>        | —       | M8    | N12   | T12   | 115 | 2,400.00 | 139.20 |
| <b>PIO2_40</b>        | —       | L8    | N11   | R12   | 116 | 2,435.00 | 37.20  |
| <b>PIO2_41</b>        | 40      | M9    | N13   | T13   | 117 | 2,470.00 | 139.20 |
| <b>PIO2_42/CBSEL0</b> | 41      | L9    | L9    | R13   | 118 | 2,505.00 | 37.20  |
| <b>PIO2_43/CBSEL1</b> | 42      | P10   | P10   | V14   | 119 | 2,540.00 | 139.20 |
| <b>CDONE</b>          | 43      | M10   | M10   | T14   | 120 | 2,575.00 | 37.20  |

| iCE65L04<br>Pad Name    | DiePlus |       |       |       | Pad | X (μm)   | Y (μm)   |
|-------------------------|---------|-------|-------|-------|-----|----------|----------|
|                         | VQ100   | CB132 | CB196 | CB284 |     |          |          |
| <b>CRESET_B</b>         | 44      | L10   | L10   | R14   | 121 | 2,625.00 | 139.20   |
| <b>PIOS_00/SPI_SO</b>   | 45      | M11   | M11   | T15   | 122 | 2,690.00 | 37.20    |
| <b>PIOS_01/SPI_SI</b>   | 46      | P11   | P11   | V15   | 123 | 2,740.00 | 139.20   |
| <b>GND</b>              | 47      | —     | P6    | Y16   | 124 | 2,790.00 | 37.20    |
| <b>PIOS_02/SPI_SCK</b>  | 48      | P12   | P12   | V16   | 125 | 2,840.00 | 139.20   |
| <b>PIOS_03/SPI_SS_B</b> | 49      | P13   | P13   | V17   | 126 | 2,890.00 | 37.20    |
| <b>SPI_VCC</b>          | 50      | L11   | L11   | R15   | 127 | 2,990.00 | 37.20    |
| <b>TDI</b>              | N/A     | M12   | M12   | T16   | 128 | 3,610.80 | 342.00   |
| <b>TMS</b>              | N/A     | P14   | P14   | V18   | 129 | 3,712.80 | 392.00   |
| <b>TCK</b>              | N/A     | L12   | L12   | R16   | 130 | 3,610.80 | 442.00   |
| <b>TDO</b>              | N/A     | N14   | N14   | U18   | 131 | 3,712.80 | 492.00   |
| <b>TRST_B</b>           | N/A     | M14   | M14   | T18   | 132 | 3,610.80 | 542.00   |
| <b>PIO1_00</b>          | 51      | L14   | K11   | R18   | 133 | 3,712.80 | 592.00   |
| <b>PIO1_01</b>          | 52      | K12   | L13   | P16   | 134 | 3,610.80 | 642.00   |
| <b>PIO1_02</b>          | 53      | K11   | K12   | P15   | 135 | 3,712.80 | 692.00   |
| <b>PIO1_03</b>          | 54      | K14   | M13   | P18   | 136 | 3,610.80 | 727.00   |
| <b>GND</b>              | 55      | J14   | J14   | N18   | 137 | 3,712.80 | 762.00   |
| <b>GND</b>              | 55      | J14   | J14   | N18   | 138 | 3,610.80 | 797.00   |
| <b>PIO1_04</b>          | 56      | J12   | J10   | N16   | 139 | 3,712.80 | 832.00   |
| <b>PIO1_05</b>          | 57      | J11   | L14   | N15   | 140 | 3,610.80 | 867.00   |
| <b>VCCIO_1</b>          | 58      | H14   | H14   | M18   | 141 | 3,712.80 | 902.00   |
| <b>VCCIO_1</b>          | —       | —     | —     | —     | 142 | 3,610.80 | 937.00   |
| <b>PIO1_06</b>          | 59      | H12   | J11   | M16   | 143 | 3,712.80 | 972.00   |
| <b>PIO1_07</b>          | 60      | H11   | K14   | M15   | 144 | 3,610.80 | 1,007.00 |
| <b>PIO1_08</b>          | —       | —     | H10   | W20   | 145 | 3,712.80 | 1,042.00 |
| <b>PIO1_09</b>          | —       | —     | J13   | V20   | 146 | 3,610.80 | 1,077.00 |
| <b>PIO1_10</b>          | —       | —     | J12   | U20   | 147 | 3,712.80 | 1,112.00 |
| <b>VCC</b>              | 61      | H9    | N7    | M13   | 148 | 3,610.80 | 1,147.00 |
| <b>VCC</b>              | —       | —     | —     | —     | 149 | 3,712.80 | 1,182.00 |
| <b>PIO1_11</b>          | —       | —     | H13   | T22   | 150 | 3,610.80 | 1,217.00 |
| <b>PIO1_12</b>          | —       | —     | H12   | R22   | 151 | 3,712.80 | 1,252.00 |
| <b>PIO1_13</b>          | —       | —     | —     | P22   | 152 | 3,610.80 | 1,287.00 |
| <b>PIO1_14</b>          | —       | —     | —     | N22   | 153 | 3,712.80 | 1,322.00 |
| <b>PIO1_15</b>          | —       | —     | G13   | T20   | 154 | 3,610.80 | 1,357.00 |
| <b>PIO1_16</b>          | —       | —     | H11   | R20   | 155 | 3,712.80 | 1,392.00 |
| <b>PIO1_17</b>          | —       | —     | G14   | P20   | 156 | 3,610.80 | 1,427.00 |
| <b>GND</b>              | —       | —     | K10   | N20   | 157 | 3,712.80 | 1,462.00 |
| <b>GND</b>              | —       | —     | —     | —     | 158 | 3,610.80 | 1,497.00 |
| <b>PIO1_18</b>          | —       | —     | G10   | M20   | 159 | 3,712.80 | 1,532.00 |
| <b>GBIN3/PIO1_19</b>    | 62      | F14   | G12   | K18   | 160 | 3,610.80 | 1,567.00 |
| <b>GBIN2/PIO1_20</b>    | 63      | G14   | F10   | L18   | 161 | 3,712.80 | 1,602.00 |
| <b>PIO1_21</b>          | —       | —     | F14   | K20   | 162 | 3,610.80 | 1,637.00 |
| <b>VCCIO_1</b>          | —       | —     | H14   | J20   | 163 | 3,712.80 | 1,672.00 |
| <b>VCCIO_1</b>          | —       | —     | —     | —     | 164 | 3,610.80 | 1,707.00 |
| <b>PIO1_22</b>          | —       | —     | F13   | H20   | 165 | 3,712.80 | 1,742.00 |
| <b>PIO1_23</b>          | —       | —     | D13   | G20   | 166 | 3,610.80 | 1,777.00 |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| iCE65L04<br>Pad Name | DiePlus |       |       |       | Pad | X (μm)   | Y (μm)   |
|----------------------|---------|-------|-------|-------|-----|----------|----------|
|                      | VQ100   | CB132 | CB196 | CB284 |     |          |          |
| PIO1_24              | —       | —     | G11   | F20   | 167 | 3,712.80 | 1,812.00 |
| PIO1_25              | —       | —     | F11   | E20   | 168 | 3,610.80 | 1,847.00 |
| PIO1_26              | —       | —     | E10   | D20   | 169 | 3,712.80 | 1,882.00 |
| PIO1_27              | —       | —     | E14   | C20   | 170 | 3,610.80 | 1,917.00 |
| GND                  | —       | G8    | G8    | L12   | 171 | 3,712.80 | 1,952.00 |
| GND                  | —       | —     | —     | —     | 172 | 3,610.80 | 1,987.00 |
| PIO1_28              | —       | —     | F12   | G22   | 173 | 3,712.80 | 2,022.00 |
| PIO1_29              | —       | G12   | D14   | L16   | 174 | 3,610.80 | 2,057.00 |
| PIO1_30              | 64      | G11   | E13   | L15   | 175 | 3,712.80 | 2,092.00 |
| PIO1_31              | 65      | F12   | C14   | K16   | 176 | 3,610.80 | 2,127.00 |
| VCC                  | —       | —     | K13   | L20   | 177 | 3,712.80 | 2,162.00 |
| VCC                  | —       | —     | —     | —     | 178 | 3,610.80 | 2,197.00 |
| PIO1_32              | 66      | E14   | E11   | J18   | 179 | 3,712.80 | 2,232.00 |
| PIO1_33              | —       | F11   | C13   | K15   | 180 | 3,610.80 | 2,267.00 |
| VCCIO_1              | 67      | F9    | F9    | K13   | 181 | 3,712.80 | 2,302.00 |
| VCCIO_1              | —       | —     | —     | —     | 182 | 3,610.80 | 2,337.00 |
| PIO1_34              | 68      | E12   | E12   | J16   | 183 | 3,712.80 | 2,377.00 |
| PIO1_35              | 69      | D14   | B14   | H18   | 184 | 3,610.80 | 2,427.00 |
| GND                  | 70      | G9    | G9    | L13   | 185 | 3,712.80 | 2,477.00 |
| PIO1_36              | 71      | E11   | B13   | J15   | 186 | 3,610.80 | 2,527.00 |
| PIO1_37              | 72      | D12   | D12   | H16   | 187 | 3,712.80 | 2,577.00 |
| PIO1_38              | 73      | C14   | C12   | G18   | 188 | 3,610.80 | 2,627.00 |
| PIO1_39              | 74      | B14   | D11   | F18   | 189 | 3,712.80 | 2,677.00 |
| VPP_2V5              | 75      | A14   | A14   | E18   | 190 | 3,610.80 | 2,739.68 |
| VPP_FAST             | 76      | A13   | A13   | E17   | 191 | 3,097.00 | 2,962.80 |
| VCC                  | 77      | F8    | F8    | K12   | 192 | 2,997.00 | 2,860.80 |
| VCC                  | 77      | F8    | F8    | K12   | 193 | 2,947.00 | 2,962.80 |
| PIO0_00              | 78      | A12   | C11   | E16   | 194 | 2,897.00 | 2,860.80 |
| PIO0_01              | —       | C12   | —     | G16   | 195 | 2,847.00 | 2,962.80 |
| PIO0_02              | 79      | A11   | A12   | E15   | 196 | 2,797.00 | 2,860.80 |
| PIO0_03              | 80      | C11   | B11   | G15   | 197 | 2,747.00 | 2,962.80 |
| PIO0_04              | —       | D11   | —     | H15   | 198 | 2,697.00 | 2,860.80 |
| PIO0_05              | 81      | A10   | D10   | E14   | 199 | 2,647.00 | 2,962.80 |
| PIO0_06              | 82      | C10   | A11   | G14   | 200 | 2,612.00 | 2,860.80 |
| PIO0_07              | 83      | D10   | D9    | H14   | 201 | 2,577.00 | 2,962.80 |
| GND                  | 84      | A9    | H6    | E13   | 202 | 2,542.00 | 2,860.80 |
| GND                  | —       | —     | —     | —     | 203 | 2,507.00 | 2,962.80 |
| PIO0_08              | 85      | C9    | C10   | G13   | 204 | 2,472.00 | 2,860.80 |
| PIO0_09              | 86      | D9    | A10   | H13   | 205 | 2,437.00 | 2,962.80 |
| PIO0_10              | 87      | C8    | B10   | G12   | 206 | 2,402.00 | 2,860.80 |
| PIO0_11              | —       | D8    | E9    | H12   | 207 | 2,367.00 | 2,962.80 |
| PIO0_12              | —       | —     | —     | A18   | 208 | 2,332.00 | 2,860.80 |
| PIO0_13              | —       | —     | —     | A17   | 209 | 2,297.00 | 2,962.80 |
| PIO0_14              | —       | —     | —     | A16   | 210 | 2,262.00 | 2,860.80 |
| PIO0_15              | —       | —     | —     | A15   | 211 | 2,227.00 | 2,962.80 |
| VCCIO_0              | 88      | A8    | A8    | E12   | 212 | 2,192.00 | 2,860.80 |
| VCCIO_0              | —       | —     | —     | —     | 213 | 2,157.00 | 2,962.80 |

| iCE65L04<br>Pad Name | DiePlus |       |       |       | Pad | X (μm)   | Y (μm)   |
|----------------------|---------|-------|-------|-------|-----|----------|----------|
|                      | VQ100   | CB132 | CB196 | CB284 |     |          |          |
| PI00_16              | —       | —     | —     | C19   | 214 | 2,122.00 | 2,860.80 |
| PI00_17              | —       | —     | C9    | C18   | 215 | 2,087.00 | 2,962.80 |
| PI00_18              | —       | —     | B9    | C17   | 216 | 2,052.00 | 2,860.80 |
| PI00_19              | —       | —     | D8    | C16   | 217 | 2,017.00 | 2,962.80 |
| PI00_20              | —       | —     | C8    | C15   | 218 | 1,982.00 | 2,860.80 |
| PI00_21              | —       | —     | E8    | C14   | 219 | 1,947.00 | 2,962.80 |
| PI00_22              | —       | —     | B8    | C13   | 220 | 1,912.00 | 2,860.80 |
| GBIN1/PI00_23        | 89      | A7    | E7    | E11   | 221 | 1,877.00 | 2,962.80 |
| GND                  | —       | —     | B12   | C12   | 222 | 1,842.00 | 2,860.80 |
| GND                  | —       | —     | —     | —     | 223 | 1,807.00 | 2,962.80 |
| GBIN0/PI00_24        | 90      | A6    | A7    | E10   | 224 | 1,772.00 | 2,860.80 |
| PI00_25              | —       | —     | D7    | C11   | 225 | 1,737.00 | 2,962.80 |
| PI00_26              | —       | —     | C7    | C10   | 226 | 1,702.00 | 2,860.80 |
| PI00_27              | —       | —     | E6    | C9    | 227 | 1,667.00 | 2,962.80 |
| VCC                  | —       | —     | B7    | C8    | 228 | 1,632.00 | 2,860.80 |
| VCC                  | —       | —     | —     | —     | 229 | 1,597.00 | 2,962.80 |
| PI00_28              | —       | —     | A6    | C7    | 230 | 1,562.00 | 2,860.80 |
| PI00_29              | —       | —     | B6    | C6    | 231 | 1,527.00 | 2,962.80 |
| PI00_30              | —       | —     | A5    | C5    | 232 | 1,492.00 | 2,860.80 |
| PI00_31              | —       | —     | D6    | C4    | 233 | 1,457.00 | 2,962.80 |
| GND                  | —       | F7    | F7    | K11   | 234 | 1,422.00 | 2,860.80 |
| GND                  | —       | —     | —     | —     | 235 | 1,387.00 | 2,962.80 |
| PI00_32              | —       | —     | —     | C3    | 236 | 1,352.00 | 2,860.80 |
| PI00_33              | —       | —     | —     | A7    | 237 | 1,317.00 | 2,962.80 |
| PI00_34              | —       | —     | —     | A6    | 238 | 1,282.00 | 2,860.80 |
| PI00_35              | —       | —     | —     | A5    | 239 | 1,247.00 | 2,962.80 |
| PI00_36              | 91      | C7    | C6    | G11   | 240 | 1,212.00 | 2,860.80 |
| VCCIO_0              | 92      | F6    | F6    | K10   | 241 | 1,177.00 | 2,962.80 |
| VCCIO_0              | 92      | F6    | F6    | K10   | 242 | 1,142.00 | 2,860.80 |
| PI00_37              | 93      | D7    | C5    | H11   | 243 | 1,107.00 | 2,962.80 |
| PI00_38              | 94      | C6    | B5    | G10   | 244 | 1,072.00 | 2,860.80 |
| PI00_39              | 95      | A5    | A4    | E9    | 245 | 1,037.00 | 2,962.80 |
| PI00_40              | 96      | D6    | B4    | H10   | 246 | 1,002.00 | 2,860.80 |
| PI00_41              | 97      | C5    | D5    | G9    | 247 | 967.00   | 2,962.80 |
| PI00_42              | —       | A4    | A3    | E8    | 248 | 917.00   | 2,860.80 |
| GND                  | 98      | G7    | G7    | L11   | 249 | 867.00   | 2,962.80 |
| PI00_43              | 99      | D5    | B3    | H9    | 250 | 817.00   | 2,860.80 |
| PI00_44              | —       | C4    | C4    | G8    | 251 | 767.00   | 2,962.80 |
| PI00_45              | 100     | A3    | A2    | E7    | 252 | 717.00   | 2,860.80 |
| PI00_46              | —       | A2    | A1    | E6    | 253 | 667.00   | 2,962.80 |
| PI00_47              | —       | A1    | B2    | E5    | 254 | 617.00   | 2,860.80 |

## iCE65L08

Table 46 lists all the pads on the iCE65L08 die and how these pads connect to the balls or pins in the supported package styles. Most VCC, VCCIO, and GND pads are double-bonded inside the package although the table shows only a single connection.

For additional information on the iCE65L08 DiePlus product, please refer to the following data sheet.

### ■ DiePlusAdvantage FPGA Known Good Die

**Table 46: iCE65L08 Die Cross Reference**

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |         |           |
|----------------------|--------------------|-------|---------|---------|-----------|
|                      | CB196              | CB284 | Pad     | X (μm)  | Y (μm)    |
| PIO3_00/DP00A        | —                  | B1    | 1       | 129.735 | 3,882.665 |
| PIO3_01/DP00B        | —                  | C1    | 2       | 231.735 | 3,837.665 |
| PIO3_02/DP01A        | C1                 | F5    | 3       | 129.735 | 3,792.665 |
| PIO3_03/DP01B        | B1                 | G5    | 4       | 231.735 | 3,747.665 |
| GND                  | C2                 | K5    | 5       | 129.735 | 3,702.665 |
| GND                  | —                  | —     | 6       | 231.735 | 3,657.665 |
| VCCIO_3              | E3                 | J7    | 7       | 129.735 | 3,612.665 |
| VCCIO_3              | —                  | —     | 8       | 231.735 | 3,567.665 |
| PIO3_04/DP02A        | D3                 | E3    | 9       | 129.735 | 3,512.665 |
| PIO3_05/DP02B        | C3                 | F3    | 10      | 231.735 | 3,477.665 |
| PIO3_06/DP03A        | D1                 | G3    | 11      | 129.735 | 3,442.665 |
| PIO3_07/DP03B        | D2                 | H3    | 12      | 231.735 | 3,407.665 |
| VCC                  | F2                 | D3    | 13      | 129.735 | 3,372.665 |
| VCC                  | —                  | —     | 14      | 231.735 | 3,337.665 |
| PIO3_08/DP04A        | D4                 | D1    | 15      | 129.735 | 3,302.665 |
| PIO3_09/DP04B        | E4                 | E1    | 16      | 231.735 | 3,267.665 |
| PIO3_10/DP05A        | —                  | H1    | 17      | 129.735 | 3,232.665 |
| PIO3_11/DP05B        | —                  | J1    | 18      | 231.735 | 3,197.665 |
| GND                  | F1                 | M10   | 19      | 129.735 | 3,162.665 |
| GND                  | —                  | —     | 20      | 231.735 | 3,127.665 |
| PIO3_12/DP06A        | E2                 | H5    | 21      | 129.735 | 3,092.665 |
| PIO3_13/DP06B        | E1                 | J5    | 22      | 231.735 | 3,057.665 |
| GND                  | L3                 | J3    | 23      | 129.735 | 3,022.665 |
| GND                  | —                  | —     | 24      | 231.735 | 2,987.665 |
| PIO3_14/DP07A        | F5                 | K1    | 25      | 129.735 | 2,952.665 |
| PIO3_15/DP07B        | E5                 | L1    | 26      | 231.735 | 2,917.665 |
| VCCIO_3              | E3                 | K3    | 27      | 129.735 | 2,882.665 |
| VCCIO_3              | —                  | —     | 28      | 231.735 | 2,847.665 |
| VCC                  | G6                 | L10   | 29      | 129.735 | 2,812.665 |
| VCC                  | —                  | —     | 30      | 231.735 | 2,777.665 |
| PIO3_16/DP08A        | F4                 | G7    | 31      | 129.735 | 2,742.665 |
| PIO3_17/DP08B        | F3                 | H7    | 32      | 231.735 | 2,707.665 |
| VCCIO_3              | K1                 | F1    | 33      | 129.735 | 2,672.665 |
| VCCIO_3              | —                  | —     | 34      | 231.735 | 2,637.665 |
| GND                  | —                  | G1    | 35      | 129.735 | 2,602.665 |
| GND                  | —                  | —     | 36      | 231.735 | 2,567.665 |
| PIO3_18/DP09A        | G3                 | K8    | 37      | 129.735 | 2,532.665 |
| PIO3_19/DP09B        | G4                 | K7    | 38      | 231.735 | 2,497.665 |

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |         |           |
|----------------------|--------------------|-------|---------|---------|-----------|
|                      | CB196              | CB284 | Pad     | X (μm)  | Y (μm)    |
| PIO3_20/DP10A        | —                  | H8    | 39      | 129.735 | 2,462.665 |
| PIO3_21/DP10B        | —                  | J8    | 40      | 231.735 | 2,427.665 |
| PIO3_22/DP11A        | G1                 | T1    | 41      | 129.735 | 2,392.665 |
| PIO3_23/DP11B        | G2                 | U1    | 42      | 231.735 | 2,357.665 |
| VCCIO_3              | K1                 | N10   | 43      | 129.735 | 2,322.665 |
| VCCIO_3              | —                  | —     | 44      | 231.735 | 2,287.665 |
| VREF                 | N/A                | M1    | 45      | 129.735 | 2,252.665 |
| VREF                 | N/A                | —     | 46      | 231.735 | 2,217.665 |
| GND                  | J5                 | N1    | 47      | 129.735 | 2,182.665 |
| GND                  | —                  | —     | 48      | 231.735 | 2,147.665 |
| VCCIO_3              | J6                 | P1    | 49      | 129.735 | 2,112.665 |
| VCCIO_3              | —                  | —     | 50      | 231.735 | 2,077.665 |
| GND                  | H6                 | R1    | 51      | 129.735 | 2,042.665 |
| GND                  | —                  | —     | 52      | 231.735 | 2,007.665 |
| PIO3_24/DP12A        | H4                 | L3    | 53      | 129.735 | 1,972.665 |
| GBIN7/PIO3_25/DP12B  | H3                 | L5    | 54      | 231.735 | 1,937.665 |
| GND                  | H7                 | V1    | 55      | 129.735 | 1,902.665 |
| GBIN6/PIO3_26/DP13A  | H1                 | M5    | 56      | 231.735 | 1,867.665 |
| PIO3_27/DP13B        | H2                 | M3    | 57      | 129.735 | 1,832.665 |
| PIO3_28/DP14A        | —                  | N7    | 58      | 231.735 | 1,798.665 |
| PIO3_29/DP14B        | —                  | N5    | 59      | 129.735 | 1,762.665 |
| PIO3_30/DP15A        | J1                 | N3    | 60      | 231.735 | 1,727.665 |
| PIO3_31/DP15B        | J2                 | P3    | 61      | 129.735 | 1,692.665 |
| GND                  | J5                 | M11   | 62      | 231.735 | 1,657.665 |
| GND                  | —                  | —     | 63      | 129.735 | 1,622.665 |
| PIO3_32/DP16A        | H5                 | W1    | 64      | 231.735 | 1,587.665 |
| PIO3_33/DP16B        | G5                 | Y1    | 65      | 129.735 | 1,552.665 |
| VCCIO_3              | J6                 | R3    | 66      | 231.735 | 1,517.665 |
| VCCIO_3              | —                  | —     | 67      | 129.735 | 1,482.665 |
| GND                  | J5                 | T3    | 68      | 231.735 | 1,447.665 |
| GND                  | —                  | —     | 69      | 129.735 | 1,412.665 |
| PIO3_34/DP17A        | K2                 | AA1   | 70      | 231.735 | 1,377.665 |
| PIO3_35/DP17B        | J3                 | AB1   | 71      | 129.735 | 1,342.665 |
| PIO3_36/DP18A        | —                  | L7    | 72      | 231.735 | 1,307.665 |
| PIO3_37/DP18B        | —                  | L8    | 73      | 129.735 | 1,272.665 |
| PIO3_38/DP19A        | —                  | M7    | 74      | 231.735 | 1,237.665 |
| PIO3_39/DP19B        | —                  | M8    | 75      | 129.735 | 1,202.665 |
| PIO3_40/DP20A        | L1                 | P7    | 76      | 231.735 | 1,167.665 |
| PIO3_41/DP20B        | L2                 | P8    | 77      | 129.735 | 1,132.665 |
| VCC                  | J4                 | N8    | 78      | 231.735 | 1,097.665 |
| VCC                  | —                  | —     | 79      | 129.735 | 1,062.665 |
| PIO3_42/DP21A        | K4                 | R5    | 80      | 231.735 | 1,027.665 |
| PIO3_43/DP21B        | K3                 | T5    | 81      | 129.735 | 992.665   |
| VCCIO_3              | K1                 | P5    | 82      | 231.735 | 957.665   |
| VCCIO_3              | —                  | —     | 83      | 129.735 | 912.665   |
| GND                  | L3                 | R7    | 84      | 231.735 | 867.665   |
| GND                  | —                  | —     | 85      | 129.735 | 822.67    |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |         |         |
|----------------------|--------------------|-------|---------|---------|---------|
|                      | CB196              | CB284 | Pad     | X (μm)  | Y (μm)  |
| PIO3_44/DP22A        | M1                 | U3    | 86      | 231.735 | 777.67  |
| PIO3_45/DP22B        | M2                 | V3    | 87      | 129.735 | 732.67  |
| PIO3_46/DP23A        | N1                 | U5    | 88      | 231.735 | 687.67  |
| PIO3_47/DP23B        | N2                 | V5    | 89      | 129.735 | 642.67  |
| PIO3_48/DP24A        | —                  | W3    | 90      | 231.735 | 597.67  |
| PIO3_49/DP24B        | —                  | Y3    | 91      | 129.735 | 552.665 |
| PIO2_00              | P1                 | AB2   | 92      | 510.0   | 139.5   |
| PIO2_01              | M3                 | R8    | 93      | 560.0   | 37.5    |
| PIO2_02              | P2                 | Y4    | 94      | 610.0   | 139.5   |
| GND                  | P6                 | AB5   | 95      | 660.0   | 37.5    |
| GND                  | —                  | —     | 96      | 710.0   | 139.5   |
| PIO2_03              | M4                 | T7    | 97      | 760.0   | 37.5    |
| PIO2_04              | N3                 | AB3   | 98      | 810.0   | 139.5   |
| PIO2_05              | —                  | R9    | 99      | 859.3   | 37.5    |
| PIO2_06              | —                  | Y5    | 100     | 910.0   | 139.5   |
| PIO2_07              | L4                 | T8    | 101     | 960.0   | 37.5    |
| PIO2_08              | P3                 | V6    | 102     | 1,012.5 | 139.5   |
| VCCIO_2              | M5                 | T9    | 103     | 1,047.5 | 37.5    |
| VCCIO_2              | —                  | —     | 104     | 1,082.5 | 139.5   |
| PIO2_09              | P4                 | R10   | 105     | 1,117.5 | 37.5    |
| PIO2_10              | N4                 | AB4   | 106     | 1,152.5 | 139.5   |
| GND                  | H8                 | V10   | 107     | 1,187.5 | 37.5    |
| GND                  | —                  | —     | 108     | 1,222.5 | 139.5   |
| PIO2_11              | K5                 | V7    | 109     | 1,257.5 | 37.5    |
| PIO2_12              | P5                 | Y7    | 110     | 1,292.5 | 139.5   |
| PIO2_13              | —                  | V9    | 111     | 1,327.5 | 37.5    |
| PIO2_14              | —                  | Y6    | 112     | 1,362.5 | 139.5   |
| PIO2_15              | —                  | AB7   | 113     | 1,397.5 | 37.5    |
| PIO2_16              | —                  | AB6   | 114     | 1,432.5 | 139.5   |
| PIO2_17              | L5                 | Y9    | 115     | 1,467.5 | 37.5    |
| PIO2_18              | N5                 | V8    | 116     | 1,502.3 | 139.5   |
| GND                  | P6                 | N12   | 117     | 1,537.3 | 37.5    |
| GND                  | —                  | —     | 118     | 1,572.5 | 139.5   |
| PIO2_19              | N6                 | AB8   | 119     | 1,607.5 | 37.5    |
| PIO2_20              | K6                 | AB9   | 120     | 1,642.5 | 139.5   |
| VCC                  | J7                 | Y8    | 121     | 1,677.5 | 37.5    |
| VCC                  | —                  | —     | 122     | 1,712.5 | 139.5   |
| PIO2_21              | L6                 | T10   | 123     | 1,747.5 | 37.5    |
| PIO2_22              | M6                 | AB10  | 124     | 1,782.5 | 139.5   |
| PIO2_23              | —                  | AB11  | 125     | 1,817.5 | 37.5    |
| PIO2_24              | —                  | AB12  | 126     | 1,852.5 | 139.5   |
| PIO2_25              | L7                 | Y10   | 127     | 1,887.5 | 37.5    |
| PIO2_26              | P7                 | AB13  | 128     | 1,922.5 | 139.5   |
| PIO2_27              | K7                 | AB14  | 129     | 1,957.5 | 37.5    |
| VCCIO_2              | N10                | Y11   | 130     | 1,992.5 | 139.5   |
| VCCIO_2              | —                  | —     | 131     | 2,027.5 | 37.5    |

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |         |        |
|----------------------|--------------------|-------|---------|---------|--------|
|                      | CB196              | CB284 | Pad     | X (μm)  | Y (μm) |
| PIO2_28              | —                  | Y13   | 132     | 2,062.5 | 139.5  |
| GBIN5/PIO2_29        | M7                 | V11   | 133     | 2,097.5 | 37.5   |
| GBIN4/PIO2_30        | N8                 | V12   | 134     | 2,132.5 | 139.5  |
| GND                  | J8                 | Y12   | 135     | 2,167.5 | 37.5   |
| GND                  | —                  | —     | 136     | 2,202.5 | 139.5  |
| PIO2_31              | P8                 | Y14   | 137     | 2,237.5 | 37.5   |
| PIO2_32              | —                  | AB15  | 138     | 2,272.5 | 139.5  |
| PIO2_33              | M8                 | V13   | 139     | 2,307.5 | 37.5   |
| PIO2_34              | —                  | AB16  | 140     | 2,342.5 | 139.5  |
| PIO2_35              | L8                 | Y15   | 141     | 2,377.5 | 37.5   |
| PIO2_36              | —                  | AB17  | 142     | 2,412.5 | 139.5  |
| PIO2_37              | N9                 | AB18  | 143     | 2,447.5 | 37.5   |
| PIO2_38              | —                  | AB19  | 144     | 2,482.5 | 139.5  |
| PIO2_39              | —                  | AB20  | 145     | 2,517.5 | 37.5   |
| PIO2_40              | —                  | AB21  | 146     | 2,552.5 | 139.5  |
| PIO2_41              | —                  | Y17   | 147     | 2,587.5 | 37.5   |
| PIO2_42              | —                  | AB22  | 148     | 2,622.5 | 139.5  |
| PIO2_43              | —                  | Y18   | 149     | 2,657.5 | 37.5   |
| PIO2_44              | P9                 | Y19   | 150     | 2,692.5 | 139.5  |
| VCC                  | N7                 | N11   | 151     | 2,727.5 | 37.5   |
| VCC                  | —                  | —     | 152     | 2,762.5 | 139.5  |
| PIO2_45              | M9                 | Y20   | 153     | 2,797.5 | 37.5   |
| PIO2_46              | K8                 | T11   | 154     | 2,832.5 | 139.5  |
| VCCIO_2              | J9                 | N13   | 155     | 2,867.5 | 37.5   |
| VCCIO_2              | —                  | —     | 156     | 2,902.5 | 139.5  |
| PIO2_47              | N11                | R11   | 157     | 2,937.5 | 37.5   |
| GND                  | J8                 | M12   | 158     | 2,972.5 | 139.5  |
| GND                  | —                  | —     | 159     | 3,007.5 | 37.5   |
| PIO2_48              | N12                | T12   | 160     | 3,042.5 | 139.5  |
| PIO2_49              | K9                 | R12   | 161     | 3,077.5 | 37.5   |
| PIO2_50              | N13                | T13   | 162     | 3,112.5 | 139.5  |
| PIO2_51/CBSEL0       | L9                 | R13   | 163     | 3,147.5 | 37.5   |
| PIO2_52/CBSEL1       | P10                | V14   | 164     | 3,182.5 | 139.5  |
| CDONE                | M10                | T14   | 165     | 3,217.5 | 37.5   |
| CRESET_B             | L10                | R14   | 166     | 3,260.0 | 139.5  |
| PIOS_00/SPI_SO       | M11                | T15   | 167     | 3,320.0 | 37.5   |
| PIOS_01/SPI_SI       | P11                | V15   | 168     | 3,370.0 | 139.5  |
| GND                  | J8                 | Y16   | 169     | 3,420.0 | 37.5   |
| GND                  | —                  | —     | 170     | 3,470.0 | 139.5  |
| PIOS_02/SPI_SCK      | P12                | V16   | 171     | 3,520.0 | 37.5   |
| PIOS_03/SPI_SS_B     | P13                | V17   | 172     | 3,570.0 | 139.5  |
| VCC                  | —                  | —     | 173     | 3,620.0 | 37.5   |
| VCC                  | —                  | —     | 174     | 3,670.0 | 139.5  |
| SPI_VCC              | L11                | R15   | 175     | 3,720.0 | 37.5   |
| SPI_VCC              | —                  | —     | 176     | 3,770.0 | 139.5  |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |         |           |
|----------------------|--------------------|-------|---------|---------|-----------|
|                      | CB196              | CB284 | Pad     | X (μm)  | Y (μm)    |
| <b>TDI</b>           | M12                | T16   | 177     | 4,470.5 | 634.615   |
| <b>TMS</b>           | P14                | V18   | 178     | 4,572.5 | 684.615   |
| <b>TCK</b>           | L12                | R16   | 179     | 4,470.5 | 734.615   |
| <b>TDO</b>           | N14                | U18   | 180     | 4,572.5 | 784.615   |
| <b>TRST_B</b>        | M14                | T18   | 181     | 4,470.5 | 834.615   |
| <b>PIO1_00</b>       | M13                | R18   | 182     | 4,572.5 | 884.615   |
| <b>PIO1_01</b>       | K11                | P16   | 183     | 4,470.5 | 934.615   |
| <b>PIO1_02</b>       | L13                | P15   | 184     | 4,572.5 | 984.615   |
| <b>PIO1_03</b>       | L14                | P18   | 185     | 4,470.5 | 1,034.615 |
| <b>GND</b>           | G9                 | N18   | 186     | 4,572.5 | 1,084.615 |
| <b>GND</b>           | —                  | —     | 187     | 4,470.5 | 1,134.615 |
| <b>PIO1_04</b>       | J11                | N16   | 188     | 4,572.5 | 1,184.615 |
| <b>PIO1_05</b>       | K12                | N15   | 189     | 4,470.5 | 1,234.62  |
| <b>VCCIO_1</b>       | F9                 | M18   | 190     | 4,572.5 | 1,287.115 |
| <b>VCCIO_1</b>       | —                  | —     | 191     | 4,470.5 | 1,322.115 |
| <b>PIO1_06</b>       | J12                | M15   | 192     | 4,572.5 | 1,357.115 |
| <b>PIO1_07</b>       | K14                | M16   | 193     | 4,470.5 | 1,392.115 |
| <b>PIO1_08</b>       | —                  | T20   | 194     | 4,572.5 | 1,427.115 |
| <b>PIO1_09</b>       | —                  | W20   | 195     | 4,470.5 | 1,462.115 |
| <b>PIO1_10</b>       | —                  | V20   | 196     | 4,572.5 | 1,497.115 |
| <b>VCC</b>           | H9                 | M13   | 197     | 4,470.5 | 1,532.115 |
| <b>VCC</b>           | —                  | —     | 198     | 4,572.5 | 1,567.115 |
| <b>PIO1_11</b>       | —                  | R20   | 199     | 4,470.5 | 1,602.115 |
| <b>PIO1_12</b>       | —                  | Y22   | 200     | 4,572.5 | 1,637.115 |
| <b>PIO1_13</b>       | —                  | AA22  | 201     | 4,470.5 | 1,672.115 |
| <b>PIO1_14</b>       | —                  | U20   | 202     | 4,572.5 | 1,707.115 |
| <b>PIO1_15</b>       | J13                | W22   | 203     | 4,470.5 | 1,742.115 |
| <b>PIO1_16</b>       | H11                | P20   | 204     | 4,572.5 | 1,777.115 |
| <b>PIO1_17</b>       | J10                | V22   | 205     | 4,470.5 | 1,812.115 |
| <b>PIO1_18</b>       | H12                | U22   | 206     | 4,572.5 | 1,847.115 |
| <b>GND</b>           | K10                | N20   | 207     | 4,470.5 | 1,882.115 |
| <b>GND</b>           | —                  | —     | 208     | 4,572.5 | 1,917.110 |
| <b>PIO1_19</b>       | H13                | T22   | 209     | 4,470.5 | 1,952.115 |
| <b>PIO1_20</b>       | —                  | M20   | 210     | 4,572.5 | 1,987.115 |
| <b>PIO1_21</b>       | H10                | R22   | 211     | 4,470.5 | 2,022.115 |
| <b>PIO1_22</b>       | —                  | P22   | 212     | 4,572.5 | 2,057.115 |
| <b>VCCIO_1</b>       | F9                 | J20   | 213     | 4,470.5 | 2,092.115 |
| <b>VCCIO_1</b>       | —                  | —     | 214     | 4,572.5 | 2,127.115 |
| <b>PIO1_23</b>       | G10                | M22   | 215     | 4,470.5 | 2,162.115 |
| <b>PIO1_24</b>       | G11                | N22   | 216     | 4,572.5 | 2,197.115 |
| <b>PIO1_25</b>       | —                  | K22   | 217     | 4,470.5 | 2,232.115 |
| <b>PIO1_26</b>       | —                  | L22   | 218     | 4,572.5 | 2,267.115 |
| <b>GBIN3/PIO1_27</b> | G12                | K18   | 219     | 4,470.5 | 2,302.11  |
| <b>GBIN2/PIO1_28</b> | F10                | L18   | 220     | 4,572.5 | 2,337.115 |
| <b>PIO1_29</b>       | —                  | J22   | 221     | 4,470.5 | 2,372.115 |

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |           |           |
|----------------------|--------------------|-------|---------|-----------|-----------|
|                      | CB196              | CB284 | Pad     | X (μm)    | Y (μm)    |
| PIO1_30              | —                  | K20   | 222     | 4,572.5   | 2,407.115 |
| PIO1_31              | G14                | F22   | 223     | 4,470.5   | 2,442.115 |
| PIO1_32              | —                  | G22   | 224     | 4,572.5   | 2,477.115 |
| PIO1_33              | F11                | E22   | 225     | 4,470.5   | 2,512.115 |
| PIO1_34              | F12                | L16   | 226     | 4,572.5   | 2,547.115 |
| PIO1_35              | G13                | D22   | 227     | 4,470.5   | 2,582.115 |
| GND                  | G8                 | L12   | 228     | 4,572.5   | 2,617.115 |
| GND                  | —                  | —     | 229     | 4,470.5   | 2,652.115 |
| PIO1_36              | E10                | K16   | 230     | 4,572.5   | 2,687.12  |
| VCCIO_1              | H14                | H22   | 231     | 4,470.5   | 2,722.12  |
| VCCIO_1              | —                  | —     | 232     | 4,572.5   | 2,757.12  |
| PIO1_37              | F14                | H20   | 233     | 4,470.5   | 2,792.12  |
| PIO1_38              | E11                | J18   | 234     | 4,572.5   | 2,827.12  |
| PIO1_39              | D12                | C22   | 235     | 4,470.5   | 2,862.12  |
| PIO1_40              | F13                | J16   | 236     | 4,572.5   | 2,897.12  |
| PIO1_41              | E13                | B22   | 237     | 4,470.5   | 2,932.12  |
| PIO1_42              | E12                | H18   | 238     | 4,572.5   | 2,967.12  |
| PIO1_43              | E14                | G20   | 239     | 4,470.5   | 3,002.12  |
| PIO1_44              | —                  | L15   | 240     | 4,572.5   | 3,037.12  |
| PIO1_45              | —                  | A22   | 241     | 4,470.5   | 3,072.12  |
| PIO1_46              | —                  | H16   | 242     | 4,572.5   | 3,107.12  |
| VCC                  | K13                | L20   | 243     | 4,470.5   | 3,142.12  |
| VCC                  | —                  | —     | 244     | 4,572.5   | 3,177.12  |
| PIO1_47              | D14                | F20   | 245     | 4,470.5   | 3,229.615 |
| PIO1_48              | D11                | K15   | 246     | 4,572.5   | 3,279.615 |
| VCCIO_1              | H14                | K13   | 247     | 4,470.5   | 3,329.615 |
| VCCIO_1              | —                  | —     | 248     | 4,572.5   | 3,379.615 |
| PIO1_49              | C14                | E20   | 249     | 4,470.5   | 3,429.62  |
| PIO1_50              | D13                | J15   | 250     | 4,572.5   | 3,479.615 |
| GND                  | J14                | L13   | 251     | 4,470.5   | 3,529.615 |
| GND                  | —                  | —     | 252     | 4,572.5   | 3,579.615 |
| PIO1_51              | B14                | D20   | 253     | 4,470.5   | 3,629.615 |
| PIO1_52              | C13                | G18   | 254     | 4,572.5   | 3,679.595 |
| PIO1_53              | B13                | C20   | 255     | 4,470.5   | 3,729.595 |
| PIO1_54              | C12                | F18   | 256     | 4,572.5   | 3,779.595 |
| VPP_2V5              | A14                | E18   | 257     | 4,470.5   | 3,879.575 |
| VPP_FAST             | A13                | E17   | 258     | 3,866.975 | 4,054.5   |
| VCC                  | F8                 | K12   | 259     | 3,766.98  | 4,156.5   |
| VCC                  | —                  | —     | 260     | 3,716.98  | 4,054.5   |
| PIO0_00              | —                  | G16   | 261     | 3,666.98  | 4,156.5   |
| PIO0_01              | —                  | C19   | 262     | 3,616.98  | 4,054.5   |
| PIO0_02              | C11                | H15   | 263     | 3,566.98  | 4,156.5   |
| PIO0_03              | —                  | C18   | 264     | 3,516.98  | 4,054.5   |
| PIO0_04              | A12                | H14   | 265     | 3,466.98  | 4,156.5   |
| VCCIO_0              | F6                 | A21   | 266     | 3,416.98  | 4,054.5   |
| PIO0_05              | B11                | C17   | 267     | 3,366.98  | 4,156.5   |
| PIO0_06              | D10                | E16   | 268     | 3,316.98  | 4,054.5   |
| PIO0_07              | A11                | G15   | 269     | 3,266.98  | 4,156.5   |

# iCE65 Ultra Low-Power mobileFPGA™ Family

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |          |         |
|----------------------|--------------------|-------|---------|----------|---------|
|                      | CB196              | CB284 | Pad     | X (μm)   | Y (μm)  |
| <b>GND</b>           | F7                 | E13   | 270     | 3,216.98 | 4,054.5 |
| <b>GND</b>           | —                  | —     | 271     | 3,166.98 | 4,156.5 |
| <b>PIO0_08</b>       | D9                 | E15   | 272     | 3,116.98 | 4,054.5 |
| <b>PIO0_09</b>       | C10                | G14   | 273     | 3,064.48 | 4,156.5 |
| <b>PIO0_10</b>       | A10                | A20   | 274     | 3,029.48 | 4,054.5 |
| <b>PIO0_11</b>       | B10                | H13   | 275     | 2,994.48 | 4,156.5 |
| <b>PIO0_12</b>       | —                  | A19   | 276     | 2,959.48 | 4,054.5 |
| <b>PIO0_13</b>       | E9                 | G13   | 277     | 2,924.48 | 4,156.5 |
| <b>PIO0_14</b>       | —                  | C16   | 278     | 2,889.48 | 4,054.5 |
| <b>PIO0_15</b>       | —                  | E14   | 279     | 2,854.48 | 4,156.5 |
| <b>VCCIO_0</b>       | F6                 | E12   | 280     | 2,819.48 | 4,054.5 |
| <b>VCCIO_0</b>       | —                  | —     | 281     | 2,784.48 | 4,156.5 |
| <b>PIO0_16</b>       | —                  | A18   | 282     | 2,749.48 | 4,054.5 |
| <b>PIO0_17</b>       | —                  | A17   | 283     | 2,714.48 | 4,156.5 |
| <b>PIO0_18</b>       | C9                 | C15   | 284     | 2,679.48 | 4,054.5 |
| <b>PIO0_19</b>       | —                  | A16   | 285     | 2,644.48 | 4,156.5 |
| <b>PIO0_20</b>       | B9                 | C14   | 286     | 2,609.48 | 4,054.5 |
| <b>PIO0_21</b>       | —                  | H12   | 287     | 2,574.48 | 4,156.5 |
| <b>PIO0_22</b>       | D8                 | A15   | 288     | 2,539.48 | 4,054.5 |
| <b>PIO0_23</b>       | C8                 | H11   | 289     | 2,504.48 | 4,156.5 |
| <b>PIO0_24</b>       | E8                 | C13   | 290     | 2,469.48 | 4,054.5 |
| <b>PIO0_25</b>       | —                  | A14   | 291     | 2,434.48 | 4,156.5 |
| <b>GND</b>           | B12                | C12   | 292     | 2,399.48 | 4,054.5 |
| <b>GND</b>           | —                  | —     | 293     | 2,364.48 | 4,156.5 |
| <b>PIO0_26</b>       | B8                 | A13   | 294     | 2,329.48 | 4,054.5 |
| <b>PIO0_27</b>       | D7                 | A12   | 295     | 2,294.48 | 4,156.5 |
| <b>PIO0_28</b>       | —                  | C11   | 296     | 2,259.48 | 4,054.5 |
| <b>GBIN1/PIO0_29</b> | E7                 | E11   | 297     | 2,224.48 | 4,156.5 |
| <b>GBIN0/PIO0_30</b> | A7                 | E10   | 298     | 2,189.48 | 4,054.5 |
| <b>PIO0_31</b>       | —                  | G12   | 299     | 2,154.48 | 4,156.5 |
| <b>VCCIO_0</b>       | A8                 | A8    | 300     | 2,119.48 | 4,054.5 |
| <b>VCCIO_0</b>       | —                  | —     | 301     | 2,084.48 | 4,156.5 |
| <b>PIO0_32</b>       | C7                 | A11   | 302     | 2,049.48 | 4,054.5 |
| <b>PIO0_33</b>       | —                  | G11   | 303     | 2,014.48 | 4,156.5 |
| <b>PIO0_34</b>       | E6                 | A10   | 304     | 1,979.48 | 4,054.5 |
| <b>PIO0_35</b>       | —                  | C10   | 305     | 1,944.48 | 4,156.5 |
| <b>VCC</b>           | B7                 | C8    | 306     | 1,909.48 | 4,054.5 |
| <b>VCC</b>           | —                  | —     | 307     | 1,874.48 | 4,156.5 |
| <b>PIO0_36</b>       | —                  | A9    | 308     | 1,839.48 | 4,054.5 |
| <b>PIO0_37</b>       | A6                 | A7    | 309     | 1,804.48 | 4,156.5 |
| <b>PIO0_38</b>       | B6                 | C9    | 310     | 1,769.48 | 4,054.5 |
| <b>PIO0_39</b>       | A5                 | A6    | 311     | 1,734.48 | 4,156.5 |
| <b>GND</b>           | G7                 | K11   | 312     | 1,699.48 | 4,054.5 |
| <b>GND</b>           | —                  | —     | 313     | 1,664.48 | 4,156.5 |
| <b>PIO0_40</b>       | D6                 | E9    | 314     | 1,629.48 | 4,054.5 |
| <b>PIO0_41</b>       | C6                 | G10   | 315     | 1,594.48 | 4,156.5 |

| iCE65L08<br>Pad Name | Available Packages |       | DiePlus |          |         |
|----------------------|--------------------|-------|---------|----------|---------|
|                      | CB196              | CB284 | Pad     | X (μm)   | Y (μm)  |
| <b>PI00_42</b>       | C5                 | A5    | 316     | 1,559.48 | 4,054.5 |
| <b>PI00_43</b>       | B5                 | G9    | 317     | 1,524.48 | 4,156.5 |
| <b>PI00_44</b>       | A4                 | A3    | 318     | 1,489.48 | 4,054.5 |
| <b>PI00_45</b>       | —                  | A4    | 319     | 1,454.48 | 4,156.5 |
| <b>PI00_46</b>       | —                  | A2    | 320     | 1,419.48 | 4,054.5 |
| <b>PI00_47</b>       | —                  | C7    | 321     | 1,384.48 | 4,156.5 |
| <b>PI00_48</b>       | —                  | C6    | 322     | 1,331.98 | 4,054.5 |
| <b>VCCIO_0</b>       | A8                 | K10   | 323     | 1,281.98 | 4,156.5 |
| <b>VCCIO_0</b>       | —                  | —     | 324     | 1,231.98 | 4,054.5 |
| <b>PI00_49</b>       | —                  | E8    | 325     | 1,181.98 | 4,156.5 |
| <b>PI00_50</b>       | B4                 | A1    | 326     | 1,131.98 | 4,054.5 |
| <b>PI00_51</b>       | C4                 | E7    | 327     | 1,081.98 | 4,156.5 |
| <b>PI00_52</b>       | A3                 | C5    | 328     | 1,031.98 | 4,054.5 |
| <b>PI00_53</b>       | B3                 | E6    | 329     | 981.98   | 4,156.5 |
| <b>PI00_54</b>       | D5                 | C3    | 330     | 931.98   | 4,054.5 |
| <b>GND</b>           | A9                 | L11   | 331     | 881.98   | 4,156.5 |
| <b>GND</b>           | —                  | —     | 332     | 831.98   | 4,054.5 |
| <b>PI00_55</b>       | B2                 | G8    | 333     | 781.98   | 4,156.5 |
| <b>PI00_56</b>       | A2                 | C4    | 334     | 731.98   | 4,054.5 |
| <b>PI00_57</b>       | A1                 | H10   | 335     | 681.98   | 4,156.5 |
| <b>PI00_58</b>       | —                  | E5    | 336     | 631.98   | 4,054.5 |
| <b>PI00_59</b>       | —                  | H9    | 337     | 581.98   | 4,156.5 |

## Electrical Characteristics

All parameter limits are specified under worst-case supply voltage, temperature, and processing conditions.

### Absolute Maximum Ratings

Stresses beyond those listed under Table 47 may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions is not implied. Exposure to absolute maximum conditions for extended periods of time adversely affects device reliability.

**Table 47: Absolute Maximum Ratings**

| Symbol                                                               | Description                                                                                      | Min  | Max                                | Units |
|----------------------------------------------------------------------|--------------------------------------------------------------------------------------------------|------|------------------------------------|-------|
| <b>VCC</b>                                                           | Core supply Voltage                                                                              | -0.5 | 1.42                               | V     |
| <b>VPP_2V5</b>                                                       | VPP_2V5 NVCM programming and operating supply                                                    |      |                                    | V     |
| <b>VPP_FAST</b>                                                      | Optional fast NVCM programming supply                                                            |      |                                    | V     |
| <b>VCCIO_0</b><br><b>VCCIO_1</b><br><b>VCCIO_2</b><br><b>SPI_VCC</b> | I/O bank supply voltage (I/O Banks 0, 1, and 2 plus SPI interface)                               | -0.5 | 4.00                               | V     |
| <b>VCCIO_3</b>                                                       | I/O Bank 3 supply voltage                                                                        | -0.5 | iCE65L01: 4.00<br>iCE65L04/08: 3.6 | V     |
| <b>VIN_0</b><br><b>VIN_1</b><br><b>VIN_2</b><br><b>VIN_SPI</b>       | Voltage applied to PIO pin within a specific I/O bank (I/O Banks 0, 1, and 2 plus SPI interface) | -1.0 | 5.5                                | V     |
| <b>VIN_3</b><br><b>VIN_VREF</b>                                      | Voltage applied to PIO pin within I/O Bank 3                                                     | -0.5 | iCE65L01: 4.00<br>iCE65L04/08: 3.6 | V     |
| <b>IOUT</b>                                                          | DC output current per pin                                                                        | —    | 20                                 | mA    |
| <b>T<sub>J</sub></b>                                                 | Junction temperature                                                                             | -55  | 125                                | °C    |
| <b>T<sub>STG</sub></b>                                               | Storage temperature, no bias                                                                     | -65  | 150                                | °C    |

### Recommended Operating Conditions

**Table 48: Recommended Operating Conditions**

| Symbol                                              | Description                                                |                                                                                       | Minimum                          | Nominal              | Maximum        | Units |
|-----------------------------------------------------|------------------------------------------------------------|---------------------------------------------------------------------------------------|----------------------------------|----------------------|----------------|-------|
| VCC                                                 | Core supply voltage                                        | –L: Ultra-Low Power mode                                                              | 0.95                             | 1.00                 | 1.05           | V     |
|                                                     |                                                            | –L: Low Power                                                                         | 1.14                             | 1.20                 | 1.26           | V     |
|                                                     |                                                            | –T: High Performance                                                                  |                                  |                      |                |       |
| VPP_2V5                                             | VPP_2V5 NVCM programming and operating supply              | Release from Power-on Reset                                                           | 1.30                             | —                    | 3.47           | V     |
|                                                     |                                                            | Configure from NVCM                                                                   | 2.30                             | —                    | 3.47           | V     |
|                                                     |                                                            | NVCM programming                                                                      | 2.30                             | —                    | 3.00           | V     |
| VPP_FAST                                            | Optional fast NVCM programming supply                      |                                                                                       | Leave unconnected in application |                      |                |       |
| SPI_VCC                                             | SPI interface supply voltage                               |                                                                                       | 1.71                             | —                    | 3.47           | V     |
| VCCIO_0<br>VCCIO_1<br>VCCIO_2<br>VCCIO_3<br>SPI_VCC | I/O standards, all banks*                                  | <b>LVC MOS33</b>                                                                      | 3.14                             | 3.30                 | 3.47           | V     |
|                                                     |                                                            | <b>Non-standard voltage:</b><br>in between 2.5V and 3.3V<br>use LVC MOS25 in iCEcube2 | Nominal<br>-5%                   | 2.5< Nominal<br><3.3 | Nominal<br>+5% | V     |
|                                                     |                                                            | <b>LVC MOS25, LVDS</b>                                                                | 2.38                             | 2.50                 | 2.63           | V     |
|                                                     |                                                            | <b>LVC MOS18, SubLVDS</b>                                                             | 1.71                             | 1.80                 | 1.89           | V     |
|                                                     |                                                            | <b>LVC MOS15</b>                                                                      | 1.43                             | 1.50                 | 1.58           | V     |
|                                                     |                                                            |                                                                                       |                                  |                      |                |       |
| VCCIO_3                                             | I/O standards only available<br>in iCE65L04/08 I/O Bank 3* | <b>SSTL2</b>                                                                          | 2.38                             | 2.50                 | 2.63           | V     |
|                                                     |                                                            | <b>SSTL18</b>                                                                         | 1.71                             | 1.80                 | 1.89           | V     |
|                                                     |                                                            | <b>MDDR</b>                                                                           | 1.71                             | 1.80                 | 1.89           | V     |
| T <sub>A</sub>                                      | Ambient temperature                                        | Commercial (C)                                                                        | 0                                | —                    | 70             | °C    |
|                                                     |                                                            | Industrial (I)                                                                        | –40                              | —                    | 85             | °C    |
| T <sub>PROG</sub>                                   | NVCM programming temperature                               |                                                                                       | 10                               | 25                   | 30             | °C    |

#### NOTE:

VPP\_FAST is only used for fast production programming. Leave floating or unconnected in application. When the iCE65 device is active, VPP\_2V5 must be connected to a valid voltage.

## I/O Characteristics

**Table 49: PIO Pin Electrical Characteristics**

| Symbol       | Description                                          | Conditions                                           | Minimum | Nominal | Maximum  | Units      |
|--------------|------------------------------------------------------|------------------------------------------------------|---------|---------|----------|------------|
| $I_I$        | Input pin leakage current                            | I/O Bank 0, 1, 2<br>$V_{IN} = V_{CCIO_{max}}$ to 0 V |         |         | $\pm 10$ | $\mu A$    |
|              |                                                      | I/O Bank 3<br>$V_{IN} = V_{CCIO_{max}}$              |         |         |          |            |
| $I_{OZ}$     | Three-state I/O pin (Hi-Z) leakage current           | $V_O = V_{CCIO_{max}}$ to 0 V                        |         |         | $\pm 10$ | $\mu A$    |
| $C_{PIO}$    | PIO pin input capacitance                            |                                                      |         | 6       |          | pF         |
| $C_{GBIN}$   | GBIN global buffer pin input capacitance             |                                                      |         | 6       |          | pF         |
| $R_{PULLUP}$ | Internal PIO pull-up resistance during configuration | $V_{CCIO} = 3.3V$                                    |         | 40      |          | k $\Omega$ |
|              |                                                      | $V_{CCIO} = 2.5V$                                    |         | 50      |          | k $\Omega$ |
|              |                                                      | $V_{CCIO} = 1.8V$                                    |         | 90      |          | k $\Omega$ |
|              |                                                      | $V_{CCIO} = 1.5V$                                    |         |         |          | k $\Omega$ |
|              |                                                      | $V_{CCIO} = 1.2V$                                    |         |         |          | k $\Omega$ |
| $V_{HYST}$   | Input hysteresis                                     | $V_{CCIO} = 1.5V$ to 3.3V                            |         | 50      |          | mV         |

**NOTE:** All characteristics are characterized and may or may not be tested on each pin on each device.

### Single-ended I/O Characteristics

**Table 50: I/O Characteristics (I/O Banks 0, 1, 2 and SPI only) (I/O Bank 3 iCE65L01 only)**

| I/O Standard | Nominal I/O Bank Supply Voltage | Input Voltage (V)               |           | Output Voltage (V) |          | Output Current at Voltage (mA) |          |
|--------------|---------------------------------|---------------------------------|-----------|--------------------|----------|--------------------------------|----------|
|              |                                 | $V_{IL}$                        | $V_{IH}$  | $V_{OL}$           | $V_{OH}$ | $I_{OL}$                       | $I_{OH}$ |
| LVC MOS33    | 3.3V                            | 0.80                            | 2.00      | 0.4                | 2.40     | 8                              | 8        |
| LVC MOS25    | 2.5V                            | 0.70                            | 1.70      | 0.4                | 2.00     | 6                              | 6        |
| LVC MOS18    | 1.8V                            | 35% VCCIO                       | 65% VCCIO | 0.4                | 1.40     | 4                              | 4        |
| LVC MOS15    | 1.5V                            | Not supported<br>Use I/O Bank 3 |           | 0.4                | 1.20     | 2                              | 2        |

**Table 51: I/O Characteristics (I/O Bank 3 and iCE65L04/08 only)**

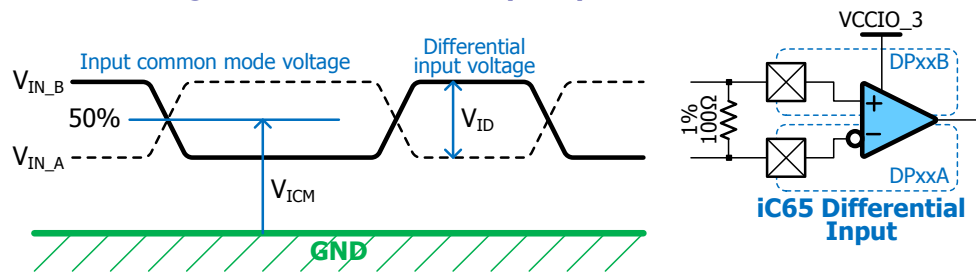
| I/O Standard    | Supply Voltage | Input Voltage (V) |               | Output Voltage (V) |               | I/O Attribute Name | mA at Voltage       |
|-----------------|----------------|-------------------|---------------|--------------------|---------------|--------------------|---------------------|
|                 |                | Max. $V_{IL}$     | Min. $V_{IH}$ | Max. $V_{OL}$      | Min. $V_{OH}$ |                    | $I_{OL}$ , $I_{OH}$ |
| LVC MOS33       | 3.3V           | 0.80              | 2.20          | 0.4                | 2.40          | SL_LVC MOS33_8     | $\pm 8$             |
| LVC MOS25       | 2.5V           | 0.70              | 1.70          | 0.4                | 2.00          | SB_LVC MOS25_16    | $\pm 16$            |
|                 |                |                   |               |                    |               | SB_LVC MOS25_12    | $\pm 12$            |
|                 |                |                   |               |                    |               | SB_LVC MOS25_8 *   | $\pm 8$             |
|                 |                |                   |               |                    |               | SB_LVC MOS25_4     | $\pm 4$             |
| LVC MOS18       | 1.8V           | 35% VCCIO         | 65% VCCIO     | 0.4                | VCCIO-0.45    | SB_LVC MOS18_10    | $\pm 10$            |
|                 |                |                   |               |                    |               | SB_LVC MOS18_8     | $\pm 8$             |
|                 |                |                   |               |                    |               | SB_LVC MOS18_4 *   | $\pm 4$             |
|                 |                |                   |               |                    |               | SB_LVC MOS18_2     | $\pm 2$             |
| LVC MOS15       | 1.5V           | 35% VCCIO         | 65% VCCIO     | 25% VCCIO          | 75% VCCIO     | SB_LVC MOS15_4     | $\pm 4$             |
|                 |                |                   |               |                    |               | SB_LVC MOS15_2 *   | $\pm 2$             |
| MDDR            | 1.8V           | 35% VCCIO         | 65% VCCIO     | 0.4                | VCCIO-0.45    | SB_MDDR10          | $\pm 10$            |
|                 |                |                   |               |                    |               | SB_MDDR8           | $\pm 8$             |
|                 |                |                   |               |                    |               | SB_MDDR4 *         | $\pm 4$             |
|                 |                |                   |               |                    |               | SB_MDDR2           | $\pm 2$             |
| SSTL2 (Class 2) | 2.5V           | VREF-0.180        | VREF+0.180    | 0.35               | VTT+0.430     | SB_SSTL2_CLASS_2   | $\pm 16.2$          |
| SSTL2 (Class 1) |                |                   |               | 0.54               |               | SB_SSTL2_CLASS_1   | $\pm 8.1$           |
| SSTL18 (Full)   | 1.8V           | VREF-0.125        | VREF+0.125    | 0.28               | VTT+0.280     | SB_SSTL18_FULL     | $\pm 13.4$          |
| SSTL18 (Half)   |                |                   |               | VTT-0.475          | VTT+0.475     | SB_SSTL18_HALF     | $\pm 6.7$           |

**NOTES:**

SSTL2 and SSTL18 I/O standards require the VREF input pin, which is only available on the CB284 package and die-based products.

## Differential Inputs

**Figure 50: Differential Input Specifications**



Input common mode voltage:

$$V_{ICM} = \frac{VCCIO\_3}{2} \pm \Delta V_{ICM}$$

Differential input voltage:

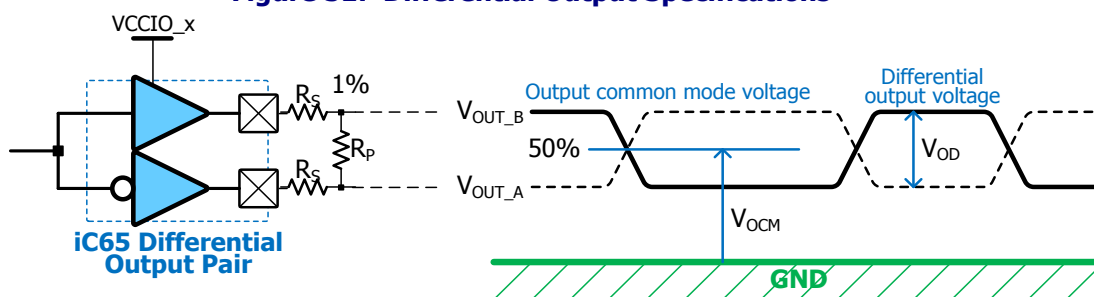
$$V_{ID} = |V_{IN\_B} - V_{IN\_A}|$$

**Table 52: Recommended Operating Conditions for Differential Inputs**

| I/O Standard   | VCCIO_3 (V) |      |      | V <sub>ID</sub> (mV) |     |     | V <sub>ICM</sub> (V)        |                      |                             |
|----------------|-------------|------|------|----------------------|-----|-----|-----------------------------|----------------------|-----------------------------|
|                | Min         | Nom  | Max  | Min                  | Nom | Max | Min                         | Nom                  | Max                         |
| <b>LVDS</b>    | 2.38        | 2.50 | 2.63 | 250                  | 350 | 450 | $\frac{VCCIO\_3}{2} - 0.30$ | $\frac{VCCIO\_3}{2}$ | $\frac{VCCIO\_3}{2} + 0.30$ |
| <b>SubLVDS</b> | 1.71        | 1.80 | 1.89 | 100                  | 150 | 200 | $\frac{VCCIO\_3}{2} - 0.25$ | $\frac{VCCIO\_3}{2}$ | $\frac{VCCIO\_3}{2} + 0.25$ |

## Differential Outputs

**Figure 51: Differential Output Specifications**



Output common mode voltage:

$$V_{OCM} = \frac{VCCIO\_x}{2} \pm \Delta V_{OCM}$$

Differential output voltage:

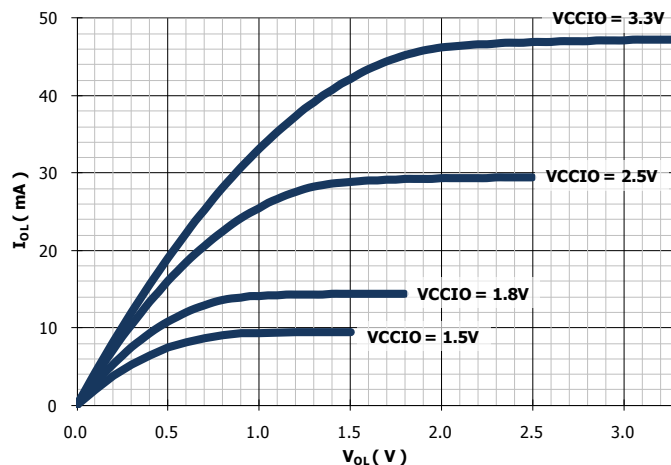
$$V_{OD} = |V_{OUT\_B} - V_{OUT\_A}|$$

**Table 53: Recommended Operating Conditions for Differential Outputs**

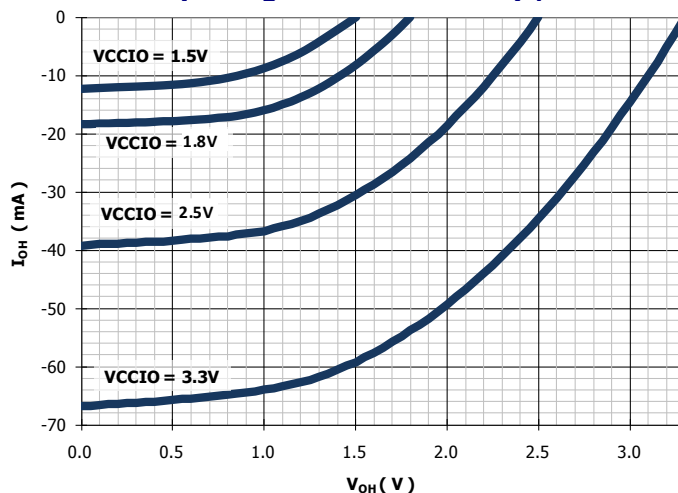
| I/O Standard   | VCCIO_x (V) |      |      | Ω              |                | V <sub>OD</sub> (mV) |     |     | V <sub>OCM</sub> (V)     |                   |                          |
|----------------|-------------|------|------|----------------|----------------|----------------------|-----|-----|--------------------------|-------------------|--------------------------|
|                | Min         | Nom  | Max  | R <sub>S</sub> | R <sub>P</sub> | Min                  | Nom | Max | Min                      | Nom               | Max                      |
| <b>LVDS</b>    | 2.38        | 2.50 | 2.63 | 150            | 140            | 300                  | 350 | 400 | $\frac{VCCIO}{2} - 0.15$ | $\frac{VCCIO}{2}$ | $\frac{VCCIO}{2} + 0.15$ |
| <b>SubLVDS</b> | 1.71        | 1.80 | 1.89 | 270            | 120            | 100                  | 150 | 200 | $\frac{VCCIO}{2} - 0.10$ | $\frac{VCCIO}{2}$ | $\frac{VCCIO}{2} + 0.10$ |

## I/O Banks 0, 1, 2 and SPI Bank Characteristic Curves

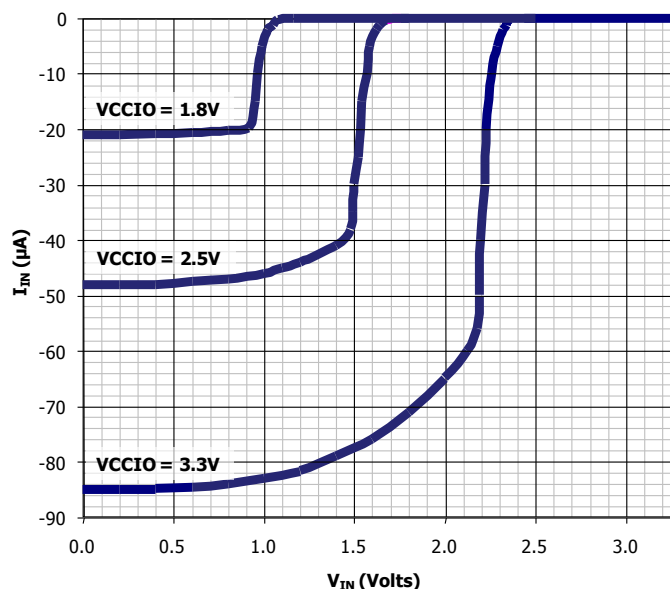
**Figure 52: Typical LVC MOS Output Low Characteristics (I/O Banks 0, 1, 2, and SPI)**



**Figure 53: Typical LVC MOS Output High Characteristics (I/O Banks 0, 1, 2, and SPI)**



**Figure 54: Input with Internal Pull-Up Resistor Enabled (I/O Banks 0, 1, 2, and SPI)**



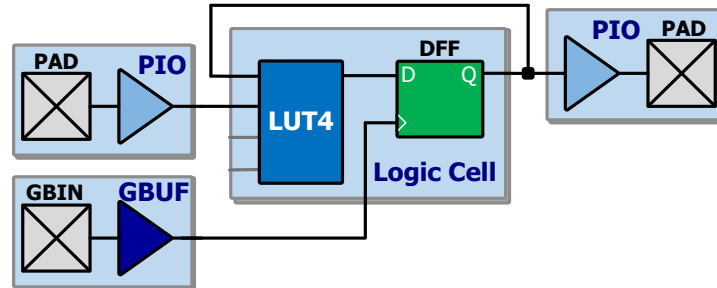
## AC Timing Guidelines

The following examples provide some guidelines of device performance. The actual performance depends on the specific application and how it is physically implemented in the iCE65 FPGA using the Lattice iCEcube software. The following guidelines assume typical conditions (VCC = 1.0 V or 1.2 V as specified, temperature = 25 °C). Apply derating factors using the iCEcube timing analyzer to adjust to other operating regimes.

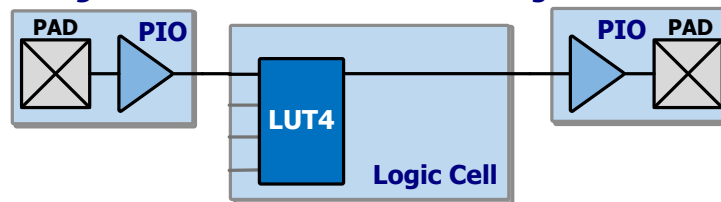
### Programmable Logic Block (PLB) Timing

Table 54 provides timing information for the logic in a Programmable Logic Block (PLB), which includes the paths shown in Figure 55 and Figure 56.

**Figure 55 PLB Sequential Timing Circuit**



**Figure 56 PLB Combinational Timing Circuit**



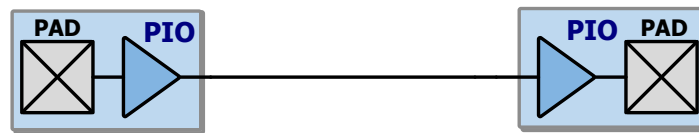
**Table 54: Typical Programmable Logic Block (PLB) Timing**

| Symbol                    | From            | To              | Device: iCE65                                                                                                                                     | L01   | L04, L08 |       | Units |     |
|---------------------------|-----------------|-----------------|---------------------------------------------------------------------------------------------------------------------------------------------------|-------|----------|-------|-------|-----|
|                           |                 |                 | Power/Speed Grade                                                                                                                                 | –T    | –L       | –T    |       |     |
|                           |                 |                 | Nominal VCC                                                                                                                                       | 1.2 V | 1.0 V    | 1.2 V |       |     |
|                           |                 |                 | Description                                                                                                                                       | Typ.  | Typ.     | Typ.  |       |     |
| Sequential Logic Paths    |                 |                 |                                                                                                                                                   |       |          |       |       |     |
| F <sub>TOGGLE</sub>       | GBIN input      | GBIN input      | Flip-flop toggle frequency. DFF flip-flop output fed back to LUT4 input with 4-input XOR, clocked on same clock edge.                             | 256   | 224      | 256   | 256   | MHz |
| t <sub>CKO</sub>          | DFF clock input | PIO output      | Logic cell flip-flop (DFF) clock-to-output time, measured from the DFF CLK input to PIO output, including interconnect delay.                     | 5.4   | 16.5     | 8.7   | 7.1   | ns  |
| t <sub>GBCKLC</sub>       | GBIN input      | DFF clock input | Global Buffer Input (GBIN) delay, though Global Buffer (GBUF) clock network to clock input on the logic cell DFF flip-flop.                       | 2.2   | 7.3      | 3.8   | 2.7   | ns  |
| t <sub>SULI</sub>         | PIO input       | GBIN input      | Minimum setup time on PIO input, through LUT4, to DFF flip-flop D-input before active clock edge on the GBIN input, including interconnect delay. | 1.0   | 4.0      | 2.1   | 1.2   | ns  |
| t <sub>HDLI</sub>         | GBIN input      | PIO input       | Minimum hold time on PIO input, through LUT4, to DFF flip-flop D-input after active clock edge on the GBIN input, including interconnect delay.   | 0     | 0        | 0     | 0     | ns  |
| Combinational Logic Paths |                 |                 |                                                                                                                                                   |       |          |       |       |     |
| t <sub>LUT4IN</sub>       | PIO input       | LUT4 input      | Asynchronous delay from PIO input pad to adjacent PLB interconnect.                                                                               | 2.6   | 9.8      | 5.2   | 3.3   | ns  |
| t <sub>ILO</sub>          | LUT4 input      | LUT4 output     | Logic cell LUT4 combinational logic propagation delay, regardless of logic complexity from input to output.                                       | 0.6   | 1.9      | 1.0   | 0.6   | ns  |
| t <sub>LUT4IN</sub>       | LUT4 output     | PIO output      | Asynchronous delay from adjacent PLB interconnect to PIO output pad.                                                                              | 4.9   | 16.0     | 8.4   | 6.6   | ns  |

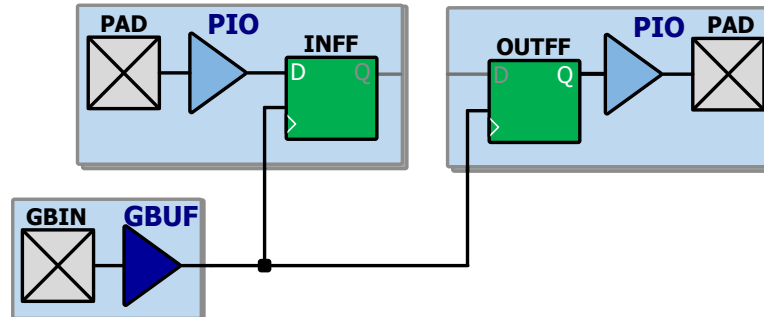
## Programmable Input/Output (PIO) Block

Table 55 provides timing information for the logic in a Programmable Logic Block (PLB), which includes the paths shown in Figure 57 and Figure 58. The timing shown is for the LVCMOS25 I/O standard in all I/O banks. The iCEcube development software reports timing adjustments for other I/O standards.

**Figure 57: Programmable I/O (PIO) Pad-to-Pad Timing Circuit**



**Figure 58: Programmable I/O (PIO) Sequential Timing Circuit**



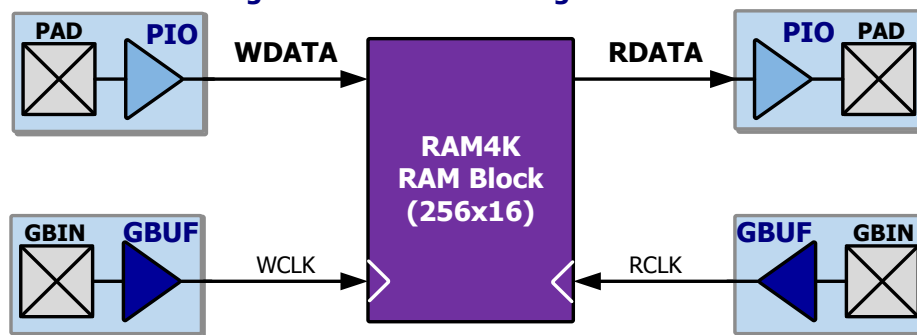
**Table 55: Typical Programmable Input/Output (PIO) Timing (LVCMOS25)**

| Symbol                   | From              | To                | Device: iCE65                                                                                                                 | L01   | L04, L08 |       |       | Units |
|--------------------------|-------------------|-------------------|-------------------------------------------------------------------------------------------------------------------------------|-------|----------|-------|-------|-------|
|                          |                   |                   | Power/Speed Grad                                                                                                              | −T    | −L       |       | −T    |       |
|                          |                   |                   | Nominal VCC                                                                                                                   | 1.2 V | 1.0 V    | 1.2 V | 1.2 V |       |
|                          |                   |                   | Description                                                                                                                   | Typ.  | Typ.     | Typ.  | Typ.  |       |
| Synchronous Output Paths |                   |                   |                                                                                                                               |       |          |       |       |       |
| t <sub>OCKO</sub>        | OUTFF clock input | PIO output        | Delay from clock input on OUTFF output flip-flop to PIO output pad.                                                           | 4.7   | 13.8     | 7.3   | 5.6   | ns    |
| t <sub>GBCKIO</sub>      | GBIN input        | OUTFF clock input | Global Buffer Input (GBIN) delay, though Global Buffer (GBUF) clock network to clock input on the PIO OUTFF output flip-flop. | 2.1   | 7.3      | 3.8   | 2.6   | ns    |
| Synchronous Input Paths  |                   |                   |                                                                                                                               |       |          |       |       |       |
| t <sub>SUPDIN</sub>      | PIO input         | GBIN input        | Setup time on PIO input pin to INFF input flip-flop before active clock edge on GBIN input, including interconnect delay.     | 0     | 0        | 0     | 0     | ns    |
| t <sub>HDPDIN</sub>      | GBIN input        | PIO input         | Hold time on PIO input to INFF input flip-flop after active clock edge on the GBIN input, including interconnect delay.       | 2.7   | 7.1      | 3.6   | 2.8   | ns    |
| Pad to Pad               |                   |                   |                                                                                                                               |       |          |       |       |       |
| t <sub>PADIN</sub>       | PIO input         | Inter-connect     | Asynchronous delay from PIO input pad to adjacent interconnect.                                                               | 2.5   | 9.5      | 5.0   | 3.2   | ns    |
| t <sub>PADO</sub>        | Inter-connect     | PIO output        | Asynchronous delay from adjacent interconnect to PIO output pad including interconnect delay.                                 | 4.5   | 14.6     | 7.7   | 6.2   | ns    |

## RAM4K Block

Table 56 provides timing information for the logic in a RAM4K block, which includes the paths shown in Figure 59.

**Figure 59: RAM4K Timing Circuit**



**Table 56: Typical RAM4K Block Timing**

| Symbol                               | From             | To               | Device: ICE65                                                                                                                    | L01   | L04, L08 |       |       | Units |
|--------------------------------------|------------------|------------------|----------------------------------------------------------------------------------------------------------------------------------|-------|----------|-------|-------|-------|
|                                      |                  |                  | Power/Speed Grade                                                                                                                | −T    | −L       | −L    | −T    |       |
|                                      |                  |                  | Nominal VCC                                                                                                                      | 1.2 V | 1.0 V    | 1.2 V | 1.2 V |       |
|                                      |                  |                  | Description                                                                                                                      | Typ.  | Typ.     | Typ.  | Typ.  |       |
| Write Setup/Hold Time                |                  |                  |                                                                                                                                  |       |          |       |       |       |
| tSUWD                                | PIO input        | GBIN input       | Minimum write data setup time on PIO inputs before active clock edge on GBIN input, include interconnect delay.                  | 0.6   | 3.1      | 1.7   | 0.8   | ns    |
| tHDWD                                | GBIN input       | PIO input        | Minimum write data hold time on PIO inputs after active clock edge on GBIN input, including interconnect delay.                  | 0     | 0        | 0     | 0     | ns    |
| Read Clock-Output-Time               |                  |                  |                                                                                                                                  |       |          |       |       |       |
| tCKORD                               | RCLK clock input | PIO output       | Clock-to-output delay from RCLK input pin, through RAM4K RDATA output flip-flop to PIO output pad, including interconnect delay. | 5.6   | 17.1     | 9.1   | 7.3   | ns    |
| tGBCKRM                              | GBIN input       | RCLK clock input | Global Buffer Input (GBIN) delay, though Global Buffer (GBUF) clock network to the RCLK clock input.                             | 2.1   | 7.3      | 3.8   | 2.6   | ns    |
| Write and Read Clock Characteristics |                  |                  |                                                                                                                                  |       |          |       |       |       |
| tRMWCKH                              | WCLK RCLK        | WCLK RCLK        | Write clock High time                                                                                                            | 0.54  | 1.14     | 0.54  | 0.54  | ns    |
| tRMWCKL                              |                  |                  | Write clock Low time                                                                                                             | 0.63  | 1.32     | 0.63  | 0.63  | ns    |
| tRMWCYC                              |                  |                  | Write clock cycle time                                                                                                           | 1.27  | 2.64     | 1.27  | 1.27  | ns    |
| FWMAX                                |                  |                  | Sustained write clock frequency                                                                                                  | 256   | 256      | 256   | 256   | MHz   |

## Internal Configuration Oscillator Frequency

Table 57 shows the operating frequency for the iCE65's internal configuration oscillator.

**Table 57: Internal Oscillator Frequency**

| Symbol     | Oscillator Mode       | Frequency (MHz) |      | Description                                                                           |
|------------|-----------------------|-----------------|------|---------------------------------------------------------------------------------------|
|            |                       | Min.            | Max. |                                                                                       |
| $f_{OSCD}$ | <b>Default</b>        | 4.0             | 6.8  | Default oscillator frequency. Slow enough to safely operate with any SPI serial PROM. |
| $f_{OSCL}$ | <b>Low Frequency</b>  | 14              | 21   | Supported by most SPI serial Flash PROMs                                              |
| $f_{OSCH}$ | <b>High Frequency</b> | 21              | 31   | Supported by some high-speed SPI serial Flash PROMs                                   |
|            | <b>Off</b>            | 0               | 0    | Oscillator turned off by default after configuration to save power.                   |

## Configuration Timing

Table 58 shows the maximum time to configure an iCE65 device, by oscillator mode. The calculations use the slowest frequency for a given oscillator mode from Table 57 and the maximum configuration bitstream size from Table 1 which includes full RAM4K block initialization. The configuration bitstream selects the desired oscillator mode based on the performance of the configuration data source.

**Table 58: Maximum SPI Master or NVCM Configuration Timing by Oscillator Mode**

| Symbol        | Description                                                                                     | Device          | Default | Low Freq. | High Freq. | Units |
|---------------|-------------------------------------------------------------------------------------------------|-----------------|---------|-----------|------------|-------|
| $t_{CONFIGL}$ | Time from when minimum Power-on Reset (POR) threshold is reached until user application starts. | <b>iCE65L01</b> | 53      | 25        | 11         | ms    |
|               |                                                                                                 | <b>iCE65L04</b> | 115     | 55        | 25         | ms    |
|               |                                                                                                 | <b>iCE65L08</b> | 230     | 110       | 50         | ms    |

Table 59 provides timing for the CRESET\_B and CDONE pins.

**Table 59: General Configuration Timing**

| Symbol    | From       | To              | Description                                                                                          | All Grades                   |      | Units        |    |
|-----------|------------|-----------------|------------------------------------------------------------------------------------------------------|------------------------------|------|--------------|----|
|           |            |                 |                                                                                                      | Min.                         | Max. |              |    |
| tCRESET_B | CRESET_B   | CRESET_B        | Minimum CRESET_B Low pulse width required to restart configuration, from falling edge to rising edge | 200                          | —    | ns           |    |
| tDONE_IO  | CDONE High | PIO pins active | Number of configuration clock cycles after CDONE goes High before the PIO pins are activated.        | —                            | 49   | Clock cycles |    |
|           |            |                 | SPI Peripheral Mode (Clock = SPI_SCK, cycles measured rising-edge to rising-edge)                    | Depends on SPI_SCK frequency |      |              |    |
|           |            |                 | NVCM or SPI Master Mode by internal oscillator frequency setting (Clock = internal oscillator)       | Default                      | 7.20 | 12.25        | μs |
|           |            |                 |                                                                                                      | Low                          | 2.34 | 3.50         | μs |
|           |            |                 |                                                                                                      | High                         | 1.59 | 2.33         | μs |

Table 60 provides various timing specifications for the SPI peripheral mode interface.

**Table 60: SPI Peripheral Mode Timing**

| Symbol          | From     | To      | Description                                                                                                                                                                    |          | All Grades |       | Units   |
|-----------------|----------|---------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------|------------|-------|---------|
|                 |          |         |                                                                                                                                                                                |          | Min.       | Max.  |         |
| $t_{CR\_SCK}$   | CRESET_B | SPI_SCK | Minimum time from a rising edge on CRESET_B until the first SPI write operation, first SPI_SCK. During this time, the iCE65 FPGA is clearing its internal configuration memory | iCE65L01 | 800        | —     | $\mu s$ |
|                 |          |         |                                                                                                                                                                                | iCE65L04 | 800        |       |         |
|                 |          |         |                                                                                                                                                                                | iCE65L08 | 1200       |       |         |
| $t_{SUSPISI}$   | SPI_SI   | SPI_SCK | Setup time on SPI_SI before the rising SPI_SCK clock edge                                                                                                                      |          | 12         | —     | ns      |
| $t_{HDSPI SI}$  | SPI_SCK  | SPI_SI  | Hold time on SPI_SI after the rising SPI_SCK clock edge                                                                                                                        |          | 12         | —     | ns      |
| $t_{SPISCKH}$   | SPI_SCK  | SPI_SCK | SPI_SCK clock High time                                                                                                                                                        |          | 20         | —     | ns      |
| $t_{SPISCKL}$   | SPI_SCK  | SPI_SCK | SPI_SCK clock Low time                                                                                                                                                         |          | 20         | —     | ns      |
| $t_{SPISCKCYC}$ | SPI_SCK  | SPI_SCK | SPI_SCK clock period*                                                                                                                                                          |          | 40         | 1,000 | ns      |
| $f_{SPI\_SCK}$  | SPI_SCK  | SPI_SCK | Sustained SPI_SCK clock frequency*                                                                                                                                             |          | 1          | 25    | MHz     |

\* = Applies after sending the synchronization pattern.

## Power Consumption Characteristics

### Core Power

Table 61 shows the power consumed on the internal VCC supply rail when the device is filled with 16-bit binary counters, measured with a 32.768 kHz and at 32.0 MHz. Low power (–L) at 1.0 V operation and high-performance (–T) version at 1.2V operation is provided.

**Table 61: VCC Power Consumption for Device Filled with 16-Bit Binary Counters**

| Symbol      | Description            | Grade | VCC  | iCE65L01 |      | iCE65L04 |      | iCE65L08 |      | Units   |
|-------------|------------------------|-------|------|----------|------|----------|------|----------|------|---------|
|             |                        |       |      | Typical  | Max. | Typical  | Max. | Typical  | Max. |         |
| $I_{CC0K}$  | $f = 0$ ,              | –L    | 1.0V | 12       |      | 26       |      | 54       |      | $\mu A$ |
|             |                        | –T    | 1.2V | 19       |      | 43       |      | 90       |      |         |
| $I_{CC32K}$ | $f \leq 32.768$<br>kHz | –L    | 1.0V | 15       |      | 31       |      | 62       |      | $\mu A$ |
|             |                        | –T    | 1.2V | 23       |      | 50       |      | 100      |      |         |
| $I_{CC32M}$ | $f = 32.0$<br>MHz      | –L    | 1.0V | 3        |      | 7        |      | 14       |      | mA      |
|             |                        | –T    | 1.2V | 4        |      | 8        |      | 17       |      |         |

### I/O Power

Table 62 provides the static current by I/O bank. The typical current for I/O Banks 0, 1, 2 and the SPI bank is not measurable within the accuracy of the test environment. The PIOs in I/O Bank 3 use different circuitry and dissipate a small amount of static current.

**Table 62: I/O Bank Static Current (f = 0 MHz)**

| Symbol         | Description |                                                                                                                                          | Typical                               | Max | Units   |
|----------------|-------------|------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------|-----|---------|
| $I_{CC0\ 0}$   | I/O Bank 0  | Static current consumption per I/O bank.<br>$f = 0$ MHz. No PIO pull-up resistors enabled. All inputs grounded. All outputs driving Low. | $\ll 1$                               |     | $\mu A$ |
| $I_{CC0\ 1}$   | I/O Bank 1  |                                                                                                                                          | $\ll 1$                               |     | $\mu A$ |
| $I_{CC0\ 2}$   | I/O Bank 2  |                                                                                                                                          | $\ll 1$                               |     | $\mu A$ |
| $I_{CC0\ 3}$   | I/O Bank 3  |                                                                                                                                          | iCE65L01: $\ll 1$<br>iCE65L04/08: 1.2 |     | $\mu A$ |
| $I_{CC0\ SPI}$ | SPI Bank    |                                                                                                                                          | $\ll 1$                               |     | $\mu A$ |

NOTE: The typical static current for I/O Banks 0, 1, 2, and the SPI bank is less than the accuracy of the device tester.

### Power Estimator

To estimate the power consumption for a specific application, please download and use the iCE65 Power Estimator Spreadsheet or use the power estimator built into the iCEcube software.

### ■ iCE65 Power Estimator Spreadsheet

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## Notes

## Revision History

| Version      | Date         | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            |
|--------------|--------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>2.42</b>  | 30-MAR-2012  | Changed company name. Updated <a href="#">Table 1</a>                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  |
| <b>2.41</b>  | 1-AUG-2011   | Added VQ100 marking for NVCM programming.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |
| <b>2.4</b>   | 13-MAY-2011  | Added L01 CB121 package <a href="#">Figure 39</a> . Added note “else VCCIO_1 draws current” to JTAG inputs TCK, TDI and TMS do not have the input pull-up resistor and must be tied off to GND when unused, <a href="#">Table 32</a> . Input pin leakage current <a href="#">Table 49</a> split by bank. QN84 package drawing, <a href="#">Figure 35</a> , added note “underside metal is at ground potential”, increased thermal resistance. Added Marking Format and Thermal resistance to CB81 Packag Mechanical Drawing <a href="#">Figure 33</a> . Added coplanarity specification to VQ100 Package Mechanical Drawing <a href="#">Figure 37</a>                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  |
| <b>2.3</b>   | 18-OCT-2010  | Added L01 CB81 and L08 CB132 packages.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                 |
| <b>2.2.3</b> | 12-OCT-2010  | Changed <a href="#">Figure 29: Application Processor Waveforms for SPI Peripheral Mode Configuration Process</a> and <a href="#">Table 60</a> from 300 µs CRESET_B to 800 µs for iCE65L01/04 and 1200 µs for iCE65L08.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                 |
| <b>2.2.2</b> | 8-OCT-2010   | Added iCE65L04 marking specification to <a href="#">Figure 47</a> CB196 Package Mechanical Drawing.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |
| <b>2.2.1</b> | 5-OCT-2010   | Changed FSPI_SCK from 0.125 MHz to 1 MHz in <a href="#">SPI Peripheral Configuration Interface</a> and in <a href="#">Table 60</a> .                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
| <b>2.2</b>   | 6-AUG-2010   | Programmable Interconnect section removed.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                             |
| <b>2.1.1</b> | 26-MAY-2010  | Switched labels on <a href="#">Figure 53</a> LVCMOS Output High, VCCIO = 1.8V with VCCIO = 2.5V.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       |
| <b>2.1</b>   | 15-MAR-2010  | Added JTAG unused input tie off guideline. Added marking specification and thermal characteristics to package drawings. Added production datasheet for iCE65L01 with timing update, including QN84, VQ100 and CB132. Added NVCM shut-off on SPI configuration. Added non-standard VCCIO operating conditions. Increased the minimum voltage supply specification for LVCMOS33 to 3.14V in <a href="#">Table 48</a> .                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
| <b>2.0.1</b> | 12-NOV-2009  | Recommended Operation Conditions, <a href="#">Table 47</a> , replaced junction with ambient.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| <b>2.0</b>   | 14-SEPT-2009 | Finalized production data sheet for iCE65L04 and iCE65L08. Improved SubLVDS input specification V <sub>ICM</sub> in <a href="#">Table 52</a> . CS63 and CC72 packages removed and placed in iCE DiCE KGD, Known Good Die datasheet. Added “IBIS Models for I/O Banks 0, 1, 2 and the SPI Bank”. Added “Printed Circuit Board Layout Information”.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                      |
| <b>1.5.1</b> | 13-JUL-2009  | Updated the text in “ <a href="#">SPI PROM Requirements</a> ” section. Minor label change in <a href="#">Figure 48</a> .                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |
| <b>1.5</b>   | 20-JUN-2009  | Updated timing information and added –T high-speed device option (affected <a href="#">Figure 2</a> , <a href="#">Table 48</a> , <a href="#">Table 54</a> , <a href="#">Table 55</a> , <a href="#">Table 56</a> , and <a href="#">Table 61</a> ). Added support for 3.3V LVCMOS I/Os in I/O Bank 3 (affected <a href="#">Figure 7</a> , <a href="#">Table 5</a> , <a href="#">Table 7</a> , <a href="#">Table 8</a> , <a href="#">Table 47</a> , <a href="#">Table 48</a> , and <a href="#">Table 51</a> ). Added a section about the <a href="#">SPI Peripheral Configuration Interface</a> and timing in <a href="#">Table 60</a> . Added a warning that a Warm Boot operation can only jump to another configuration image that has Warm Boot disabled. Updated configuration image size and configuration time for the iCE65L02 in <a href="#">Table 27</a> and <a href="#">Table 58</a> . Reduced the minimum voltage supply specification for LVCMOS33 to 2.7V in <a href="#">Table 48</a> . Added information about which power rails can be disconnected without effecting the Power-On Reset (POR) circuit and clarified description of VPP_2V5 pin in <a href="#">Table 36</a> . Added I/O characterization curves ( <a href="#">Figure 52</a> , <a href="#">Figure 53</a> , and <a href="#">Figure 54</a> ). Minor changes to <a href="#">Figure 20</a> and <a href="#">Figure 21</a> . Changed timing per <a href="#">Figures 54-58</a> and <a href="#">Tables 55-57</a> . |
| <b>1.4.4</b> | 25-MAR-2009  | Clarified the voltage requirements for the VPP_2V5 pin in <a href="#">Table 36</a> and notes under <a href="#">Table 48</a> .                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                          |
| <b>1.4.3</b> | 9-MAR-2009   | Removed volatile-only (-V) product offering from <a href="#">Figure 2</a> . Corrected NC on ball V22, removed it for ball T22 on CB284 package ( <a href="#">Figure 48</a> ).                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                          |
| <b>1.4.2</b> | 27-FEB-2009  | Updated <a href="#">Table 14</a> , <a href="#">Table 23</a> , <a href="#">Table 26</a> , <a href="#">Table 30</a> , <a href="#">Table 33</a> , <a href="#">Table 35</a> , and <a href="#">Table 46</a> . Updated I/O Bank 3 information in <a href="#">Table 7</a> and <a href="#">Table 48</a> .                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                      |
| <b>1.4.1</b> | 24-FEB-2009  | Based on characterization data, reduced 32KHz operating current by 40% in <a href="#">Table 1</a> , <a href="#">Table 61</a> , and <a href="#">Figure 1</a> . Corrected that SSTL18 standards require VREF pin in <a href="#">Table 7</a> . Correct ball numbers for GBIN4/GBIN5 for CS110 package.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |
| <b>1.4</b>   | 9-FEB-2009   | Added footprint and pinout information for the VQ100 Very-thin Quad Flat Package. Added footprint for iCE65L08 in CB196 ( <a href="#">Figure 46</a> ) and added <a href="#">Table 43</a> showing the differences between the ‘L04 and ‘L08 in the CB196 package. Unified the package footprint nomenclature in the <a href="#">Package and Pinout Information</a> section. Added note to <a href="#">Global Buffer Inputs</a> that the differential clock direct input is not available on the CB132 package. Added tables showing the ball/pin number for various control functions, by package ( <a href="#">Table 14</a> , <a href="#">Table 23</a> , <a href="#">Table 26</a> , <a href="#">Table 30</a> , and <a href="#">Table 33</a> ). Corrected the GBIN/GBUF designations. GBIN4 and GBIN5 were swapped as were GBIN6 and GBIN7. This change affected all pinout tables and footprint diagrams. Updated and corrected “Differential Global Buffer Input.” Tested and corrected the clock-enable and reset connections between global buffers and various resources ( <a href="#">Table 11</a> , <a href="#">Table 12</a> , and <a href="#">Table 13</a> ). Added “Automatic Global Buffer Insertion, Manual Insertion.” Added “Die Cross Reference” section. Improved industrial temperature range by lowering                                                                                                                                                               |

|            |             |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            |
|------------|-------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|            |             | minimum temperature to –40°C in <a href="#">Figure 2</a> and <a href="#">Table 48</a> . Added NVCM programming temperature to <a href="#">Table 48</a> .                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
| <b>1.3</b> | 17-DEC-2008 | Added footprint and pinout information for the CS110 Wafer-Level Chip-Scale Ball Grid Array. Clarified that the CB196 footprint shown is for the iCE65L04; the iCE65L08 footprint for the CB196 package is similar but different. Added updated information on <a href="#">Differential Inputs and Outputs</a> , including support for SubLVDS. Updated <a href="#">Electrical Characteristics</a> and <a href="#">AC Timing Guidelines</a> sections. Added support for the LVCMOS15 I/O standard. Corrected the diagram showing the direct differential clock input, <a href="#">Figure 16</a> . Updated the number of I/Os by package in <a href="#">Table 34</a> . Updated company address. Other minor updates throughout.                                                                                                                                                                             |
| <b>1.2</b> | 11-OCT-2008 | Updated I/O Bank 3 characteristics in <a href="#">Table 7</a> and <a href="#">Table 51</a> . Corrected label in <a href="#">Figure 14</a> . Added JTAG configuration to <a href="#">Table 20</a> . Added pull-up resistor information in <a href="#">Table 22</a> and <a href="#">Figure 21</a> . Added “ <a href="#">Internal Device Reset</a> ” section. Updated internal oscillator performance in and <a href="#">Table 57</a> . Updated configuration timing in <a href="#">Table 58</a> based on new oscillator timing. Completely reorganized the “ <a href="#">Package and Pinout Information</a> ” section. Added information on CS63 and CB196 packages. Updated information on VPP_2V5 signal in <a href="#">Table 36</a> . Reduced package height for CB132 and CB284 packages to 1.0 mm. Added “ <a href="#">Differential Inputs</a> ” and “ <a href="#">Differential Outputs</a> ” sections. |
| <b>1.1</b> | 4-SEPT-2008 | Updated package roadmap ( <a href="#">Table 2</a> ) and updated ordering codes ( <a href="#">Figure 2</a> ). Updated <a href="#">Figure 7</a> . Updated <a href="#">Figure 24</a> . Added CS63 package footprint ( <a href="#">Figure 36</a> ), pinout ( <a href="#">Table 39</a> ) and Package.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| <b>1.0</b> | 31-MAY-2008 | Initial public release.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |

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